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Renesas Electronics Corporation

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H8/38076R Group

Hardware Manual

Renesas 16-Bit Single-Chip Microcomputer
H8 Family/H8/300H Super Low Power Series

H8/38076RF

H8/38076R

H8/38075R

H8/38074R

H8/38073R

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...nally, the input pins of certain products through unpowered input pins are in their open states, intermediate levels are induced by noise in the vicinity, or through current flows internally, and a malfunction may occur.

3. Processing before Initialization

Note: When power is first supplied, the product's state is undefined.

The states of internal circuits are undefined until full power is supplied through the chip and a low level is input on the reset pin. During the period where the states are undefined, the register settings and the output state of each pin are also undefined in your system so that it does not malfunction because of processing while it is in the undefined state. For those products which have a reset function, reset the LSI immediately after the power supply has been turned on.

4. Prohibition of Access to Undefined or Reserved Addresses

Note: Access to undefined or reserved addresses is prohibited.

The undefined or reserved addresses may be used to expand functions, or test registers may have been allocated to these addresses. Do not access these registers; the operation is not guaranteed if they are accessed.

manual.

5. Contents
6. Overview
7. Description of Functional Modules
 - CPU and System-Control Modules
 - On-Chip Peripheral Modules

The configuration of the functional description of each module differs according to the module. However, the generic style includes the following items:

- i) Feature
- ii) Input/Output Pin
- iii) Register Description
- iv) Operation
- v) Usage Note

When designing an application system that includes this LSI, take notes into account. Each section includes notes in relation to the descriptions given, and usage notes are given, as required, in the final part of each section.

8. List of Registers
9. Electrical Characteristics
10. Appendix
11. Index

5. When the on-chip debugging emulator is used, address breaks can be set as either available to the user or for use by the on-chip debugging emulator. If address breaks are set as being available by the on-chip debugging emulator, the address break control registers must not be accessed by the on-chip debugging emulator.
6. When the on-chip debugging emulator is used, $\overline{\text{NMI}}$ is an input pin, P16 and P36 are input pins, and P37 is an output pin.
7. When on-board programming/erasing is performed in boot mode, the SCI3 (P41/RXD) and SCI2 (P42/TXD) is used.
8. When using the on-chip debugging emulator, set the FROMCKSTP bit in clock halt register to 1.

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H8/38076R Group manuals:

Document Title	Document ID
H8/38076R Group Hardware Manual	This manual
H8/300H Series Software Manual	REJ09BC

User's manuals for development tools:

Document Title	Document ID
H8S, H8/300 Series C/C++ Compiler, Assembler, Optimizing Linkage Editor User's Manual	REJ10BC
H8S, H8/300 Series Simulator/Debugger User's Manual	ADE-702
H8S, H8/300 Series High-performance Embedded Workshop 3 Tutorial	REJ10BC
H8S, H8/300 Series High-performance Embedded Workshop 3 User's Manual	REJ10BC



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1.2 Internal Block Diagram 3

Figure 1.1 Internal Block Diagram of H8/38076R Group

Note 2 amended

2. The SCK4, SI4, SO4, and NMI pins are not available on-chip.

1.4 Pin Functions 19

Table 1.4 Pin Functions

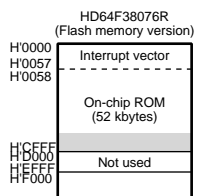
Table amended

Type	Symbol	Pin No.		Pad No. ^{*1}	Pad No. ^{*2}	I/O	Functions
		FP-80A, TFP-80C	TLP-85V				
16-bit timer pulse unit (TPU)	TIOCA1	80	A3	81	80	I/O	Pins for the TGR1A input or output comparison or PWM output.
	TIOCB1	1	B1	1	1	Input	Pins for the TGR1B input.
	TIOCA2	2	C1	2	2	I/O	Pins for the TGR2A input or output comparison or PWM output.
	TIOCB2	3	B2	3	3	Input	Pins for the TGR2B input.

2.1 Address Space and Memory Map 24

Figure 2.1 Memory Map

Figure amended



Note amended

When the on-chip debugging emulator is used, the addresses H'C000 to H'CFFF and from H'F380 to H'F77F are used by the emulator and not accessible by the user.

3.2 Reset	61, 62	Replaced
3.3 Interrupts	63	<p>Description amended</p> <p>... and WKP7 to WKP0) and 25 internal interrupts (for the memory version) or 24 internal ...</p> <p>... The interrupt controller can set interrupts other than NMI to one of three mask levels in order to control multiple interrupts. The interrupt priority registers A to E (IPRA to IPRE) of the interrupt controller set the interrupt mask level.</p>
3.5.1 Notes on Stack Area Use	66	<p>Description amended</p> <p>To save register values, use PUSH.W Rn (MOV.W Rn, @SP) or PUSH.L ERn (MOV.L ERn, @-SP). To restore registers, use POP.W Rn (MOV.W @SP+, Rn) or POP.L ERn (MOV.L @SP+, ERn).</p> <p>During interrupt exception handling or when an RTE instruction is executed, CCR contents are saved and restored in word.</p>
Section 4 Interrupt Controller	71	Description amended
4.1 Features		<ul style="list-style-type: none"> • Mask levels settable with IPR <p>An interrupt priority register (IPR) is provided for setting mask levels. Three mask levels can be set for each mode of all interrupts except NMI and address break.</p>

Register (INTM)		(Before) Priority level → (After) Mask level
4.4.1 External Interrupts	84	<p>(2) WKP7 to WKP0 Interrupts</p> <p>... The interrupt mask level can be set by IPR.</p> <p>(3) IRQ4, IRQ3, IRQ1, and IRQ0 Interrupts</p> <p>... The interrupt mask level can be set by IPR.</p> <p>(4) IRQAEC Interrupts</p> <p>... The interrupt mask level can be set by IPR.</p>
4.4.2 Internal Interrupts	85	<ul style="list-style-type: none"> The interrupt mask level can be set by IPR.
4.5 Interrupt Exception Handling Vector Table		<p>Description amended</p> <p>... The lower the vector number, the higher the priority. priority within a module is fixed. Mask levels for Interrupts other than NMI and address break can be modified by IPR.</p>

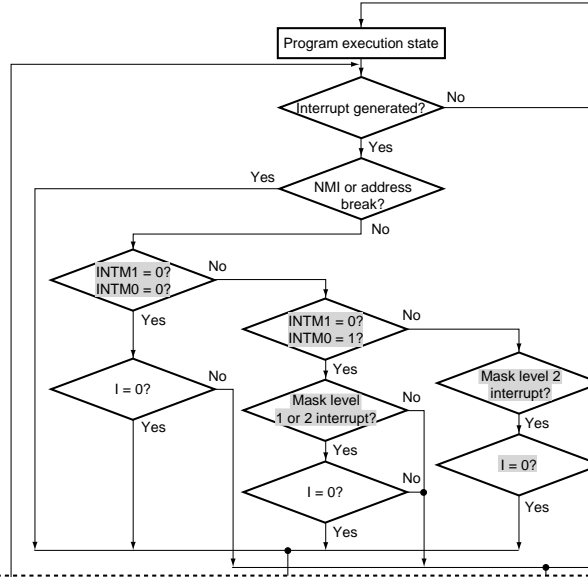
- When the I bit is cleared to 0, the INTM1 bit is cleared and the INTM0 bit is set to 1, interrupt requests with mask level 1 or 2 are held pending.

- When the I bit, INTM1 bit, and INTM0 bit are all cleared, all interrupt requests are accepted.

3. If contention occurs between interrupts that are not held pending by the INTM1 and INTM0 bits in the INTM register, the I bit in CCR, the interrupt with the highest priority as shown in table 4.2 is selected, regardless of the IPR setting.

Figure 4.2 Flowchart of Procedure Up to Interrupt Acceptance

Figure amended



1. One state for internal interrupts and two states for external interrupts.

4.7.2 Instructions that Disable Interrupts 94

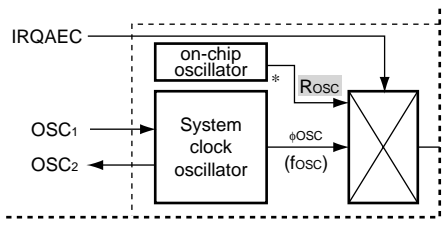
Description amended

When an interrupt request is generated, an interrupt is sent to the CPU after the interrupt controller has determined the mask level.

Section 5 Clock Pulse Generators 96

Figure amended

Figure 5.1 Block Diagram of Clock Pulse Generators (Masked ROM Version) (2)



5.2 System Clock Generator 99

Figure amended

Figure 5.2 Typical Connection to Crystal Resonator

Frequency	Manufacturer	Product Type	C ₁ , C ₂ Recommendation Value
4.19 MHz	Kyocera Kinseki Corporation	HC-491U-S	22 pF ±20%

5.2.4 On-Chip Oscillator Selection Method (Supported only by the Masked ROM Version) 100

Description amended

... The setting takes effect when the rest is cleared. When the on-chip oscillator is selected, ...

	102	Description added
		Notes on Use of Subclock Generator Circuit
		The drive capacity of the subclock generator circuit is limited in order to reduce current consumption when operating in subclock mode. As a result, there may not be sufficient margin to accommodate some resonators. Be sure to select a resonator with an equivalent series resistance (R_s) corresponding to that shown in figure 5.6.
5.3.3 External Clock Input Method	103	Title amended
5.4.1 Prescaler S		Description amended
		The output from prescaler S is shared by the on-chip peripheral modules. In active (medium-speed) mode and sleep (medium-speed) mode,
5.5.3 Definition of Oscillation Stabilization Wait Time	106, 107	Replaced
5.5.6 Note on Using Power-On Reset Circuit	108	Description amended
		The LSI's internal power-on reset circuit can be adjusted by connecting an external capacitor to the $\overline{\text{RES}}$ pin. Adjust the capacitance of the external capacitor to ensure sufficient oscillation stabilization time before reset clearing. For details, see section 21, Power-On Reset Circuit.

4: Noise Elimination Sampling Frequency Selection

The subclock pulse generator generates the signal (ϕ_w) and the system clock pulse generator generates the oscillator clock (ϕ_{osc}). This bit selects the sampling frequency of ϕ_{osc} when ϕ_w is same as ϕ_{osc} . $\phi_{osc} = 2$ to 10 MHz, clear this bit to 0. **Set it to 1 when internal oscillator is used.**

0: Sampling rate is $\phi_{osc}/16$.
 1: Sampling rate is $\phi_{osc}/4$.

1	SA1	0	R/W	Subactive Mode Clock Select 1 and 0
0	SA0	0	R/W	Select the operating clock frequency in subactive and subsleep modes. The values of SA1 and SA0 are written to in subactive mode. change if they are written to in subactive mode.
				00: $\phi_w/8$ 01: $\phi_w/4$ 1X: $\phi_w/2$

6.1.3 Clock Halt Registers 1 and 2 (CKSTPR1 and CKSTPR2) 113

Table amended

Bit	Bit Name	Initial Value	R/W	Description
7	S4CKSTP ^{*1} *	1	R/W ^{*1}	SCI4 Module Standby SCI4 enters standby mode when this bit is cleared to 0.
3	—	1	R/W	Reserved This readable/writable bit is reserved.
2	TFCKSTP	1	R/W	Timer F Module Standby Timer F enters standby mode when this bit is cleared to 0.
1	FROMCKSTP ^{*1} *	1	R/W ^{*1}	Flash Memory Module Standby Flash memory enters standby mode when this bit is cleared to 0.

mode						mode (direct transition)
0	1	0	*	1		Active (medium- speed) mode (direct transition)

Table 6.3 Internal State in Each Operating Mode

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Note amended

Function		Watch Mode	Subactive Mode	Subsleep Mode	Standby Mode
Peripheral modules	RTC	Functioning/ retained ⁹	Functioning/ retained ⁹	Functioning/ retained ⁹	Functioning/ retained ⁹
	Asynchronous event counter	Functioning ⁸	Functioning	Functioning	Functioning ^{8,6}
	Timer F	Functioning/ retained ⁷	Functioning/ retained ⁷	Functioning/ retained ⁷	Retained
	TPU	Retained	Retained	Retained	Retained
	WDT	Functioning ⁹ / retained	Functioning ⁹ / retained	Functioning ⁹ / retained	Functioning ⁹ / retained
	SCI3/IrDA	Reset	Functioning/ retained ²	Functioning/ retained ²	Reset

Notes:

6. Only incrementing of the external event timer by ECL overflow interrupts operate.

7. Functioning if $\phi w/4$ is selected as an internal clock. Hold retained otherwise.

8. Functioning if the on-chip oscillator is selected.

9. Functioning if the internal time keeping time-base function is selected and retained if the interval timer is selected.

transition takes place and a transition is made instead of watch mode.

Note: If a direct transition is attempted while the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible.

6.3.1 Direct Transition from Active (High-Speed) Mode to Active (Medium-Speed) Mode 125	Description amended
	Example: When $\phi_{osc}/8$ is selected as the CPU operating clock following transition, and the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible. Direct transition time = $(2 + 1) \times t_{osc} + 14 \times 8t_{osc} = 115t_{osc}$
6.3.2 Direct Transition from Active (High-Speed) Mode to Subactive Mode 126	Description amended
	Example: When $\phi_w/8$ is selected as the CPU operating clock following transition, and the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible. Direct transition time = $(2 + 1) \times 1t_{osc} + 14 \times 1t_{subcyc} = 3t_{osc} + 14t_{subcyc}$
6.3.3 Direct Transition from Active (Medium-Speed) Mode to Active (High-Speed) Mode 127	Description amended
	Example: When $\phi_{osc}/8$ is selected as the CPU operating clock before transition, and the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible. Direct transition time = $(2 + 1) \times 8t_{osc} + 14 \times t_{osc} = 38t_{osc}$
6.3.4 Direct Transition from Active (Medium-Speed) Mode to Subactive Mode 127	Description amended
	Example: When $\phi_{osc}/8$ is selected as the CPU operating clock before transition, and the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible. Direct transition time = $(2 + 1) \times 8t_{osc} + 14 \times 1t_{subcyc} = 24t_{osc} + 14t_{subcyc}$
6.3.5 Direct Transition from Subactive Mode to Active (High-Speed) Mode 128	Description amended
	Example: When $\phi_w/8$ is selected as the CPU operating clock before transition, and the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible. time = 8192 states Direct transition time = $(2 + 1) \times 8t_w + (8192 + 14) \times t_{osc} = 24t_w + 8192t_{osc} + 14t_{osc}$
6.3.6 Direct Transition from Subactive Mode to Active (Medium-Speed) Mode 128	Description amended
	Example: When $\phi_w/8$ is selected as the CPU operating clock before transition, and the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible. selected as the CPU operating clock following transition, and the I bit in the ICR is set to 1, the device remains in sleep or watch mode, and recovery is not possible. 8,192 states Direct transition time = $(2 + 1) \times 8t_w + (8192 + 14) \times 8t_{osc} = 24t_w + 65648t_{osc} + 112t_{osc}$

• P15/TIOCB2 pin

TPU Channel 2 Setting	Next table (1)	Next table (2)	Next table (3)	
PCR15	—	0	1	0
Pin Function	—	P15 input pin	P15 output pin	P15 input pin
				TIOCB2 input pin

Note: * When the MD1 and MD0 bits are set to B'00 and the IOB3 bit to 1, the pin function becomes the TIOCB2 input pin.

Clear PCR15 to 0 when using TIOCB2 as an input pin.

TPU Channel 2 Setting	(2)	(3)	(1)	
MD1, MD0	B'00		B'10, B'01, B'11	
IOB3 to IOB0	B'0000	B'1xxx	B'0001 to B'0111	B'xxxx
CCLR1, CCLR0	B'xx			
Output Function	—		Setting prohibited	

[Legend] x: Don't care.

	B'1xxx	B'0101 to B'0111			
CCLR1, CCLR0	—	—	—	—	Other than B'01
Output Function	—	Output compare output	—	PWM mode 1* output	PWM mode 2 output

[Legend] x: Don't care.

Note: * The output of the TIOCB2 pin is disabled.

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• P13/TIOCB1/TCLKB pin

TPU Channel 1 Setting	Next table (1)	Next table (2)		Next table (3)
		0	1	
PCR13	—	0	1	0
Pin Function	—	P13 input pin	P13 output pin	P13 input pin
				TIOCB1 input pin
		TCLKB input pin*		

Note: * When the TPSC2 to TPSC0 bits in TCR_1 or TCR_2 are set to B'101, the pin becomes the TCLKB input pin.

Clear PCR13 to 0 when using TCLKB as an input pin.

TPU Channel 1 Setting	(2)	(3)	(1)	
			B'00	B'10, B'01
MD1, MD0			B'00	B'10, B'01
IOB3 to IOB0	B'0000	B'1xxx	B'0001 to B'0111	B'xxxx
CCLR1, CCLR0	B'xx			
Output Function	—	Setting prohibited		

[Legend] x: Don't care.

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• P12/TIOCA1/TCLKA pin

Notes: 1. When the MD1 and MD0 bits are set to B'00 and the IOA3 bit to 1, the pin becomes the TIOCA1 input pin.

Clear PCR12 to 0 when using TIOCA1 as an input pin.

2. When the TPSC2 to TPSC0 bits in TCR_1 or TCR_2 are set to B'100, the pin becomes the TCLKA input pin.

Clear PCR12 to 0 when using TCLKA as an input pin.

• P31/RXD32/SDA pin

The pin function is switched as shown below according to the combination of the PCR3, ICE bit in ICCR1, and RE bit in SCR32.

ICE	0			
RE bit	0		1	
PCR31	0	1	x	
Pin Function	P31 input pin	P31 output pin	RXD32 output pin	SDA pin

[Legend] x: Don't care.

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• P30/SCK32/TMOW pin

The pin function is switched as shown below according to the combination of the TMOW bit in PMR3, PCR30 bit in PCR3, CKE bit 1 and CKE bit 0 bits in SCR32, and COM bit in SCR32.

TMOW	0			
CKE bit 1	0		1	
CKE bit 0	0		1	x
COM bit	0		1	x
PCR30	0	1	x	
Pin Function	P30 input pin	P30 output pin	SCK32 output pin	SCK32 input pin

[Legend] x: Don't care.

TMIF	0					
CKE1	0			1		
CKE0	0		1	0	1	
COM	0		1	x	x	
PCR40	0	1	x	x	x	
Pin Function	P40 input pin	P40 output pin	SCK31 output pin	SCK31 input pin	Setting prohibited	TMIF pin

[Legend] x: Don't care.

9.8.4 Pin Functions 190

Description amended

• P92/ $\overline{\text{IRQ4}}$ pin

IRQ4	0		1
PCR92	0	1	0
Pin Function	P92 input pin	P92 output pin	$\overline{\text{IRQ4}}$ input pin

9.9.3 Pin Functions 192, 193 Replaced

9.10.3 Pin Functions 197

Description amended

• PB2/AN2/ $\overline{\text{IRQ3}}$ pin

IRQ3	0		1
CH3 to CH0	Other than B'0110	B'0110	x
Pin Function	PB2 input pin	AN2 input pin	$\overline{\text{IRQ3}}$ input pin

[Legend] x: Don't care.

• PB1/AN1/ $\overline{\text{IRQ1}}$ pin

IRQ1	0		1
CH3 to CH0	Other than B'0101	B'0101	x
Pin Function	PB1 input pin	AN1 input pin	$\overline{\text{IRQ1}}$ input pin

[Legend] x: Don't care.

- If an unused pin is an output pin, it is recommended to use one of the following ways:

- Set the output of the unused pin to high and pull it up with an external resistor of approximately 100 kΩ.
- Set the output of the unused pin to low and pull it down to GND with an external resistor of approximately 100 kΩ.

10.3.5 RTC Control Register 1 (RTCCR1) 206

Table amended

Bit	Bit Name	Initial Value	R/W	Description
3	—	0	R/W*	Reserved
2 to 0	—	All 0	—	Reserved These bits are always read as 0.

Note: * Only 0 can be written to this bit.

10.3.7 Clock Source Select Register (RTCCSR) 208

Description amended

... A free running counter controls start/stop of counter operation by the RUN bit in RTCCR1. When a clock other than φw is selected, ...

Bit	Bit Name	Initial Value	R/W	Description
3	RCS3	1	R/W	Clock Source Selection
2	RCS2	0	R/W	0000: φ/8..... Free running counter operation
1	RCS1	0	R/W	0001: φ/32..... Free running counter operation
0	RCS0	0	R/W	0010: φ/128..... Free running counter operation 0011: φ/256..... Free running counter operation 0100: φ/512..... Free running counter operation 0101: φ/2048..... Free running counter operation 0110: φ/4096..... Free running counter operation 0111: φ/8192..... Free running counter operation 1000: φw/4..... RTC operation Settings other than the above are prohibited.

If an OCRFL write and compare match signal generation occur simultaneously, the compare match signal is invalid. However, if the compare match signal may or may not be generated with the written data and the counter value match. ...

227 Description amended
 (2) TCFL, OCRFL
 If an OCRFL write and compare match signal generation occur simultaneously, the compare match signal is invalid. However, if the compare match signal may or may not be generated with the written data and the counter value match. ...

11.6.3 Flag Clearing 227 Description amended
 For ST of (1) formula, please substitute the longest number of execution states in used instruction.

Section 12 16-Bit Timer Pulse Unit (TPU) 231 Description amended
 A maximum 2-phase PWM output is possible in combination with synchronous operation

12.1 Features

Table 12.1 TPU Functions 232

Table amended

Item	Channel 1	Channel 2
I/O pin	TIOCA1	TIOCA2
Input pin	TIOCB1	TIOCB2
Counter clear function	TGR compare match or input capture	TGR compare match or input capture
Compare match output	0 output	0
	1 output	0
	Toggle output	0

Table 12.2 Pin Configuration

Channel	Symbol	I/O	Function
1	TIOCA1	I/O	TGRA_1 input capture input/output capture input/output/PWM output pin
	TIOCB1	Input	TGRB_1 input capture input
2	TIOCA2	I/O	TGRA_2 input capture input/output capture input/output/PWM output pin
	TIOCB2	Input	TGRB_2 input capture input

12.3.3 Timer I/O Control Register (TIOR)

Table 12.7 TIOR_1 (Channel 1)

239 Table amended

Bit 7 IOB3	Bit 6 IOB2	Bit 5 IOB1	Bit 4 IOB0	TGRB_1 Function	Description TIOCB1 Pin Function
0	0	0	0	Output compare register	Output disabled
			1		Setting prohibited
1	0	0	0	Output compare register	Setting prohibited
			1		
			0		
			1		
			0		
			1		

Table 12.8 TIOR_2 (Channel 2)

240 Table amended

Bit 7 IOB3	Bit 6 IOB2	Bit 5 IOB1	Bit 4 IOB0	TGRB_2 Function	Description TIOCB2 Pin Function
0	0	0	0	Output compare register	Output disabled
			1		Setting prohibited
1	0	0	0	Output compare register	Setting prohibited
			1		
			0		
			1		
			0		
			1		

Functions

(2) Waveform Output by Compare Match

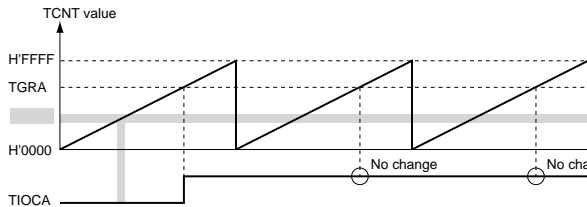
Figure 12.9 Example of 1 Output Operation

Figure 12.9 shows an example of 1 output.

... and settings have been made such that 1 is output to compare match A [REDACTED]. ...

253

Figure title and figure amended



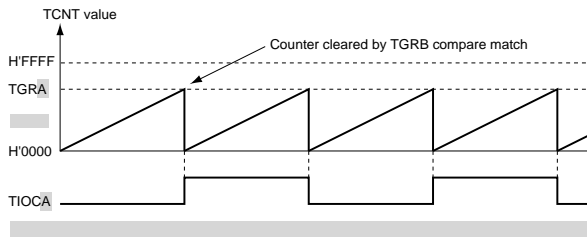
253

Description amended

In this example, TCNT has been designated as a periodic counter (with counter clearing on compare match A), and settings have been made such that the output is toggled by compare match A [REDACTED].

Figure 12.10 Example of Toggle Output Operation

Figure amended



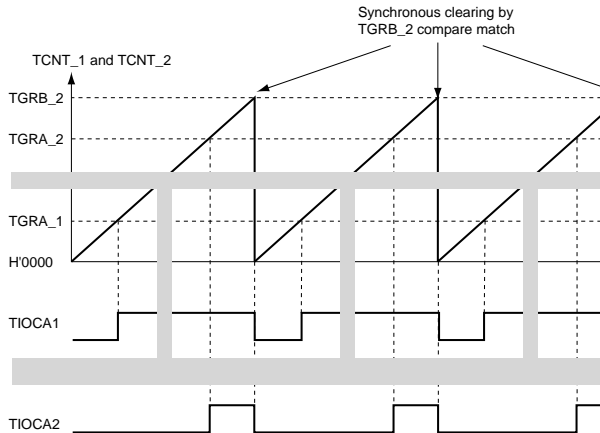
as the TGRB output value.
 ... TGRB_2 compare match is set as the TCNT clearing and 0 is set for the initial output value and 1 for the output of the other TGR registers (TGRA_1, TGRB_1, and TGRB_2) outputting a 2-phase PWM waveform.

In this case, the value set in TGRB_2 is used as the cycle

Figure 12.19
 Example of PWM
 Mode Operation (2)

262

Figure amended



13.3.1 Event
 Counter PWM
 Compare Register
 (ECPWCR)

281

Description added

Always read or write to this register in word size.

13.3.2 Event
 Counter PWM Data
 Register (ECPWDR)

282

Description added

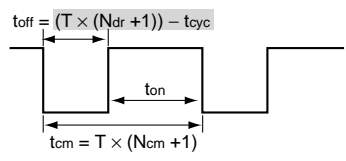
Always read or write to this register in word size.

Bit	Bit Name	Initial Value	R/W	Description
7	ECL7	0	R	Either the external asynchronous event AE
6	ECL6	0	R	$\phi/4$, or $\phi/8$ can be selected as the input clock
5	ECL5	0	R	ECL can be cleared to H'00 by clearing CR to 0.
4	ECL4	0	R	
3	ECL3	0	R	
2	ECL2	0	R	
1	ECL1	0	R	
0	ECL0	0	R	

13.4.4 Event Counter 290
PWM Operation

Figure 13.4 Event Counter Operation Waveform

Figure amended



- ton: Clock input enable time
- toff: Clock input disable time
- tcm: One conversion period
- T: ECPWM input clock period
- Ndr: Value of ECPWDR
- Fixed low when Ndr = 0
- Ncm: Value of ECPWCR
- tcyc: System clock (ϕ) cycle

Table 13.2 Examples 291
of Event Counter PWM Operation

Table amended

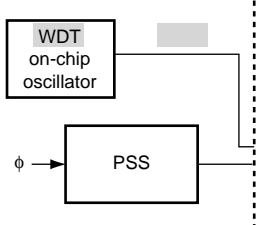
Clock Source Selection	Clock Source Cycle (T)*	ECPWCR Value (Ncm)	ECPWDR Value (Ndr)	toff = $T \times (Ndr + 1)$	tcm = $T \times (Ncm + 1)$	t
$\phi/2$	0.5 μ s	H'7A11	H'16E3	2.92975 ms	15.625 ms	1
$\phi/4$	1 μ s	D'31249	D'5859	5.85975 ms	31.25 ms	2
$\phi/8$	2 μ s			11.71975 ms	62.5 ms	5
$\phi/16$	4 μ s			23.43975 ms	125.0 ms	1
$\phi/32$	8 μ s			46.87975 ms	250.0 ms	2
$\phi/64$	16 μ s			93.75975 ms	500.0 ms	4

	294	Description added 7. If the flash version is used with the IRQAEC pin fixed level, simply switching to a mask ROM version will result in on-chip oscillator being used.
14.1 Features	295	... or the WDT on-chip oscillator can be selected as timer-counter clock.

Figure 14.1 Block Diagram of Watchdog Timer

296

Figure amended



14.2.1 Timer Control/Status Register WD1 (TCSRWD1)	298	Note * added
--	-----	--------------

Bit	Bit Name	Initial Value	R/W	Description
2	WDON	0	R/W	Watchdog Timer On* TCWD starts counting up when the WDON bit is set to 1 and halts when the WDON bit is cleared to 0.

Note: * When transitioning to the watch mode or standby mode while the main internal oscillator is selected (CKS3 = 1) using timer mode register WD (TMWD), make sure to clear the WDON bit to 0 to halt operation of TCWD.

14.3.1 Watchdog Timer Mode 302

Description amended

... The internal reset signal is output for a period of 256 cycles. ...

Figure 14.2 Example of Watchdog Timer Operation

Figure amended

(Before) $512\phi_{OSC}$ clock cycles → (After) $256\phi_{OSC}$ clock cycles

14.3.2 Interval Timer Mode 303

Figure amended

(Before) $WT/\overline{IT} = 0$ → (After) $WT/\overline{IT} = 1$

Figure 14.3 Interval Timer Mode Operation

$TME = 1$

Section 15 Serial Communication Interface 3 (SCI3, IrDA) 305

Description amended

The serial communication interface 3 (SCI3) can handle asynchronous and clocked synchronous serial communication or an Asynchronous Communication Interface Adapter

The SCI3_1 can transmit and receive IrDA ...

15.3.5 Serial Mode Register (SMR) 312

Table amended

Bit	Bit Name	Initial Value	R/W	Description
2	MP	0	R/W	5-Bit Communication
<p>When this bit is set to 1, the 5-bit communication format is enabled. When writing 1 to this bit, write 1 to bit 5 (RE) at the same time. In addition, 1 must be written to bit 3 (MPIE) in the serial mode register (SCR) before writing 1 to this bit.</p>				

enabled only, when $\phi w/2$ is selected for the operating clock.
 For the relationship between the bit rate register and the baud rate, see section 15.3.8, Bit Rate Register (BRR). n is the decimal representation of n in BRR (see section 15.3.8, Bit Rate Register (BRR)).

15.3.6 Serial Control Register (SCR) 315

Table amended

Bit	Bit Name	Initial Value	R/W	Description
3	MPIE	0	R/W	Reserved

15.3.7 Serial Status Register (SSR) 318

Table amended

Bit	Bit Name	Initial Value	R/W	Description
1	MPBR	0	R	Reserved This bit is read-only and reserved. It cannot be written to.
0	MPBT	0	R/W	Reserved The write value should always be 0.

OSC: ϕ_{osc} value (Hz)

n: Baud rate generator input clock number (n = 0, 2, or 3)

(The relation between n and the clock is shown in table 15.3)

Table 15.3
Examples of BRR
Settings for Various
Bit Rates
(Asynchronous
Mode) (1)

320

Table amended

Bit Rate (bit/s)	32.8kHz			38.4kHz			2MHz			2.05	
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N
110	—	—	—	—	—	—	2	35	-1.36	2	3
150	—	—	—	0	3	0.00	2	25	0.16	2	2
200	—	—	—	0	2	0.00	2	19	-2.34	3	4
250	—	1	2.50	—	—	—	0	249	0.00	3	3
300	—	—	—	0	1	0.00	0	207	0.16	0	2
600	—	—	—	0	0	0.00	0	103	0.16	0	1
1200	—	—	—	—	—	—	0	51	0.16	0	5
2400	—	—	—	—	—	—	0	25	0.16	0	2

Table 15.3
Examples of BRR
Settings for Various
Bit Rates
(Asynchronous
Mode) (2)

321

Table amended

Bit Rate (bit/s)	2.4576MHz			3MHz			3.6864MHz				
	n	N	Error (%)	n	N	Error (%)	n	N	Error (%)	n	N
110	3	10	-0.83	2	52	0.50	2	64	0.70	2	7
150	3	7	0.00	2	38	0.16	3	11	0.00	2	5
200	3	5	0.00	2	28	1.02	3	8	0.00	2	3
250	2	18	1.05	2	22	1.90	2	28	-0.69	2	3
300	3	3	0.00	3	4	-2.34	3	5	0.00	2	2
600	3	1	0.00	0	155	0.16	3	2	0.00	0	2

Maximum Bit Rate
for Each Frequency
(Asynchronous
Mode)

OSC (MHz)	Maximum Bit Rate (bit/s)	Setting	
		n	N
0.0328	512.5	0	0
0.0384	600	0	0
2	62500	0	0

Table 15.6 BRR
Settings for Various
Bit Rates (Clocked
Synchronous Mode)
(1)

325

Table amended

φ	32.8 kHz			38.4 kHz			2 M		
	n	N	Error (%)	n	N	Error (%)	n	N	E
200	0	20	-2.38	0	23	0.00	2	155	0
250	0	15	2.50	0	18	1.05	2	124	0
300	0	13	-2.38	0	15	0.00	2	103	0
500	0	7	2.50	—	—	—	2	62	—
1k	0	3	2.50	—	—	—	2	30	0

Table 15.6 BRR
Settings for Various
Bit Rates (Clocked
Synchronous Mode)
(2)

326

Table and note amended

φ	4 MHz			8 MHz			10 M		
	n	N	Error (%)	n	N	Error (%)	n	N	E
10k	0	99	0.00	0	199	0.00	2	15	—

Note: * Continuous transmission/reception is not possible.

The value set in BRR is given by the following formula:

Active (medium-speed/high-speed) or sleep (medium-speed/high-speed)

$$N = \frac{OSC}{4 \times 2^{2n} \times B} - 1$$

Subactive or subsleep

$$N = \frac{OSC}{8 \times 2^{2n} \times B} - 1$$

B: Bit rate (bit/s)

N: BRR setting for baud rate generator (0 ≤ N ≤ 255)

OSC: φ_{osc} value (Hz)

n: Baud rate generator input clock number (n = 0, 2, or 3)

(The relation between n and the clock is shown in table 15.7.)

Selects whether the polarity of output data of the TXD31 pin is inverted or not.
 0: Output data of TXD31 pin is not inverted.
 1: Output data of TXD31 pin is inverted.

RXD31 Pin Input Data Inversion Switch
 Selects whether the polarity of input data of the RXD31 pin is inverted or not.
 0: Input data of RXD31 pin is not inverted.
 1: Input data of RXD31 pin is inverted.

0 SCINV0 0 R/W

15.4.1 Clock 332

Table 15.8 Data Transfer Formats (Asynchronous Mode)

Table amended

SMR				Serial Data Transfer Format and Frame Length										
CHR	PE	MP	STOP	1	2	3	4	5	6	7	8	9	10	11
0	0	1	0	Setting prohibited										
0	0	1	1	Setting prohibited										
1	0	1	0	Setting prohibited										
1	0	1	1	Setting prohibited										

Table 15.9 SMR 333

Settings and Corresponding Data Transfer Formats

Table amended

SMR						Data Transfer Format		
Bit 7 COM	Bit 6 CHR	Bit 2 MP	Bit 5 PE	Bit 3 STOP	Mode	Data Length	Parity Bit	Stop Length
0	0	1	0	0	Asynchronous mode	Setting prohibited		
				1				
			1	0		5-bit data	No	1 bit
			1	1				
	1		0	0		Setting prohibited		
			1	1				
			1	0		5-bit data	Yes	1 bit
			1	1				

15.4.2 SCI3 335

Initialization
 Figure 15.4 Sample SCI3 Initialization Flowchart

Figure amended

[4] Wait at least one bit interval, then set the TE bit or PE bit of the SCR to 1. Setting bits TE and RE enables the TXD31 (TXD32) and RXD31 (RXD32) pins to be used. Also set the RIE and TEIE bits,



15.6 Multiprocessor Communication Function	—	Deleted
15.6.1 Transmission	348	Description amended ... a high-level pulse width of at least 1.41 μs to 1.6 μs c specified.
Figure 15.16 IrDA Transmission and Reception	349	Figure amended (Before) ... 3/16 bit cycle → (After) ... 3/16 bit rate
15.6.2 Reception	349	Description amended If a pulse has a high-level width of less than 1.41 μs, ...
15.8.2 Mark State and Break Sending	354	Description amended Regardless of the value of TE, when the SPCR31 (SPC in SPCR is cleared to 0, the TXD31 (TXD32) pin is used I/O port whose direction (input or output) and level are determined by PCR and PDR. This can be used to set the TXD31 (TXD32) pin to mark state (high level) or send a during serial data transmission. To maintain the commu line at mark state (1) until SPCR31 (SPCR32) in SPCR 1, set both PCR and PDR to 1. As SPCR31 (SPCR32) i is cleared to 0 at this point, the TXD31 (TXD32) pin bec I/O port, and 1 is output from the TXD31 (TXD32) pin. T break during serial transmission, first set PCR to 1 and then clear SPCR31 (SPCR32) and TE to 0. If TE is to 0 immediately after SPCR31 (SPCR32) is cleared to transmitter is initialized regardless of the current transm state after TE is cleared, and when SPCR31 (SPCR32) cleared to 0 the TXD31 (TXD32) pin becomes an I/O po is output from it.

18.7 Usage Notes 396

Description amended

If a large capacitance is provided externally as a countermeasure, the input load essentially comprises of internal input resistance of 10 k Ω , and the signal source impedance can be ignored.

18.7.3 Additional Usage Notes 397

Title amended

19.3.1 LCD Port Control Register (LPCR) 402

Table amended

Table 19.2 Duty Cycle and Common Function Selection

Bit 7: DTS1	Bit 6: DTS0	Bit 5: CMX	Duty Cycle	Common Drivers	Notes [⊗]
0	0	0	Static	COM1	Leave COM4, COM3, and COM2 in state
		1		COM4 to COM1	COM4, COM3, and COM2 output the waveform as COM1
	1	0	1/2 duty	COM2 to COM1	Leave COM4 and COM3 in open drain state
		1		COM4 to COM1	COM4 outputs the same waveform as COM2 outputs the same waveform
1	0	0	1/3 duty	COM3 to COM1	Leave COM4 in open drain state
		1		COM4 to COM1	Leave COM4 in open drain state
	1	0	1/4 duty	COM4 to COM1	—
		1			

Note: [⊗] If SGS3 to SGS0 are set to B'0000, the power supply voltage level of PA0 to PA3 and COM4 is V_{CC}. If the setting of SGS3 to SGS0 is other than B'0000, the power supply voltage level of PA0 to PA3 and COM1 to COM4 is the LCD drive power supply voltage level.

19.3.2 LCD Control Register (LCR) 403

Note 3 amended

Table 19.4 Frame Frequency Selection

3. This is the frame frequency in active (medium-speed mode) when $\phi_{OSC} = 2$ MHz.

$$V2 \text{ voltage} = (A + B + C) \times 2/3$$

$$V3 \text{ voltage} = (A + B + C) / 3$$

After monitoring voltage A, set B and C so the voltage is 3 V.

19.3.5 BGR Control Register (BGRMR) 409

Description amended

Bit	Bit Name	Initial Value	R/W	Description
2 to 0		All 0	R/W	Reserved <small>This bit is always read as 0, and only 0 can be written to it.</small>

19.4.3 3-V Constant-Voltage Power Supply Circuit 417

Note 4 added

4. Initially, the step-up circuit output voltage differs among individual devices due to production variation. Therefore, be sure to adjust the settings of the LCD trimming register individually for each device.

19.5 Usage Notes 420

Added

19.5.1 Pin Processing when No LCD Controller/Driver Is Used

19.5.2 Pin Processing when No 3 V Constant Voltage Circuit Is Used

If the $\overline{\text{RES}}$ pin rising time is t , the capacitance (C_{RES}) connected to the $\overline{\text{RES}}$ pin can be computed using the formula below. For more information about the on-chip resistor (R_p), see section Electrical Characteristics. The power supply rising time should not exceed half the $\overline{\text{RES}}$ rising time (t). The $\overline{\text{RES}}$ rising time should also equal or exceed the oscillation stabilization

23.1 Register Addresses (Address Order)

472

Table amended

Register Name	Abbreviation	Bit No.	Address	Module Name	Description
Event counter H	ECH	8	H'FF96	AEC* ¹	8/
Event counter L	ECL	8	H'FF97	AEC* ¹	8/

473

Register Name	Abbreviation	Bit No.	Address	Module Name	Description
8-bit timer counter FH	TCFH	8	H'FFB8	Timer F	8/
8-bit timer counter FL	TCFL	8	H'FFB9	Timer F	8/
Output compare register FH	OCRFH	8	H'FFBA	Timer F	8/
Output compare register FL	OCRFL	8	H'FFBB	Timer F	8/

23.2 Register Bits

477

Table amended

Register Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
IPRA	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0

479

Register Abbreviation	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
SMR3_2	COM	CHR	PE	PM	STOP	MP	CKS1	CKS0
BRR3_2	BRR7	BRR6	BRR5	BRR4	BRR3	BRR2	BRR1	BRR0
SCR3_2	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
TDR3_2	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR1	TDR0
SSR3_2	TDRE	RDRF	OER	FER	PER	TEND	MPBR	MPB0
RDR3_2	RDR7	RDR6	RDR5	RDR4	RDR3	RDR2	RDR1	RDR0

TSR_1	Initialized	—	—	—	—	—	—	■
TCNT_1	Initialized	—	—	—	—	—	—	■
TGRA_1	Initialized	—	—	—	—	—	—	■
TGRB_1	Initialized	—	—	—	—	—	—	■
TCR_2	Initialized	—	—	—	—	—	—	■
TMDR_2	Initialized	—	—	—	—	—	—	■
TIOR_2	Initialized	—	—	—	—	—	—	■
TIER_2	Initialized	—	—	—	—	—	—	■
TSR_2	Initialized	—	—	—	—	—	—	■
TCNT_2	Initialized	—	—	—	—	—	—	■
TGRA_2	Initialized	—	—	—	—	—	—	■
TGRB_2	Initialized	—	—	—	—	—	—	■

483

Register Abbreviation	Reset	Active	Sleep	Watch	Subactive	Subsleep	Standby	M
RTCFLG	■	—	—	—	—	—	—	R
RSECDR	■	—	—	—	—	—	—	
RMINDR	■	—	—	—	—	—	—	
RHRDR	■	—	—	—	—	—	—	
RWKDR	—	—	—	—	—	—	—	
RTCCR1	—	—	—	—	—	—	—	
RTCCR2	—	—	—	—	—	—	—	

24.2.2 DC
Characteristics

491

Table amended

Table 24.2 DC
Characteristics

Item	Symbol	Applicable Pins	Test Condition	Values		
				Min.	Typ.	Max.
Input high voltage	V_{IH}	RES, NMI*, WKP0 to WKP7, IRQ4, AEVL, AEVH, TMIF, ADTRG, SCK32, SCK31, SCK4		0.9V _{CC}	—	V _{CC} + 0.3
		IRQ0, IRQ1, IRQ3		0.9V _{CC}	—	AV _{CC} + 0.3

24.2.3 AC
Characteristics

497

Table amended

Table 24.3 Control
Signal Timing

Item	Symbol	Applicable Pins	Test Condition	Values				
				Min.	Typ.	Max.		
Oscillation stabilization time	t_s	OSC1, OSC2	Crystal resonator (V _{CC} = 2.7 to 3.6 V)	—	0.8	2.0		
				Crystal resonator (V _{CC} = 2.2 to 3.6 V)	—	1.2	3	
				Ceramic resonator (V _{CC} = 2.2 to 3.6 V)	—	20	45	
				Ceramic resonator (other than above)	—	80	—	
				Other than above	—	—	50	
				×1, ×2	V _{CC} = 2.2 to 3.6 V	—	—	2.0
				Other than above	—	—	4	—

Table 24.5 I²C Bus
Interface Timing

500

Condition amended

V_{CC} = 1.8 V to 3.6 V, AV_{CC} = 1.8 V to 3.6 V, V_{SS} = 0.0 V, to +75°C, unless otherwise specified.

Characteristics

Table 24.8 Power-On Reset Circuit Characteristics

Item	Symbol	Test Condition	Values			Unit
			Min.	Typ.	Max.	
Reset voltage	V _{rst}		0.7V _{cc}	0.8V _{cc}	0.9V _{cc}	V
Power supply rise time	t _{vtr}		The V _{cc} rise time should be shorter than half the RES rise time.			
Reset count time	t _{out}		0.8	—	8.0	μs
Count start time	t _{cr}		Adjustable by the value of the external capacitance of the RES pin.			
On-chip pull-up resistance	R _p	V _{cc} = 3.0 V	60	100	—	kΩ

24.2.8 Flash Memory Characteristics—Preliminary—

Condition A amended

$AV_{CC} = 2.7\text{ V to }3.6\text{ V}$, $DV_{CC} = 2.7\text{ V to }3.6\text{ V}$, $V_{SS} = AV_{SS} - 0.0\text{ V}$, ...

Table 24.10 Flash Memory Characteristics

Condition B amended

$AV_{CC} = 1.8\text{ V to }3.6\text{ V}$, $DV_{CC} = 2.2\text{ V to }3.6\text{ V}$, $V_{SS} = AV_{SS} - 0.0\text{ V}$, ...

24.4.1 Power Supply Voltage and Operating Range

Note 1 amended

... the minimum operating frequency (ϕ) is 2 MHz

(2) Power Supply Voltage and Operating Frequency Range

24.4.2 DC Characteristics

Table amended

Table 24.12 DC Characteristics

Item	Symbol	Applicable Pins	Test Condition	Values			Unit
				Min.	Typ.	Max.	
Input high voltage	V _{ih}	RES, NMI, WKP0 to WKP7, IRQ4, AEVL, AEVH, TMIF, ADTRG, SCK32, SCK31		0.9V _{cc}	—	V _{cc} + 0.3	V
		IRQ0, IRQ1, IRQ3		0.9V _{cc}	—	AV _{cc} + 0.3	

Characteristics

Table 24.13 Control Signal Timing

Item	Symbol	Applicable Pins	Test Condition	Values			Unit
				Min.	Typ.	Max.	
System clock oscillation frequency	f_{osc}	OSC1, OSC2	$V_{cc} = 2.7$ to 3.6 V	2.0	—	10.0	MHz
			$V_{cc} = 1.8$ to 3.6 V	2.0	—	4.2	
On-chip oscillator oscillation frequency	R_{osc}		When on-chip oscillator is selected $V_{cc} = 2.7$ to 3.6 V	1.0	—	10.0	
			When on-chip oscillator is selected $V_{cc} = 1.8$ to 2.7 V	0.5	—	4.2	
OSC clock (ϕ_{osc}) cycle time	t_{osc}	OSC1, OSC2	$V_{cc} = 2.7$ to 3.6 V	100	—	500 (1000)	ns
			$V_{cc} = 1.8$ to 3.6 V	238	—	500 (1000)	
On-chip oscillator clock (ϕ_{osc}) cycle time	t_{osc}		When on-chip oscillator is selected $V_{cc} = 2.7$ to 3.6 V	100	—	1000	
			When on-chip oscillator is selected $V_{cc} = 1.8$ to 2.7 V	238	—	2000	

517

Item	Symbol	Applicable Pins	Test Condition	Values			Unit
				Min.	Typ.	Max.	
Oscillation stabilization time	t_s	OSC1, OSC2	Crystal resonator $V_{cc} = 2.7$ to 3.6 V	—	0.8	2.0	ms
			Crystal resonator $V_{cc} = 2.2$ to 3.6 V	—	1.2	3.0	
			Ceramic resonator $V_{cc} = 2.2$ to 3.6 V	—	20	45	μ s
			Ceramic resonator Other than above	—	80	—	
			Other than above	—	—	50	ms
			When on-chip oscillator is selected	—	—	100	μ s
			X1, X2	$V_{cc} = 2.2$ to 3.6 V	—	—	2.0
	Other than above	—	4	—			

Converter
Characteristics

$V_{CC} = 1.8\text{ V to }3.6\text{ V}$, $AV_{CC} = 1.8\text{ V to }3.6\text{ V}$, $V_{SS} = 0.0\text{ V}$,
otherwise specified.

Table 24.16 A/D
Converter
Characteristics

522

Item	Symbol	Applicable Pins	Test Condition	Values			Unit
				Min.	Typ.	Max.	
Conversion time			$AV_{CC} = 2.7\text{ V to }3.6\text{ V}$ $V_{CC} = 2.7\text{ V to }3.6\text{ V}$	6.2	—	124	μs
			$AV_{CC} = 2.0\text{ V to }3.6\text{ V}$ $V_{CC} = 2.0\text{ V to }3.6\text{ V}$	14.7	—	124	
			Other than above	31	—	124	

24.4.6 Power-On
Reset Circuit
Characteristics

524

Table amended

Table 24.18 Power-
On Reset Circuit
Characteristics

Item	Symbol	Test Condition	Values			Unit
			Min.	Typ.	Max.	
Reset voltage	V_{rst}		0.7V _{CC}	0.8V _{CC}	0.9V _{CC}	V
Power supply rise time	t_{vtr}		The V _{CC} rise time should be shorter than half the RES rise time.			
Reset count time	t_{out}		0.8	—	4.0	μs
Count start time	t_{cr}		Adjustable by the value of the external capacitor of the RES pin.			
On-chip pull-up resistance	R_p	$V_{CC} = 3.0\text{ V}$	60	100	—	k Ω

24.4.7 Watchdog
Timer Characteristics

525

Table amended

Table 24.19 Watchdog
Timer Characteristics

(Before) On-chip oscillator overflow time
(After) **WDT** on-chip oscillator overflow time

24.7 Recommended
Resonators

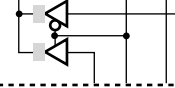
529

Table amended

Table 24.20
Recommended Crystal
Resonators

Frequency (MHz)	Manufacturer	Product Type
4.194	Kyocera Kinseki Corporation	HC-491U-S
10	Kyocera Kinseki Corporation	HC-491U-S

V_{SS}



C. Product Code 581
Lineup

Table amended

Product Classification				Product Code	Model Marking	Pack (Pac)
H8/38076R Group	H8/38076R	Flash memory version	Wide-rang specifications	HD64F38076RH10W	F38076H10	80 p
				HD64F38076RW10W	F38076W10	80 p
				HD64F38076RLP10WV	F38076RLP10WV	80 p (TLF)

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4.3.2	Wakeup Edge Select Register (WEGR).....
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4.3.4	Interrupt Enable Register 2 (IENR2)
4.3.5	Interrupt Request Register 1 (IRR1)
4.3.6	Interrupt Request Register 2 (IRR2)
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	9.1.5	Pin Functions
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9.4.4	Port Mode Register 5 (PMR5)
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9.6.1	Port Data Register 7 (PDR7).....
9.6.2	Port Control Register 7 (PCR7)
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9.8	Port 9.....
9.8.1	Port Data Register 9 (PDR9).....
9.8.2	Port Control Register 9 (PCR9)
9.8.3	Port Mode Register 9 (PMR9)
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RTC (can be used as a free-running counter)

Asynchronous event counter (AEC)

LCD controller/driver

Timer F

16-bit timer pulse unit (TPU)

14-bit PWM

Watchdog timer

SCI (Asynchronous or clocked synchronous serial communication interface)

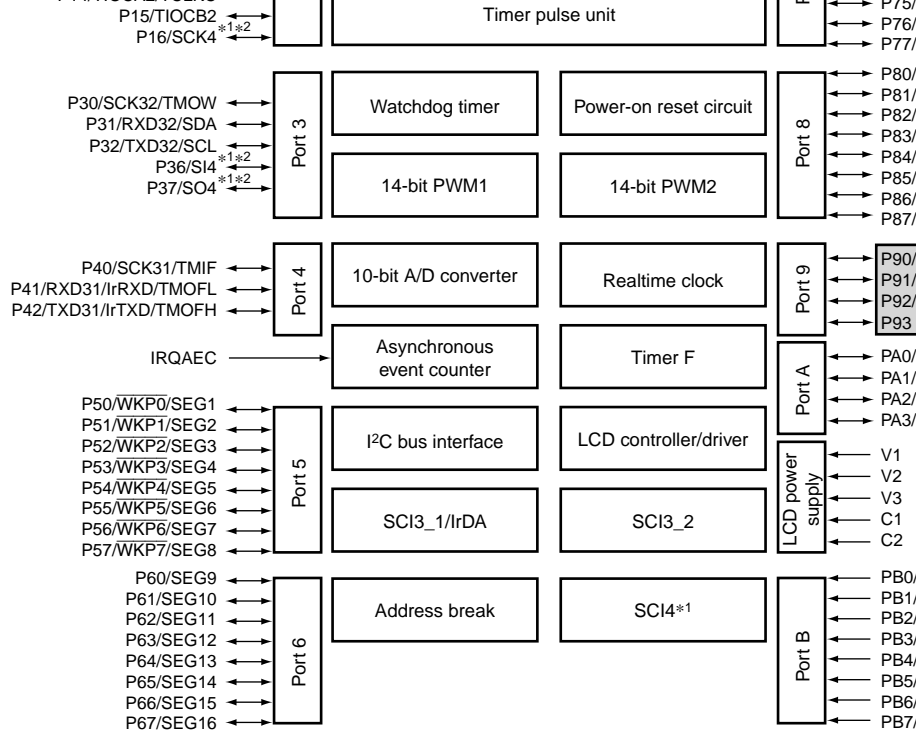
I²C bus interface (conforms to the I²C bus interface format that is advocated by Philips Electronics)

10-bit A/D converter

* 4-kbyte area of 52-kbyte ROM is used for the on-chip debugging emulator. When the on-chip debugging emulator is not used, 52-kbyte area is available.

- General I/O ports
I/O pins: 55 I/O pins, including 4 large current ports ($I_{OL} = 15 \text{ mA}$, @ $V_{OL} = 1.0 \text{ V}$)
Input-only pins: 8 input pins
- Supports various power-down states
- Compact package

Package	Code	Old Code	Body Size	Pin Pitch	Ren
QFP-80	PRQP0080JB-A	FP-80A	14 × 14 mm	0.65 mm	
TQFP-80	PTQP0080KC-A	TFP-80C	12 × 12 mm	0.5 mm	
P-TFLGA-85	PTLG0085JA-A	TLP-85V	7 × 7 mm	0.65 mm	



- Notes:
1. The SCI4 pins, such as SCK4, SI4, and SO4, are supported only by the F-ZTAT version.
 2. The SCK4, SI4, SO4, and NMI pins are not available when the on-chip emulator debugger is used. These pins are not available as ports.
 3. Supported only by the masked ROM version.

Figure 1.1 Internal Block Diagram of H8/38076R Group

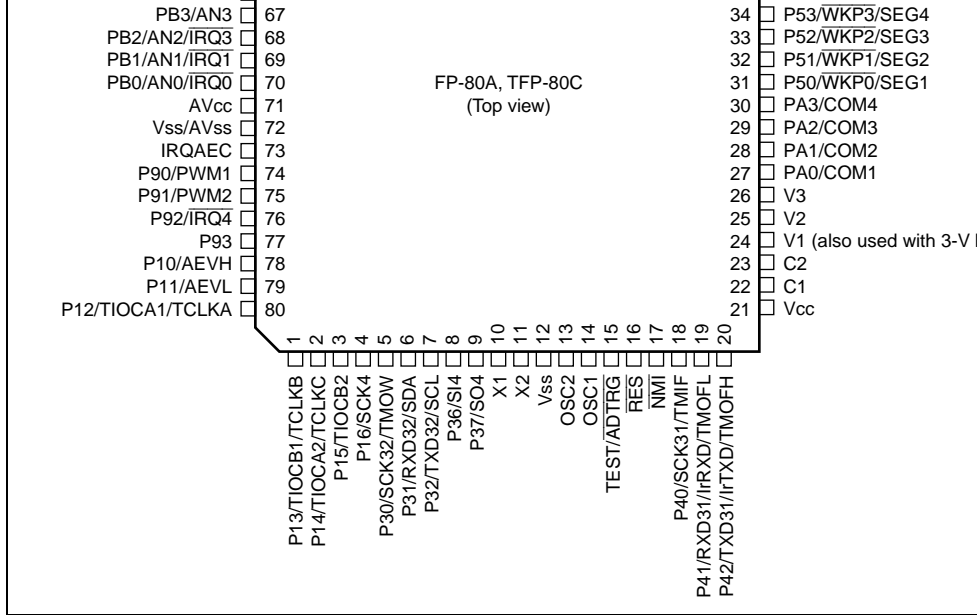
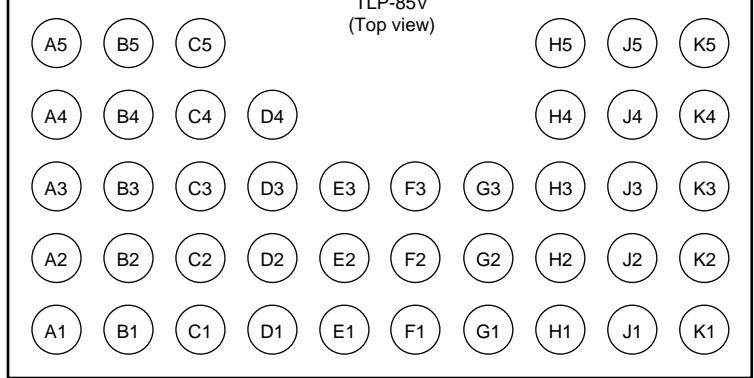


Figure 1.2 Pin Assignment of H8/38076R Group (FP-80A, TFP-80C)



Note: For details on pin correspondence, refer to table 1.1.

Figure 1.3 Pin Assignment of H8/38076R Group (TLP-85V)

P32/TXD32/SCL	D2
P36/SI4	E1
P37/SO4	E3
X1	F2
X2	E2
Vss	F3
OSC2	G3
OSC1	F1
TEST/ADTRG	G2
RES	H2
NMI	G1
P40/SCK31/TMIF	H3
P41/RXD31/IrRXD/TMOFL	J1
P42/TXD31/IrTXD/TMOFH	H1
NC	K1
Vcc	K2
C1	K3
C2	J2
V1	J3
V2	K4
V3	H4
PA0/COM1	J4
PA1/COM2	K5

P55/WKP5/SEG6	J8
P56/WKP6/SEG7	K7
P57/WKP7/SEG8	H8
P60/SEG9	K9
P61/SEG10	K8
NC	K10
P62/SEG11	J10
P63/SEG12	H10
P64/SEG13	J9
P65/SEG14	H9
P66/SEG15	G10
P67/SEG16	G8
P70/SEG17	G9
P71/SEG18	F10
P72/SEG19	F8
P73/SEG20	E9
P74/SEG21	F9
P75/SEG22	E8
P76/SEG23	D8
P77/SEG24	E10
P80/SEG25	D9
P81/SEG26	C9
P82/SEG27	D10
P83/SEG28	C8

PB5/AN5	A7
PB4/AN4	C7
PB3/AN3	B7
PB2/AN2/ $\overline{\text{IRQ3}}$	A6
PB1/AN1/ $\overline{\text{IRQ1}}$	C6
PB0/AN0/ $\overline{\text{IRQ0}}$	B5
Avcc	B6
Vss/Avss	C5
IRQAEC	C4
P90/PWM1	A5
P91/PWM2	B4
P92/ $\overline{\text{IRQ4}}$	B3
P93	A4
P10/AEVH	C3
P11/AEVL	A2
P12/TIOCA1/TCLKA	A3
NC	A1
NC	D4

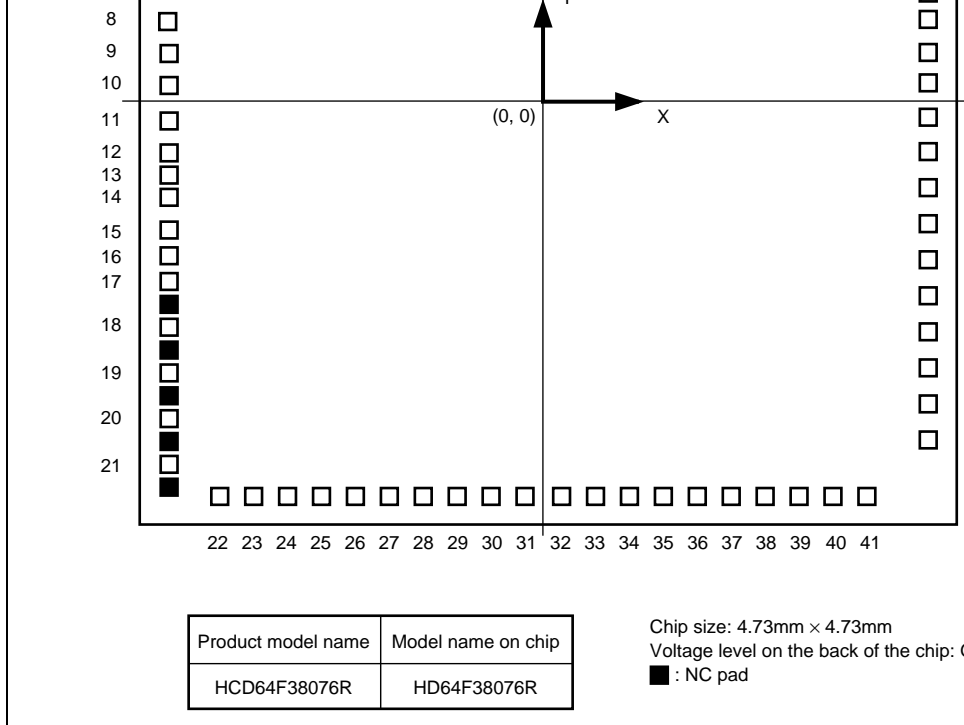


Figure 1.4 Pad Assignment of HCD64F38076R (Top View)

7	P32/TXD32/SCL	-2223	732
8	P36/SI4	-2223	523
9	P37/SO4	-2223	314
10	X1	-2223	105
11	X2	-2223	-105
12	AVss	-2223	-314
13	Vss	-2223	-418
14	OSC2	-2223	-523
15	OSC1	-2223	-732
16	TEST/ADTRG	-2223	-941
17	$\overline{\text{RES}}$	-2223	-1150
18	$\overline{\text{NMI}}$	-2223	-1360
19	P40/SCK31/TMIF	-2223	-1569
20	P41/RXD31/IrRXD/TMOFL	-2223	-1778
21	P42/TXD31/IrTXD/TMOFH	-2223	-1987
22	Vcc	-1987	-2223
23	C1	-1775	-2223
24	C2	-1569	-2223
25	V1	-1360	-2223
26	V2	-1150	-2223
27	V3	-941	-2223
28	PA0/COM1	-732	-2223
29	PA1/COM2	-523	-2223

37	P55/WKP5/SEG6	1150	-2223
38	P56/WKP6/SEG7	1360	-2223
39	P57/WKP7/SEG8	1569	-2223
40	P60/SEG9	1778	-2223
41	P61/SEG10	1987	-2223
42	P62/SEG11	2223	-1987
43	P63/SEG12	2223	-1778
44	P64/SEG13	2223	-1569
45	P65/SEG14	2223	-1360
46	P66/SEG15	2223	-1150
47	P67/SEG16	2223	-941
48	P70/SEG17	2223	-732
49	P71/SEG18	2223	-523
50	P72/SEG19	2223	-314
51	P73/SEG20	2223	-105
52	P74/SEG21	2223	105
53	P75/SEG22	2223	314
54	P76/SEG23	2223	523
55	P77/SEG24	2223	660
56	P80/SEG25	2223	941
57	P81/SEG26	2223	1222
58	P82/SEG27	2223	1360
59	P83/SEG28	2223	1569
60	P84/SEG29	2223	1778

68	PB3/AN3	732	2223
69	PB2/AN2/ $\overline{\text{IRQ3}}$	523	2223
70	PB1/AN1/ $\overline{\text{IRQ1}}$	314	2223
71	PB0/AN0/ $\overline{\text{IRQ0}}$	105	2223
72	AVcc	-105	2223
73	Vss/AVss	-314	2223
74	IRQAEC	-523	2223
75	P90/PWM1	-732	2223
76	P91/PWM2	-941	2223
77	P92/ $\overline{\text{IRQ4}}$	-1150	2223
78	P93	-1360	2223
79	P10/AEVH	-1569	2223
80	P11/AEVL	-1778	2223
81	P12/TIOCA1/TCLKA	-1987	2223

Note: The power supply (Vss) pads in pad numbers 12 and 13 must not be open but connected to the Vss voltage level. When the TEST pad in pad number 16 is not used as the $\overline{\text{ADTRG}}$ pin, it must be connected to the Vss voltage level. If not, this LSI does not operate correctly. When the TEST pad is used as the $\overline{\text{ADTRG}}$ pin, the function should be changed to $\overline{\text{ADTRG}}$ pin at Vss voltage level during a reset in advance.

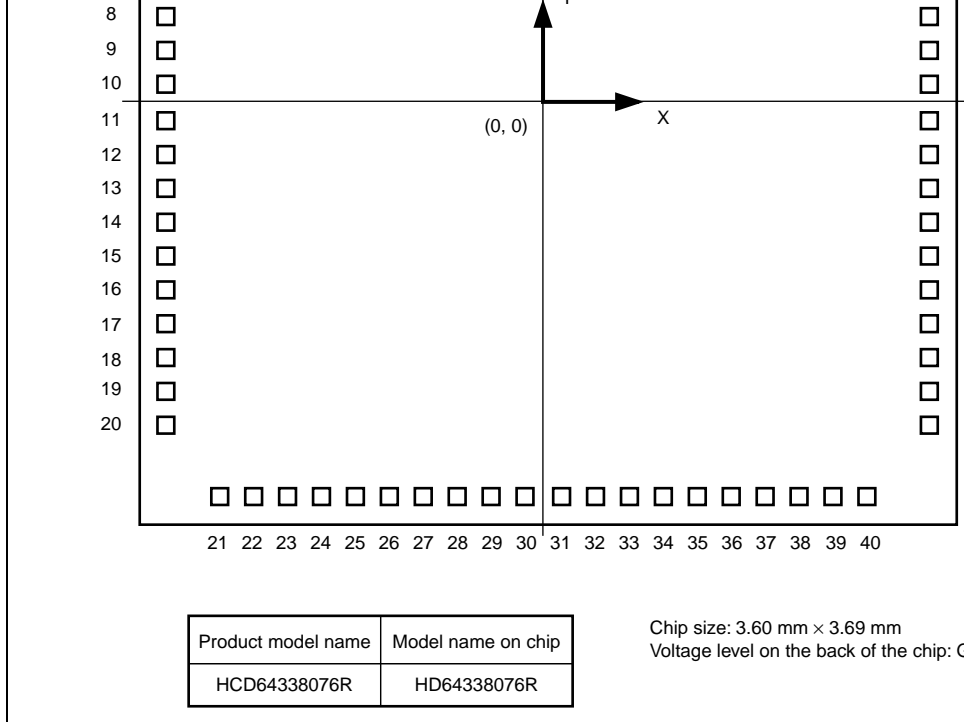


Figure 1.5 Pad Assignment of HCD64338076R (Top View)

7	P32/TXD32/SCL	-1683	547
8	P36	-1683	391
9	P37	-1683	234
10	X1	-1683	97
11	X2	-1683	-29
12	VSS	-1683	-234
13	OSC2	-1683	-391
14	OSC1	-1683	-575
15	TEST/ADTRG	-1683	-703
16	$\overline{\text{RES}}$	-1683	-859
17	$\overline{\text{NMI}}$	-1683	-1016
18	P40/SCK31/TMIF	-1683	-1172
19	P41/RXD31/IrRXD/TMOFL	-1683	-1328
20	P42/TXD31/IrTXD/TMOFH	-1683	-1484
21	VCC	-1448	-1728
22	C1	-1208	-1728
23	C2	-1085	-1728
24	V1	-963	-1728
25	V2	-841	-1728
26	V3	-689	-1728
27	PA0/COM1	-536	-1728
28	PA1/COM2	-384	-1728
29	PA2/COM3	-231	-1728

37	P56/WKP6/SEG7	994	-1728
38	P57/WKP7/SEG8	1146	-1728
39	P60/SEG9	1298	-1728
40	P61/SEG10	1448	-1728
41	P62/SEG11	1683	-1484
42	P63/SEG12	1683	-1328
43	P64/SEG13	1683	-1159
44	P65/SEG14	1683	-1016
45	P66/SEG15	1683	-859
46	P67/SEG16	1683	-703
47	P70/SEG17	1683	-547
48	P71/SEG18	1683	-391
49	P72/SEG19	1683	-234
50	P73/SEG20	1683	-78
51	P74/SEG21	1683	78
52	P75/SEG22	1683	234
53	P76/SEG23	1683	391
54	P77/SEG24	1683	547
55	P80/SEG25	1683	703
56	P81/SEG26	1683	859
57	P82/SEG27	1683	1016
58	P83/SEG28	1683	1172
59	P84/SEG29	1683	1328
60	P85/SEG30	1683	1484

68	PB2/AN2/IRQ3	384	1728
69	PB1/AN1/ $\overline{\text{IRQ1}}$	231	1728
70	PB0/AN0/ $\overline{\text{IRQ0}}$	79	1728
71	AVCC	-79	1728
72	VSS/AVSS	-231	1728
73	IRQAEC	-384	1728
74	P90/PWM1	-536	1728
75	P91/PWM2	-689	1728
76	P92/ $\overline{\text{IRQ4}}$	-841	1728
77	P93	-994	1728
78	P10/AEVH	-1146	1728
79	P11/AEVL	-1298	1728
80	P12/TIOCA1/TCLKA	-1448	1728

Note: The power supply (Vss) pads in pad number 12 must not be open but connected. When the TEST pad in pad number 15 is not used as the ADTRG pin, it must be connected to the Vss voltage level. If not, this LSI does not operate correctly.
When the TEST pad is used as the ADTRG pin, the function should be changed to ADTRG pin at Vss voltage level during a reset in advance.

	AVcc	71	B6	72	71	Input	Analog power supply pins for the A/D converter. When the A/D converter is not used, connect this pin to the system power supply.
	AVss	72 (= Vss)	C5 (= Vss)	73	72	Input	Ground pins for the A/D converter. Connect this pin to the system power supply (0 V).
	V1 to V3	24 to 26	J3, K4, H4	25 to 27	24 to 26	Input	Power supply pins for the LCD controller/driver.
	C1	22	K3	23	22	Input	Capacitance pins for stepping LCD drive power supply.
	C2	23	J2	24	23	Input	
Clock pins	OSC1	14	F1	15	14	Input	These pins connect with a ceramic resonator for the system clock or can be used to input an external clock.
	OSC2	13	G3	14	13	Output	See section 5, Clock Pulse Generators, for a typical connection.
	X1	10	F2	10	10	Input	These pins connect with a 38.4-kHz crystal resonator for the subclock. See section 5, Clock Generators, for a typical connection.
	X2	11	E2	11	11	Output	

							see section 10.4.2, External Input Timing.
Interrupt pins	$\overline{\text{NMI}}$	17	G1	18	17	Input	NMI interrupt request pins. Non-maskable interrupt request pin.
	$\overline{\text{IRQ0}}$	70	B5	71	70	Input	External interrupt request input pin.
	$\overline{\text{IRQ1}}$	69	C6	70	69	Input	Can select the rising or falling edge.
	$\overline{\text{IRQ3}}$	68	A6	69	68	Input	
	$\overline{\text{IRQ4}}$	76	B3	77	76	Input	
	IRQAEC	73	C4	74	73	Input	Interrupt input pins for the asynchronous event counter. This pin enables the asynchronous event input. In the masked mode version, this pin controls turning the on-chip oscillator during power-down.
	$\overline{\text{WKP0}}$ to $\overline{\text{WKP7}}$	31 to 38	J5, H6, H7, K6, J7, J8, K7, H8	32 to 39	31 to 38	Input	Wakeup interrupt request input pins. Can select the rising or falling edge.

	TIOCB2	3	B2	3	3	Input	Pins for the TGR2B input clock.
	TCLKA	80	A3	81	80	Input	External clock input pins.
	TCLKB	1	B1	1	1	Input	
	TCLKC	2	C1	2	2	Input	
Timer F	TMIF	18	H3	19	18	Input	Event input pins for input to F counter.
	TMOFL	19	J1	20	19	Output	Output pins for waveforms by the timer FL output compare function.
	TMOFH	20	H1	21	20	Output	Output pins for waveforms by the timer FH output compare function.
Asynchronous event counter (AEC)	AEVL	79	A2	80	79	Input	Event input pins for input to asynchronous event counter.
	AEVH	78	C3	79	78	Input	
RTC	TMOW	5	D1	5	5	Output	Divided clock output pins for RTC.
14-bit PWM	PWM1	74	A5	75	74	Output	Output pins for waveforms by the 14-bit PWM in PWM 1 and 2.
	PWM2	75	B4	76	75	Output	

or on-chip emulator debugging.
this pin is not available.

Serial communication interface 3 (SCI3)	SCK31	18	H3	19	18	I/O	SCI3_1 clock I/O pins.
	RXD31/ IrRXD	19	J1	20	19	Input	SCI3_1 data input pins or data output pins for the IrDA format.
	TXD31/ IrTXD	20	H1	21	20	Output	SCI3_1 data output pins or data output pins for the IrDA format.
	SCK32	5	D1	5	5	I/O	SCI3_2 clock I/O pins.
	RXD32	6	D3	6	6	Input	SCI3_2 data input pins.
	TXD32	7	D2	7	7	Output	SCI3_2 data output pins.
A/D converter	AN0 to AN2	70 to 68	B5, C6, A6	71 to 69	70 to 68	Input	Analog data input pins for the A/D converter.
	AN3 to AN7*4	67 to 63	B7, C7, A7, B8, B9	68 to 64	67 to 63	Input	
	ADTRG	15	G2	16	15	Input	External trigger input pins for the A/D converter.
I ² C bus interface 2 (IIC2)	SDA	6	D3	6	6	I/O	IIC data I/O pins.
	SCL	7	D2	7	7	I/O	IIC clock I/O pins.

			H9, G8				
	SEG17 to SEG24	47 to 54	G9, F10, F8, E9, F9, E8, D8, E10	48 to 55	47 to 54	Output	
	SEG25 to SEG32	55 to 62	D9, C9, D10, C8, B10, C10, A9, A8	56 to 63	55 to 62	Output	
I/O ports	P10 to P12	78 to 80	C3, A2, A3	79 to 81	78 to 80	I/O	7-bit I/O pins. Input or output designated for each bit by the port control register 1 (PCR1).
	P13 to P16	1 to 4	B1, C1, B2, C2	1 to 4	1 to 4		
	P30 to P32, P36, P37	5 to 9	D1, D3, D2, E1, E3	5 to 9	5 to 9	I/O	5-bit I/O pins. Input or output designated for each bit by the port control register 3 (PCR3).
	P40 to P42	18 to 20	H3, J1, H1	19 to 21	18 to 20	I/O	3-bit I/O pins. Input or output designated for each bit by the port control register 4 (PCR4).
	P50 to P57	31 to 38	J5, H6, H7, K6, J7, J8, K7, H8	32 to 39	31 to 38	I/O	8-bit I/O pins. Input or output designated for each bit by the port control register 5 (PCR5).
	P60 to P67	39 to 46	K9, K8, J10, H10, J9, H9, G10, G8	40 to 47	39 to 46	I/O	8-bit I/O pins. Input or output designated for each bit by the port control register 6 (PCR6).

P90 to P93	74 to 77	A5, B4, B3, A4	75 to 78	74 to 77	I/O	4-bit I/O pins. Input or output designated for each bit by m the port control register 9 (P
PA0 to PA3	27 to 30	J4, K5, H5, J6	28 to 31	27 to 30	I/O	4-bit I/O pins. Input or output designated for each bit by m the port control register A (P
PB0 to PB7	70 to 63	B5, C6, A6, B7, C7, A7, B8, B9	71 to 64	70 to 63	Input	8-bit input-only pins

-
- Notes: 1. Pad no. for the flash memory version.
2. Pad no. for the masked ROM version.

- General-register architecture
 - Sixteen 16-bit general registers also usable as sixteen 8-bit registers and eight 16-bit or eight 32-bit registers
- Sixty-two basic instructions
 - 8/16/32-bit data transfer and arithmetic and logic instructions
 - Multiply and divide instructions
 - Powerful bit-manipulation instructions
- Eight addressing modes
 - Register direct [Rn]
 - Register indirect [@ERn]
 - Register indirect with displacement [@(d:16,ERn) or @(d:24,ERn)]
 - Register indirect with post-increment or pre-decrement [@ERn+ or @-ERn]
 - Absolute address [@aa:8, @aa:16, @aa:24]
 - Immediate [#xx:8, #xx:16, or #xx:32]
 - Program-counter relative [@(d:8,PC) or @(d:16,PC)]
 - Memory indirect [@@aa:8]
- 64-kbyte address space
- High-speed operation
 - All frequently-used instructions execute in one or two states
 - 8/16/32-bit register-register add/subtract : 2 state
 - 8 × 8-bit register-register multiply : 14 states
 - 16 ÷ 8-bit register-register divide : 14 states
 - 16 × 16-bit register-register multiply : 22 states
 - 32 ÷ 16-bit register-register divide : 22 states

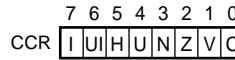
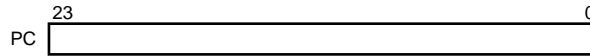
H'0057 H'0058	Interrupt vector	H'0057 H'0058	Interrupt vector	H'0057 H'0058	Interrupt vector	H'0057 H'0058	Interrupt vector	H'0057 H'0058	Interrupt vector
H'0057 H'0058	On-chip ROM (52 kbytes)	H'0057 H'0058	On-chip ROM (48 kbytes)	H'0057 H'0058	On-chip ROM (40 kbytes)	H'0057 H'0058	On-chip ROM (32 kbytes)	H'0057 H'0058	On-chip ROM (24 kbytes)
H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used
H'0057 H'0058	Internal I/O registers	H'0057 H'0058	Internal I/O registers	H'0057 H'0058	Internal I/O registers	H'0057 H'0058	Internal I/O registers	H'0057 H'0058	Internal I/O registers
H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used
H'0057 H'0058	LCD RAM (16 bytes)	H'0057 H'0058	LCD RAM (16 bytes)	H'0057 H'0058	LCD RAM (16 bytes)	H'0057 H'0058	LCD RAM (16 bytes)	H'0057 H'0058	LCD RAM (16 bytes)
H'0057 H'0058	On-chip RAM (3 kbytes)	H'0057 H'0058	On-chip RAM (2 kbytes)	H'0057 H'0058	On-chip RAM (2 kbytes)	H'0057 H'0058	On-chip RAM (1 kbytes)	H'0057 H'0058	On-chip RAM (1 kbytes)
H'0057 H'0058	Internal I/O registers (128 bytes)	H'0057 H'0058	Internal I/O registers (128 bytes)	H'0057 H'0058	Internal I/O registers (128 bytes)	H'0057 H'0058	Internal I/O registers (128 bytes)	H'0057 H'0058	Internal I/O registers (128 bytes)
H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used	H'0057 H'0058	Not used

Note: When the on-chip debugging emulator is used, the areas from H'C000 to H'CFFF and from H'F380 to H'FFFF are used by the emulator and not accessible by the user.

Figure 2.1 Memory Map

ER2	E2	R2H	R2L
ER3	E3	R3H	R3L
ER4	E4	R4H	R4L
ER5	E5	R5H	R5L
ER6	E6	R6H	R6L
ER7	E7	(SP) R7H	R7L

Control Registers (CR)



[Legend]

- | | |
|------------------------------|--------------------|
| SP: Stack pointer | H: Half-carry flag |
| PC: Program counter | U: User bit |
| CCR: Condition-code register | N: Negative flag |
| I: Interrupt mask bit | Z: Zero flag |
| UI: User bit | V: Overflow flag |
| | C: Carry flag |

Figure 2.2 CPU Registers

The R registers divide into 8-bit registers designated by the letters RH (R0H to R7H) and to R7L). These registers are functionally equivalent, providing a maximum of sixteen 8-bit registers.

The usage of each register can be selected independently.

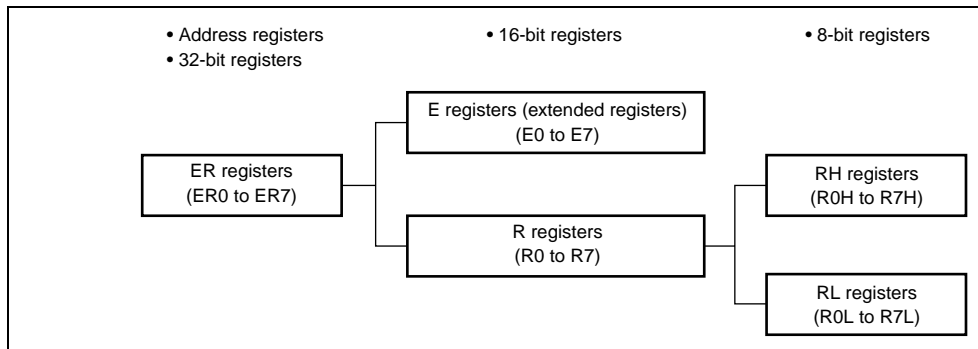


Figure 2.3 Usage of General Registers

General register ER7 has the function of the stack pointer (SP) in addition to its general-purpose function, and is used implicitly in exception handling and subroutine calls. Figure 2.4 shows the relationship between the stack pointer and the stack area.

2.2.2 Program Counter (PC)

This 24-bit counter indicates the address of the next instruction the CPU will execute. The least significant bit of all CPU instructions is 2 bytes (one word), so the least significant PC bit is ignored. (When an instruction is fetched, the least significant PC bit is regarded as 0). The PC is initialized to the start address is loaded by the vector address generated during reset exception-handling sequence.

2.2.3 Condition-Code Register (CCR)

This 8-bit register contains internal CPU status information, including an interrupt mask (I), half-carry (H), negative (N), zero (Z), overflow (V), and carry (C) flags. The I bit is initialized by reset exception-handling sequence, but other bits are not initialized.

Some instructions leave flag bits unchanged. Operations can be performed on the CCR by LDC, STC, ANDC, ORC, and XORC instructions. The N, Z, V, and C flags are used as conditions for conditional branch (Bcc) instructions.

For the action of each instruction on the flag bits, see Appendix A.1, Instruction List.

When the ADD.B, ADDX.B, SUB.B, SUBX.B, or NEG.B instruction is executed, this flag is set to 1 if there is a carry or borrow at bit 3, and cleared to 0 otherwise. When the ADD.W, SUB.W, CMP.W, or NEG.W instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 11, and cleared to 0 otherwise. When the ADD.L, SUB.L, CMP.L, or NEG.L instruction is executed, the H flag is set to 1 if there is a carry or borrow at bit 27, and cleared to 0 otherwise.

4	U	Undefined	R/W	User Bit Can be written and read by software using the STC, ANDC, ORC, and XORC instructions.
3	N	Undefined	R/W	Negative Flag Stores the value of the most significant bit of data. Set to 1 if the sign bit is 1, and cleared to 0 otherwise.
2	Z	Undefined	R/W	Zero Flag Set to 1 to indicate zero data, and cleared to 0 to indicate non-zero data.
1	V	Undefined	R/W	Overflow Flag Set to 1 when an arithmetic overflow occurs, and cleared to 0 at other times.
0	C	Undefined	R/W	Carry Flag Set to 1 when a carry occurs, and cleared to 0 otherwise. Used by: <ul style="list-style-type: none"> • Add instructions, to indicate a carry • Subtract instructions, to indicate a borrow • Shift and rotate instructions, to indicate a carry The carry flag is also used as a bit accumulator for bit manipulation instructions.

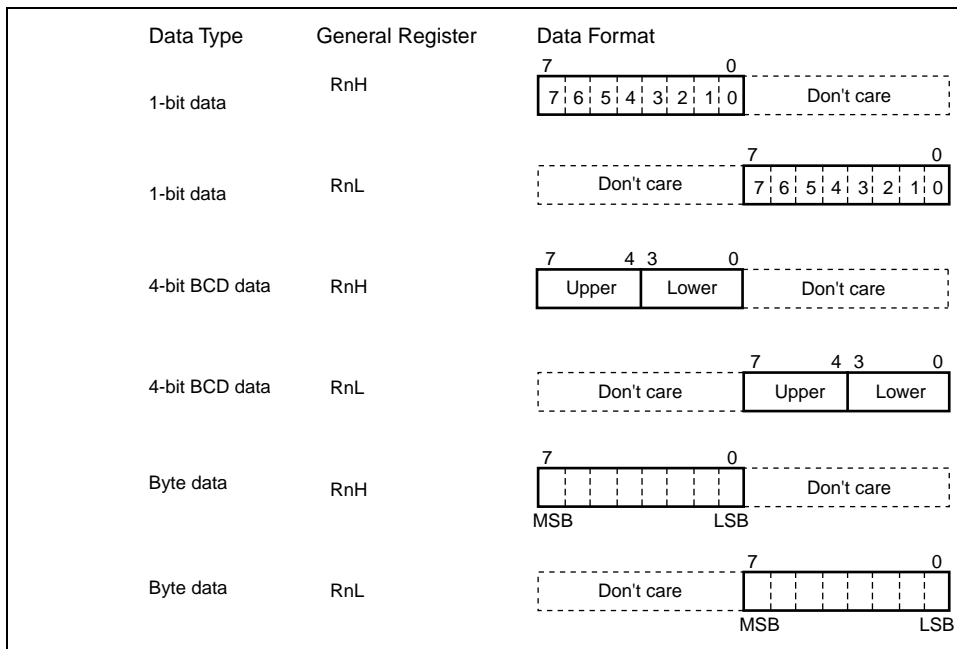


Figure 2.5 General Register Data Formats (1)



MSB

[Legend]

ERn: General register ER

En: General register E

Rn: General register R

RnH: General register RH

RnL: General register RL

MSB: Most significant bit

LSB: Least significant bit

Figure 2.5 General Register Data Formats (2)

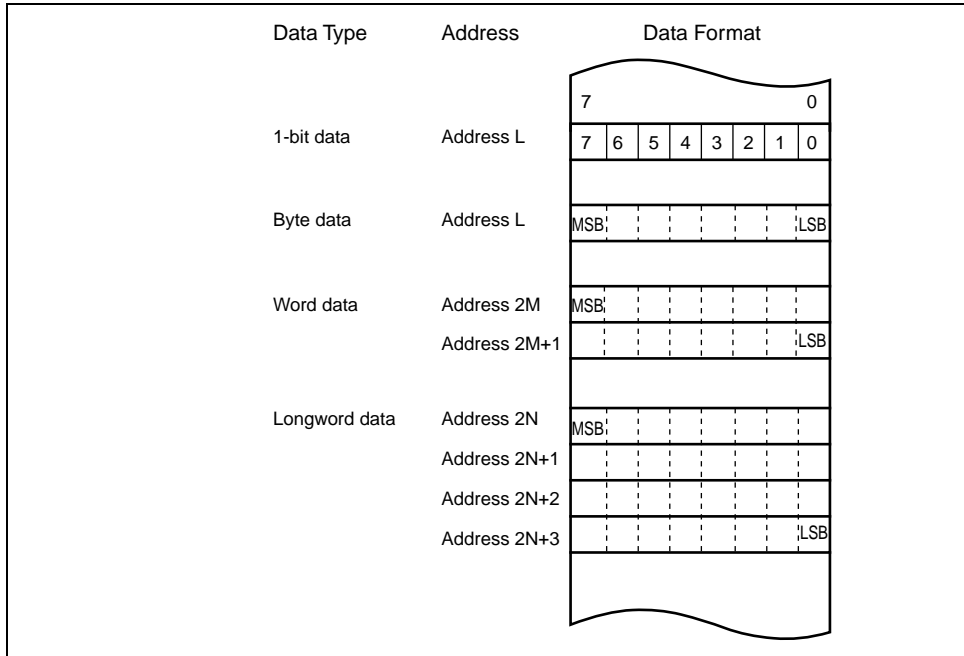


Figure 2.6 Memory Data Formats

Rd	General register (destination)
Rs	General register (source)*
Rn	General register*
ERn	General register (32-bit register or address register)
(EAd)	Destination operand
(EAs)	Source operand
CCR	Condition-code register
N	N (negative) flag in CCR
Z	Z (zero) flag in CCR
V	V (overflow) flag in CCR
C	C (carry) flag in CCR
PC	Program counter
SP	Stack pointer
#IMM	Immediate data
disp	Displacement
+	Addition
-	Subtraction
×	Multiplication
÷	Division
^	Logical AND
∨	Logical OR
⊕	Logical XOR
→	Move
¬	NOT (logical complement)

MOVFP	B	(EAs) → Rd Cannot be used in this LSI.
MOVTPE	B	Rs → (EAs) Cannot be used in this LSI.
POP	W/L	@SP+ → Rn Pops a general register from the stack. POP.W Rn is identical to MOV.W Rn, @SP+, Rn. POP.L ERn is identical to MOV.L @SP+, ERn.
PUSH	W/L	Rn → @-SP Pushes a general register onto the stack. PUSH.W Rn is identical to MOV.W Rn, @-SP. PUSH.L ERn is identical to MOV.L ERn, @-SP.

Note: * Refers to the operand size.
 B: Byte
 W: Word
 L: Longword

DEC		Increments or decrements a general register by 1 or 2. (Byte operand can be incremented or decremented by 1 only.)
ADDS SUBS	L	$Rd \pm 1 \rightarrow Rd$, $Rd \pm 2 \rightarrow Rd$, $Rd \pm 4 \rightarrow Rd$ Adds or subtracts the value 1, 2, or 4 to or from data in a 32-bit register.
DAA DAS	B	Rd (decimal adjust) $\rightarrow Rd$ Decimal-adjusts an addition or subtraction result in a general register referring to the CCR to produce 4-bit BCD data.
MULXU	B/W	$Rd \times Rs \rightarrow Rd$ Performs unsigned multiplication on data in two general registers: 8 bits \times 8 bits \rightarrow 16 bits or 16 bits \times 16 bits \rightarrow 32 bits.
MULXS	B/W	$Rd \times Rs \rightarrow Rd$ Performs signed multiplication on data in two general registers: 8 bits \times 8 bits \rightarrow 16 bits or 16 bits \times 16 bits \rightarrow 32 bits.
DIVXU	B/W	$Rd \div Rs \rightarrow Rd$ Performs unsigned division on data in two general registers: either 8 bits \div 8 bits \rightarrow 8-bit quotient and 8-bit remainder or 32 bits \div 16 bits \rightarrow 16-bit quotient and 16-bit remainder.

Note: * Refers to the operand size.

B: Byte

W: Word

L: Longword

general register.

EXTU	W/L	Rd (zero extension) → Rd Extends the lower 8 bits of a 16-bit register to word size, or the bits of a 32-bit register to longword size, by padding with zeros left.
EXTS	W/L	Rd (sign extension) → Rd Extends the lower 8 bits of a 16-bit register to word size, or the bits of a 32-bit register to longword size, by extending the sign

Note: * Refers to the operand size.

B: Byte

W: Word

L: Longword

NOT	B/W/L	$\neg (Rd) \rightarrow (Rd)$ Takes the one's complement (logical complement) of general register contents.
-----	-------	---

Note: * Refers to the operand size.
 B: Byte
 W: Word
 L: Longword

Table 2.5 Shift Instructions

Instruction	Size*	Function
SHAL SHAR	B/W/L	Rd (shift) \rightarrow Rd Performs an arithmetic shift on general register contents.
SHLL SHLR	B/W/L	Rd (shift) \rightarrow Rd Performs a logical shift on general register contents.
ROTL ROTR	B/W/L	Rd (rotate) \rightarrow Rd Rotates general register contents.
ROTXL ROTXR	B/W/L	Rd (rotate) \rightarrow Rd Rotates general register contents through the carry flag.

Note: * Refers to the operand size.
 B: Byte
 W: Word
 L: Longword

Inverts a specified bit in a general register or memory operand and the carry flag. The bit number is specified by 3-bit immediate data or the lower three bits of a general register.

BTST	B	$\neg (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow Z$ Tests a specified bit in a general register or memory operand and clears the Z flag accordingly. The bit number is specified by 3-bit immediate data or the lower three bits of a general register.
BAND	B	$C \wedge (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ANDs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIAND	B	$C \wedge \neg (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ANDs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag. The bit number is specified by 3-bit immediate data.
BOR	B	$C \vee (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ORs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIOR	B	$C \vee \neg (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ ORs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag. The bit number is specified by 3-bit immediate data.
BXOR	B	$C \oplus (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ XORs the carry flag with a specified bit in a general register or memory operand and stores the result in the carry flag.
BIXOR	B	$C \oplus \neg (<\text{bit-No.}> \text{ of } <\text{EAd}>) \rightarrow C$ XORs the carry flag with the inverse of a specified bit in a general register or memory operand and stores the result in the carry flag. The bit number is specified by 3-bit immediate data.

BIST

B

$\neg C \rightarrow$ (<bit-No.> of <EAd>)

Transfers the inverse of the carry flag value to a specified bit in register or memory operand.

The bit number is specified by 3-bit immediate data.

Note: * Refers to the operand size.

B: Byte

BCC(BHS)	Carry clear (high or same)	$C = 0$
BCS(BLO)	Carry set (low)	$C = 1$
BNE	Not equal	$Z = 0$
BEQ	Equal	$Z = 1$
BVC	Overflow clear	$V = 0$
BVS	Overflow set	$V = 1$
BPL	Plus	$N = 0$
BMI	Minus	$N = 1$
BGE	Greater or equal	$N \oplus V = 0$
BLT	Less than	$N \oplus V = 1$
BGT	Greater than	$Z \vee (N \oplus V) = 0$
BLE	Less or equal	$Z \vee (N \oplus V) = 1$

JMP	—	Branches unconditionally to a specified address.
BSR	—	Branches to a subroutine at a specified address.
JSR	—	Branches to a subroutine at a specified address.
RTS	—	Returns from a subroutine

Note: * Bcc is the general name for conditional branch instructions.

word access.

ANDC	B	$CCR \wedge \#IMM \rightarrow CCR$ Logically ANDs the CCR with immediate data.
ORC	B	$CCR \vee \#IMM \rightarrow CCR$ Logically ORs the CCR with immediate data.
XORC	B	$CCR \oplus \#IMM \rightarrow CCR$ Logically XORs the CCR with immediate data.
NOP	—	$PC + 2 \rightarrow PC$ Only increments the program counter.

Note: * Refers to the operand size.

B: Byte

W: Word

else next;

Transfers a data block. Starting from the address set in ER5, transfers data for the number of bytes set in R4L or R4 to the address located in ER6.

Execution of the next instruction begins as soon as the transfer is completed.

on the operand. The operation field always includes the first four bits of the instruction. Some instructions have two operation fields.

(2) Register Field

Specifies a general register. Address registers are specified by 3 bits, and data registers by 4 bits. Some instructions have two register fields. Some have no register field.

(3) Effective Address Extension

8, 16, or 32 bits specifying immediate data, an absolute address, or a displacement. A24-bit address or displacement is treated as a 32-bit data in which the first 8 bits are 0 (H'00).

(4) Condition Field

Specifies the branching condition of Bcc instructions.

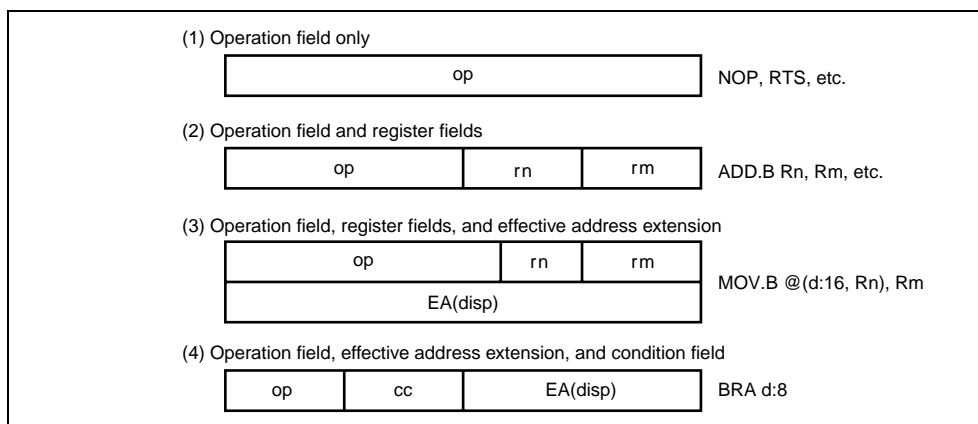


Figure 2.7 Instruction Formats

Arithmetic and logic instructions can use the register direct and immediate modes. Data instructions can use all addressing modes except program-counter relative and memory indirect. Bit-manipulation instructions use register direct, register indirect, or the absolute address (`@aa:8`) to specify an operand, and register direct (BSET, BCLR, BNOT, and BTST instructions) or immediate (3-bit) addressing mode to specify a bit number in the operand.

Table 2.10 Addressing Modes

No.	Addressing Mode	Symbol
1	Register direct	Rn
2	Register indirect	@ERn
3	Register indirect with displacement	@(d:16,ERn)/@(d:24,ERn)
4	Register indirect with post-increment Register indirect with pre-decrement	@ERn+ @-ERn
5	Absolute address	@aa:8/@aa:16/@aa:24
6	Immediate	#xx:8/#xx:16/#xx:32
7	Program-counter relative	@(d:8,PC)/@(d:16,PC)
8	Memory indirect	@@aa:8

(1) Register Direct—Rn

The register field of the instruction specifies an 8-, 16-, or 32-bit general register containing the operand. R0H to R7H and R0L to R7L can be specified as 8-bit registers. R0 to R7 and R0H to R7H can be specified as 16-bit registers. ER0 to ER7 can be specified as 32-bit registers.

- Register indirect with post-increment—@ERn+

The register field of the instruction code specifies an address register (ERn) the lower 8 bits of which contains the address of a memory operand. After the operand is accessed, 1, 2, or 4 is added to the address register contents (32 bits) and the sum is stored in the address register. The value added is 1 for byte access, 2 for word access, or 4 for longword access. For the byte or longword access, the register value should be even.

- Register indirect with pre-decrement—@-ERn

The value 1, 2, or 4 is subtracted from an address register (ERn) specified by the register field in the instruction code, and the lower 24 bits of the result is the address of a memory operand. The result is also stored in the address register. The value subtracted is 1 for byte access, 2 for word access, or 4 for longword access. For the word or longword access, the register value should be even.

(5) Absolute Address—@aa:8, @aa:16, @aa:24

The instruction code contains the absolute address of a memory operand. The absolute address may be 8 bits long (@aa:8), 16 bits long (@aa:16), 24 bits long (@aa:24)

For an 8-bit absolute address, the upper 16 bits are all assumed to be 1 (H'FFFF). For a 16-bit absolute address the upper 8 bits are a sign extension. A 24-bit absolute address can access the entire address space.

The access ranges of absolute addresses for this LSI are those shown in table 2.11, because the upper 8 bits are ignored.

operand.

The ADDS, SUBS, INC, and DEC instructions contain immediate data implicitly. Some manipulation instructions contain 3-bit immediate data in the instruction code, specifying a number.

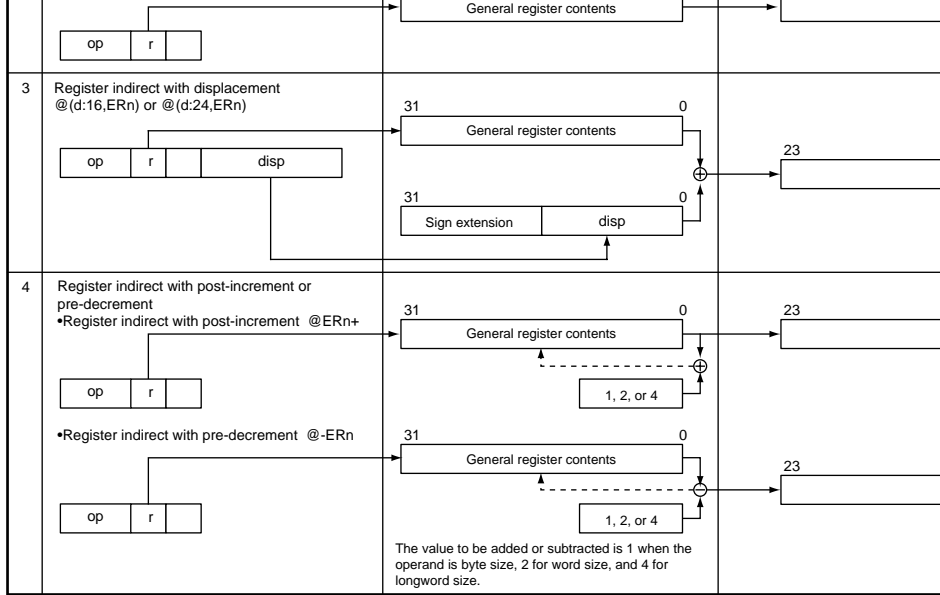
(7) Program-Counter Relative—@(d:8, PC) or @(d:16, PC)

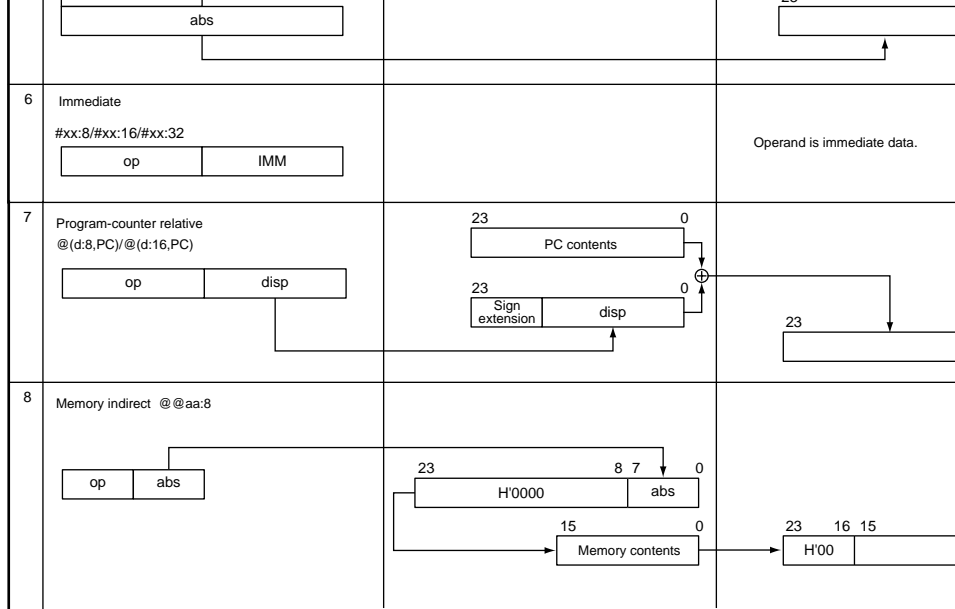
This mode is used in the BSR instruction. An 8-bit or 16-bit displacement contained in the instruction is sign-extended and added to the 24-bit PC contents to generate a branch address. The PC value to which the displacement is added is the address of the first byte of the next instruction, so the possible branching range is -126 to +128 bytes (-63 to +64 words) or -32766 to +32766 bytes (-16383 to +16384 words) from the branch instruction. The resulting value should be an even number.

(8) Memory Indirect—@@aa:8

This mode can be used by the JMP and JSR instructions. The instruction code contains an absolute address specifying a memory operand. This memory operand contains a branch address. The memory operand is accessed in words, generating a 16-bit branch address. Figure 2-10 shows how to specify branch address for in memory indirect mode. The upper bits of the absolute address are all assumed to be 0, so the address range is 0 to 255 (H'0000 to H'00FF).

Note that the first part of the address range is also the exception vector area.





[Legend]

- r, rm, rn : Register field
- op : Operation field
- disp : Displacement
- IMM : Immediate data
- abs : Absolute address

in byte or word size. Figure 2.9 shows the on-chip memory access cycle.

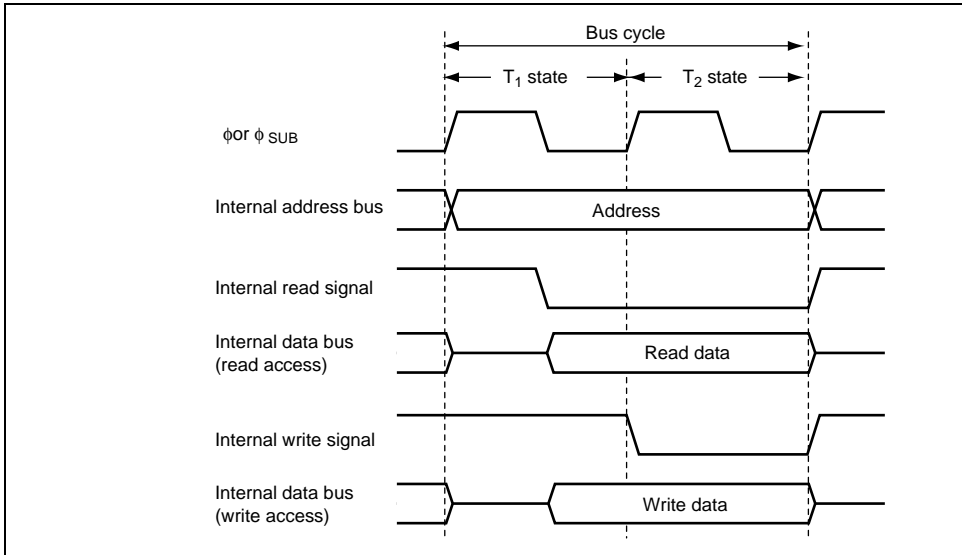


Figure 2.9 On-Chip Memory Access Cycle

module.

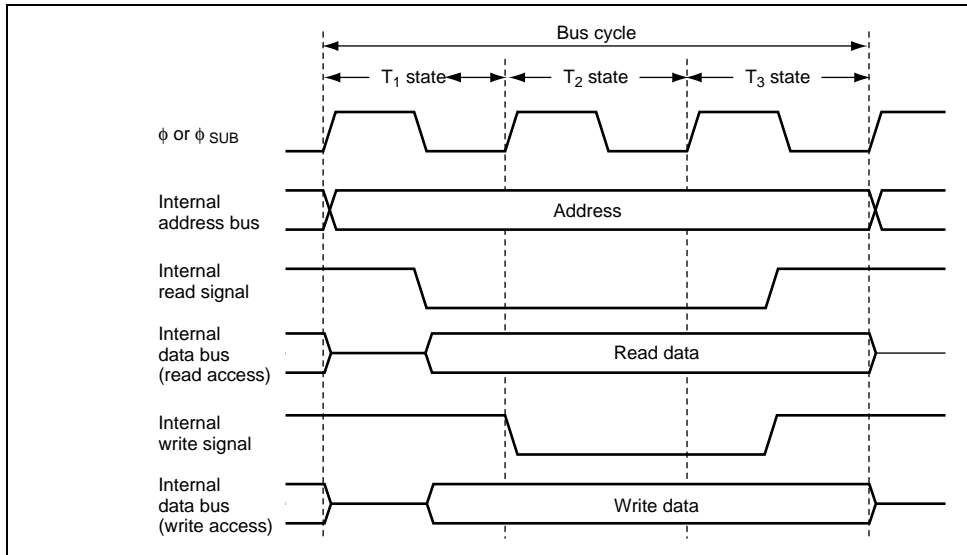


Figure 2.10 On-Chip Peripheral Module Access Cycle (3-State Access)

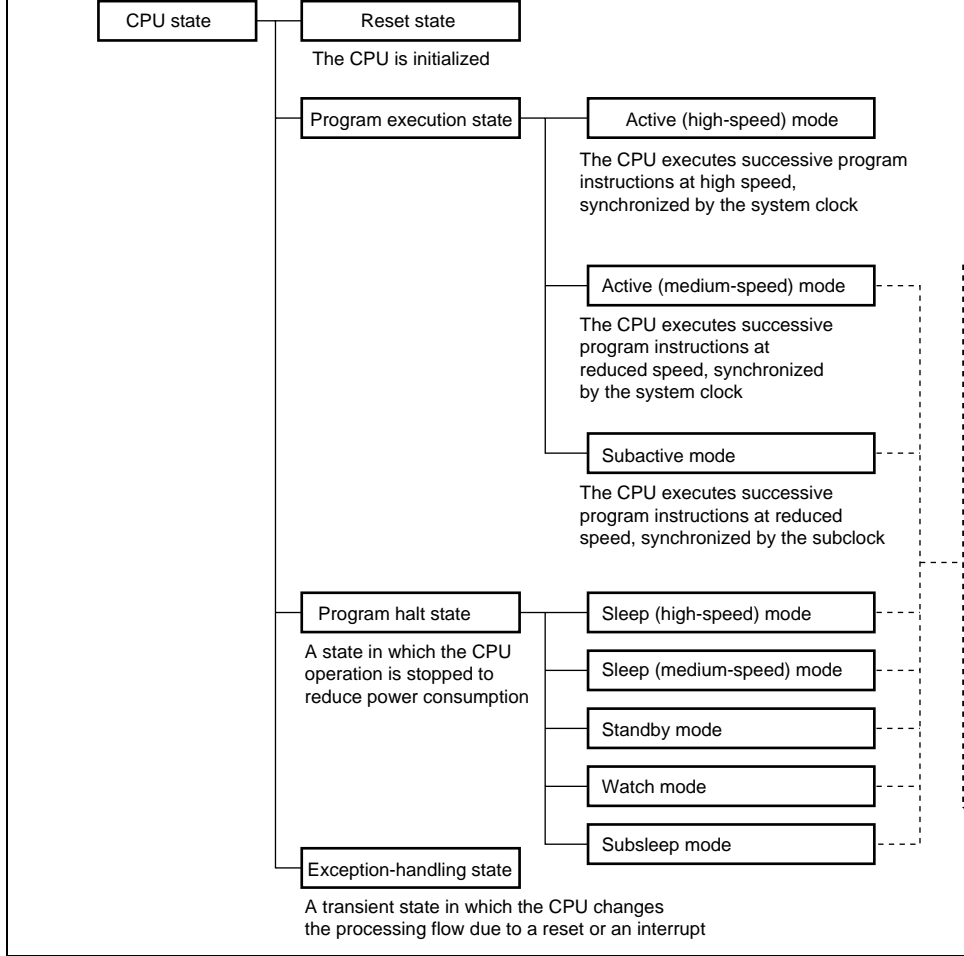


Figure 2.11 CPU Operating States

2.8 Usage Notes

2.8.1 Notes on Data Access to Empty Areas

The address space of this LSI includes empty areas in addition to the ROM, RAM, and on-chip I/O registers areas available to the user. When data is transferred from CPU to empty areas, the transferred data will be lost. This action may also cause the CPU to malfunction. When data is transferred from an empty area to CPU, the contents of the data cannot be guaranteed.

2.8.2 EEPMOV Instruction

EEPMOV is a block-transfer instruction and transfers the byte size of data indicated by R4L, which starts from the address indicated by R5, to the address indicated by R6. Set R4L and R6 such that the end address of the destination address (value of R6 + R4L) does not exceed H'FFFF. The value of R6 must not change from H'FFFF to H'0000 during execution).

Example 1: Bit manipulation for the timer load register and timer counter

Figure 2.13 shows an example of a timer in which two timer registers are assigned to the same address. When a bit-manipulation instruction accesses the timer load register and timer counter of a reloadable timer, since these two registers share the same address, the following operations take place.

1. Data is read in byte units.
2. The CPU sets or resets the bit to be manipulated with the bit-manipulation instruction.
3. The written data is written again in byte units to the timer load register.

The timer is counting, so the value read is not necessarily the same as the value in the timer load register. As a result, bits other than the intended bit in the timer counter may be modified. The modified value may be written to the timer load register.

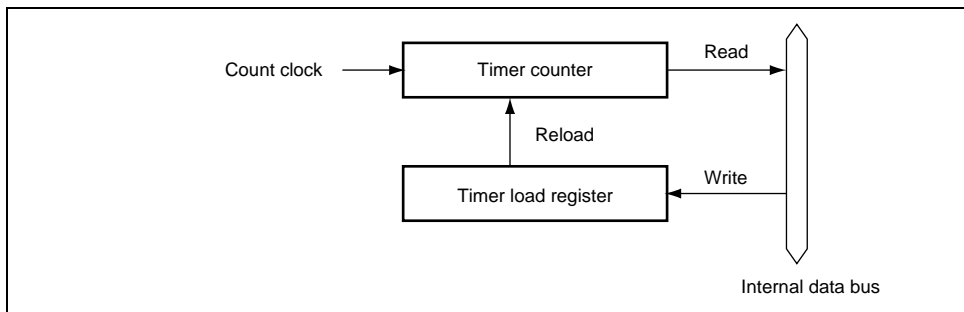


Figure 2.13 Example of Timer Configuration with Two Registers Allocated to the Same Address

PCR5	0	0	1	1	1	1	1
PDR5	1	0	0	0	0	0	0

- BSET instruction executed instruction

```
BSET #0, @PDR5
```

The BSET instruction is executed for port 5.

- After executing BSET instruction

	P57	P56	P55	P54	P53	P52	P51
Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	0	1	0	0	0	0	0

- Description on operation

1. When the BSET instruction is executed, first the CPU reads port 5.

Since P57 and P56 are input pins, the CPU reads the pin states (low-level and high-level input).

P55 to P50 are output pins, so the CPU reads the value in PDR5. In this example PDR5 value of H'80, but the value read by the CPU is H'40.

2. Next, the CPU sets bit 0 of the read data to 1, changing the PDR5 data to H'41.

	P57	P56	P55	P54	P53	P52	P51
Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	1	0	0	0	0	0	0
RAM0	1	0	0	0	0	0	0

- BSET instruction executed

```
BSET    #0,    @RAM0
```

The BSET instruction is executed designating the work area (RAM0).

- After executing BSET instruction

```
MOV.B   @RAM0, R0L
MOV.B   R0L,   @PDR5
```

The work area (RAM0) value is written to PDR5

	P57	P56	P55	P54	P53	P52	P51
Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	1	0	0	0	0	0	0
RAM0	1	0	0	0	0	0	0

Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	1	0	0	0	0	0	0

- BCLR instruction executed

```
BCLR #0, @PCR5
```

The BCLR instruction is executed for PCR5.

- After executing BCLR instruction

	P57	P56	P55	P54	P53	P52	P51
Input/output	Output	Output	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	1	1	1	1	1	1	1
PDR5	1	0	0	0	0	0	0

- Description on operation

1. When the BCLR instruction is executed, first the CPU reads PCR5. Since PCR5 is a write-only register, the CPU reads a value of H'FF, even though the PCR5 value is actually H'3F.
2. Next, the CPU clears bit 0 in the read data to 0, changing the data to H'FE.
3. Finally, H'FE is written to PCR5 and BCLR instruction execution ends.

As a result of this operation, bit 0 in PCR5 becomes 0, making P50 an input port. However, bits 7 and 6 in PCR5 change to 1, so that P57 and P56 change from input pins to output pins. To prevent this problem, store a copy of the PDR5 data in a work area in memory and then manipulate data of the bit in the work area, then write this data to PDR5.

PDR5	1	0	0	0	0	0	0
RAM0	0	0	1	1	1	1	1

- BCLR instruction executed

```
BCLR    #0,    @RAM0
```

The BCLR instructions executed for the PCR5 work area (RAM0).

- After executing BCLR instruction

```
MOV.B   @RAM0, R0L
MOV.B   R0L,  @PCR5
```

The work area (RAM0) value is written to PCR5.

	P57	P56	P55	P54	P53	P52	P51
Input/output	Input	Input	Output	Output	Output	Output	Output
Pin state	Low level	High level	Low level	Low level	Low level	Low level	Low level
PCR5	0	0	1	1	1	1	1
PDR5	1	0	0	0	0	0	0
RAM0	0	0	1	1	1	1	1

External interrupts other than NMI and internal interrupts other than address break are masked by the I bit in CCR, and kept masked while the I bit is set to 1. Exception handling starts after the current instruction or exception handling ends, if an interrupt request has been issued.

system use			
Reserved for system use	Break interrupts (mode transition)	2	H'0004 to H'0005
External interrupt	NMI	3	H'0006 to H'0007
Reserved for system use	Break conditions satisfied	4	H'0008 to H'0009
Address break	Break conditions satisfied	5	H'000A to H'000B
External interrupts	IRQ0	6	H'000C to H'000D
	IRQ1	7	H'000E to H'000F
	IRQAEC	8	H'0010 to H'0011
	IRQ3	9	H'0012 to H'0013
	IRQ4	10	H'0014 to H'0015
	WKP0	11	H'0016 to H'0017
	WKP1	12	H'0018 to H'0019
	WKP2	13	H'001A to H'001B
	WKP3	14	H'001C to H'001D
	WKP4	15	H'001E to H'001F
	WKP5	16	H'0020 to H'0021
	WKP6	17	H'0022 to H'0023
	WKP7	18	H'0024 to H'0025
Internal interrupts*	—	19 to 43	H'0026 to H'0056

Note: * For details on the vector table of internal interrupts, refer to section 4.5, Interrupt Exception Handling Vector Table.

Watchdog timer

Counter overflow

For details, see section 14, Watchdog Timer.

3.2.1 Reset Exception Handling

When a reset source occurs, all processing halts and the LSI enters the reset state. A reset initializes the internal state of the CPU and the registers of on-chip peripheral modules.

To ensure that this LSI is reset using the $\overline{\text{RES}}$ pin, proceed as follows.

- At power-on, or if the system clock pulse generator is stopped
Hold the $\overline{\text{RES}}$ pin low until the operation of the clock pulse generator stabilizes.
- If the system clock pulse generator is running
Hold the $\overline{\text{RES}}$ pin for the duration of the t_{REL} state specified in the electrical characteristics.

When a reset source is generated, reset exception handling starts and the LSI performs the following operations.

1. The internal state of the CPU and the registers of the on-chip peripheral modules are reset, and the I bit in CCR is set to 1.
2. The reset exception handling vector address (H'0000 and H'0001) is read and transferred to the PC, and then program execution starts from the address indicated by the PC.

The reset exception handling sequence triggered by the $\overline{\text{RES}}$ pin is shown in figure 3.1.

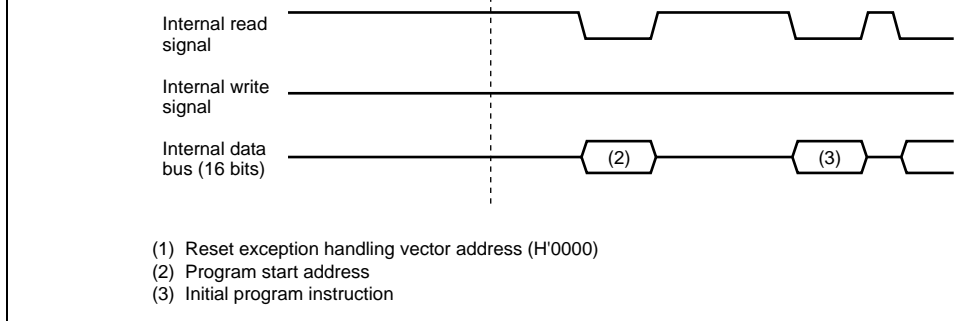


Figure 3.1 Reset Exception Handling Sequence

3.2.2 Interrupt Immediately after Reset

Immediately after a reset, if an interrupt is accepted before the stack pointer (SP) is initialized and CCR will not be pushed onto the stack correctly, resulting in program runaway. To prevent this, immediately after reset exception handling all interrupts are masked. For this reason, the initial program instruction is always executed immediately after a reset. This instruction should initialize the stack pointer (e.g. `MOV.L #xx: 32, SP`).

NMI is an interrupt with the highest priority and accepted at all times. Interrupts are controlled by the interrupt controller. The interrupt controller can set interrupts other than NMI to one of 16 mask levels in order to control multiple interrupts. The interrupt priority registers (A to E, IPRE) of the interrupt controller set the interrupt mask level.

For details on interrupts, see section 4, Interrupt Controller.

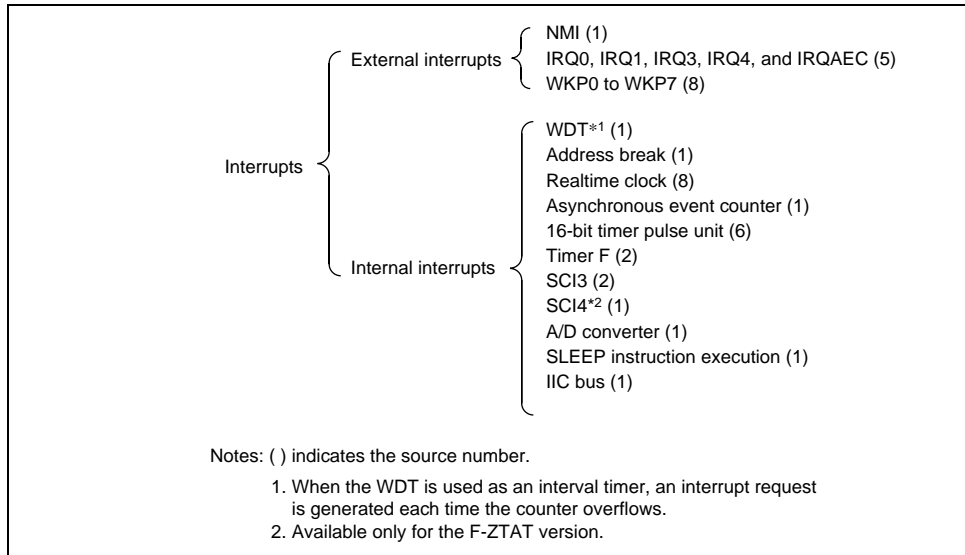
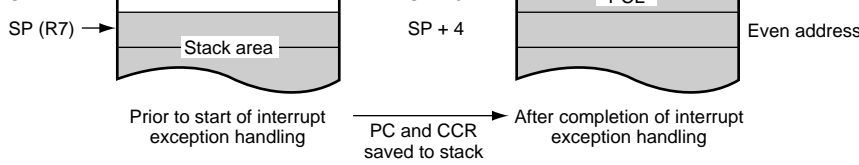


Figure 3.2 Interrupt Sources and their Numbers



[Legend]

PCH: Upper 8 bits of program counter (PC)

PCL: Lower 8 bits of program counter (PC)

CCR: Condition code register

SP: Stack pointer

- Notes: 1. PC shows the address of the first instruction to be executed upon return from the interrupt handling routine.
2. Register contents must always be saved and restored by word length, starting from an even-numbered address.
- * Ignored when returning from the interrupt handling routine.

Figure 3.3 Stack Status after Exception Handling

Instruction fetch	4
Internal processing	4

Note: * Excluding EEPMOV instruction.

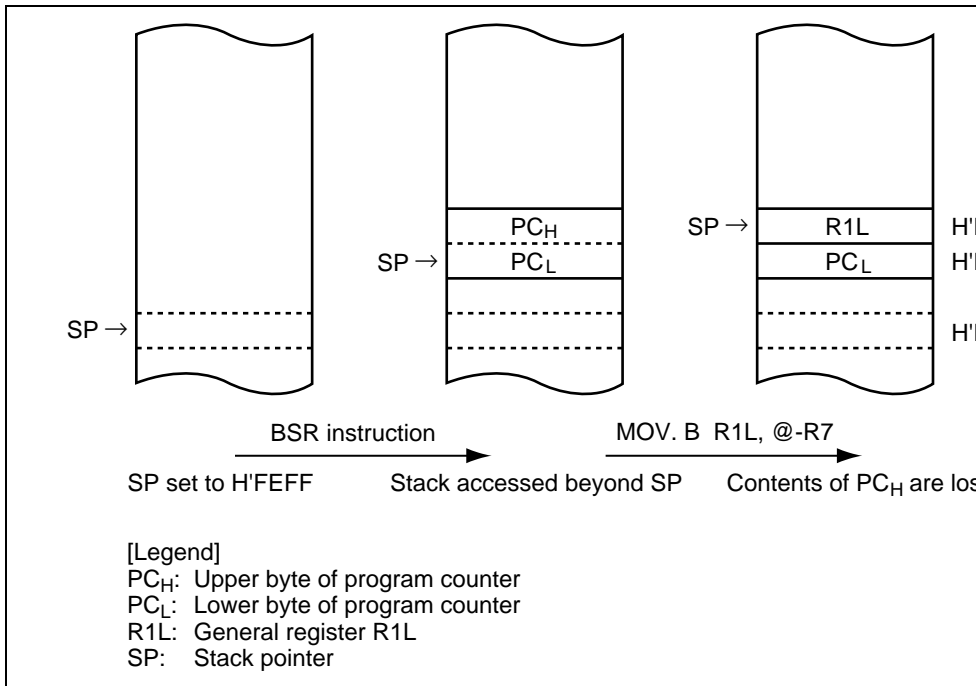


Figure 3.4 Operation when Odd Address is Set in SP

During interrupt exception handling or when an RTE instruction is executed, CCR contents are saved and restored in word size. Both the upper and lower bytes of word data are saved to stack; on return, the even address contents are restored to CCR while the odd address contents are ignored.

request flag may be set to 1, even if a valid edge has not arrived on the selected IRQAE pin. This is because the interrupt request flag is set to 1 when the IECPWM (PWM output for the AEC) is enabled. Therefore, be sure to clear the interrupt request flag after switching the pin function.

Table 3.4 shows the conditions under which interrupt request flags are set to 1 in this wa

	IRREC2	When an edge as designated by the AIEGS1 and AIEGS0 bits in AIEGS is detected because the values of the IRQAEC pin and of IECPWM are different (e.g., when the rising edge has been selected and the ECPWME bit in AEGSR is changed from 1 to 0 while the IRQAEC pin is low and IECPWM is 1).
	IRRI1	When the IRQ1 bit in PMRB is changed from 0 to 1 while the $\overline{\text{IRQ1}}$ pin is low and the IEG1 bit in IEGR is 0. When the IRQ1 bit in PMRB is changed from 1 to 0 while the $\overline{\text{IRQ1}}$ pin is low and the IEG1 bit in IEGR is 1.
	IRRI0	When the IRQ0 bit in PMRB is changed from 0 to 1 while the $\overline{\text{IRQ0}}$ pin is low and the IEG0 bit in IEGR is 0. When the IRQ0 bit in PMRB is changed from 1 to 0 while the $\overline{\text{IRQ0}}$ pin is low and the IEG0 bit in IEGR is 1.
IWPR	IWPF7	When the WKP7 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP7}}$ pin is low.
	IWPF6	When the WKP6 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP6}}$ pin is low.
	IWPF5	When the WKP5 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP5}}$ pin is low.
	IWPF4	When the WKP4 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP4}}$ pin is low.
	IWPF3	When the WKP3 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP3}}$ pin is low.
	IWPF2	When the WKP2 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP2}}$ pin is low.
	IWPF1	When the WKP1 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP1}}$ pin is low.
	IWPF0	When the WKP0 bit in PMR5 is changed from 0 to 1 while the $\overline{\text{WKP0}}$ pin is low.

However, the procedure in figure 3.5 is recommended because IECPWM is an internal signal and determining its value is complicated.

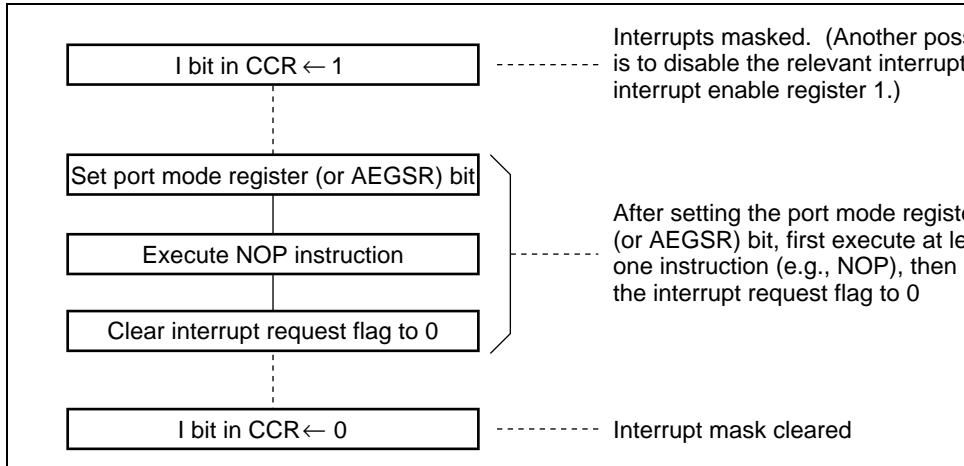


Figure 3.5 Port Mode Register (or AEGSR) Setting and Interrupt Request Clearing Procedure

BCLR #1, @IRR1:8

MOV.B R1L, @IRR1:8 (set the value of R1L to B'11111101)

(2) Example of a malfunction

When flags are cleared with multiple instructions, other flags might be cleared during execution of the instructions, even though they are currently set, and this will cause a malfunction.

Here is an example in which IRR10 is cleared and disabled in the process of clearing IRR1 (in IRR1).

MOV.B @IRR1:8,R1L IRR10 = 0 at this time

AND.B #B'11111101,R1L Here, IRR10 = 1

MOV.B R1L,@IRR1:8 IRR10 is cleared to 0

In the above example, it is assumed that an IRQ0 interrupt is generated while the AND.B instruction is executing.

The IRQ0 interrupt is disabled because, although the original objective is clearing IRR1, IRR10 is also cleared.

- Interrupts can be enabled or disabled in three levels by the INTM1 and INTM0 bits in the interrupt mask register (INTM).
- Fourteen external interrupts
 - NMI is the highest-priority interrupt, and is accepted at all times. Rising or falling edge sensing can be selected for NMI. Rising or falling edge sensing can be selected for I/O interrupt sources.
 - IRQ1, IRQ3, IRQ4, and WKP0 to WKP7. Rising, falling, or both edge sensing can be selected for IRQAEC.

A block diagram of the interrupt controller is shown in figure 4.1.

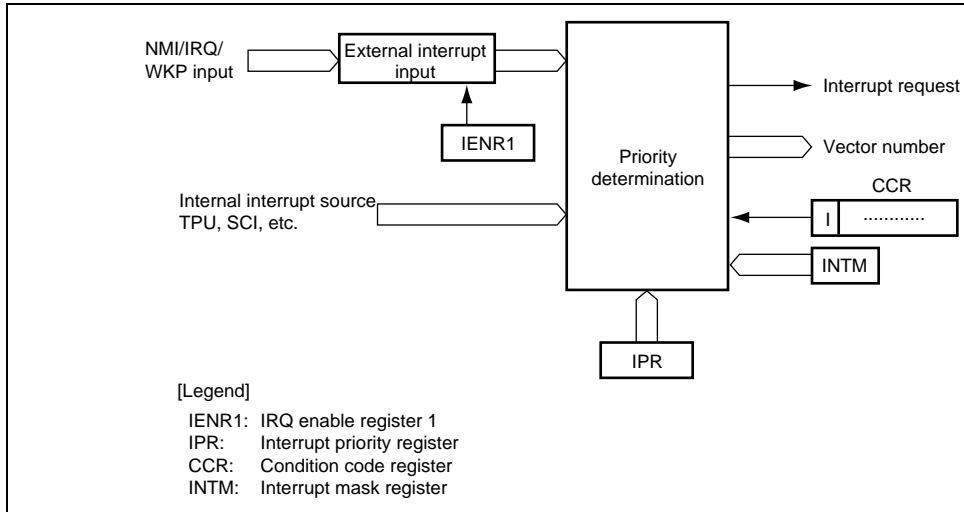


Figure 4.1 Block Diagram of Interrupt Controller

$\overline{\text{IRQ4}}$	Input	Maskable external interrupt pins
$\overline{\text{IRQ3}}$	Input	Rising or falling edge can be selected
$\overline{\text{IRQ1}}$	Input	
$\overline{\text{IRQ0}}$	Input	
$\overline{\text{WKP7}}$ to $\overline{\text{WKP0}}$	Input	Maskable external interrupt pins Accepted at a rising or falling edge

4.3 Register Descriptions

The interrupt controller has the following registers.

- Interrupt edge select register (IEGR)
- Wakeup edge select register (WEGR)
- Interrupt enable register 1 (IENR1)
- Interrupt enable register 2 (IENR2)
- Interrupt request register 1 (IRR1)
- Interrupt request register 2 (IRR2)
- Wakeup interrupt request register (IWPR)
- Interrupt priority register A (IPRA)
- Interrupt priority register B (IPRB)
- Interrupt priority register C (IPRC)
- Interrupt priority register D (IPRD)
- Interrupt priority register E (IPRE)
- Interrupt mask register (INTM)

6	TMIFEG	0	R/W	TMIF Edge Select 0: Detects a falling edge of the TMIF pin input 1: Detects a rising edge of the TMIF pin input
5	ADTRGNEG	0	R/W	$\overline{\text{ADTRG}}$ Edge Select 0: Detects a falling edge of the $\overline{\text{ADTRG}}$ pin input 1: Detects a rising edge of the $\overline{\text{ADTRG}}$ pin input
4	IEG4	0	R/W	IRQ4 Edge Select 0: Detects a falling edge of the $\overline{\text{IRQ4}}$ pin input 1: Detects a rising edge of the $\overline{\text{IRQ4}}$ pin input
3	IEG3	0	R/W	IRQ3 Edge Select 0: Detects a falling edge of the $\overline{\text{IRQ3}}$ pin input 1: Detects a rising edge of the $\overline{\text{IRQ3}}$ pin input
2	—	—	—	Reserved
1	IEG1	0	R/W	IRQ1 Edge Select 0: Detects a falling edge of the $\overline{\text{IRQ1}}$ pin input 1: Detects a rising edge of the $\overline{\text{IRQ1}}$ pin input
0	IEG0	0	R/W	IRQ0 Edge Select 0: Detects a falling edge of the $\overline{\text{IRQ0}}$ pin input 1: Detects a rising edge of the $\overline{\text{IRQ0}}$ pin input

				0: Detects a falling edge of the $\overline{WKP6}$ pin input 1: Detects a rising edge of the $\overline{WKP6}$ pin input
5	WKEGS5	0	R/W	WKP5 Edge Select 0: Detects a falling edge of the $\overline{WKP5}$ pin input 1: Detects a rising edge of the $\overline{WKP5}$ pin input
4	WKEGS4	0	R/W	WKP4 Edge Select 0: Detects a falling edge of the $\overline{WKP4}$ pin input 1: Detects a rising edge of the $\overline{WKP4}$ pin input
3	WKEGS3	0	R/W	WKP3 Edge Select 0: Detects a falling edge of the $\overline{WKP3}$ pin input 1: Detects a rising edge of the $\overline{WKP3}$ pin input
2	WKEGS2	0	R/W	WKP2 Edge Select 0: Detects a falling edge of the $\overline{WKP2}$ pin input 1: Detects a rising edge of the $\overline{WKP2}$ pin input
1	WKEGS1	0	R/W	WKP1 Edge Select 0: Detects a falling edge of the $\overline{WKP1}$ pin input 1: Detects a rising edge of the $\overline{WKP1}$ pin input
0	WKEGS0	0	R/W	WKP0 Edge Select 0: Detects a falling edge of the $\overline{WKP0}$ pin input 1: Detects a rising edge of the $\overline{WKP0}$ pin input

				This bit is always read as 1.
5	IENWP	0	R/W	Wakeup Interrupt Request Enable The WKP7 to WKP0 interrupt requests are enabled when this bit is set to 1.
4	IEN4	0	R/W	IRQ4 Interrupt Request Enable The IRQ4 interrupt request is enabled when this bit is set to 1.
3	IEN3	0	R/W	IRQ3 Interrupt Request Enable The IRQ3 interrupt request is enabled when this bit is set to 1.
2	IENEC2	0	R/W	IRQAEC Interrupt Request Enable The IRQAEC interrupt request is enabled when this bit is set to 1.
1	IEN1	0	R/W	IRQ1 Interrupt Request Enable The IRQ1 interrupt request is enabled when this bit is set to 1.
0	IEN0	0	R/W	IRQ0 Interrupt Request Enable The IRQ0 interrupt request is enabled when this bit is set to 1.

6	IENAD	0	R/W	A/D Converter Interrupt Request Enable The A/D converter interrupt request is enabled when this bit is set to 1.
5	—	0	R/W	Reserved This bit is read/write enable reserved bit.
4	—	1	R/W	Reserved This bit is always read as 1.
3	IENTFH	0	R/W	Timer FH Interrupt Request Enable The timer FH interrupt request is enabled when this bit is set to 1.
2	IENTFL	0	R/W	Timer FL Interrupt Request Enable The timer FL interrupt request is enabled when this bit is set to 1.
1	—	1	R/W	Reserved This bit is always read as 1.
0	IENEC	0	R/W	Asynchronous Event Counter Interrupt Request Enable The asynchronous event counter interrupt request is enabled when this bit is set to 1.

				When the IRQ4 pin is set as the interrupt input and the specified edge is detected [Clearing condition] When 0 is written to this bit
3	IRRI3	0	R/(W)*	IRQ3 Interrupt Request Flag [Setting condition] When the IRQ3 pin is set as the interrupt input and the specified edge is detected [Clearing condition] When 0 is written to this bit
2	IRREC2	0	R/(W)*	IRQAEC Interrupt Request Flag [Setting condition] When the IRQAEC pin is set as the interrupt input and the specified edge is detected [Clearing condition] When 0 is written to this bit
1	IRRI1	0	R/(W)*	IRQ1 Interrupt Request Flag [Setting condition] When the IRQ1 pin is set as the interrupt input and the specified edge is detected [Clearing condition] When 0 is written to this bit

4.3.6 Interrupt Request Register 2 (IRR2)

IRR2 indicates the interrupt request status of the direct transition, A/D converter, timer F, and asynchronous event counter.

Bit	Bit Name	Initial Value	R/W	Description
7	IRRDT	0	R/(W)*	Direct Transition Interrupt Request Flag [Setting condition] When the SLEEP instruction is executed and a direct transition is made while the DTON bit in SYSCON is set to 1 [Clearing condition] When 0 is written to this bit
6	IRRAD	0	R/(W)*	A/D Converter Interrupt Request Flag [Setting condition] When A/D conversion ends [Clearing condition] When 0 is written to this bit
5	—	0	R	Reserved This bit is always read as 0.
4	—	1	R/W	Reserved This bit is always read as 1.

				[Clearing condition] When 0 is written to this bit
1	—	1	R/W	Reserved This bit is always read as 1.
0	IRREC	0	R/(W)*	Asynchronous Event Counter Interrupt Reque [Setting condition] When the asynchronous event counter overflo [Clearing condition] When 0 is written to this bit

Note: * Only a write of 0 for flag clearing is possible.

				[Clearing condition] When 0 is written to this bit
6	IWPF6	0	R/W	WKP6 Interrupt Request Flag [Setting condition] When the $\overline{WKP6}$ pin is set as the interrupt input, the specified edge is detected [Clearing condition] When 0 is written to this bit
5	IWPF5	0	R/W	WKP5 Interrupt Request Flag [Setting condition] When the $\overline{WKP5}$ pin is set as the interrupt input, the specified edge is detected [Clearing condition] When 0 is written to this bit
4	IWPF4	0	R/W	WKP4 Interrupt Request Flag [Setting condition] When the $\overline{WKP4}$ pin is set as the interrupt input, the specified edge is detected [Clearing condition] When 0 is written to this bit
3	IWPF3	0	R/W	WKP3 Interrupt Request Flag [Setting condition] When the $\overline{WKP3}$ pin is set as the interrupt input, the specified edge is detected [Clearing condition] When 0 is written to this bit

When the $\overline{WKP1}$ pin is set as the interrupt input,
the specified edge is detected

[Clearing condition]

When 0 is written to this bit

0

IWPF0

0

R/W

WKP0 Interrupt Request Flag

[Setting condition]

When the $\overline{WKP0}$ pin is set as the interrupt input,
the specified edge is detected

[Clearing condition]

When 0 is written to this bit

6	IPRn6	0	R/W	source. 00: Mask level 0 (Lowest) 01: Mask level 1 1*: Mask level 2 (Highest)
5	IPRn5	0	R/W	Set the mask level of the corresponding interrupt source. 00: Mask level 0 (Lowest) 01: Mask level 1 1*: Mask level 2 (Highest)
4	IPRn4	0	R/W	
3	IPRn3	0	R/W	Set the mask level of the corresponding interrupt source. 00: Mask level 0 (Lowest) 01: Mask level 1 1*: Mask level 2 (Highest)
2	IPRn2	0	R/W	
1	IPRn1	0	R/W	Set the mask level of the corresponding interrupt source. 00: Mask level 0 (Lowest) 01: Mask level 1 1*: Mask level 2 (Highest)
0	IPRn0	0	R/W	

[Legend] *: Don't care.
n = A to E

0	INTM0	0	R/W	1*: Mask an interrupt with mask level 1 or less
				01: Mask an interrupt with mask level 0
				00: Accept all interrupts

[Legend] *: Don't care.

4.4 Interrupt Sources

4.4.1 External Interrupts

There are 14 external interrupts: NMI, WKP7 to WKP0, IRQ4, IRQ3, IRQAEC, IRQ1,

(1) NMI Interrupt

NMI is the highest-priority interrupt, and is always accepted by the CPU regardless of the I bit in CCR. The NMIEG bit in IEGR can be used to select whether an interrupt is recognized at a rising edge or a falling edge on the NMI pin.

(2) WKP7 to WKP0 Interrupts

WKP7 to WKP0 interrupts are requested by the rising or falling edge input signals at the $\overline{\text{WKP0}}$ pins.

When the rising or falling edge is input while the $\overline{\text{WKP7}}$ to $\overline{\text{WKP0}}$ pin functions are selected in PMR5, the corresponding bit in IWPR is set to 1 and an interrupt request is generated.

Clearing the IENWP bit in IENR1 to 0 disables the wakeup interrupt request to be accepted. Setting the I bit in CCR to 1 masks all interrupts.

selected by PMRB and PMR9, the corresponding bit in IRR1 is set to 1 and an interrupt request is generated.

Clearing the IEN4, IEN3, IEN1, and IEN0 bits in IENR1 to 0 disables the interrupt request. An interrupt request is not accepted. Setting the I bit in CCR to 1 masks all interrupts.

The interrupt mask level can be set by IPR.

(4) IRQAEC Interrupts

An IRQAEC interrupt is requested by an input signal at the IRQAEC pin or IECPWM (PWM output for the AEC). When the IRQAEC pin is used as an external interrupt pin, clear the IECPWME bit in AEGSR to 0.

Using the AIEGS1 and AIEGS0 bits in AEGSR, it is possible to select whether an interrupt is generated by a rising edge, falling edge, or both edges.

When the IENEC2 bit in IENR1 is set to 1 and the specified edge is input, the corresponding bit in IRR1 is set to 1 and an interrupt request is generated.

When exception handling for the IRQAEC interrupt is accepted, the I bit in CCR is set to 1.

The interrupt mask level can be set by IPR.

4.5 Interrupt Exception Handling Vector Table

Table 4.2 shows interrupt exception handling sources, vector addresses, and interrupt priority. The lower the vector number, the higher the priority. The priority within a module is fixed. Levels for interrupts other than NMI and address break can be modified by IPR.

	IRQ3	9	H'0012	IPRA1, IPRA0
	IRQ4	10	H'0014	
	WKP0	11	H'0016	IPRB7, IPRB6
	WKP1	12	H'0018	
	WKP2	13	H'001A	
	WKP3	14	H'001C	
	WKP4	15	H'001E	
	WKP5	16	H'0020	
	WKP6	17	H'0022	
	WKP7	18	H'0024	
RTC	0.25-second overflow	19	H'0026	IPRB5, IPRB4
	0.5-second overflow	20	H'0028	
	Second periodic overflow	21	H'002A	
	Minute periodic overflow	22	H'002C	
	Hour periodic overflow	23	H'002E	
	Day-of-week periodic overflow	24	H'0030	
	Week periodic overflow	25	H'0032	
	Free-running overflow	26	H'0034	

	TG2B (TG2B input capture/compare match)	33	H'0042	
	TCI2V (overflow 2)	34	H'0044	
Timer F	Timer FL compare match Timer FL overflow	35	H'0046	IPRC3, IPRC2
	Timer FH compare match Timer FH overflow	36	H'0048	
SCI4*	Receive data full/transmit data empty Transmit end/receive error	37	H'004A	IPRC1, IPRC0
SCI3_1	Transmit completion/transmit data empty Receive data full/overrun error Framing error/parity error	38	H'004C	IPRD7, IPRD6
SCI3_2	Transmit completion/transmit data empty Receive data full/overrun error Framing error/parity error	39	H'004E	IPRD5, IPRD4
IIC	Transmit data empty/transmit end Receive data full/overrun error NACK detection Arbitration/overrun error	40	H'0050	IPRD3, IPRD2
10-bit A/D	A/D conversion end	42	H'0054	IPRE7, IPRE6
(SLEEP instruction execution)	Direct transition	43	H'0056	IPRE5, IPRE4

Note: * Supported only by the F-ZTAT version.

Four-level interrupt masking is controlled according to the combination of the I bit in CCR and the INTM1 and INTM0 bits in INTM.

Table 4.3 Interrupt Control States

CCR I	INTM		States
	INTM1	INTM0	
1	*	*	All interrupts other than NMI and address break are masked.
0	1	*	Interrupts with mask level 1 or less are masked.
	0	1	Interrupts with mask level 0 are masked.
	0	0	All interrupts are accepted.

[Legend]*: Don't care.

1. If an interrupt source whose enable bit is set to 1 occurs, an interrupt request is sent to the interrupt controller.
2. The following control operations are performed by referencing the INTM1 and INTM0 bits in INTM and the I bit in CCR.
 - When the I bit is set to 1, the interrupt request is held pending.
 - When the I bit is cleared to 0 and the INTM1 bit is set to 1, interrupts with mask level 1 or less are held pending.
 - When the I bit is cleared to 0, the INTM1 bit is cleared to 0, and the INTM0 bit is set to 1, interrupt requests with mask level 0 are held pending.
 - When the I bit, INTM1 bit, and INTM0 bit are all cleared to 0, all interrupt requests are accepted.
3. If contention occurs between interrupts that are not held pending by the INTM1 and INTM0 bits in the INTM register and the I bit in CCR, the interrupt with the highest priority as shown in table 4.2 is selected, regardless of the IPR setting.

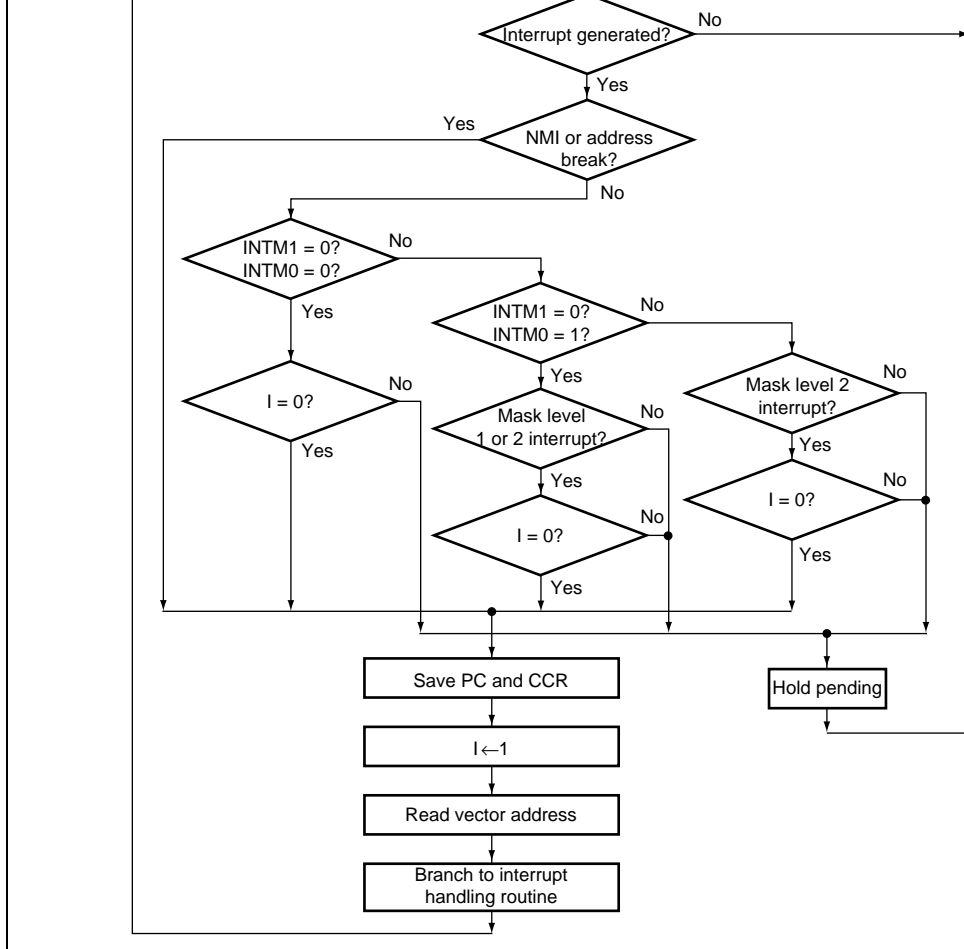


Figure 4.2 Flowchart of Procedure Up to Interrupt Acceptance

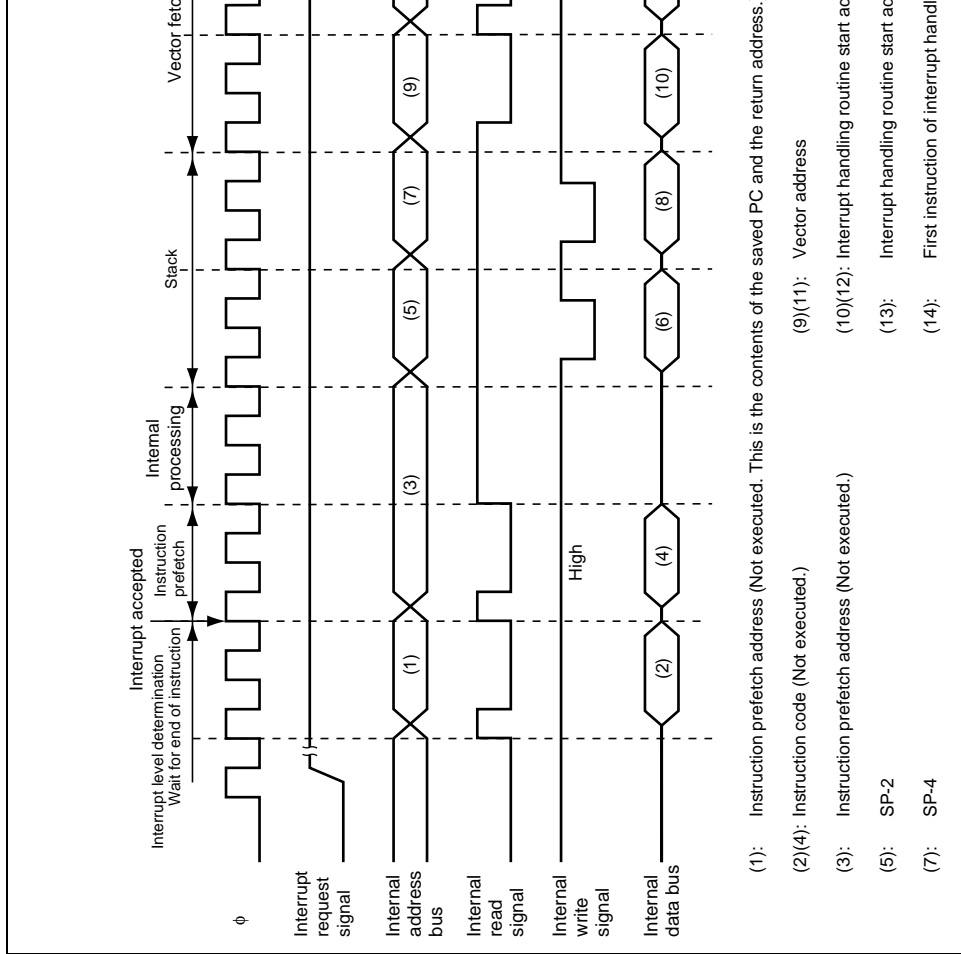


Figure 4.3 Interrupt Exception Handling Sequence

3	PC, CCR stack	4
4	Vector fetch	4
5	Instruction fetch* ²	4
6	Internal processing* ³	4
Total		19 to 41

- Notes: 1. One state for internal interrupts and two states for external interrupts.
2. Prefetch after interrupt acceptance and interrupt handling routine prefetch.
3. Internal processing after interrupt acceptance and internal processing after vector

will be executed for the higher-priority interrupt, and the lower-priority interrupt will be masked. The same also applies when an interrupt source flag is cleared to 0.

Figure 4.4 shows an example in which the TGIEA bit in TIER of the 16-bit timer pulse is cleared to 0.

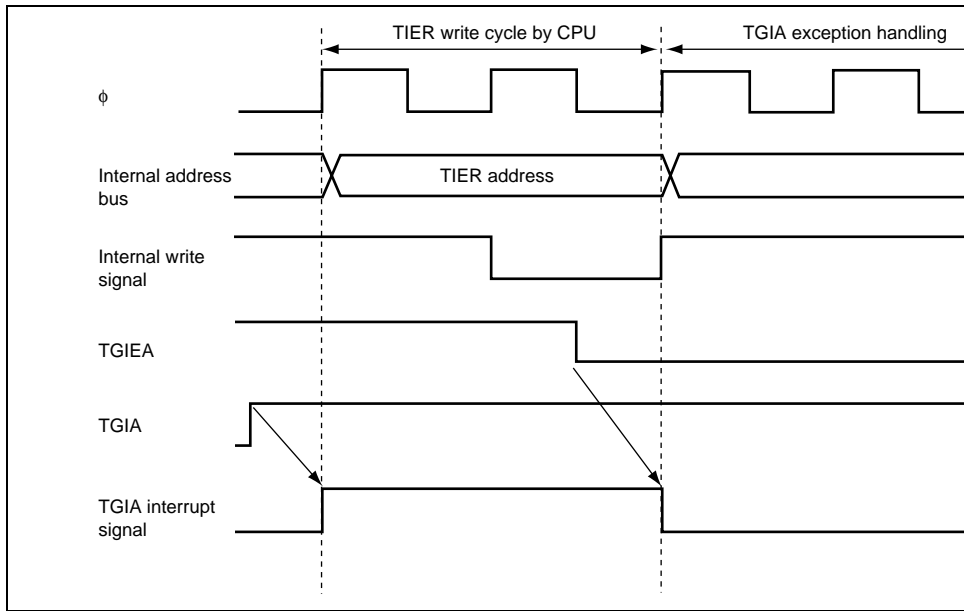


Figure 4.4 Contention between Interrupt Generation and Disabling

The above contention will not occur if an enable bit or interrupt source flag is cleared to 0 before the interrupt is masked.

Interrupt operation differs between the EEPMOV.B instruction and the EEPMOV.W instruction.

With the EEPMOV.B instruction, an interrupt request (including NMI) issued during transfer is not accepted until the transfer is completed.

With the EEPMOV.W instruction, even if an interrupt request other than the NMI is issued during transfer, the interrupt is not accepted until the transfer is completed. If the NMI interrupt request is issued, NMI exception handling starts at a break in the transfer cycle. The PC value saved on the stack in this case is the address of the next instruction.

Therefore, if an NMI interrupt is generated during execution of an EEPMOV.W instruction, the following coding should be used.

```
L1:  EEPMOV.W
      MOV.W   R4, R4
      BNE    L1
```

4.7.4 IENR Clearing

When an interrupt request is disabled by clearing the interrupt enable register or when the interrupt request register is cleared, the interrupt request should be masked (I bit = 1). If the above operation is executed while the I bit is 0 and contention between the instruction execution and the interrupt request generation occurs, exception handling, which corresponds to the interrupt request generated after instruction execution of the above operation is completed, is executed.

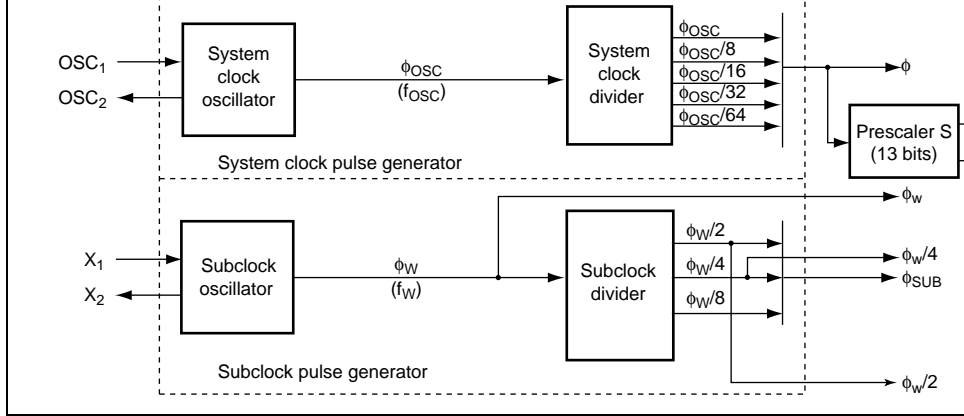


Figure 5.1 Block Diagram of Clock Pulse Generators (Flash Memory Version)

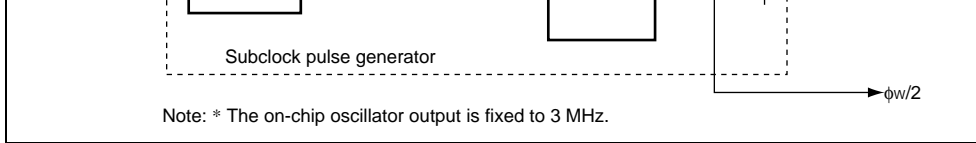


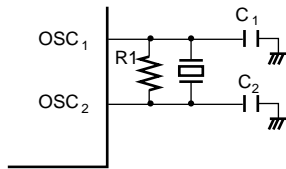
Figure 5.1 Block Diagram of Clock Pulse Generators (Masked ROM Version)

The basic clock signals that drive the CPU and on-chip peripheral modules are ϕ and ϕ_{SUB} . The system clock is divided by prescaler S to become a clock signal from $\phi/8192$ to $\phi/2$. Both the system clock and subclock signals are provided to the on-chip peripheral modules.

Since the on-chip oscillator is available for the masked ROM version, the reference clock can be selected to be output from the on-chip oscillator or system clock oscillator by the input level of the IRQAEC pin.

7	32KSTOP	0	R/W	Subclock Oscillator Operation Control 0: Subclock oscillator operates 1: Subclock oscillator stops
6	—	0	R/W	Reserved This bit is readable/writable.
5 to 0	—	All 0	—	Reserved These bits cannot be modified.

2	IRQAEC	—	R	IRQAEC flag This bit indicates the IRQAEC pin input level set during resets. 0: IRQAEC pin set to GND during resets 1: IRQAEC pin set to Vcc during resets
1	OSCF	—	R	OSC flag This bit indicates the oscillator operating with the clock pulse generator. 0: System clock oscillator operating (on-chip oscillator stopped) 1: On-chip oscillator operating (system clock oscillator stopped)
0	—	0	R/W	Reserved Never write 1 to this bit, as it can cause the LSI malfunction.



R1 = 1 MΩ ±20%

Note: Consult with the crystal resonator manufacturer to determine the circuit constants.

Frequency	Manufacturer	Product Type	C ₁ , C ₂ Recommendation
4.19 MHz	Kyocera Kinseki Corporation	HC-491U-S	22 pF ±20%

Figure 5.2 Typical Connection to Crystal Resonator

Figure 5.3 Typical Connection to Ceramic Resonator

5.2.3 External Clock Input Method

Connect an external clock signal to pin OSC1, and leave pin OSC2 open. Figure 5.4 shows typical connection. The duty cycle of the external clock signal must be 45 to 55%.

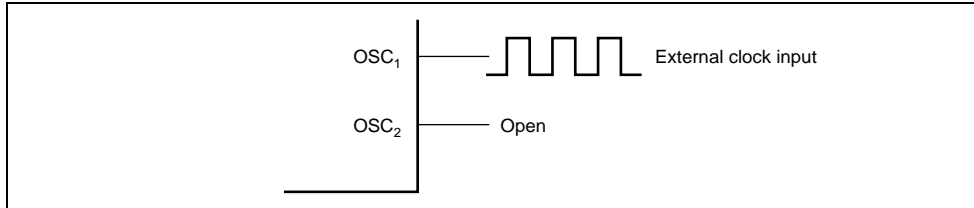


Figure 5.4 Example of External Clock Input

5.2.4 On-Chip Oscillator Selection Method (Supported only by the Masked ROM Version)

The on-chip oscillator is selected by the input level of the IRQAEC pin during a reset. The selection method of the system clock oscillator and the on-chip oscillator is listed in table 5.1. The input level of the IRQAEC pin during a reset* should be fixed either to V_{cc} or GND, depending on the oscillator type to be selected. The setting takes effect when the reset is cleared. When the on-chip oscillator is selected, to connect a resonator to OSC1 or OSC2 is not necessary. In this case, the OSC1 pin should be fixed to V_{cc} or GND.

Note: * This reset represents an external reset or power-on reset, but not a reset by the watchdog timer.

Clock pulses can be supplied to the subclock generator by connecting a 32.768-kHz or 38.4-kHz crystal resonator, as shown in figure 5.5. Notes described in section 5.5.2, Notes on Board Configuration, also apply to this connection.

The 32KSTOP bit in the SUB32CR register can stop the subclock oscillator with the subclock oscillator program. To stop the subclock oscillator, set the SUB32CR register in active mode. When restoring from the subclock stopped condition, use the subclock after the oscillator stabilization time has elapsed, as the same as for the power supply.

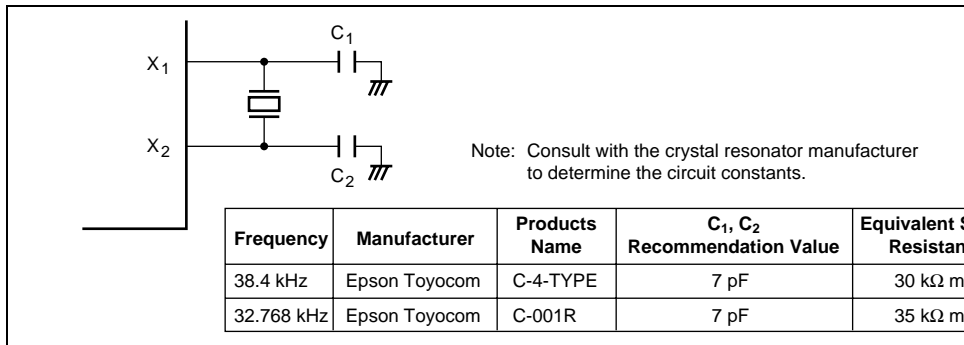


Figure 5.5 Typical Connection to 32.768-kHz/38.4-kHz Crystal Resonator

Figure 5.6 shows the equivalent circuit of the crystal resonator.

The drive capacity of the subclock generator circuit is limited in order to reduce current consumption when operating in the subclock mode. As a result, there may not be sufficient additional margin to accommodate some resonators. Be sure to select a resonator with an equivalent series resistance (R_s) corresponding to that shown in figure 5.6.

5.3.2 Pin Connection when not Using Subclock

When the subclock is not used, connect the X_1 pin to GND and leave the X_2 pin open, as shown in figure 5.7.

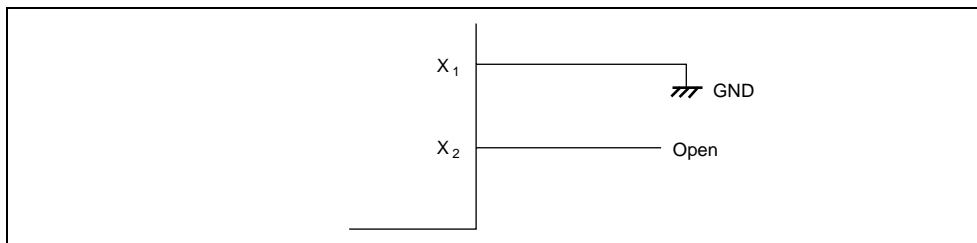


Figure 5.7 Pin Connection when not Using Subclock

Figure 5.8 Pin Connection when Inputting External Clock

Frequency	Subclock (ϕ_w)
Duty	45% to 55%

5.4 Prescalers

This LSI is equipped with an on-chip prescaler (prescaler S).

Prescaler S is a 13-bit counter using the system clock (ϕ) as its input clock. Its prescaled provide internal clock signals for on-chip peripheral modules.

5.4.1 Prescaler S

Prescaler S is a 13-bit counter using the system clock (ϕ) as its input clock. A divided output is used as an internal clock of an on-chip peripheral module. Prescaler S is initialized to H'0000 at reset, and starts counting up on exit from the reset state. In standby mode, watch mode, suspend mode, and subsleep mode, the system clock pulse generator stops. Prescaler S also stops counting. Prescaler S is initialized to H'0000. The CPU cannot read from or write to prescaler S.

The output from prescaler S is shared by the on-chip peripheral modules. In active (medium-speed) mode and sleep (medium-speed) mode, the clock input to prescaler S is determined by the division ratio designated by the MA1 and MA0 bits in SYSCR2.

resonator arrangement.

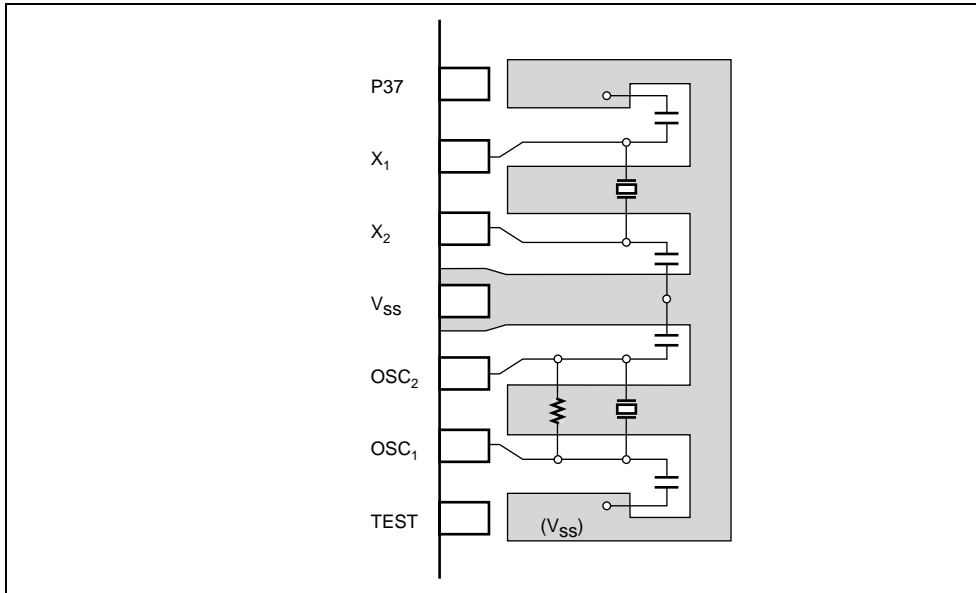
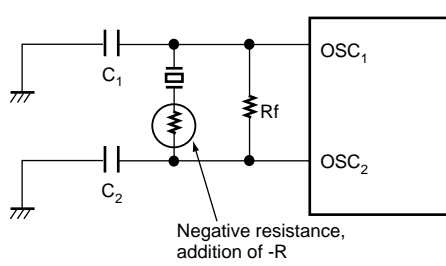
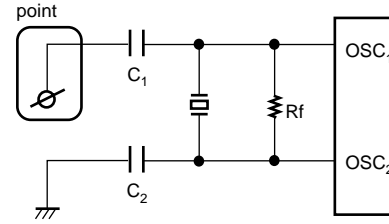


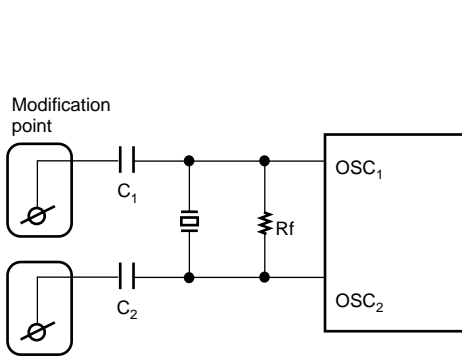
Figure 5.9 Example of Crystal and Ceramic Resonator Arrangement



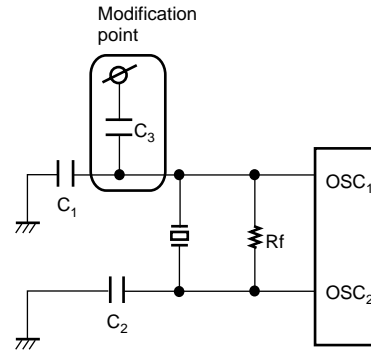
(1) Negative Resistance Measuring Circuit



(2) Oscillator Circuit Modification Suggestion 1



(3) Oscillator Circuit Modification Suggestion 2



(4) Oscillator Circuit Modification Suggestion 3

Figure 5.10 Negative Resistance Measurement and Circuit Modification Suggestion

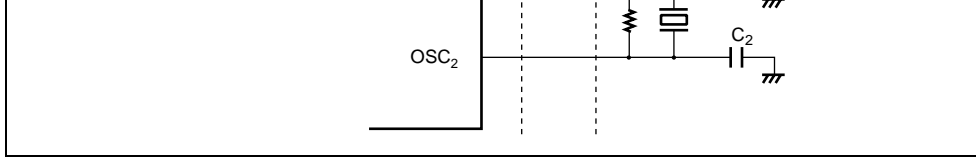


Figure 5.11 Example of Incorrect Board Design

Note: When a crystal resonator or ceramic resonator is connected, consult with the crystal resonator and ceramic resonator manufacturers to determine the circuit constants. The constants differ according to the resonator, stray capacitance of the mounting, and so on.

5.5.3 Definition of Oscillation Stabilization Wait Time

Figure 5.12 shows the oscillation waveform (OSC2), system clock (ϕ), and microcomputer operating mode when a transition is made from standby mode, watch mode, or subactive mode to active (high-speed/medium-speed) mode, with a resonator connected to the system clock oscillator.

As shown in figure 5.12, when a transition is made from a mode in which the system clock oscillator is halted to active (high-speed/medium-speed) mode, the sum of the following times (oscillation start time and wait time) is required.

(1) Oscillation Start Time

The time from the point at which the system clock oscillator oscillation waveform starts to the point when an interrupt is generated, until generation of the system clock starts.

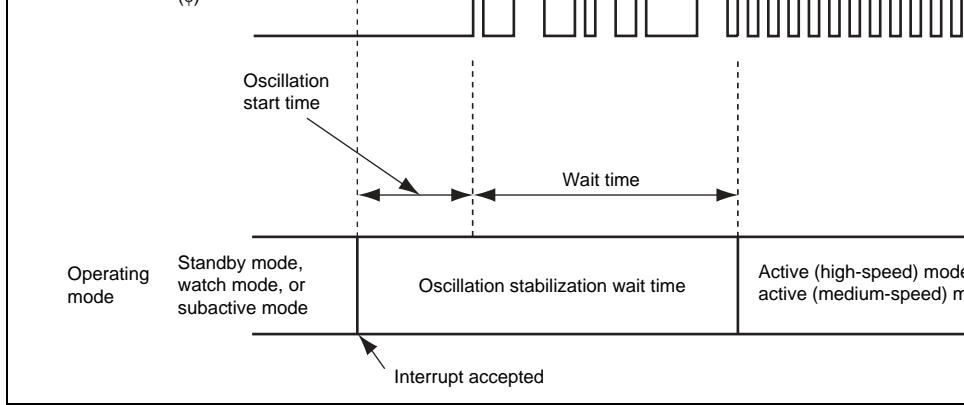


Figure 5.12 Oscillation Stabilization Wait Time

The required the oscillation stabilization time is the same as the “oscillation stabilization at power-on specified in the AC characteristics. Set STS2 to STS0 in SYSCR1 so that the wait time is equal to or greater than t_{RC} .

If a resonator is connected to the system clock oscillator, it is important to carefully evaluate the characteristics of the actual circuitry mounted on the board when a transition is made from standby mode, watch mode, or subactive mode to active (high-speed/medium-speed) mode. Set the wait time that will allow sufficient increase in the oscillation amplitude of OSC1 and OSC2. The oscillation start time will differ depending on the mounted circuitry constants and stray capacitance. Therefore, consult with the manufacturer of the resonator when setting the oscillation stabilization wait time.

the power supply potential. In this state, the oscillation waveform may be disrupted, leading to an unstable system clock and incorrect operation of the microcomputer.

If incorrect operation occurs, change the setting of the standby timer select bits 2 to 0 (STSTS0) (bits 6 to 4 in the system control register 1 (SYSCR1)) to give a longer wait time.

For example, if incorrect operation occurs with a wait time setting of 1,024 states, check operation with a wait time setting of 2,048 states or more.

If the same kind of incorrect operation occurs after a reset as after a state transition, hold the pin low for a longer period.

5.5.6 Note on Using Power-On Reset Circuit

The LSI's internal power-on reset circuit can be adjusted by connecting an external capacitor to the $\overline{\text{RES}}$ pin. Adjust the capacitance of the external capacitor to ensure sufficient oscillation stabilization time before reset clearing. For details, see section 21, Power-On Reset Circuit.

- Subactive mode
The CPU and all on-chip peripheral modules are operable on the subclock. The subclock frequency can be selected from $\phi_w/2$, $\phi_w/4$, and $\phi_w/8$.
- Sleep (high-speed) mode
The CPU halts. On-chip peripheral modules are operable on the system clock.
- Sleep (medium-speed) mode
The CPU halts. On-chip peripheral modules are operable on the system clock. The system clock frequency can be selected from $\phi_{osc}/8$, $\phi_{osc}/16$, $\phi_{osc}/32$, and $\phi_{osc}/64$.
- Subsleep mode
The CPU halts. The on-chip peripheral modules are operable on the subclock. The subclock frequency can be selected from $\phi_w/2$, $\phi_w/4$, and $\phi_w/8$.
- Watch mode
The CPU halts. The on-chip peripheral modules are operable on the subclock.
- Standby mode
The CPU and all on-chip peripheral modules halt.
- Module standby function
Independent of the above modes, power consumption can be reduced by halting on-chip peripheral modules that are not used in module units.

Note: In this manual, active (high-speed) mode and active (medium-speed) mode are collectively called active mode.

SYSCR1 controls the power-down modes, as well as SYSCR2.

Bit	Bit Name	Initial Value	R/W	Description
7	SSBY	0	R/W	<p>Software Standby</p> <p>Selects the mode to transit after the execution of the SLEEP instruction.</p> <p>0: A transition is made to sleep mode or subsleep mode.</p> <p>1: A transition is made to standby mode or wait mode.</p> <p>For details, see table 6.2.</p>
6	STS2	0	R/W	Standby Timer Select 2 to 0
5	STS1	0	R/W	Designate the time the CPU and peripheral modules wait for stable clock operation after exiting from standby mode, subactive mode, subsleep mode, or wait mode to active mode or sleep mode due to an interrupt. The designation should be made according to the operating frequency so that the waiting time is at least equal to the oscillation stabilization time. The relationship between the specified value and the number of wait states is shown in table 6.1.
4	STS0	0	R/W	

When an external clock is to be used, the minimum value (STS2 = 1, STS1 = 0, STS0 = 1) is recommended. If the internal oscillator is used, the settings CT = 1, STS = 1, and STS0 = 0 are recommended. If the setting other than the recommended value is made, operation may start before the end of the waiting time.

0	MA0	1	R/W	Select the operating clock frequency in active (high-speed) mode and sleep (medium-speed) mode. MA1 and MA0 bits should be written to in active (high-speed) mode or subactive mode.
				00: ϕ OSC/8
				01: ϕ OSC/16
				10: ϕ OSC/32
				11: ϕ OSC/64

Table 6.1 Operating Frequency and Waiting Time

Bit			Operating Frequency			
STS2	STS1	STS0	Waiting Time	2 MHz	4.19 MHz	10 MHz
0	0	0	8,192 states	4.1	1.953	0.1
		1	16,384 states	8.2	3.907	1.0
	1	0	1,024 states	0.512	0.244	0.0
		1	2,048 states	1.024	0.488	0.0
1	0	0	4,096 states	2.048	0.977	0.0
		1	2 states (external clock input)	0.001	0.0005	0.0
	1	0	8 states	0.004	0.0019	0.0
		1	16 states	0.008	0.0038	0.0

Note: Time unit is ms.

When an external clock is input, bits STS2 to STS0 should be set as external clock input mode before mode transition is executed. When an external clock is not used, the bits should not be set as external clock input mode.

generates the oscillator clock (ϕ_{OSC}). This bit selects the sampling frequency of ϕ_{OSC} when ϕ_W is sampled. If $\phi_{OSC} = 2$ to 10 MHz, clear this bit to 0. Set it to 1 if the internal oscillator is used.

0: Sampling rate is $\phi_{OSC}/16$.

1: Sampling rate is $\phi_{OSC}/4$.

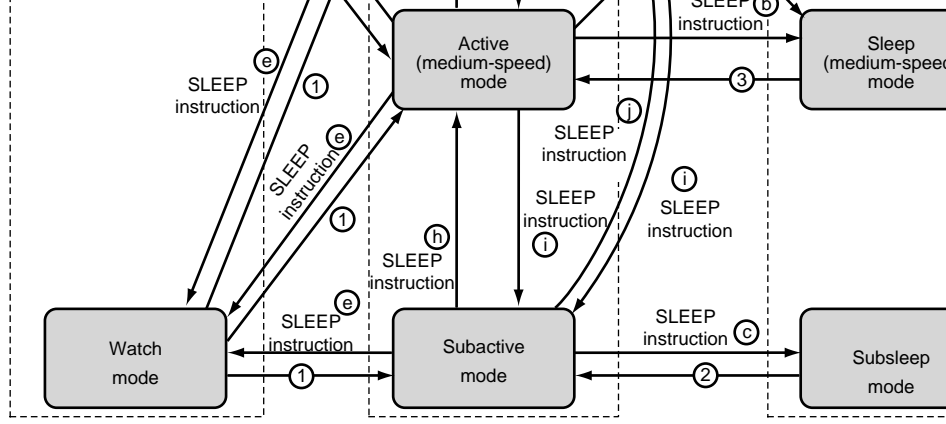
3	DTON	0	R/W	<p>Direct Transfer on Flag</p> <p>Selects the mode to which the transition is made when the SLEEP instruction is executed with bits SS1, SS2, TMA3, and LSON in SYSCR1 and bit MSON in SYSCR2. For details, see table 6.2.</p>
2	MSON	0	R/W	<p>Medium Speed on Flag</p> <p>After standby, watch, or sleep mode is cleared, this bit selects active (high-speed) or active (medium-speed) mode.</p> <p>0: Operation in active (high-speed) mode</p> <p>1: Operation in active (medium-speed) mode</p>
1	SA1	0	R/W	Subactive Mode Clock Select 1 and 0
0	SA0	0	R/W	<p>Select the operating clock frequency in subactive and subsleep modes. The values of SA1 and SA0 do not change if they are written to in subactive mode.</p> <p>00: $\phi_W/8$</p> <p>01: $\phi_W/4$</p> <p>1X: $\phi_W/2$</p>

[Legend] X: Don't care.

6	S31CKSTP	1	R/W	SCI3 Module Standby* ² SCI31 enters standby mode when this bit is cleared to 0.
5	S32CKSTP	1	R/W	SCI3 Module Standby* ² SCI32 enters standby mode when this bit is cleared to 0.* ¹
4	ADCKSTP	1	R/W	A/D Converter Module Standby A/D converter enters standby mode when this bit is cleared to 0.
3	—	1	R/W	Reserved This readable/writable bit is reserved.
2	TFCKSTP	1	R/W	Timer F Module Standby Timer F enters standby mode when this bit is cleared to 0.
1	FROMCKSTP* ¹ * ⁴	1	R/W* ¹	Flash Memory Module Standby Flash memory enters standby mode when this bit is cleared to 0.
0	RTCKSTP	1	R/W	RTC Module Standby RTC enters standby mode when this bit is cleared to 0.

				The IIC2 enters standby mode when this bit is cleared to 0.
4	PW2CKSTP	1	R/W	PWM2 Module Standby The PWM2 enters standby mode when this bit is cleared to 0.
3	AECCKSTP	1	R/W	Asynchronous Event Counter Module Standby The asynchronous event counter enters standby mode when this bit is cleared to 0.
2	WDCKSTP	1	R/W* ³	Watchdog Timer Module Standby The watchdog timer enters standby mode when this bit is cleared to 0.
1	PW1CKSTP	1	R/W	PWM1 Module Standby The PWM1 enters standby mode when this bit is cleared to 0.
0	LDCKSTP	1	R/W	LCD Module Standby The LCD controller/driver enters standby mode when this bit is cleared to 0.

- Notes:
1. This is a reserved bit which is not readable/writable in the masked ROM version.
 2. When the SCI module standby is set, all registers in the SCI3 enter the reset state.
 3. This bit is valid when the WDON bit in TCSRW is 0. If this bit is cleared to 0 while the WDON bit is set to 1 (while the watchdog timer is operating), this bit is cleared to 0. However, the watchdog timer does not enter module standby mode and continues operating. When the watchdog timer stops operating and the WDON bit is cleared by software, this bit is valid and the watchdog timer enters module standby mode.
 4. This bit should be set to 1 when the on-chip debugger is used.



→ : Transition is made after exception handling is executed.

Power-down modes

Mode Transition Conditions (1)

	LSON	MSON	SSBY	TMA3	DTON
(a)	0	0	0	*	0
(b)	0	1	0	*	0
(c)	1	*	0	1	0
(d)	0	*	1	0	0
(e)	*	*	1	1	0
(f)	0	0	0	*	1
(g)	0	1	0	*	1
(h)	0	1	1	1	1
(i)	1	*	1	1	1
(j)	0	0	1	1	1

* Don't care

Mode Transition Conditions (2)

	Interrupt Sources
①	RTC, timer F, IRQ0 interrupt, AEC, WKP7 to WKP0 interrupts
②	RTC, timer F, TPU, SCI3 interrupt, IRQ1, IRQ0, IRQAEC interrupts, WKP7 interrupts, AEC
③	All interrupts
④	IRQ1, IRQ0, WKP7 to WKP0 interrupts, AEC

Note: A transition between different modes cannot be made to occur simply because an interrupt request is generated. Make sure to enable interrupt requests.

Figure 6.1 Mode Transition Diagram

					(medium-speed) mode	(medium-speed) mode	
0	0	1	0	0	Standby mode	Active (high-speed) mode	d
0	1	1	0	0	Standby mode	Active (medium-speed) mode	d
0	0	1	1	0	Watch mode	Active (high-speed) mode	e
0	1	1	1	0	Watch mode	Active (medium-speed) mode	e
1	*	1	1	0	Watch mode	Subactive mode	e
0	0	0	*	1	Active (high-speed) mode (direct transition)	—	—
0	1	0	*	1	Active (medium-speed) mode (direct transition)	—	g
1	*	1	1	1	Subactive mode (direct transition)	—	i

0	0	1	0	0	Standby mode	Active (high-speed) mode	d
0	1	1	0	0	Standby mode	Active (medium-speed) mode	d
0	0	1	1	0	Watch mode	Active (high-speed) mode	e
0	1	1	1	0	Watch mode	Active (medium-speed) mode	e
1	1	1	1	0	Watch mode	Subactive mode	e
0	0	0	*	1	Active (high-speed) mode (direct transition)	—	f
0	1	0	*	1	Active (medium-speed) mode (direct transition)	—	—
1	*	1	1	1	Subactive mode (direct transition)	—	i

1	*	1	1	0	Watch mode	Subactive mode e	
0	0	1	1	1	Active (high-speed) mode (direct transition)	—	j
0	1	1	1	1	Active (medium-speed) mode (direct transition)	—	h
1	*	1	1	1	Subactive mode (direct transition)	—	—

[Legend] *: Don't care.

						Functioning		
Peripheral modules	RTC	Functioning	Functioning	Functioning	Functioning	Functioning/ retained ^{*5}	Functioning/ retained ^{*9}	Functioning/ retained ^{*8}
	Asynchronous event counter					Functioning ^{*6}	Functioning	Functioning
	Timer F					Functioning/ retained ^{*7}	Functioning/ retained ^{*7}	Functioning/ retained ^{*7}
	TPU					Retained	Retained	Retained
	WDT					Functioning ^{*8} / retained	Functioning ^{*8} / retained	Functioning ^{*8} / retained
	SCI3/IrDA					Reset	Functioning/ retained ^{*2}	Functioning/ retained ^{*2}
	IIC2					Retained	Retained	Retained
	PWM					Retained	Retained	Retained
	A/D converter					Retained	Retained	Retained
	LCD					Functioning/ retained ^{*3}	Functioning/ retained ^{*3}	Functioning/ retained ^{*3}

- Notes:
1. Register contents are retained. Output is the high-impedance state.
 2. Functioning if $\phi_w/2$ is selected as an internal clock, or halted and retained otherwise.
 3. Functioning if ϕ_w , $\phi_w/2$, or $\phi_w/4$ is selected as a clock to be used. Halted and retained otherwise.
 4. Functioning if the timekeeping time-base function is selected.
 5. An external interrupt request is ignored. Contents of the interrupt request register are not affected.
 6. Only incrementing of the external event timer by ECL/ECH and overflow interrupt can operate.
 7. Functioning if $\phi_w/4$ is selected as an internal clock. Halted and retained otherwise.
 8. Functioning if the on-chip oscillator is selected.
 9. Functioning if the internal time keeping time-base function is selected and retained. Interval timer is selected.

mode to active (medium-speed) mode.

When the $\overline{\text{RES}}$ pin goes low, the CPU goes into the reset state and sleep mode is cleared. interrupt request signal is synchronous with the system clock, the maximum time of $2/\phi$ delayed from the point at which an interrupt request signal occurs until the interrupt exception handling is started.

Furthermore, it sometimes operates with half state early timing at the time of transition to active (medium-speed) mode.

6.2.2 Standby Mode

In standby mode, the system clock oscillator stops, so the CPU and on-chip peripheral modules stop functioning when the WDT disables the on-chip oscillator operation. However, as long as the rated voltage is supplied, the contents of CPU registers, on-chip RAM, and some on-chip peripheral module registers are retained. On-chip RAM contents will be retained as long as the voltage set by the RAM data retention voltage is provided. The I/O ports go to the high-impedance state.

Standby mode is cleared by an interrupt. When an interrupt is requested, the system clock oscillator generator starts. After the time set in bits STS2 to STS0 in SYSCR1 has elapsed, standby mode is cleared and interrupt exception handling starts. After standby mode is cleared, a transition occurs to active (high-speed) or active (medium-speed) mode according to the MSON bit in SYSCR1. Standby mode is not cleared if the I bit in CCR is set to 1 or the requested interrupt is disabled by the interrupt enable bit.

When the $\overline{\text{RES}}$ pin goes low, the system clock oscillator starts. Since system clock signals are supplied to the entire chip as soon as the system clock oscillator starts functioning, the $\overline{\text{RES}}$ pin must be kept low until the system clock oscillator output stabilizes (except when the power

Watch mode is cleared by an interrupt. When an interrupt is requested, watch mode is cleared and interrupt exception handling starts. When watch mode is cleared by an interrupt, a transition is made to active (high-speed) mode, active (medium-speed) mode, or subactive mode depending on the settings of the LSON bit in SYSCR1 and the MSON bit in SYSCR2. When the transition is made to active mode, after the time set in bits STS2 to STS0 in SYSCR1 has elapsed, interrupt exception handling starts. Watch mode is not cleared if the I bit in CCR is set to 1 or the request interrupt is disabled by the interrupt enable register.

When the $\overline{\text{RES}}$ pin goes low, the system clock pulse generator starts. Since system clock pulses are supplied to the entire chip as soon as the system clock pulse generator starts functioning, the $\overline{\text{RES}}$ pin must be kept low until the pulse generator output stabilizes. After the pulse generator output has stabilized, the CPU starts reset exception handling if the $\overline{\text{RES}}$ pin is driven high.

6.2.4 Subsleep Mode

In subsleep mode, the CPU operation stops but on-chip peripheral modules other than the A/D converter and PWM function. As long as a required voltage is applied, the contents of CPU registers, the on-chip RAM, and some registers of the on-chip peripheral modules are retained. I/O ports keep the same states as before the transition.

Subsleep mode is cleared by an interrupt. When an interrupt is requested, subsleep mode is cleared and interrupt exception handling starts. After subsleep mode is cleared, a transition is made to active (high-speed) mode, active (medium-speed) mode, or subactive mode. Subsleep mode is not cleared if the I bit in CCR is set to 1 or the request interrupt is disabled by the interrupt enable register.

When the $\overline{\text{RES}}$ pin goes low, the system clock pulse generator starts. Since system clock pulses are supplied to the entire chip as soon as the system clock pulse generator starts functioning, the $\overline{\text{RES}}$ pin must be kept low until the pulse generator output stabilizes. After the pulse generator output has stabilized, the CPU starts reset exception handling if the $\overline{\text{RES}}$ pin is driven high.

When the $\overline{\text{RES}}$ pin goes low, the system clock pulse generator starts. Since system clock are supplied to the entire chip as soon as the system clock pulse generator starts functioning, the $\overline{\text{RES}}$ pin must be kept low until the pulse generator output stabilizes. After the pulse generator output has stabilized, the CPU starts reset exception handling if the $\overline{\text{RES}}$ pin is driven high.

The operating frequency of subactive mode is selected from $\phi_w/2$, $\phi_w/4$, and $\phi_w/8$ by the SA0 bits in SYSCR2.

6.2.6 Active (Medium-Speed) Mode

In active (medium-speed) mode, the system clock oscillator, subclock oscillator, CPU, and chip peripheral module function.

Active (medium-speed) mode is cleared by the SLEEP instruction. When active (medium-speed) mode is cleared, a transition to standby mode is made depending on the combination of bits SSBY, LSON, and TMA3 in SYSCR1, a transition to watch mode is made depending on the combination of bits SSBY and TMA3 in SYSCR1, or a transition to sleep mode is made depending on the combination of bits SSBY and LSON in SYSCR1. Moreover, a transition to active (high-speed) mode or subactive mode is made by a direct transition. Active (medium-speed) mode is not cleared if the I bit in CCR is set to 1 or the requested interrupt is disabled in the interrupt enable register. When the $\overline{\text{RES}}$ pin goes low, the CPU goes into the reset state and active (medium-sleep) mode is cleared.

Furthermore, it sometimes operates with half state early timing at the time of transition to active (medium-speed) mode.

In active (medium-speed) mode, the on-chip peripheral modules function at the clock frequency set by the MA1 and MA0 bits in SYSCR1.

Note: If a direct transition is attempted while the F bit in CCR is set to 1, the device remains in sleep or watch mode, and recovery is not possible.

(1) Direct transfer from active (high-speed) mode to active (medium-speed) mode

When a SLEEP instruction is executed in active (high-speed) mode while the SSBY and TMA3 bits in SYSCR1 are cleared to 0 and the MSON and DTON bits in SYSCR2 are set to 1, a transition is made to active (medium-speed) mode via sleep mode.

(2) Direct transfer from active (medium-speed) mode to active (high-speed) mode

When a SLEEP instruction is executed in active (medium-speed) mode while the SSBY and TMA3 bits in SYSCR1 are cleared to 0, the MSON bit in SYSCR2 is cleared to 0, and the DTON bit in SYSCR2 is set to 1, a transition is made to active (high-speed) mode via sleep mode.

(3) Direct transfer from active (high-speed) mode to subactive mode

When a SLEEP instruction is executed in active (high-speed) mode while the SSBY, TMA3, and TMA2 bits in SYSCR1 are set to 1 and the DTON bit in SYSCR2 is set to 1, a transition is made to subactive mode via watch mode.

(4) Direct transfer from subactive mode to active (high-speed) mode

When a SLEEP instruction is executed in subactive mode while the SSBY and TMA3 bits in SYSCR1 are set to 1, the LSON bit in SYSCR1 is cleared to 0, the MSON bit in SYSCR2 is cleared to 0, and the DTON bit in SYSCR2 is set to 1, a transition is made directly to active (high-speed) mode via watch mode after the waiting time set in bits STS2 to STS0 in SYSCR1 has elapsed.

6.3.1 Direct Transition from Active (High-Speed) Mode to Active (Medium-Speed) Mode

The time from the start of SLEEP instruction execution to the end of interrupt exception (the direct transition time) is calculated by equation (1).

$$\text{Direct transition time} = \{(\text{Number of SLEEP instruction execution states}) + (\text{Number of interrupt processing states})\} \times (\text{tcyc before transition}) + (\text{Number of interrupt exception handling execution states}) \times (\text{tcyc after transition})$$

.....

Example: When $\phi_{osc}/8$ is selected as the CPU operating clock following transition to active (medium-speed) mode.

$$\text{Direct transition time} = (2 + 1) \times \text{tosc} + 14 \times 8\text{tosc} = 115\text{tosc}$$

[Legend]

tosc: OSC clock cycle time

tcyc: System clock (ϕ) cycle time

$$\text{Direct transition time} = (2 + 1) \times 1t_{\text{osc}} + 14 \times 1t_{\text{subcyc}} = 3t_{\text{osc}} + 14t_{\text{subcyc}}$$

[Legend]

tosc: OSC clock cycle time

tsubcyc: Subclock (ϕ_{SUB}) cycle time

6.3.3 Direct Transition from Active (Medium-Speed) Mode to Active (High-Speed) Mode

The time from the start of SLEEP instruction execution to the end of interrupt exception handling (the direct transition time) is calculated by equation (3).

$$\text{Direct transition time} = \{(\text{Number of SLEEP instruction execution states}) + (\text{Number of interrupt exception processing states})\} \times (\text{tcyc before transition}) + (\text{Number of interrupt exception handling execution states}) \times (\text{tcyc after transition})$$

Example: When $\phi_{\text{osc}}/8$ is selected as the CPU operating clock before transition

$$\text{Direct transition time} = (2 + 1) \times 8t_{\text{osc}} + 14 \times t_{\text{osc}} = 38t_{\text{osc}}$$

[Legend]

tosc: OSC clock cycle time

tcyc: System clock (ϕ) cycle time

$$\text{Direct transition time} = (2 + 1) \times 8t_{\text{osc}} + 14 \times 1t_{\text{subcyc}} = 24t_{\text{osc}} + 14t_{\text{subcyc}}$$

[Legend]

tosc: OSC clock cycle time

tsubcyc: Subclock (ϕ_{SUB}) cycle time

6.3.5 Direct Transition from Subactive Mode to Active (High-Speed) Mode

The time from the start of SLEEP instruction execution to the end of interrupt exception (the direct transition time) is calculated by equation (5).

$$\text{Direct transition time} = \{(\text{Number of SLEEP instruction execution states}) + (\text{Number of processing states})\} \times (\text{tsubcyc before transition}) + \{(\text{Wait time STS2 to STS0}) + (\text{Number of interrupt exception handling execution states})\} \times (\text{tcyc after transition})$$

Example: When $\phi_w/8$ is selected as the CPU operating clock before transition and time = 8192 states

$$\text{Direct transition time} = (2 + 1) \times 8t_w + (8192 + 14) \times t_{\text{osc}} = 24t_w + 8192t_{\text{osc}} + 14t_{\text{osc}}$$

[Legend]

tosc: OSC clock cycle time

tw: Watch clock cycle time

tcyc: System clock (ϕ) cycle time

tsubcyc: Subclock (ϕ_{SUB}) cycle time

Example: When $\phi_w/8$ is selected as the CPU operating clock before transition, ϕ_o selected as the CPU operating clock following transition, and the wait time is 8,192 states

$$\begin{aligned}\text{Direct transition time} &= (2 + 1) \times 8t_w + (8192 + 14) \times 8t_{osc} \\ &= 24t_w + 65648t_{osc}\end{aligned}$$

[Legend]

tosc: OSC clock cycle time

tw: Watch clock cycle time

tcyc: System clock (ϕ) cycle time

tsubcyc: Subclock (ϕ_{SUB}) cycle time

6.3.7 Notes on External Input Signal Changes before/after Direct Transition

(1) Direct transition from active (high-speed) mode to subactive mode

Since the mode transition is performed via watch mode, see section 6.5.2, Notes on External Signal Changes before/after Standby Mode.

(2) Direct transition from active (medium-speed) mode to subactive mode

Since the mode transition is performed via watch mode, see section 6.5.2, Notes on External Signal Changes before/after Standby Mode.

(3) Direct transition from subactive mode to active (high-speed) mode

Since the mode transition is performed via watch mode, see section 6.5.2, Notes on External Signal Changes before/after Standby Mode.

6.5 Usage Notes

6.5.1 Standby Mode Transition and Pin States

When a SLEEP instruction is executed in active (high-speed) mode or active (medium-speed) mode while the SSBY and TMA3 bits in SYSCR1 are set to 1 and the LSON bit in SYSIOCR1 is cleared to 0, a transition is made to standby mode. At the same time, pins go to the high-impedance state (except pins for which the pull-up MOS is designated as on). Figure 6.2 shows the timing in this case.

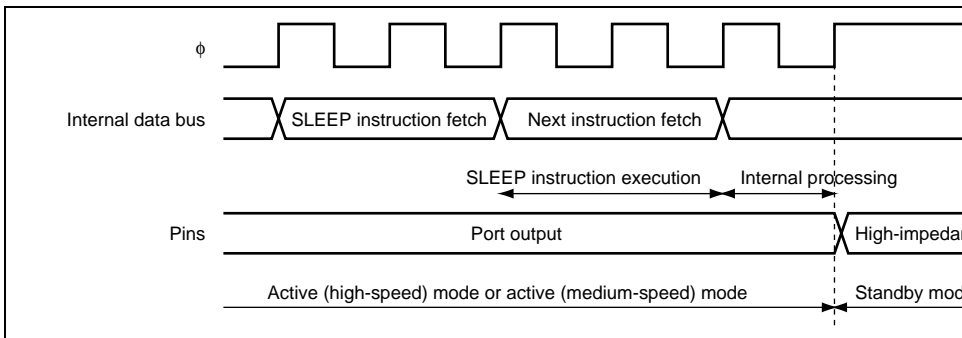


Figure 6.2 Standby Mode Transition and Pin States

(2) When External Input Signals cannot be Captured because Internal Clock Stop

The case of falling edge capture is shown in figure 6.3.

As shown in the case marked "Capture not possible," when an external input signal falls immediately after a transition to active mode or subactive mode, after oscillation is started, interrupt via a different signal, the external input signal cannot be captured if the high-level at that point is less than $2 t_{\text{cyc}}$ or $2 t_{\text{subcyc}}$.

(3) Recommended Timing of External Input Signals

To ensure dependable capture of an external input signal, high- and low-level signal widths of at least $2 t_{\text{cyc}}$ or $2 t_{\text{subcyc}}$ are necessary before a transition is made to standby mode or watch mode. This is shown in "Capture possible: case 1."

External input signal capture is also possible with the timing shown in "Capture possible: case 2" and "Capture possible: case 3," in which a $2 t_{\text{cyc}}$ or $2 t_{\text{subcyc}}$ level width is secured.

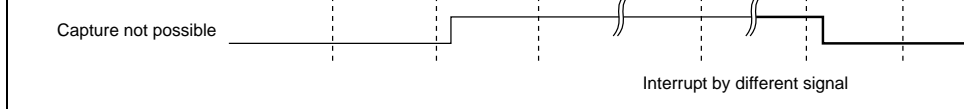


Figure 6.3 External Input Signal Capture when Signal Changes before/after Standby or Watch Mode

(4) Input Pins to which these Notes Apply

$\overline{\text{IRQ4}}$, $\overline{\text{IRQ3}}$, $\overline{\text{IRQ1}}$, $\overline{\text{IRQ0}}$, $\overline{\text{WKP7}}$ to $\overline{\text{WKP0}}$, $\overline{\text{IRQAEC}}$, $\overline{\text{TMIF}}$, $\overline{\text{ADTRG}}$, $\overline{\text{TIOCA1}}$, $\overline{\text{TIOCB1}}$, $\overline{\text{TIOCA2}}$ and $\overline{\text{TIOCB2}}$.

- On-board programming
On-board programming/erasing can be done in boot mode, in which the boot program into the chip is started to erase or program of the entire flash memory. In normal use mode, individual blocks can be erased or programmed.
- Programmer mode
Flash memory can be programmed/erased in programmer mode using a PROM programmer as well as in on-board programming mode.
- Automatic bit rate adjustment
For data transfer in boot mode, this LSI's bit rate can be automatically adjusted to match the transfer bit rate of the host.
- Programming/erasing protection
Sets software protection against flash memory programming/erasing.
- Power-down mode
Operation of the power supply circuit can be partly halted in subactive mode. As a result, memory can be read with low power consumption.
- Module standby mode
Use of module standby mode enables this module to be placed in standby mode independent when not used. (For details, refer to section 6.4, Module Standby Function.) When the debugging emulator is used, the bit 1 (FROMCKSTP) in clock stop register 1 (CKSR1) should be set to 1.

Erase unit	H'0880	H'0881	H'0882		H'088F
1 kbyte					
	H'0B80	H'0B81	H'0B82		H'0BF
	H'0C00	H'0C01	H'0C02	← Programming unit: 128 bytes →	H'0C7
Erase unit	H'0C80	H'0C81	H'0C82		H'0CF
1 kbyte					
	H'0F80	H'0F81	H'0F82		H'0FF
	H'1000	H'1001	H'1002	← Programming unit: 128 bytes →	H'107
Erase unit	H'1080	H'1081	H'1082		H'10F
28 kbytes					
	H'7F80	H'7F81	H'7F82		H'7FF
	H'8000	H'8001	H'8002	← Programming unit: 128 bytes →	H'807
Erase unit	H'8080	H'8081	H'8082		H'80F
16 kbytes					
	H'BF80	H'BF81	H'BF82		H'BF
	H'C000	H'C001	H'C002		H'C07
Erase unit	H'C080	H'C081	H'C082		H'COF
4 kbytes	H'CF80	H'CF81	H'CF82		H'CF

Figure 7.1 Flash Memory Block Configuration

7.2.1 Flash Memory Control Register 1 (FLMCR1)

FLMCR1 is a register that makes the flash memory change to program mode, program-verify mode, erase mode, or erase-verify mode. For details on register setting, refer to section 7. Memory Programming/Erasing.

Bit	Bit Name	Initial Value	R/W	Description
7	—	0	—	Reserved This bit is always read as 0.
6	SWE	0	R/W	Software Write Enable When this bit is set to 1, flash memory programming/erasing is enabled. When this bit is cleared to 0, other FLMCR1 register bits and a bits cannot be set.
5	ESU	0	R/W	Erase Setup When this bit is set to 1, the flash memory changes to the erase setup state. When it is cleared to 0, the erase setup state is cancelled. Set this bit to 1 before setting the E bit to 1 in FLMCR1.
4	PSU	0	R/W	Program Setup When this bit is set to 1, the flash memory changes to the program setup state. When it is cleared to 0, the program setup state is cancelled. Set this bit to 1 before setting the P bit in FLMCR1.
3	EV	0	R/W	Erase-Verify When this bit is set to 1, the flash memory changes to the erase-verify mode. When it is cleared to 0, the erase-verify mode is cancelled.

When this bit is set to 1 while SWE=1 and PS flash memory changes to program mode. When cleared to 0, program mode is cancelled.

7.2.2 Flash Memory Control Register 2 (FLMCR2)

FLMCR2 is a register that displays the state of flash memory programming/erasing. FLMCR2 is a read-only register, and should not be written to.

Bit	Bit Name	Initial Value	R/W	Description
7	FLER	0	R	Flash Memory Error Indicates that an error has occurred during an operation on flash memory (programming or erasing). When FLER is set to 1, flash memory goes to the error protection state. See section 7.5.3, Error Protection, for details.
6 to 0	—	All 0	—	Reserved These bits are always read as 0.

6	EB6	0	R/W	When this bit is set to 1, 4 kbytes of H'0C00 to H'0CFF will be erased.
5	EB5	0	R/W	When this bit is set to 1, 16 kbytes of H'8000 to H'80FF will be erased.
4	EB4	0	R/W	When this bit is set to 1, 28 kbytes of H'1000 to H'10FF will be erased.
3	EB3	0	R/W	When this bit is set to 1, 1 kbyte of H'0C00 to H'0CFF will be erased.
2	EB2	0	R/W	When this bit is set to 1, 1 kbyte of H'0800 to H'08FF will be erased.
1	EB1	0	R/W	When this bit is set to 1, 1 kbyte of H'0400 to H'04FF will be erased.
0	EB0	0	R/W	When this bit is set to 1, 1 kbyte of H'0000 to H'00FF will be erased.

When this bit is 0 and a transition is made to subactive mode, the flash memory enters the power-down mode. When this bit is 1, the flash memory remains in normal mode even after a transition is made to subactive mode.

6 to 0	—	All 0	—	Reserved
--------	---	-------	---	----------

These bits are always read as 0.

7.2.5 Flash Memory Enable Register (FENR)

Bit 7 (FLSHE) in FENR enables or disables the CPU access to the flash memory control registers FLMCR1, FLMCR2, EBR1, and FLPWCR.

Bit	Bit Name	Initial Value	R/W	Description
7	FLSHE	0	R/W	Flash Memory Control Register Enable Flash memory control registers can be accessed when this bit is set to 1. Flash memory control registers cannot be accessed when this bit is set to 0.
6 to 0	—	All 0	—	Reserved These bits are always read as 0.

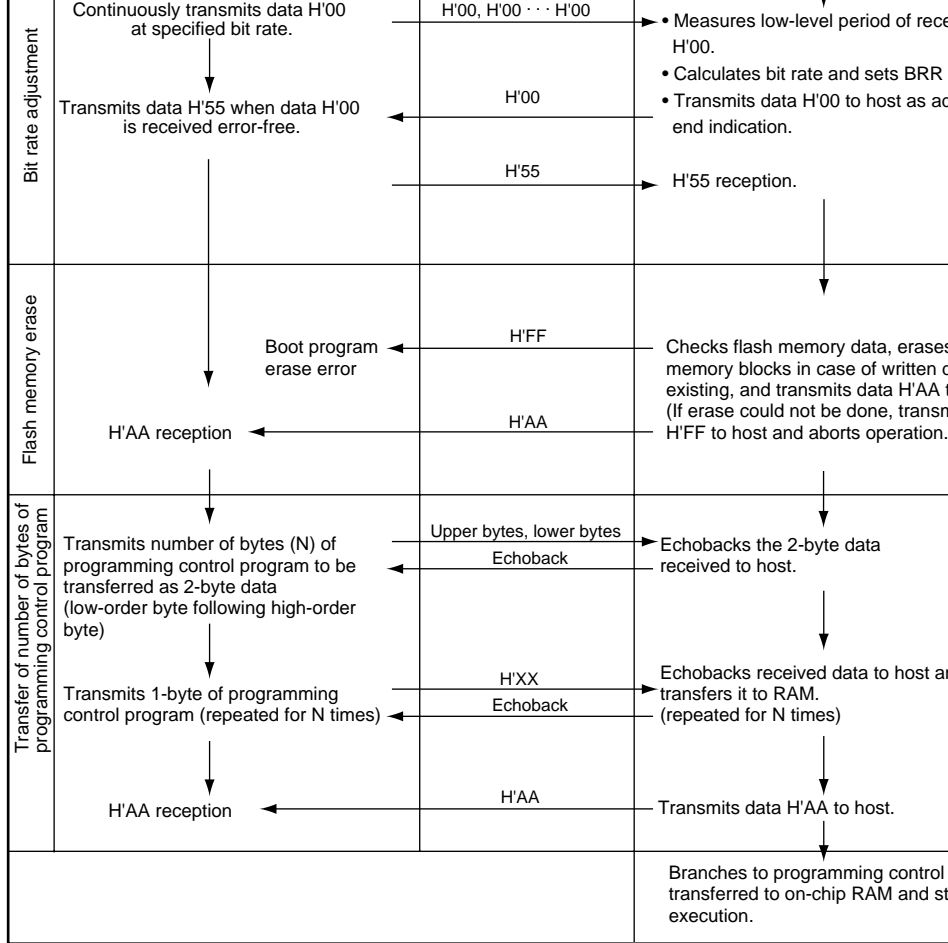
via SCI3 (channel 2). After erasing the entire flash memory, the programming control program is executed. This can be used for programming initial values in the on-board state or for a factory return when programming/erasing can no longer be done in user program mode. In user program mode, individual blocks can be erased and programmed by branching to the user program control program prepared by the user.

Table 7.1 Setting Programming Modes

TEST	$\overline{\text{NMI}}$	P36	PB0	PB1	PB2	LSI State after Reset End
0	1	X	X	X	X	User Mode
0	0	1	X	X	X	Boot Mode
1	X	X	0	0	0	Programmer Mode

[Legend] X: Don't care.

3. When the boot program is initiated, the chip measures the low-level period of asynchronous SCI communication data (H'00) transmitted continuously from the host. The chip then calculates the bit rate of transmission from the host, and adjusts the SCI3 bit rate to match that of the host. The reset should end with the RXD pin high. The RXD and TXD pins should be pulled up on the board if necessary. After the reset is complete, it takes approximately 20 states before the chip is ready to measure the low-level period.
4. After matching the bit rates, the chip transmits one H'00 byte to the host to indicate the completion of bit rate adjustment. The host should confirm that this adjustment ended normally (H'00) has been received normally, and transmit one H'55 byte to the chip. If reception cannot be performed normally, initiate boot mode again by a reset. Depending on the host's transfer bit rate and system clock frequency of this LSI, there will be a discrepancy between the bit rates of the host and the chip. To operate the SCI properly, set the host's transfer bit rate and system clock frequency of this LSI within the ranges listed in table 7.3.
5. In boot mode, a part of the on-chip RAM area is used by the boot program. The area from H'FEEF to H'0000 is the area to which the programming control program is transferred from the host. The boot program area cannot be used until the execution state in boot mode switches to the programming control program.
6. Before branching to the programming control program, the chip terminates transfer control by SCI3 (by clearing the RE and TE bits in SCR to 0), however the adjusted bit rate remains set in BRR. Therefore, the programming control program can still use it for transferring program data or verify data with the host. The TXD pin is high (PCR42 = 1, P42 = 1). The contents of the CPU general registers are undefined immediately after branching to the programming control program. These registers must be initialized at the beginning of the programming control program, as the stack pointer (SP), in particular, is used implicitly in subroutine calls, etc.
7. Boot mode can be cleared by a reset. End the reset after driving the reset pin low, wait at least 20 states, and then setting the $\overline{\text{NMI}}$ pin. Boot mode is also cleared when a WDT timeout occurs.



On-board programming/erasing of an individual flash memory block can also be performed in user program mode by branching to a user program/erase control program. The user must set the appropriate conditions and provide on-board means of supplying programming data. The flash memory blocks contain the user program/erase control program or a program that provides the user program/erase control program from external memory. As the flash memory itself cannot be read during programming/erasing, transfer the user program/erase control program to on-chip RAM before programming/erasing. Figure 7.2 shows a sample procedure for programming/erasing in user program mode. Prepare a user program/erase control program in accordance with the description in section 7.2.2.2. Flash Memory Programming/Erasing.

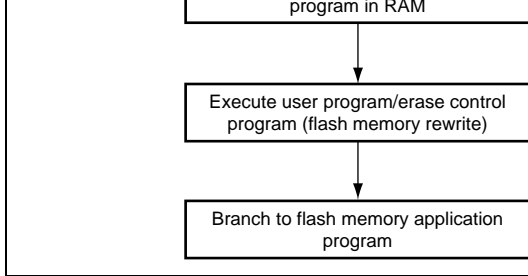
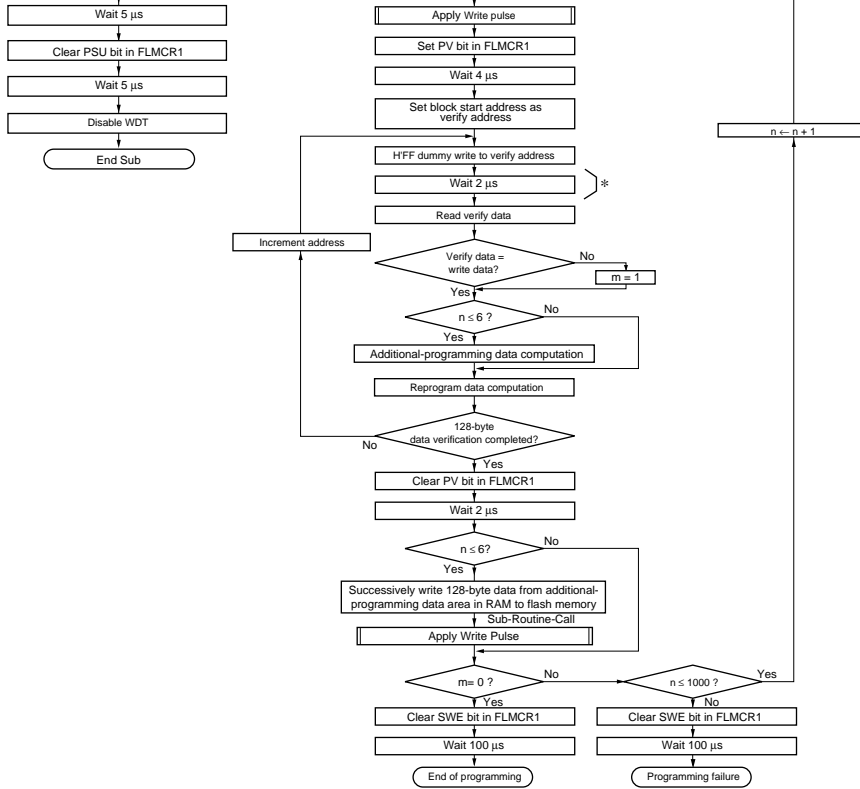


Figure 7.2 Programming/Erasing Flowchart Example in User Program Mo

7.4.1 Program/Program-Verify

When writing data or programs to the flash memory, the program/program-verify flowchart in figure 7.3 should be followed. Performing programming operations according to this will enable data or programs to be written to the flash memory without subjecting the chip to voltage stress or sacrificing program data reliability.

1. Programming must be done to an empty address. Do not reprogram an address to which programming has already been performed.
2. Programming should be carried out 128 bytes at a time. A 128-byte data transfer must be performed even if writing fewer than 128 bytes. In this case, H'FF data must be written to extra addresses.
3. Prepare the following data storage areas in RAM: A 128-byte programming data area, a 128-byte reprogramming data area, and a 128-byte additional-programming data area. Perform reprogramming data computation according to table 7.4, and additional programming data computation according to table 7.5.
4. Consecutively transfer 128 bytes of data in byte units from the reprogramming data area and additional-programming data area to the flash memory. The program address and 128 bytes of data are latched in the flash memory. The lower 8 bits of the start address in the flash memory destination area must be H'00 or H'80.
5. The time during which the P bit is set to 1 is the programming time. Table 7.6 shows the allowable programming times.
6. The watchdog timer (WDT) is set to prevent overprogramming due to program runaway. An overflow cycle of approximately 6.6 ms is allowed.
7. For a dummy write to a verify address, write 1-byte data H'FF to an address whose lower 8 bits are B'00. Verify data can be read in words or in longwords from the address to which the dummy write was performed.



Note: *The RTS instruction must not be used during the following 1. and 2. periods.
 1. A period between 128-byte data programming to flash memory and the P bit clearing
 2. A period between dummy writing of HFF to a verify address and verify data reading

Figure 7.3 Program/Program-Verify Flowchart

Reprogram Data	Verify Data	Additional Program Data	Comments
0	0	0	Additional-program
0	1	1	No additional progr
1	0	1	No additional progr
1	1	1	No additional progr

Table 7.6 Programming Time

n (Number of Writes)	Programming Time	In Additional Programming	Comments
1 to 6	30	10	
7 to 1,000	200	—	

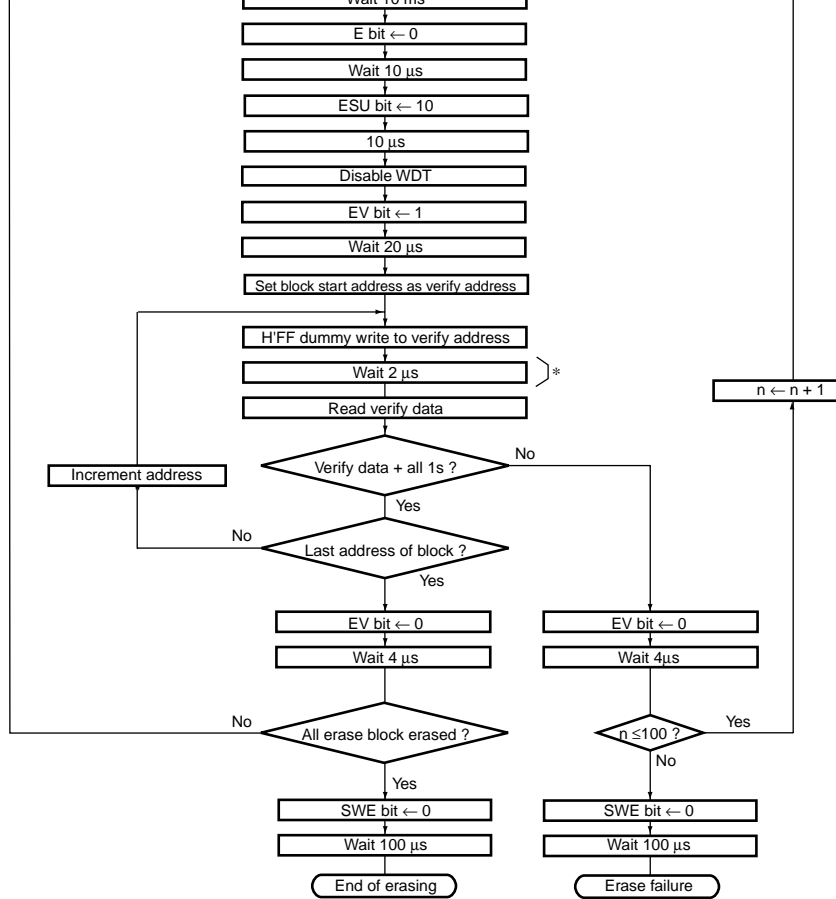
Note: Time shown in μ s.

- overflow cycle of approximately 19.8 ms is allowed.
5. For a dummy write to a verify address, write 1-byte data H'FF to an address whose low 8 bits are B'00. Verify data can be read in longwords from the address to which a dummy write was performed.
 6. If the read data is not erased successfully, set erase mode again, and repeat the erase/verify sequence as before. The maximum number of repetitions of the erase/erase-verify sequence is 100.

7.4.3 Interrupt Handling when Programming/Erasing Flash Memory

All interrupts, including the NMI interrupt, are disabled while flash memory is being programmed or erased, or while the boot program is executing, for the following three reasons:

1. Interrupt during programming/erasing may cause a violation of the programming or erasing algorithm, with the result that normal operation cannot be assured.
2. If interrupt exception handling starts before the vector address is written or during programming/erasing, a correct vector cannot be fetched and the CPU malfunctions.
3. If an interrupt occurs during boot program execution, normal boot mode sequence cannot be carried out.



Note: * The RTS instruction must not be used during a period between dummy writing of H'FF to a verify address and verify data.

Figure 7.4 Erase/Erase-Verify Flowchart

and erase block register 1 (EBR1) are initialized. In a reset via the RES pin, the reset state is entered unless the $\overline{\text{RES}}$ pin is held low until oscillation stabilizes after powering on. In the event of a reset during operation, hold the $\overline{\text{RES}}$ pin low for the $\overline{\text{RES}}$ pulse width specified in the Absolute Maximum Ratings section.

7.5.2 Software Protection

Software protection can be implemented against programming/erasing of all flash memory by clearing the SWE bit in FLMCR1. When software protection is in effect, setting the SWE bit in FLMCR1 does not cause a transition to program mode or erase mode. By setting the erase block register 1 (EBR1), erase protection can be set for individual blocks. When EBR1 is set to H'00, erase protection is set for all blocks.

7.5.3 Error Protection

In error protection, an error is detected when CPU runaway occurs during flash memory programming/erasing, or operation is not performed in accordance with the program/erase algorithm, and the program/erase operation is forcibly aborted. Aborting the program/erase operation prevents damage to the flash memory due to overprogramming or overerasing.

When the following errors are detected during programming/erasing of flash memory, the error bit in FLMCR2 is set to 1, and the error protection state is entered.

- When the flash memory of the relevant address area is read during programming/erasing (including vector read and instruction fetch)
- Immediately after exception handling excluding a reset during programming/erasing
- When a SLEEP instruction is executed during programming/erasing

7.7 Power-Down States for Flash Memory

In user mode, the flash memory will operate in either of the following states:

- Normal operating mode
The flash memory can be read and written to at high speed.
- Power-down operating mode
The power supply circuit of flash memory can be partly halted. As a result, flash memory can be read with low power consumption.
- Standby mode
All flash memory circuits are halted.

Table 7.7 shows the correspondence between the operating modes of this LSI and the flash memory. In subactive mode, the flash memory can be set to operate in power-down mode by setting the PDWND bit in FLPWCR. When the flash memory returns to its normal operating state from power-down mode or standby mode, a period to stabilize operation of the power supply that were stopped is needed. When the flash memory returns to its normal operating state, STS2 to STS0 in SYSCR1 must be set to provide a wait time of at least 20 μ s, even when an external clock is being used.

7.8 Notes on Setting Module Standby Mode

When the flash memory is set to enter module standby mode, the system clock supply is stopped to the module, the function is stopped, and the state is the same as that in standby mode. A program operation is stopped in the flash memory. Therefore operation program should be transferred to the RAM and the program should run in the RAM. Then the flash memory should be set to enter module standby mode.

Even if an interrupt source occurs while the interrupt is enabled in module standby mode, runaway may occur because the vector cannot be fetched.

Before the flash memory is set to enter module standby mode, the corresponding bit in the interrupt enable register should be cleared to 0 and the I bit in CCR should be set to 1. Then the flash memory enters module standby mode, NMI and address break interrupt requests should not be generated. Figure 7.5 shows a module standby mode setting.

Clear FROMCKSTP
bit in CRSTPR1 to 0

Figure 7.5 Module Standby Mode Setting

For details on the execution of bit manipulation instructions to the port data register (PDR) see section 2.8.3, Bit-Manipulation Instruction.

For details on block diagrams for each port, see Appendix B.1, I/O Port Block Diagrams.

9.1 Port 1

Port 1 is an I/O port also functioning as an SCI4 I/O pin, TPU I/O pin, and asynchronous counter input pin. Figure 9.1 shows its pin configuration.

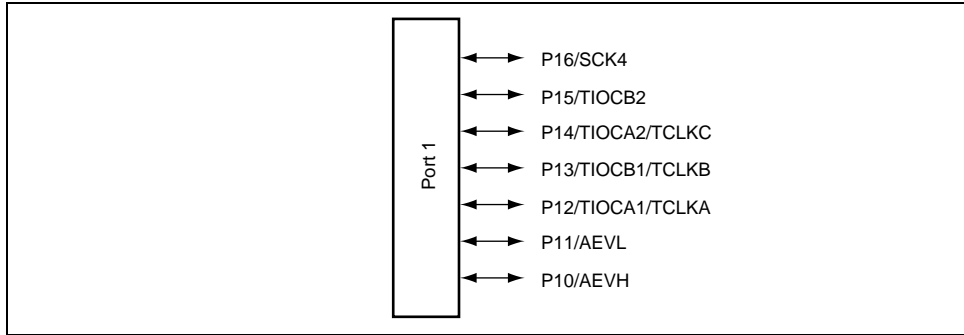


Figure 9.1 Port 1 Pin Configuration

Port 1 has the following registers.

- Port data register 1 (PDR1)
- Port control register 1 (PCR1)
- Port pull-up control register 1 (PUCR1)
- Port mode register 1 (PMR1)

3	P13	0	R/W	be modified.
2	P12	0	R/W	
1	P11	0	R/W	
0	P10	0	R/W	

9.1.2 Port Control Register 1 (PCR1)

PCR1 selects inputs/outputs in bit units for pins to be used as general I/O ports of port 1.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Setting a PCR1 bit to 1 makes the corresponding pin (P16 to P10) an output pin, while clearing the bit makes the pin an input pin. The settings in PCR1 and PDR1 are valid when the corresponding pin is designated as a general I/O pin.
6	PCR16	0	W	
5	PCR15	0	W	
4	PCR14	0	W	
3	PCR13	0	W	
2	PCR12	0	W	
1	PCR11	0	W	
0	PCR10	0	W	Bit 7 is reserved. This bit cannot be modified.

3	PUCR13	0	R/W	be modified.
2	PUCR12	0	R/W	
1	PUCR11	0	R/W	
0	PUCR10	0	R/W	

9.1.4 Port Mode Register 1 (PMR1)

PMR1 controls the selection of functions for port 1 pins.

Bit	Bit Name	Initial Value	R/W	Description
7 to 2	—	All 1	—	Reserved These bits are always read as 1 and cannot be modified.
1	AEVL	0	R/W	P11/AEVL Pin Function Switch Selects whether pin P11/AEVL is used as P11 I/O pin or AEVL. 0: P11 I/O pin 1: AEVL input pin
0	AEVH	0	R/W	P10/AEVH Pin Function Switch Selects whether pin P10/AEVH is used as P10 I/O pin or AEVH. 0: P10 I/O pin 1: AEVH input pin

PCR10	0	1	x	
Pin Function	P16 input pin	P16 output pin	SCK4 input pin* ²	SCK4 out

[Legend] x: Don't care.

Notes: 1. Supported only by the F-ZTAT™ version.

2. Only port function is available for the masked ROM version.

Note: * When the MD1 and MD0 bits are set to B'00 and the IOB3 bit to 1, the pin function becomes the TIOCB2 input pin.
Clear PCR15 to 0 when using TIOCB2 as an input pin.

TPU Channel 2 Setting	(2)	(3)	(1)	
MD1, MD0	B'00			B'10, B'01, B'
IOB3 to IOB0	B'0000	B'1xxx	B'0001 to B'0111	B'xxxx
CCLR1, CCLR0	B'xx			
Output Function	—		Setting prohibited	

[Legend] x: Don't care.

- Notes: 1. When the MD1 and MD0 bits are set to B'00 and the IOA3 bit to 1, the pin function becomes the TIOCA2 input pin.
Clear PCR14 to 0 when using TIOCA2 as an input pin.
2. When the TPSC2 to TPSC0 bits in TCR_2 are set to B'110, the pin function becomes the TCLKC input pin.
Clear PCR14 to 0 when using TCLKC as an input pin.

TPU Channel 2 Setting	(2)	(1)	(2)	(1)	(1)
MD1, MD0	B'00		B'1x	B'10	B'11
IOA3 to IOA0	B'0000 B'0100 B'1xxx	B'0001 to B'0011 B'0101 to B'0111	B'xx00	Other than B'xx00	Other than
CCLR1, CCLR0	—	—	—	—	Other than B'01
Output Function	—	Output compare output	—	PWM mode 1* output	PWM mode 2 output

[Legend] x: Don't care.

Note: * The output of the TIOCB2 pin is disabled.

			TIOCB1 input
			TCLKB input pin*

Note: * When the TPSC2 to TPSC0 bits in TCR_1 or TCR_2 are set to B'101, the pin becomes the TCLKB input pin.
Clear PCR13 to 0 when using TCLKB as an input pin.

TPU Channel 1 Setting	(2)	(3)	(1)	
MD1, MD0	B'00			B'10, B'01, B'
IOB3 to IOB0	B'0000	B'1xxx	B'0001 to B'0111	B'xxxx
CCLR1, CCLR0	B'xx			
Output Function	—	Setting prohibited		

[Legend] x: Don't care.

- Notes: 1. When the MD1 and MD0 bits are set to B'00 and the IOA3 bit to 1, the pin function becomes the TIOCA1 input pin.
Clear PCR12 to 0 when using TIOCA1 as an input pin.
2. When the TPSC2 to TPSC0 bits in TCR_1 or TCR_2 are set to B'100, the pin function becomes the TCLKA input pin.
Clear PCR12 to 0 when using TCLKA as an input pin.

TPU Channel 1 Setting	(2)	(1)	(2)	(1)	(1)
MD1, MD0	B'00		B'1x	B'10	B'11
IOA3 to IOA0	B'0000 B'0100 B'1xxx	B'0001 to B'0011 B'0101 to B'0111	B'xx00	Other than B'xx00	Other than B'11
CCLR1, CCLR0	—	—	—	—	Other than B'10
Output Function	—	Output compare output	—	PWM mode 1* output	PWM mode 2 output

[Legend] x: Don't care.

Note: * The output of the TIOCB1 pin is disabled.

The pin function is switched as shown below according to the combination of the AEVH, PMR1 and PCR10 bit in PCR.

AEVH	0		1
PCR10	0	1	x
Pin Function	P10 input pin	P10 output pin	AEVH input pin

[Legend] x: Don't care.

9.1.6 Input Pull-Up MOS

Port 1 has an on-chip input pull-up MOS function that can be controlled by software. When the PCR1 bit is cleared to 0, setting the corresponding PUCR1 bit to 1 turns on the input pull-up MOS function for that pin. The input pull-up MOS function is in the off state after a reset.

(n = 6 to 15)

PCR1n	0		1
PUCR1n	0	1	x
Input Pull-Up MOS	Off	On	Off

[Legend] x: Don't care.

Figure 9.2 Port 3 Pin Configuration

Port 3 has the following registers.

- Port data register 3 (PDR3)
- Port control register 3 (PCR3)
- Port pull-up control register 3 (PUCR3)
- Port mode register 3 (PMR3)

9.2.1 Port Data Register 3 (PDR3)

PDR3 is a register that stores data of port 3.

Bit	Bit Name	Initial Value	R/W	Description
7	P37	0	R/W	If port 3 is read while PCR3 bits are set to 1, the states stored in PDR3 are read, regardless of the actual pin states. If port 3 is read while PCR3 bits are cleared, the pin states are read.
6	P36	0	R/W	
5	—	1	—	Bits 5 to 3 are reserved. These bits are always 1 and cannot be modified.
4	—	1	—	
3	—	1	—	
2	P32	0	R/W	
1	P31	0	R/W	
0	P30	0	R/W	

3	—	1	—	PCR3 is a write-only register. These bits are read as 1.
2	PCR32	0	W	
1	PCR31	0	W	Bits 5 to 3 are reserved. These bits cannot be modified.
0	PCR30	0	W	

9.2.3 Port Pull-Up Control Register 3 (PUCR3)

PUCR3 controls the pull-up MOS of the port 3 pins in bit units.

Bit	Bit Name	Initial Value	R/W	Description
7	PUCR37	0	R/W	When a PUCR3 bit is cleared to 0, setting the corresponding PUCR3 bit to 1 turns on the pull-up MOS for the corresponding pin, while clearing the bit turns off the pull-up MOS.
6	PUCR36	0	R/W	
5	—	1	—	Bits 5 to 1 are reserved. These bits are always 1 and cannot be modified.
4	—	1	—	
3	—	1	—	
2	—	1	—	
1	—	1	—	
0	PUCR30	0	R/W	

9.2.5 Pin Functions

The relationship between the register settings and the port functions is shown below.

- P37/SO4 pin

The pin function is switched as shown below according to the combination of the TE SCR4 and PCR37 bit in PCR3.

TE* ¹	0* ¹		1* ¹
PCR37	0	1	x
Pin Function	P37 input pin	P37 output pin	SO4 output pin* ²

[Legend] x: Don't care.

Notes: 1. Supported only by the F-ZTAT™ version.

2. Only port function is available for the masked ROM version.

- P32/TXD32/SCL pin

The pin function is switched as shown below according to the combination of the PCR3, ICE bit in ICCR1, TE bit in SCR32, and SPC32 bit in SPCR.

ICE	0			
SPC32	0		1	
TE	x			
PCR32	0	1	x	
Pin Function	P32 input pin	P32 output pin	TXD32 output pin*	SCL

[Legend] x: Don't care.

Note: * If SPC32 is set to 1 and TE is cleared to 0, the mark state is entered and 1 is output from the TXD32 output pin.

- P31/RXD32/SDA pin

The pin function is switched as shown below according to the combination of the PCR3, ICE bit in ICCR1, and RE bit in SCR32.

ICE	0			
RE	0		1	
PCR31	0	1	x	
Pin Function	P31 input pin	P31 output pin	RXD32 output pin	SDA

[Legend] x: Don't care.

	pin	output pin	pin	pin	
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[Legend] x: Don't care.

9.2.6 Input Pull-Up MOS

Port 3 has an on-chip input pull-up MOS function that can be controlled by software. When PCR3 bit is cleared to 0, setting the corresponding PUCR3 bit to 1 turns on the input pull-up for that pin. The input pull-up MOS function is in the off state after a reset.

(n = 7, 6)

PCR3n	0		1
PUCR3n	0	1	x
Input Pull-Up MOS	Off	On	Off

[Legend] x: Don't care.

Figure 9.3 Port 4 Pin Configuration

Port 4 has the following registers.

- Port data register 4 (PDR4)
- Port control register 4 (PCR4)
- Port mode register 4 (PMR4)

9.3.1 Port Data Register 4 (PDR4)

PDR4 is a register that stores data of port 4.

Bit	Bit Name	Initial Value	R/W	Description
7 to 3	—	All 1	—	Reserved These bits are always read as 1 and cannot be
2	P42	0	R/W	If port 4 is read while PCR4 bits are set to 1, the
1	P41	0	R/W	stored in PDR4 are read, regardless of the actual
0	P40	0	R/W	states. If port 4 is read while PCR4 bits are cleared, the pin states are read.

0 PCR40 0 W

when the corresponding pin is designated as a I/O pin.

PCR4 is a write-only register. These bits are all read as 1.

as P42 or TXD31/IrTXD, or as TMOFH.
0: P42 I/O pin or TXD31/IrTXD output pin
1: TMOFH output pin

1	TMOFL	0	R/W	P41/RXD31/IrRXD/TMOFL Pin Function Switch Selects whether pin P41/RXD31/IrRXD/TMOFL is used as P41 or RXD31/IrRXD, or as TMOFL. 0: P41 I/O pin or RXD31/IrRXD input pin 1: TMOFL output pin
0	TMIF	0	R/W	P40/SCK31/TMIF Pin Function Switch Selects whether pin P40/SCK31/TMIF is used as P40/SCK31 or as TMIF. 0: P40/SCK31 I/O pin 1: TMIF output pin

IrE	x		0	1	
PCR42	0	1	x	x	
Pin Function	P42 input pin	P42 output pin	TXD31 output pin*	IrTXD output pin*	T ou

[Legend] x: Don't care.

Note: * If SPC31 is set to 1 and TE is cleared to 0, the mark state is entered, 1 is output from the TXD32 output pin, and 0 is output from the IrTXD pin.

- P41/RXD31/IrRXD/TMOFL pin

The pin function is switched as shown below according to the combination of the TMOFL bit in PMR4, PCR41 bit in PCR4, IrE bit in IrCR, and RE bit in SCR3.

TMOFL	0				
RE	0		1		
IrE	x		0	1	
PCR41	0	1	x	x	
Pin Function	P41 input pin	P41 output pin	RXD31 input pin	IrRXD input pin	TM outp

[Legend] x: Don't care.

	pin	pin	output pin	input pin	prohibited
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[Legend] x: Don't care.

9.4 Port 5

Port 5 is an I/O port also functioning as a wakeup interrupt input pin and LCD segment. Figure 9.4 shows its pin configuration.

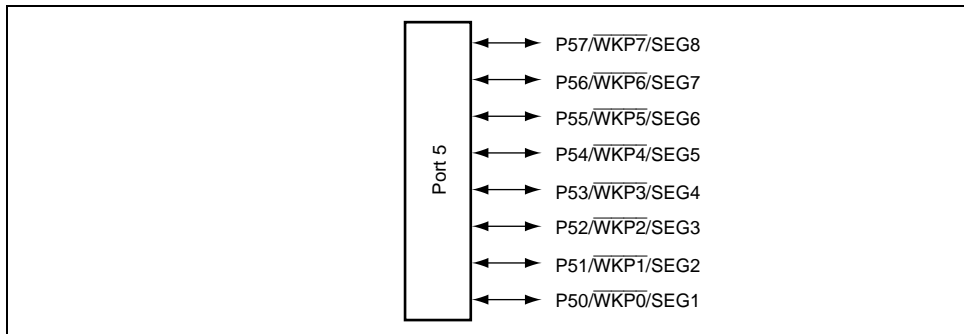


Figure 9.4 Port 5 Pin Configuration

Port 5 has the following registers.

- Port data register 5 (PDR5)
- Port control register 5 (PCR5)
- Port pull-up control register 5 (PUCR5)
- Port mode register 5 (PMR5)

3	P53	0	R/W
2	P52	0	R/W
1	P51	0	R/W
0	P50	0	R/W

9.4.2 Port Control Register 5 (PCR5)

PCR5 selects inputs/outputs in bit units for pins to be used as general I/O ports of port 5.

Bit	Bit Name	Initial Value	R/W	Description
7	PCR57	0	W	Setting a PCR5 bit to 1 makes the corresponding output pin, while clearing the bit to 0 makes the input pin. The settings in PCR5 and in PDR5 are cleared when the corresponding pin is designated as a I/O pin.
6	PCR56	0	W	
5	PCR55	0	W	
4	PCR54	0	W	
3	PCR53	0	W	PCR5 is a write-only register. These bits are always read as 1.
2	PCR52	0	W	
1	PCR51	0	W	
0	PCR50	0	W	

3	PUCR53	0	R/W
2	PUCR52	0	R/W
1	PUCR51	0	R/W
0	PUCR50	0	R/W

9.4.4 Port Mode Register 5 (PMR5)

PMR5 controls the selection of functions for port 5 pins.

Bit	Bit Name	Initial Value	R/W	Description
7	WKP7	0	R/W	P5n/WKPn/SEGN+1 Pin Function Switch
6	WKP6	0	R/W	When pin P5n/ $\overline{\text{WKPn}}$ /SEGN+1 is not used as these bits select whether the pin is used as P5n/ $\overline{\text{WKPn}}$.
5	WKP5	0	R/W	
4	WKP4	0	R/W	0: P5n I/O pin
3	WKP3	0	R/W	1: $\overline{\text{WKPn}}$ input pin (n = 7 to 0)
2	WKP2	0	R/W	
1	WKP1	0	R/W	
0	WKP0	0	R/W	

Note: For use as SEGN+1, see section 19.3.1, LCD Port Control Register (LPCR).

WKPn	0		1	x
PCR5n	0	1	x	x
Pin Function	P5n input pin	P5n output pin	$\overline{\text{WKPn}}$ input pin	SEGN+1 output pin

[Legend] x: Don't care.

- P53/ $\overline{\text{WKP3}}$ /SEG4 to P50/ $\overline{\text{WKP0}}$ /SEG1 pins

The pin function is switched as shown below according to the combination of the WKPMR5, PCR5m bit in PCR5, and SGS3 to SGS0 bits in LPCR.

(m =

SGS3 to SGS0	Other than B'0001, B'0010, B'0011, B'0100, B'0101, B'0110, B'0111, B'1000		B'0001, B'0010, B'0011, B'0101, B'0110, B'0111, B'1000
WKPM	0		1
PCR5m	0	1	x
Pin Function	P5m input pin	P5m output pin	$\overline{\text{WKPM}}$ input pin
			SEGm+1 output pin

[Legend] x: Don't care.

9.5 Port 6

Port 6 is an I/O port also functioning as an LCD segment output pin. Figure 9.5 shows its configuration.

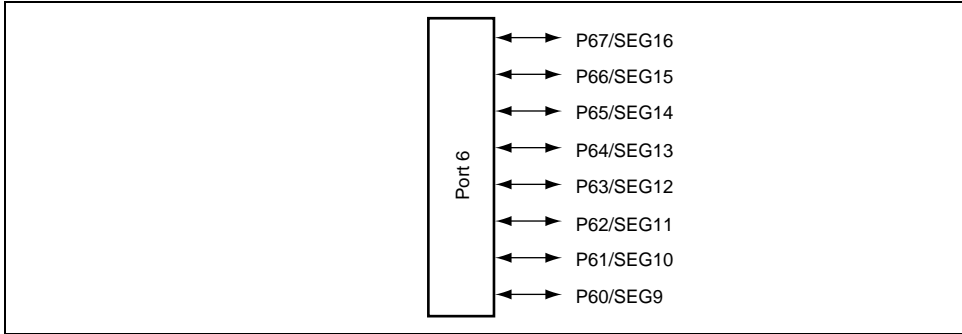


Figure 9.5 Port 6 Pin Configuration

Port 6 has the following registers.

- Port data register 6 (PDR6)
- Port control register 6 (PCR6)
- Port pull-up control register 6 (PUCR6)

3	P63	0	R/W
2	P62	0	R/W
1	P61	0	R/W
0	P60	0	R/W

9.5.2 Port Control Register 6 (PCR6)

PCR6 selects inputs/outputs in bit units for pins to be used as general I/O ports of port 6.

Bit	Bit Name	Initial Value	R/W	Description
7	PCR67	0	W	Setting a PCR6 bit to 1 makes the corresponding output pin, while clearing the bit to 0 makes the input pin. The settings in PCR6 and in PDR6 are valid when the corresponding pin is designated as a general I/O pin.
6	PCR66	0	W	
5	PCR65	0	W	
4	PCR64	0	W	
3	PCR63	0	W	PCR6 is a write-only register. These bits are always read as 1.
2	PCR62	0	W	
1	PCR61	0	W	
0	PCR60	0	W	

3	PUCR63	0	R/W
2	PUCR62	0	R/W
1	PUCR61	0	R/W
0	PUCR60	0	R/W

9.5.4 Pin Functions

The relationship between the register settings and the port functions is shown below.

- P67/SEG16 to P64/SEG13 pins

The pin function is switched as shown below according to the combination of the PCR6n and SGS3 to SGS0 bits in LPCR.

	Other than B'0100, B'0101, B'0110, B'0111, B'1000, B'1001, B'1010, B'1011		B'0100, B'0101, B'0110, B'0111, B'1000, B'1001, B'1010, B'1011
PCR6n	0	1	x
Pin Function	P6n input pin	P6n output pin	SEGN+9 output pin

[Legend] x: Don't care.

9.5.5 Input Pull-Up MOS

Port 6 has an on-chip input pull-up MOS function that can be controlled by software. When the PCR6 bit is cleared to 0, setting the corresponding PUCR6 bit to 1 turns on the input pull-up MOS function for that pin. The input pull-up MOS function is in the off state after a reset.

(n = 7 to 0)

PCR6n	0		1
PUCR6n	0	1	x
Input Pull-Up MOS	Off	On	Off

[Legend] x: Don't care.

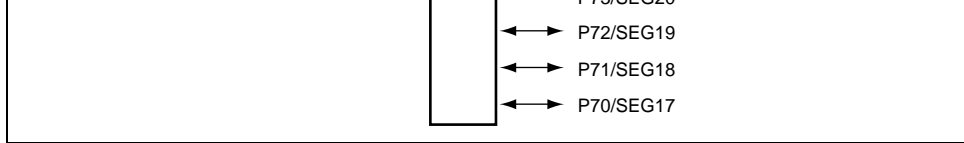


Figure 9.6 Port 7 Pin Configuration

Port 7 has the following registers.

- Port data register 7 (PDR7)
- Port control register 7 (PCR7)

9.6.1 Port Data Register 7 (PDR7)

PDR7 is a register that stores data of port 7.

Bit	Bit Name	Initial Value	R/W	Description
7	P77	0	R/W	If port 7 is read while PCR7 bits are set to 1, the states stored in PDR7 are read, regardless of the actual pin states. If port 7 is read while PCR7 bits are cleared, the pin states are read.
6	P76	0	R/W	
5	P75	0	R/W	
4	P74	0	R/W	
3	P73	0	R/W	
2	P72	0	R/W	
1	P71	0	R/W	
0	P70	0	R/W	

3	PCR73	0	W	PCR7 is a write-only register. These bits are all read as 1.
2	PCR72	0	W	
1	PCR71	0	W	
0	PCR70	0	W	

9.6.3 Pin Functions

The relationship between the register settings and the port functions is shown below.

- P77/SEG24 to P74/SEG21 pins
The pin function is switched as shown below according to the combination of the PCR7n, PCR7 and SGS3 to SGS0 bits in LPCR.

			(n = 1 to 7)
SGS3 to SGS0	Other than B'0110, B'0111, B'1000, B'1001, B'1010, B'1011, B'1100, B'1101		B'0110, B'0111, B'1000, B'1001, B'1010, B'1011, B'1100, B'1101
PCR7n	0	1	x
Pin Function	P7n input pin	P7n output pin	SEGN+17 output pin

[Legend] x: Don't care.

9.7 Port 8

Port 8 is an I/O port also functioning as an LCD segment output pin. Figure 9.7 shows its configuration.

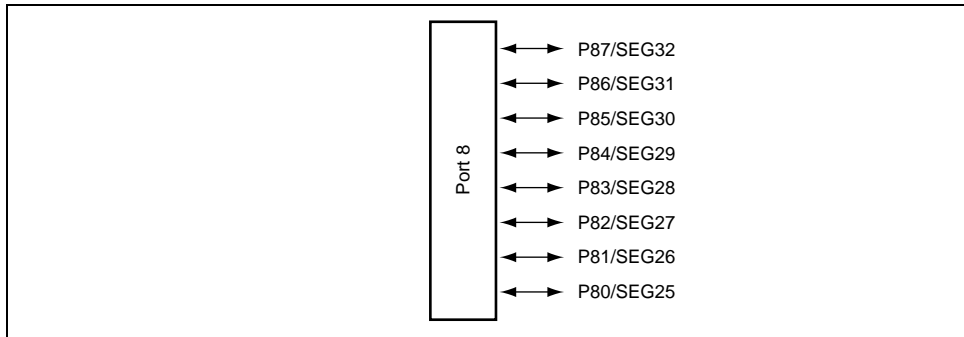


Figure 9.7 Port 8 Pin Configuration

Port 8 has the following registers.

- Port data register 8 (PDR8)
- Port control register 8 (PCR8)

3	P83	0	R/W
2	P82	0	R/W
1	P81	0	R/W
0	P80	0	R/W

9.7.2 Port Control Register 8 (PCR8)

PCR8 selects inputs/outputs in bit units for pins to be used as general I/O ports of port 8.

Bit	Bit Name	Initial Value	R/W	Description
7	PCR87	0	W	Setting a PCR8 bit to 1 makes the corresponding pin (P87 to P80) an output pin, while clearing the bit makes the pin an input pin. The settings in PCR8 and PDR8 are valid when the corresponding pin is designated as a general I/O pin. PCR8 is a write-only register. These bits are all read as 1.
6	PCR86	0	W	
5	PCR85	0	W	
4	PCR84	0	W	
3	PCR83	0	W	
2	PCR82	0	W	
1	PCR81	0	W	
0	PCR80	0	W	

PCR8n	0	1	x
Pin Function	P8n input pin	P8n output pin	SEGN+25 output pin

[Legend] x: Don't care.

- P83/SEG28 to P80/SEG25 pins

The pin function is switched as shown below according to the combination of the PCR8 and SGS3 to SGS0 bits in LPCR.

SGS3 to SGS0	Other than B'0111, B'1000, B'1001, B'1010, B'1011, B'1100, B'1101, B'1110	B'0111, B'1000, B'1001, B'1010, B'1011, B'1100, B'1101, B'1110	(m = 0 to 7)
PCR8m	0	1	x
Pin Function	P8m input pin	P8m output pin	SEGM+25 output pin

[Legend] x: Don't care.

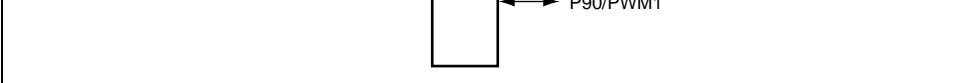


Figure 9.8 Port 9 Pin Configuration

Port 9 has the following registers.

- Port data register 9 (PDR9)
- Port control register 9 (PCR9)
- Port mode register 9 (PMR9)

9.8.1 Port Data Register 9 (PDR9)

PDR9 is a register that stores data of port 9.

Bit	Bit Name	Initial Value	R/W	Description
7 to 4	—	All 1	—	Reserved These bits are always read as 1 and cannot be
3	P93	1	R/W	If port 9 is read while PCR9 bits are set to 1, the states stored in PDR9 are read, regardless of the actual pin states. If port 9 is read while PCR9 bits are cleared, the pin states are read.
2	P92	1	R/W	
1	P91	1	R/W	
0	P90	1	R/W	

1	PCR91	0	W	when the corresponding pin is designated as an I/O pin.
0	PCR90	0	W	PCR9 is a write-only register. These bits are always read as 1.

9.8.3 Port Mode Register 9 (PMR9)

PMR9 controls the selection of functions for port 9 pins.

Bit	Bit Name	Initial Value	R/W	Description
7 to 4	—	All 1	—	Reserved These bits are always read as 1 and cannot be written.
3	—	0	R/W	Reserved Although this bit is readable/writable, 1 should not be written to this bit.
2	IRQ4	0	R/W	P92/ $\overline{\text{IRQ4}}$ Pin Function Switch Selects whether pin P92/ $\overline{\text{IRQ4}}$ is used as P92/ $\overline{\text{IRQ4}}$. 0: P92 I/O pin 1: $\overline{\text{IRQ4}}$ input pin

The relationship between the register settings and the port functions is shown below.

- P93 pin

The pin function is switched as shown below according to the PCR93 bit in PCR9.

PCR93	0	1
Pin Function	P93 input pin	P93 output pin

- P92/ $\overline{\text{IRQ4}}$ pin

The pin function is switched as shown below according to the combination of the IRQ4, PMR9 and PCR92 bit in PCR9.

IRQ4	0		1	
PCR92	0	1	0	1
Pin Function	P92 input pin	P92 output pin	$\overline{\text{IRQ4}}$ input pin	Sett prohi

- P91/PWM2, P90/PWM1 pins

The pin function is switched as shown below according to the combination of the PWMn+1 in PMR9 and PCR9n bit in PCR9.

PWMn+1	0		1
PCR9n	0	1	x
Pin Function	P9n input pin	P9n output pin	PWMn+1 output pin

[Legend] x: Don't care.

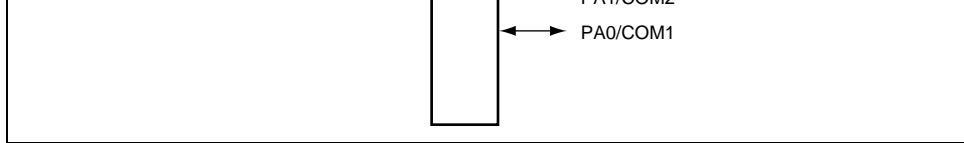


Figure 9.9 Port A Pin Configuration

Port A has the following registers.

- Port data register A (PDRA)
- Port control register A (PCRA)

9.9.1 Port Data Register A (PDRA)

PDRA is a register that stores data of port A.

Bit	Bit Name	Initial Value	R/W	Description
7 to 4	—	All 1	—	Reserved These bits are always read as 1 and cannot be
3	PA3	0	R/W	If port A is read while PCRA bits are set to 1, the states stored in PDRA are read, regardless of the actual pin states. If port A is read while PCRA bits are cleared, the pin states are read.
2	PA2	0	R/W	
1	PA1	0	R/W	
0	PA0	0	R/W	

1	PCRA1	0	W	when the corresponding pin is designated as a
0	PCRA0	0	W	I/O pin.
				PCRA is a write-only register. These bits are al
				read as 1.

9.9.3 Pin Functions

The relationship between the register settings and the port functions is shown below.

- PA3/COM4 pin

The pin function depends on bit PCRA3 in PCRA and bits DTS1 and DTS0, bit CMX0 in PCRA, bits SGS3 to SGS0 in LPCR.

DTS1 to DTS0, CMX	x		Other than B'000, B'010, B'10*	B'000, B'010, B'10*	
SGS3 to SGS0	B'0000		Other than B'0000		
PCRA3	0	1	x	0	1
Pin Function	PA3 input pin* ¹	PA3 output pin* ¹	COM4 output pin	Leave open* ²	Leave open* ²

[Legend] x: Don't care.

Note: 1. The board power supply level is Vcc.

2. The board power supply level is the LCD drive power supply voltage level.

[Legend] x: Don't care.

Note: 1. The board power supply level is Vcc.

2. The board power supply level is the LCD drive power supply voltage level.

- PA1/COM2 pin

The pin function depends on bit PCRA1 in PCRA and bits DTS1 and DTS0, bit CM2 in CM and bits SGS3 to SGS0 in LPCR.

DTS1 to DTS0, CMX	x		Other than B'000	B'000	
SGS3 to SGS0	B'0000		Other than B'0000		
PCRA1	0	1	x	0	
Pin Function	PA1 input pin* ¹	PA1 output pin* ¹	COM2 output pin	Leave open* ²	

[Legend] x: Don't care.

Note: 1. The board power supply level is Vcc.

2. The board power supply level is the LCD drive power supply voltage level.

- PA0/COM1 pin

The pin function depends on bit PCRA0 in PCRA and bits DTS1 and DTS0, bit CM1 in CM and bits SGS3 to SGS0 in LPCR.

DTS1 to DTS0, CMX	x			
SGS3 to SGS0	B'0000		Other than B'0000	
PCRA0	0	1	x	
Pin Function	PA0 input pin	PA0 output pin	COM1 output pin	

[Legend] x: Don't care.



Figure 9.10 Port B Pin Configuration

Port B has the following registers.

- Port data register B (PDRB)
- Port mode register B (PMRB)

9.10.1 Port Data Register B (PDRB)

PDRB is a register that stores data of port B.

Bit	Bit Name	Initial Value	R/W	Description
7	PB7	Undefined	R	Reading PDRB always gives the pin states. However, if a port B pin is selected as an analog input channel (CH3 to CH0 bits in AMR of the A/D converter), that pin is read as 0 regardless of the input voltage.
6	PB6	Undefined	R	
5	PB5	Undefined	R	
4	PB4	Undefined	R	
3	PB3	Undefined	R	
2	PB2	Undefined	R	
1	PB1	Undefined	R	
0	PB0	Undefined	R	

as ADTRG.

0: TEST pin

1: $\overline{\text{ADTRG}}$ input pin

For details on the setting of the $\overline{\text{ADTRG}}$ input pin, refer to section 18.4.2, External Trigger Input Timing.

3	—	1	—	Reserved This bit is always read as 1 and cannot be modified.
2	IRQ3	0	R/W	PB2/AN2/ $\overline{\text{IRQ3}}$ Pin Function Switch Selects whether pin PB2/AN2/ $\overline{\text{IRQ3}}$ is used as AN2 or as $\overline{\text{IRQ3}}$. 0: PB2/AN2 input pin 1: $\overline{\text{IRQ3}}$ input pin
1	IRQ1	0	R/W	PB1/AN1/ $\overline{\text{IRQ1}}$ Pin Function Switch Selects whether pin PB1/AN1/ $\overline{\text{IRQ1}}$ is used as AN1 or as $\overline{\text{IRQ1}}$. 0: PB1/AN1 input pin 1: $\overline{\text{IRQ1}}$ input pin
0	IRQ0	0	R/W	PB0/AN0/ $\overline{\text{IRQ0}}$ Pin Function Switch Selects whether pin PB0/AN0/ $\overline{\text{IRQ0}}$ is used as AN0 or as $\overline{\text{IRQ0}}$. 0: PB0/AN0 input pin 1: $\overline{\text{IRQ0}}$ input pin

- PB6/AN6 pin

The pin function is switched as shown below according to the CH3 to CH0 bits in AM

CH3 to CH0	Other than B'1010	B'1010
Pin Function	PB6 input pin	AN6 input pin

- PB5/AN5 pin

The pin function is switched as shown below according to the CH3 to CH0 bits in AM

CH3 to CH0	Other than B'1001	B'1001
Pin Function	PB5 input pin	AN5 input pin

- PB4/AN4 pin

The pin function is switched as shown below according to the CH3 to CH0 bits in AM

CH3 to CH0	Other than B'1000	B'1000
Pin Function	PB4 input pin	AN4 input pin

- PB3/AN3 pin

The pin function is switched as shown below according to the CH3 to CH0 bits in AM

CH3 to CH0	Other than B'0111	B'0111
Pin Function	PB3 input pin	AN3 input pin

- PB1/AN1/IRQ1 pin

The pin function is switched as shown below according to the combination of the CH3 to CH0 bits in AMR and IRQ1 bit in PMRB.

IRQ1	0		1
CH3 to CH0	Other than B'0101	B'0101	x
Pin Function	PB1 input pin	AN1 input pin	$\overline{\text{IRQ1}}$ input pin

[Legend] x: Don't care.

- PB0/AN0/IRQ0 pin

The pin function is switched as shown below according to the combination of the CH3 to CH0 bits in AMR and IRQ0 bit in PMRB.

IRQ0	0		1
CH3 to CH0	Other than B'0100	B'0100	x
Pin Function	PB0 input pin	AN0 input pin	$\overline{\text{IRQ0}}$ input pin

[Legend] x: Don't care.

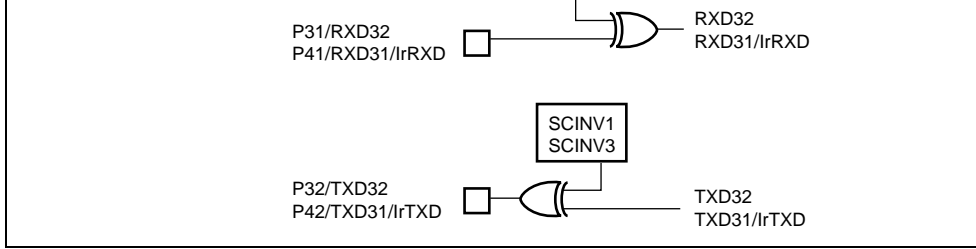


Figure 9.11 Input/Output Data Inversion Function

Bit	Bit Name	Initial Value	R/W	Description
7, 6	—	All 1	—	Reserved These bits are always read as 1 and cannot be
5	SPC32	0	R/W	P32/TXD32/SCL Pin Function Switch Selects whether pin P32/TXD32/SCL is used as P32/SCL or as TXD32. 0: P32/SCL I/O pin 1: TXD32 output pin* Note: * Set the TE32 bit in SCR32 after setting 1.

pin is to be inverted or not.

0: TXD32 output data is not inverted

1: TXD32 output data is inverted

2	SCINV2	0	R/W	RXD32 Pin Input Data Inversion Switch Specifies whether the input data polarity of the pin is to be inverted or not. 0: RXD32 input data is not inverted 1: RXD32 input data is inverted
1	SCINV1	0	R/W	TXD31/IrTXD Pin Output Data Inversion Switch Specifies whether the output data polarity of the TXD31/IrTXD pin is to be inverted or not. 0: TXD31/IrTXD output data is not inverted 1: TXD31/IrTXD output data is inverted
0	SCINV0	0	R/W	RXD31/IrRXD Pin Input Data Inversion Switch Specifies whether the input data polarity of the RXD31/IrRXD pin is to be inverted or not. 0: RXD31/IrRXD input data is not inverted 1: RXD31/IrRXD input data is inverted

Note: When the serial port control register is modified, the data being input or output upon the next data point is inverted immediately after the modification, and an invalid data change is made to the output. When modifying the serial port control register, modification must be made in increments of 1 in which data changes are invalidated.

- For a pin also used by the A/D converter, pull it up to AVcc. With an external resistor of approximately 100 k Ω .
- If an unused pin is an output pin, it is recommended to handle it in one of the following ways:
 - Set the output of the unused pin to high and pull it up to Vcc with an external resistor of approximately 100 k Ω .
 - Set the output of the unused pin to low and pull it down to GND with an external resistor of approximately 100 k Ω .

- Reset function
- Readable/writable counter of seconds, minutes, hours, and day-of-week with BCD counter
- Periodic (0.25 seconds, 0.5 seconds, one second, minute, hour, day, and week) interrupt
- 8-bit free running counter
- Selection of clock source
- Use of module standby mode enables this module to be placed in standby mode independent of the CPU when not used. (For details, refer to section 6.4, Module Standby Function.)

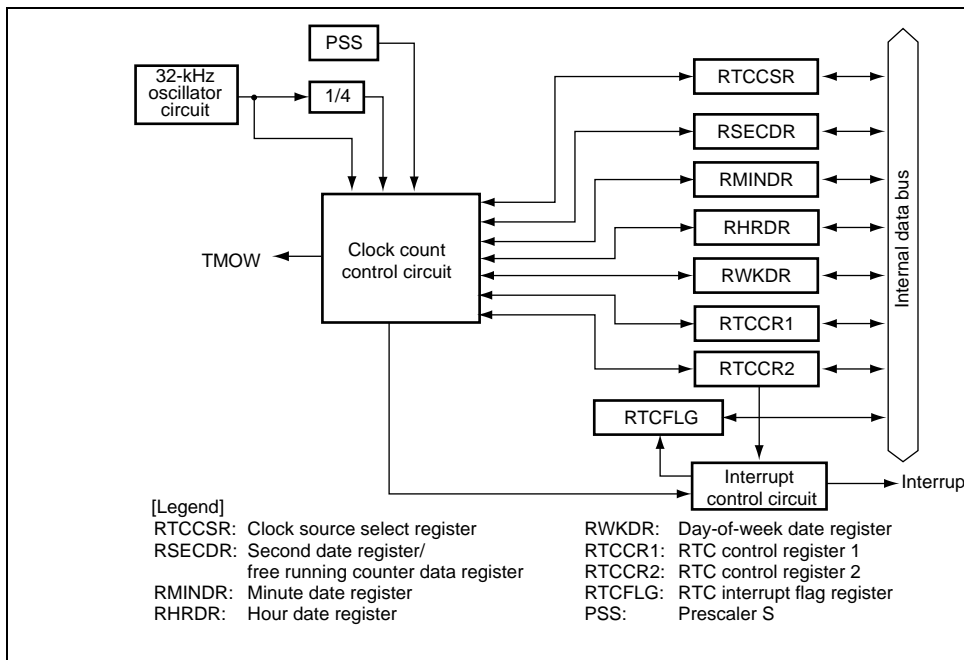


Figure 10.1 Block Diagram of RTC

The RTC has the following registers.

- Second data register/free running counter data register (RSECDR)
- Minute data register (RMINDR)
- Hour data register (RHRDR)
- Day-of-week data register (RWKDR)
- RTC control register 1 (RTCCR1)
- RTC control register 2 (RTCCR2)
- Clock source select register (RTCCSR)
- RTC Interrupt flag register (RTCFLG)

6	SC12	—	R/W	Counting Ten's Position of Seconds
5	SC11	—	R/W	Counts on 0 to 5 for 60-second counting.
4	SC10	—	R/W	
3	SC03	—	R/W	Counting One's Position of Seconds
2	SC02	—	R/W	Counts on 0 to 9 once per second. When a carry is generated, 1 is added to the ten's position.
1	SC01	—	R/W	
0	SC00	—	R/W	

10.3.2 Minute Data Register (RMINDR)

RMINDR counts the BCD-coded minute value on the carry generated once per minute by RSECDR counting. The setting range is decimal 00 to 59.

Bit	Bit Name	Initial Value	R/W	Description
7	BSY	—	R	RTC Busy This bit is set to 1 when the RTC is updating (overwriting) the values of second, minute, hour, and day-of-week data registers. When this bit is 0, the values of second, minute, hour, and day-of-week data registers must be accurate.
6	MN12	—	R/W	Counting Ten's Position of Minutes
5	MN11	—	R/W	Counts on 0 to 5 for 60-minute counting.
4	MN10	—	R/W	
3	MN03	—	R/W	Counting One's Position of Minutes
2	MN02	—	R/W	Counts on 0 to 9 once per minute. When a carry is generated, 1 is added to the ten's position.
1	MN01	—	R/W	
0	MN00	—	R/W	

registers. When this bit is 0, the values of second hour, and day-of-week data registers must be ac

6	—	0	—	Reserved This bit is always read as 0.
5	HR11	—	R/W	Counting Ten's Position of Hours
4	HR10	—	R/W	Counts on 0 to 2 for ten's position of hours.
3	HR03	—	R/W	Counting One's Position of Hours
2	HR02	—	R/W	Counts on 0 to 9 once per hour. When a carry is generated, 1 is added to the ten's position.
1	HR01	—	R/W	
0	HR00	—	R/W	

6 to 3	—	All 0	—	Reserved
These bits are always read as 0.				
2	WK2	—	R/W	Day-of-Week Counting
1	WK1	—	R/W	Day-of-week is indicated with a binary code
0	WK0	—	R/W	000: Sunday
				001: Monday
				010: Tuesday
				011: Wednesday
				100: Thursday
				101: Friday
				110: Saturday
				111: Setting prohibited

6	12/24	—	R/W	Operating Mode 0: RTC operates in 12-hour mode. RHRDR count to 11. 1: RTC operates in 24-hour mode. RHRDR count to 23.
5	PM	—	R/W	A.m./P.m. 0: Indicates a.m. when RTC is in the 12-hour mode. 1: Indicates p.m. when RTC is in the 12-hour mode.
4	RST	0	R/W	Reset 0: Normal operation 1: Resets registers and control circuits except RT and this bit. Clear this bit to 0 after having been set.
3	—	0	R/W*	Reserved
2 to 0	—	All 0	—	Reserved These bits are always read as 0.

Note: * Only 0 can be written to this bit.

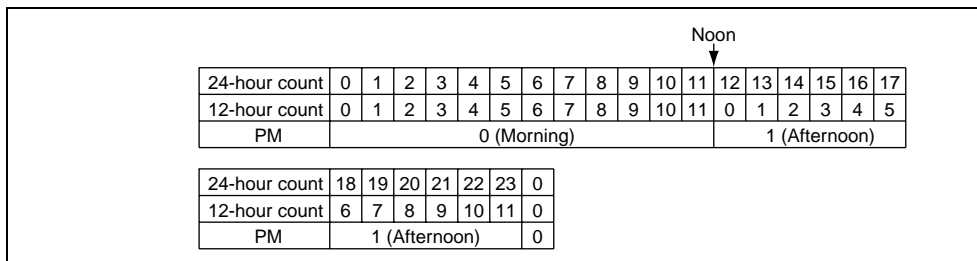


Figure 10.2 Definition of Time Expression

				0: Disables an overflow interrupt 1: Enables an overflow interrupt
6	WKIE	—	R/W	Week Periodic Interrupt Enable 0: Disables a week periodic interrupt 1: Enables a week periodic interrupt
5	DYIE	—	R/W	Day Periodic Interrupt Enable 0: Disables a day periodic interrupt 1: Enables a day periodic interrupt
4	HRIE	—	R/W	Hour Periodic Interrupt Enable 0: Disables an hour periodic interrupt 1: Enables an hour periodic interrupt
3	MNIE	—	R/W	Minute Periodic Interrupt Enable 0: Disables a minute periodic interrupt 1: Enables a minute periodic interrupt
2	1SEIE	—	R/W	One-Second Periodic Interrupt Enable 0: Disables a one-second periodic interrupt 1: Enables a one-second periodic interrupt
1	05SEIE	—	R/W	0.5-Second Periodic Interrupt Enable 0: Disables a 0.5-second periodic interrupt 1: Enables a 0.5-second periodic interrupt
0	025SEIE	—	R/W	0.25-Second Periodic Interrupt Enable 0: Disables a 0.25-second periodic interrupt 1: Enables a 0.25-second periodic interrupt

7	—	0	—	Reserved This bit is always read as 0.
6	RCS6	0	R/W	Clock Output Selection
5	RCS5	0	R/W	Select a clock output from the TMOW pin when the TMOW bit in PMR3 to 1.
4	SUB32K	0	R/W	000: $\phi/4$ 010: $\phi/8$ 100: $\phi/16$ 110: $\phi/32$ xx1: ϕ_w
3	RCS3	1	R/W	Clock Source Selection
2	RCS2	0	R/W	0000: $\phi/8$ Free running counter operation
1	RCS1	0	R/W	0001: $\phi/32$ Free running counter operation
0	RCS0	0	R/W	0010: $\phi/128$ Free running counter operation 0011: $\phi/256$ Free running counter operation 0100: $\phi/512$ Free running counter operation 0101: $\phi/2048$ Free running counter operation 0110: $\phi/4096$ Free running counter operation 0111: $\phi/8192$ Free running counter operation 1000: $\phi_w/4$ RTC operation Settings other than the above are prohibited.

[Legend] x: Don't care.

6	WKIFG	—	R/W*	[Setting condition] When a week periodic interrupt occurs [Clearing condition] 0 is written to WKIFG when WKIFG = 1
5	DYIFG	—	R/W*	[Setting condition] When a day periodic interrupt occurs [Clearing condition] 0 is written to DYIFG when DYIFG = 1
4	HRIFG	—	R/W*	[Setting condition] When an hour periodic interrupt occurs [Clearing condition] 0 is written to HRIFG when HRIFG = 1
3	MNIFG	—	R/W*	[Setting condition] When a minute periodic interrupt occurs [Clearing condition] 0 is written to MNIFG when MNIFG = 1
2	SEIFG	—	R/W*	[Setting condition] When a one-second periodic interrupt occurs [Clearing condition] 0 is written to SEIFG when SEIFG = 1
1	05SEIFG	—	R/W*	[Setting condition] When a 0.5-second periodic interrupt occurs [Clearing condition] 0 is written to 05SEIFG when 05SEIFG = 1
0	025SEIFG	—	R/W*	[Setting condition] When a 0.25-second periodic interrupt occurs [Clearing condition] 0 is written to 025SEIFG when 025SEIFG = 1

Note: * Only 0 can be written to clear the flag.

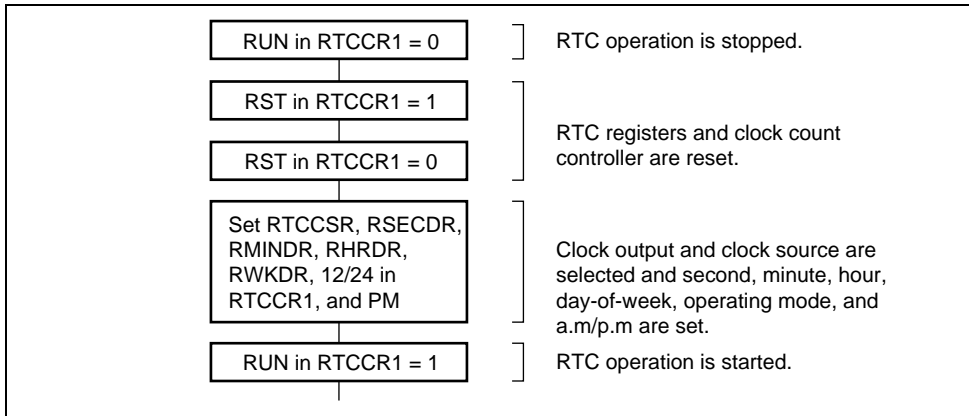


Figure 10.3 Initial Setting Procedure

bit is set to 1, the registers are updated, and the BSY bit is cleared to 0.

2. Making use of interrupts, read from the second, minute, hour, and day-of week registers. The corresponding flag of RTCFLG is set to 1 and the BSY bit is confirmed to be 0.
3. Read from the second, minute, hour, and day-of week registers twice in a row, and if there is no change in the read data, the read data is used.

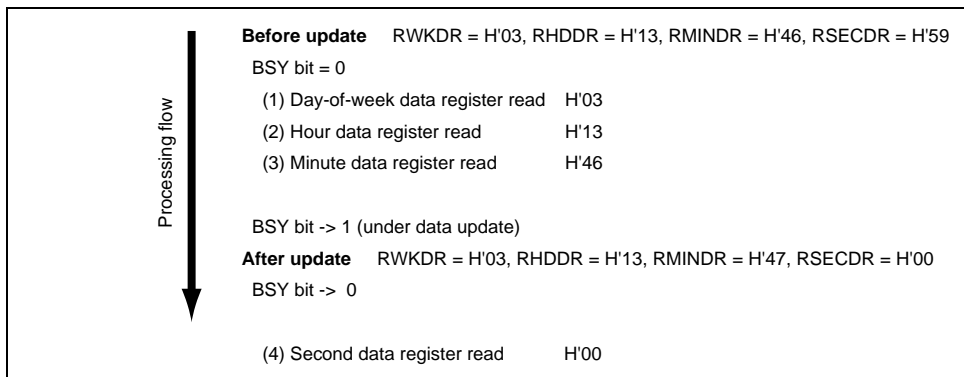


Figure 10.4 Example: Reading of Inaccurate Time Data

Table 10.2 Interrupt Sources

Interrupt Name	Interrupt Source	Interrupt En
Overflow interrupt	Occurs when the free running counter is overflown.	FOIE
Week periodic interrupt	Occurs every week when the day-of-week date register value becomes 0.	WKIE
Day periodic interrupt	Occurs every day when the day-of-week date register is counted.	DYIE
Hour periodic interrupt	Occurs every hour when the hour date register is counted.	HRIE
Minute periodic interrupt	Occurs every minute when the minute date register is counted.	MNIE
One-second periodic interrupt	Occurs every second when the one-second date register is counted.	1SEIE
0.5-second periodic interrupt	Occurs every 0.5 seconds.	05SEIE
0.25-second periodic interrupt	Occurs every 0.25 seconds.	025SEIE

a WDT overflow. As a result, its contents are undefined after power-on. Therefore, when an RTC interrupt occurs, always initialize the RTC register before setting IENRTC in IENR1 to 1.

- Choice of five counter input clocks
Internal clocks ($\phi/32$, $\phi/16$, $\phi/4$, and $\phi_w/4$) or external clocks can be selected.
- Toggle output function
Toggle output is performed to the TMOFH or TMOFL pin using a compare match signal.
The initial value of toggle output can be set.
- Counter resetting by a compare match signal
- Two interrupt sources: One compare match, one overflow
- Choice of 16-bit or 8-bit mode by settings of bits CKSH2 to CKSH0 in TCRF
- Can operate in watch mode, subactive mode, and subsleep mode
When $\phi_w/4$ is selected as an internal clock, the timer F can operate in watch mode, subactive mode, and subsleep mode.
- Use of module standby mode enables this module to be placed in standby mode independent of the CPU when not used. (For details, refer to section 6.4, Module Standby Function.)

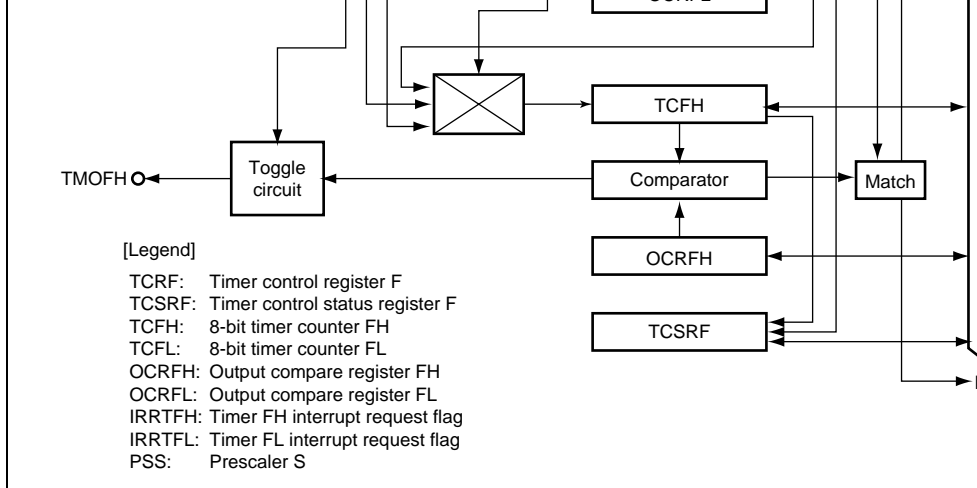


Figure 11.1 Block Diagram of Timer F

11.2 Input/Output Pins

Table 11.1 shows the input/output pins of the timer F.

Table 11.1 Pin Configuration

Name	Abbreviation	I/O	Function
Timer F event input	TMIF	Input	Event input pin to TCFL
Timer FH output	TMOFH	Output	Timer FH toggle output pin
Timer FL output	TMOFL	Output	Timer FL toggle output pin

TCF is a 16-bit read/write up-counter configured by cascaded connection of 8-bit timer counter (TCFH and TCFL). In addition to the use of TCF as a 16-bit counter with TCFH as the upper 8 bits and TCFL as the lower 8 bits, TCFH and TCFL can also be used as independent 8-bit counters.

TCFH and TCFL are initialized to H'00 upon a reset.

(1) 16-Bit Mode (TCF)

When CKSH2 is cleared to 0 in TCRF, TCF operates as a 16-bit counter. The TCF input clock is selected by bits CKSL2 to CKSL0 in TCRF.

TCF can be cleared in the event of a compare match by means of CCLR in TCSR.

When TCF overflows from H'FFFF to H'0000, OVFH is set to 1 in TCSR. If OVIEH is 1 at this time, IRRTFH is set to 1 in IRR2, and if IENTFH in IENR2 is 1, an interrupt request is sent to the CPU.

(2) 8-Bit Mode (TCFH/TCFL)

When CKSH2 is set to 1 in TCRF, TCFH and TCFL operate as two independent 8-bit counters. The TCFH (TCFL) input clock is selected by bits CKSH2 to CKSH0 (CKSL2 to CKSL0) in TCRF.

TCFH (TCFL) can be cleared in the event of a compare match by means of CCLR (CCLRH) in TCSR (TCSR).

When TCFH (TCFL) overflows from H'FF to H'00, OVFH (OVFL) is set to 1 in TCSR. If OVIEH (OVIEL) in TCSR is 1 at this time, IRRTFH (IRRFTFL) is set to 1 in IRR2, and if IENTFH (IENTFHL) in IENR2 is 1, an interrupt request is sent to the CPU.

is sent to the CPU.

Toggle output can be provided from the TMOFH pin by means of compare matches, and output level can be set by means of the TOLH bit in TCRF.

(2) 8-Bit Mode (OCRFB/OCRFL)

When CKSH2 is set to 1 in TCRF, OCRFB and OCRFL operate as two independent 8-bit registers. OCRFB contents are compared with TCFB, and OCRFL contents are with TCFB. When the OCRFB (OCRFL) and TCFB (TCFL) values match, CMFB (CMFL) is set to 1 in TCRF. At the same time, IRRFB (IRRTFL) is set to 1 in IRR2. If IENTFB (IENTFL) in IENR2 is set to 1 at this time, an interrupt request is sent to the CPU.

Toggle output can be provided from the TMOFH pin (TMOFL pin) by means of compare matches, and the output level can be set by means of the TOLH (TOLL) bit in TCRF.

6	CKSH2	0	W	Clock Select H
5	CKSH1	0	W	Select the clock input to TCFH from among fo clock sources or TCFL overflow.
4	CKSH0	0	W	000: 16-bit mode, counting on TCFL overflow 001: 16-bit mode, counting on TCFL overflow 010: 16-bit mode, counting on TCFL overflow 011: Using prohibited 100: 8-bit mode, counting on $\phi/32$ 101: 8-bit mode, counting on $\phi/16$ 110: 8-bit mode, counting on $\phi/4$ 111: 8-bit mode, counting on $\phi_w/4$
3	TOLL	0	W	Toggle Output Level L Sets the TMOFL pin output level. 0: Low level 1: High level

100: Internal clock: counting on $\phi/32$

101: Internal clock: counting on $\phi/16$

110: Internal clock: counting on $\phi/4$

111: Internal clock: counting on $\phi_w/4$

Note: * The TMIFEG bit in IEGR selects which edge of an external event is used for counting.

11.3.4 Timer Control/Status Register F (TCSR F)

TCSR F performs counter clear selection, overflow flag setting, and compare match flag setting, and controls enabling of overflow interrupt requests.

Bit	Bit Name	Initial Value	R/W	Description
7	OVFH	0	R/W*	Timer Overflow Flag H [Setting condition] When TCFH overflows from H'FF to H'00 [Clearing condition] When this bit is written to 0 after reading OVFH
6	CMFH	0	R/W*	Compare Match Flag H This is a status flag indicating that TCFH has matched OCRFH. [Setting condition] When the TCFH value matches the OCRFH value [Clearing condition] When this bit is written to 0 after reading CMFH

OCRFLH match.

In 16-bit mode:

0: TCF clearing by compare match is disabled

1: TCF clearing by compare match is enabled

In 8-bit mode:

0: TCFH clearing by compare match is disabled

1: TCFH clearing by compare match is enabled

3	OVFL	0	R/W*	Timer Overflow Flag L This is a status flag indicating that TCFL has overflowed. [Setting condition] When TCFL overflows from H'FF to H'00 [Clearing condition] When this bit is written to 0 after reading OVF
2	CMFL	0	R/W*	Compare Match Flag L This is a status flag indicating that TCFL has matched the OCRFL. [Setting condition] When the TCFL value matches the OCRFL value [Clearing condition] When this bit is written to 0 after reading CMFL

Note: * Only 0 can be written to clear the flag.

11.4 Operation

The timer F is a 16-bit counter that increments on each input clock pulse. The timer F value is constantly compared with the value set in the output compare register F, and the counter is cleared, an interrupt requested, or port output toggled, when the two values match. The timer can also be used as two independent 8-bit timers.

11.4.1 Timer F Operation

The timer F has two operating modes, 16-bit timer mode and 8-bit timer mode. The operation of each of these modes is described below.

(1) Operation in 16-Bit Timer Mode

When the CKSH2 bit is cleared to 0 in TCRF, the timer F operates as a 16-bit timer.

Following a reset, TCF is initialized to H'0000, OCRF to H'FFFF, and TCRF and TCSRFF are cleared. The counter is incremented by an input signal from an external event (TMIF pin). The TMIF pin bit in IEGR selects which edge of an external event is used for counting.

The timer F operating clock can be selected from internal clocks or external events according to the settings of bits CKSL2 to CKSL0 in TCRF.

OCRF contents are constantly compared with TCF, and when both values match, CMFHFH bit 1 in TCSRFF. If IENTFH in IENR2 is 1 at this time, an interrupt request is sent to the CPU.

When the OCRFH/OCRFL and TCFH/TCFL values match, CMFH/CMFL is set to 1 in IENTFH/IENTFL in IENR2 is 1, an interrupt request is sent to the CPU, and at the same time, TMOFH pin/TMOFL pin output is toggled. If CCLRHL/CCLRLL in TCSRFL is 1, TCFH/TCFL is cleared. The output level of the TMOFH pin/TMOFL pin can be set by TOLH/TOLL in TCSRFL.

When TCFH/TCFL overflows from H'FF to H'00, OVFH/OVFL is set to 1 in TCSRFL. If OVIH/OVIL in TCSRFL and IENTFH/IENTFL in IENR2 are both 1, an interrupt request is sent to the CPU.

11.4.2 TCF Increment Timing

(1) Internal Clock Operation

TCF is incremented by internal clock or external event input. Bits CKSH2 to CKSH0 or CKSL0 in TCRF select one of internal clock sources ($\phi/32$, $\phi/16$, $\phi/4$, or $\phi_w/4$) created by the system clock (ϕ or ϕ_w).

(2) External Event Operation

When the CKSL2 bit in TCRF is cleared to 0, external event input is selected. The counter is incremented at both rising and falling edges of external events. The TMIFEG bit in IEG selects which edge of an external event is used for counting. The external event pulse width must be longer than 2 system clocks (ϕ), or 2 subclocks (ϕ_{SUB}), depending on the operating mode. Note that an external event does not operate correctly with the lower pulse width.

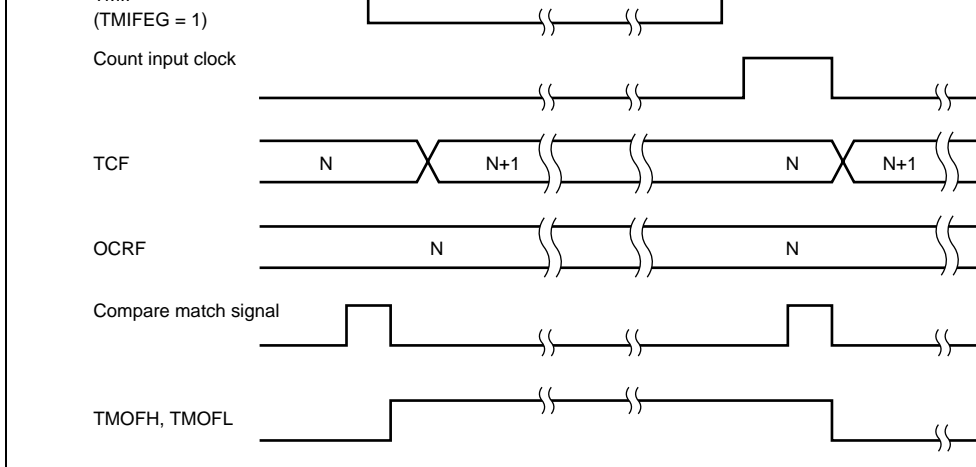


Figure 11.2 TMOFH/TMOFL Output Timing

11.4.4 TCF Clear Timing

TCF can be cleared by a compare match with OCRF.

11.4.5 Timer Overflow Flag (OVF) Set Timing

OVF is set to 1 when TCF overflows from H'FFFF to H'0000.

Table 11.2 Timer F Operating States

Operating Mode	Reset	Active	Sleep	Watch	Sub-active	Sub-sleep	Standby
TCF	Reset	Functions*	Functions*	Functions/ Halted*	Functions/ Halted*	Functions/ Halted*	Halted
OCRf	Reset	Functions	Retained	Retained	Functions	Retained	Retained
TCRF	Reset	Functions	Retained	Retained	Functions	Retained	Retained
TCSRf	Reset	Functions	Retained	Retained	Functions	Retained	Retained

Note: * When $\phi_w/4$ is selected as the TCF internal clock in active mode or sleep mode, the system clock and internal clock are mutually asynchronous, synchronization is maintained by a synchronization circuit. This results in a maximum count cycle of $1/\phi$ (s). When the counter is operated in subactive mode, watch mode, or sub-sleep mode, $\phi_w/4$ must be selected as the internal clock. The counter will not operate if any other internal clock is selected.

should be used as a port pin.

If an OCRFL write and compare match signal generation occur simultaneously, the compare match signal is invalid. However, a compare match signal may or may not be generated with the written data and the counter value match. As the compare match signal is output in synchronization with the TCFL clock, a compare match will not result in compare match signal generation if the clock is stopped.

Compare match flag CMFH is set when all 16 bits match and a compare match signal is generated. Compare match flag CMFL is set if the setting conditions for the lower 8 bits are satisfied.

When TCF overflows, OVFH is set. OVFL is set if the setting conditions are satisfied when the lower 8 bits overflow. If a TCFL write and overflow signal output occur simultaneously, the overflow signal is not output.

11.6.2 8-Bit Timer Mode

(1) TCFH, OCRFH

In toggle output, TMOFH pin output is toggled when a compare match occurs. If a TCFH write and a MOV instruction and generation of the compare match signal occur simultaneously, TMOFH is output to the TMOFH pin as a result of the TCRF write.

If an OCRFH write and compare match signal generation occur simultaneously, the compare match signal is invalid. However, a compare match signal may or may not be generated with the written data and the counter value match. The compare match signal is output in synchronization with the TCFH clock.

If a TCFH write and overflow signal output occur simultaneously, the overflow signal is not output.

If a TCFL write and overflow signal output occur simultaneously, the overflow signal is output.

11.6.3 Flag Clearing

When $\phi_w/4$ is selected as the internal clock, "Interrupt source generation signal" will be output with ϕ_w and the signal will be outputted with ϕ_w width. And, "Overflow signal" and "Compare match signal" are controlled with 2 cycles of ϕ_w signals. Those signals are output with 2 width of ϕ_w (figure 11.3)

In active (high-speed, medium-speed) mode, even if you cleared interrupt request flag during term of validity of "Interrupt source generation signal", same interrupt request flag is set (figure 11.3) And, the timer overflow flag and compare match flag cannot be cleared during term of validity of "Overflow signal" and "Compare match signal".

For interrupt request flag is set right after interrupt request is cleared, interrupt process timer FH, timer FL interrupt might be repeated. (2 in figure 11.3) Therefore, to definitely clear interrupt request flag in active (high-speed, medium-speed) mode, clear should be processed after the time that calculated with below (1) formula. And, to definitely clear timer overflow flag and compare match flag, clear should be processed after read timer control status register FCR after the time that calculated with below (1) formula.

For ST of (1) formula, please substitute the longest number of execution states in used in active mode.

In subactive mode, there are not limitation for interrupt request flag, timer overflow flag and compare match flag clear.

2. After program process returned normal handling, clear interrupt request flags (IRRTFH, IRRTFL) after more than that calculated with (1) formula.
3. After reading the timer control status register F (TCSRFB), clear the timer overflow flags (OVFB, OVFL) and compare match flags (CMFB, CMFL).
4. Enable interrupts (set IENFB, IENFL to 1).

Method 2

1. Set interrupt handling routine time to more than time that calculated with (1) formula.
2. Clear interrupt request flags (IRRTFB, IRRTFL) at the end of interrupt handling routine.
3. After read timer control status register F (TCSRFB), clear timer overflow flags (OVFB, OVFL) and compare match flags (CMFB, CMFL).

All above attentions are also applied in 16-bit mode and 8-bit mode.

**Figure 11.3 Clear Interrupt Request Flag when
Interrupt Source Generation Signal is Valid**

11.6.4 Timer Counter (TCF) Read/Write

When $\phi_w/4$ is selected as the internal clock in active (high-speed, medium-speed) mode, TCF is impossible. And when reading TCF, as the system clock and internal clock are asynchronous, TCF synchronizes with synchronization circuit. This results in a maximum read value error of ± 1 .

When reading or writing TCF in active (high-speed, medium-speed) mode is needed, please use the internal clock except for $\phi_w/4$ before read/write is performed.

In subactive mode, even if $\phi_w/4$ is selected as the internal clock, TCF can be read from normally.

- The following operations can be set for each channel:
 - Waveform output at compare match
 - Input capture function
 - Counter clear operation
 - Multiple timer counters (TCNT) can be written to simultaneously
 - Simultaneous clearing by compare match and input capture is possible
 - Register synchronous input/output is possible by synchronous counter operation
 - PWM output with any duty level is possible
 - A maximum 2-phase PWM output is possible in combination with synchronous operation
- Operation with cascaded connection
- Fast access via internal 16-bit bus
- 6-type interrupt sources
- Register data can be transmitted automatically
- Use of module standby mode enables this module to be placed in standby mode independent of the CPU when not used. (For details, refer to section 6.4, Module Standby Function.)

		TCLKC	
General registers (TGR)		TGRA_1	TGRA_2
		TGRB_1	TGRB_2
I/O pin		TIOCA1	TIOCA2
Input pin		TIOCB1	TIOCB2
Counter clear function		TGR compare match or input capture	TGR compare match or capture
Compare match output	0 output	0	—
	1 output	0	—
	Toggle output	0	—
Input capture function		0	0
Synchronous operation		0	0
PWM mode		0	0
Interrupt sources		3 sources	3 sources
		<ul style="list-style-type: none"> • Compare match or input capture 1A • Compare match or input capture 1B • Overflow 	<ul style="list-style-type: none"> • Compare match or input capture 2A • Compare match or input capture 2B • Overflow

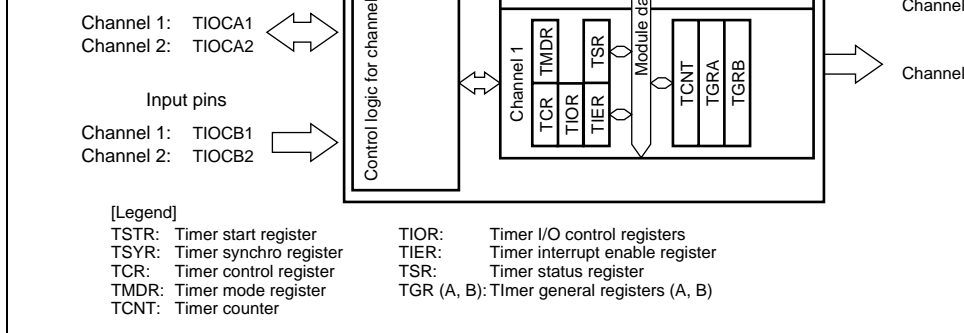


Figure 12.1 Block Diagram of TPU

12.2 Input/Output Pins

Table 12.2 Pin Configuration

Channel	Symbol	I/O	Function
Common	TCLKA	Input	External clock A input pin
	TCLKB	Input	External clock B input pin
	TCLKC	Input	External clock C input pin
1	TIOCA1	I/O	TGRA_1 input capture input/output capture input/output/PWM output pin
	TIOCB1	Input	TGRB_1 input capture input pin
2	TIOCA2	I/O	TGRA_2 input capture input/output capture input/output/PWM output pin
	TIOCB2	Input	TGRB_2 input capture input pin

- Timer status register_1 (TSR_1)
- Timer counter_1 (TCNT_1)
- Timer general register A_1 (TGRA_1)
- Timer general register B_1 (TGRB_1)

Channel 2:

- Timer control register_2 (TCR_2)
- Timer mode register_2 (TMDR_2)
- Timer I/O control register_2 (TIOR_2)
- Timer interrupt enable register_2 (TIER_2)
- Timer status register_2 (TSR_2)
- Timer counter_2 (TCNT_2)
- Timer general register A_2 (TGRA_2)
- Timer general register B_2 (TGRB_2)

Common:

- Timer start register (TSTR)
- Timer synchro register (TSYR)

5	CCLR0	0	R/W	These bits select the TCNT counter clearing source. See table 12.3 for details.
4	CKEG1	0	R/W	Clock Edge 1 and 0
3	CKEG0	0	R/W	These bits select the input clock edge. When the internal clock is counted using both edges, the clock period is halved (e.g. $\phi/4$ both edges = $\phi/2$ edge). Internal clock edge selection is valid when the input clock is $\phi/4$ or slower. If the input clock is faster, the setting is ignored and count at a rising edge is used. 00: Count at rising edge 01: Count at falling edge 1X: Count at both edges [Legend] X: Don't care
2	TPSC2	0	R/W	Timer Prescaler 2 to 0
1	TPSC1	0	R/W	These bits select the TCNT counter clock. The clock source can be selected independently for each timer.
0	TPSC0	0	R/W	See tables 12.4 and 12.5 for details.

Table 12.4 TPSC2 to TPSC0 (Channel 1)

Channel	Bit 2 TPSC2	Bit 1 TPSC1	Bit 0 TPSC0	Description
1	0	0	0	Internal clock: counts on $\phi/1$
			1	Internal clock: counts on $\phi/4$
		1	0	Internal clock: counts on $\phi/16$
			1	Internal clock: counts on $\phi/64$
	1	0	0	External clock: counts on TCLKA pin input
			1	External clock: counts on TCLKB pin input
		1	0	Internal clock: counts on $\phi/256$
			1	Counts on TCNT_2 overflow

1

0

External clock: counts on TCLKC pin input

1

Internal clock: counts on $\phi/1024$

12.3.2 Timer Mode Register (TMDR)

TMDR sets the operating mode for each channel. The TPU has a total of two TMDR registers for each channel. TMDR should be set when TCNT operation is stopped.

Bit	Bit Name	Initial Value	R/W	Description
7, 6	—	All 1	—	Reserved These bits are always read as 1 and cannot be modified.
5, 4	—	All 0	—	Reserved These bits are always read as 0 and cannot be modified.
3, 2	—	All 0	—	Reserved The write value should always be 0.
1	MD1	0	R/W	Modes 1 and 0
0	MD0	0	R/W	These bits set the timer operating mode. See table 12.6 for details.

TIOR controls TGR. The TPU has a total of two TIOR registers, one for each channel. C required as TIOR is affected by the TMDR setting.

The initial output specified by TIOR is valid when the counter is stopped (the CST bit in cleared to 0). Note also that, in PWM mode 2, the output at the point at which the counter cleared to 0 is specified.

- TIOR_1, TIOR_2

Bit	Bit Name	Initial Value	R/W	Description
7	IOB3	All 0	R/W	I/O Control B3 to B0
6	IOB2		R/W	Specify the function of TGRB.
5	IOB1		R/W	For details, refer to tables 12.7 and 12.8.
4	IOB0		R/W	
3	IOA3	All 0	R/W	I/O Control A3 to A0
2	IOA2		R/W	Specify the function of TGRA.
1	IOA1		R/W	For details, refer to tables 12.9 and 12.10.
0	IOA0		R/W	

			1		
			1	0	
			1	1	
1	0	0	0	Input capture register	Capture input source is TIOCE Input capture at rising edge
			1		Capture input source is TIOCE Input capture at falling edge
		1	X		Capture input source is TIOCE Input capture at both edges
	1	X	X		Setting prohibited

[Legend]

X: Don't care

			1		
		1	0		
			1		
1	X	0	0	Input capture register	Capture input source is TIOCB2 Input capture at rising edge
			1		Capture input source is TIOCB2 Input capture at falling edge
		1	X		Capture input source is TIOCB2 Input capture at both edges

[Legend]

X: Don't care

			1		Initial output is 0
			0		Toggle output at compare match
	1	0	0		Output disabled
			1		Initial output is 1
			0		0 output at compare match
		1	0		Initial output is 1
			1		1 output at compare match
			0		Initial output is 1
			1		Toggle output at compare match
1	0	0	0	Input capture register	Capture input source is TIOCA1
			1		Input capture at rising edge
			0		Capture input source is TIOCA1
			1		Input capture at falling edge
		1	X		Capture input source is TIOCA1
		X	X		Input capture at both edges
	1	X	X		Setting prohibited

[Legend]

X: Don't care

			1		Initial output is 0
			0		Toggle output at compare match
1	0		0		Output disabled
			1		Initial output is 1
			0		0 output at compare match
		1	0		Initial output is 1
			1		1 output at compare match
			0		Initial output is 1
			1		Toggle output at compare match
1	X	0	0	Input capture register	Capture input source is TIOCA2
			1		Input capture at rising edge
			0		Capture input source is TIOCA2
			1		Input capture at falling edge
		1	X		Capture input source is TIOCA2
			0		Input capture at both edges

[Legend]

X: Don't care

5	—	0	—	Reserved This bit is always read as 1 and cannot be modified.
4	TCIEV	0	R/W	Overflow Interrupt Enable Enables or disables interrupt requests (TCIV) by TCFV flag when the TCFV flag in TSR is set to 1. 0: Interrupt requests (TCIV) by TCFV disabled 1: Interrupt requests (TCIV) by TCFV enabled
3, 2	—	All 0	—	Reserved These bits are always read as 0 and cannot be modified.
1	TGIEB	0	R/W	TGR Interrupt Enable B Enables or disables interrupt requests (TGIB) by TGFB bit when the TGFB bit in TSR is set to 1. 0: Interrupt requests (TGIB) by TGFB bit disabled 1: Interrupt requests (TGIB) by TGFB bit enabled
0	TGIEA	0	R/W	TGR Interrupt Enable A Enables or disables interrupt requests (TGIA) by TGFA bit when the TGFA bit in TSR is set to 1. 0: Interrupt requests (TGIA) by TGFA bit disabled 1: Interrupt requests (TGIA) by TGFA bit enabled

4	TCFV	0	R/(W)*	<p>Overflow Flag</p> <p>Status flag that indicates that TCNT overflow has occurred.</p> <p>[Setting condition]</p> <p>When the TCNT value overflows (changes from to H'0000)</p> <p>[Clearing condition]</p> <p>When 0 is written to TCFV after reading TCFV =</p>
3, 2	—	All 0	—	<p>Reserved</p> <p>These bits are always read as 0 and cannot be r</p>
1	TGFB	0	R/(W)*	<p>Input Capture/Output Compare Flag B</p> <p>Status flag that indicates the occurrence of TGR capture or compare match.</p> <p>[Setting conditions]</p> <ul style="list-style-type: none"> • When TCNT = TGRB and TGRB is functioning output compare register • When TCNT value is transferred to TGRB by capture signal and TGRB is functioning as in capture register <p>[Clearing condition]</p> <ul style="list-style-type: none"> • When 0 is written to TGFB after reading TGR

capture register
[Clearing condition]

- When 0 is written to TGFA after reading TG

Note: * Only 0 can be written to clear the flag.

12.3.6 Timer Counter (TCNT)

TCNT is a 16-bit readable/writable counter. The TPU has a total of two TCNT counters each channel.

TCNT is initialized to H'0000 by a reset or in hardware standby mode.

TCNT cannot be accessed in 8-bit units; it must always be accessed in 16-bit units.

12.3.7 Timer General Register (TGR)

TGR is a 16-bit readable/writable register, functioning as either output compare or input register. The TPU has a total of four TGR registers, two for each channel. TGR is initialized to H'FFFF by a reset. TGR cannot be accessed in 8-bit units; it must always be accessed in 16-bit units.

2	CST2	0	R/W	Counter Start 2 and 1
1	CST1	0	R/W	<p>These bits select operation or stoppage for TCNT_n.</p> <p>If 0 is written to the CST bit during operation with TIOC pin designated for output, the counter stop output compare output level of the TIOC pin is reloaded. TIOR is written to when the CST bit is cleared to 0. TIOC pin output level will be changed to the set initial output level.</p> <p>0: TCNT_n count operation is stopped 1: TCNT_n performs count operation</p>

0	—	0	—	Reserved
---	---	---	---	----------

The write value should always be 0.

1	SYNC1	0	R/W	<p>These bits select whether operation is independent or synchronous. When synchronous operation is selected, the synchronous presetting of multiple channels, and synchronous clearing by counter clearing on a channel, are possible.</p> <p>To set synchronous operation, the SYNC bits are set to 1. To set synchronous clearing, in addition to the SYNC bit, the TCNT clearing source must also be set to 1 by means of bits CCLR1 and CCLR0 in TCR.</p> <p>0: TCNT_n operates independently (TCNT presetting/clearing is unrelated to other channels)</p> <p>1: TCNT_n performs synchronous operation (TCNT synchronous presetting/synchronous clearing is possible)</p>
0	—	0	—	<p>Reserved</p> <p>The write value should always be 0.</p>

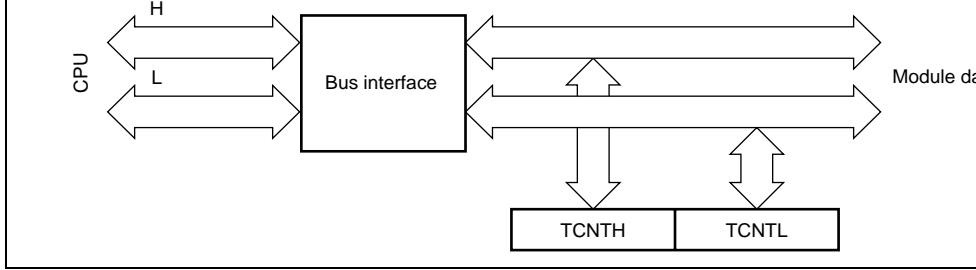


Figure 12.2 16-Bit Register Access Operation [CPU ↔ TCNT (16 Bits)]

12.4.2 8-Bit Registers

Registers other than TCNT and TGR are 8-bit. They can also be read and written to in 8-bit.

Examples of 8-bit register access operation are shown in figures 12.3 and 12.4.

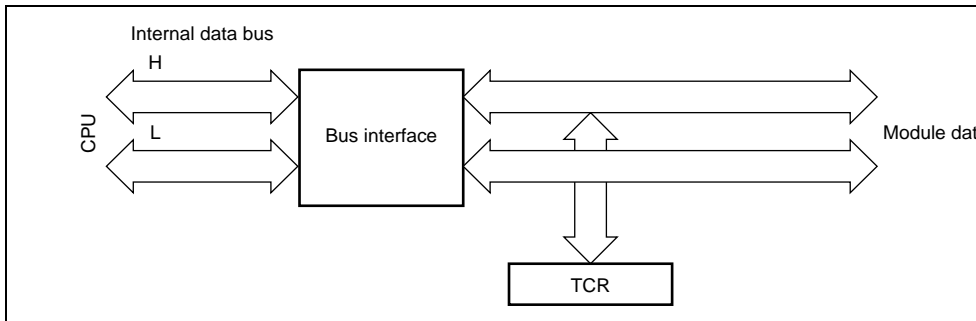


Figure 12.3 8-Bit Register Access Operation [CPU ↔ TCR (Upper 8 Bits)]

When one of bits CS11 and CS12 is set to 1 in TSTR, TCNT1 for the corresponding channel begins counting. TCNT can operate as a free-running counter, periodic counter, for exam

(a) Example of Count Operation Setting Procedure

Figure 12.5 shows an example of the count operation setting procedure.

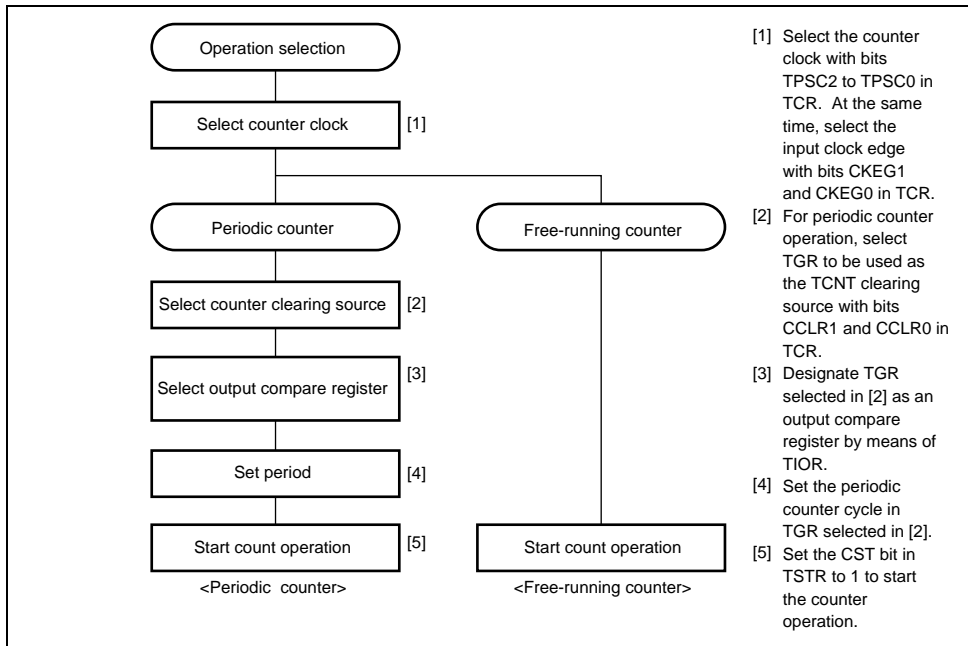


Figure 12.5 Example of Counter Operation Setting Procedure

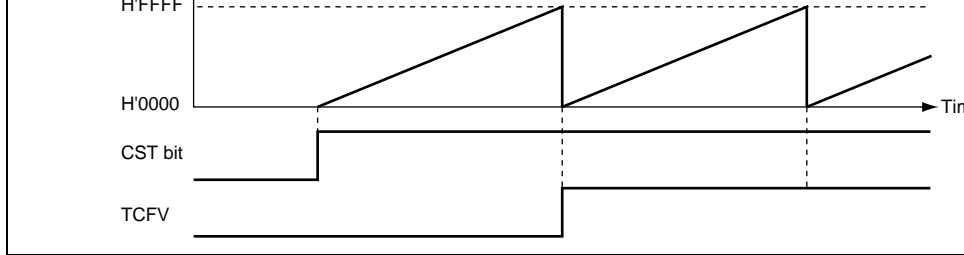


Figure 12.6 Free-Running Counter Operation

When compare match is selected as the TCNT clearing source, TCNT for the relevant channel performs periodic count operation. TGR for setting the period is designated as an output compare register, and counter clearing by compare match is selected by means of bits CCLR0 and CCLR1 in TCR. After the settings have been made, TCNT starts up-count operation as a periodic count when the corresponding bit in TSTR is set to 1. When the count value matches the value of the TGR, the TGF bit in TSR is set to 1 and TCNT is cleared to H'0000.

If the value of the corresponding TGIE bit in TIER is 1 at this point, the TPU requests a compare match interrupt. After a compare match, TCNT starts counting up again from H'0000.

Figure 12.7 illustrates periodic counter operation.

(2) Waveform Output by Compare Match

The TPU can perform 0, 1, or toggle output from the corresponding output pin using compare match.

(a) Example of Setting Procedure for Waveform Output by Compare Match

Figure 12.8 shows an example of the setting procedure for waveform output by compare

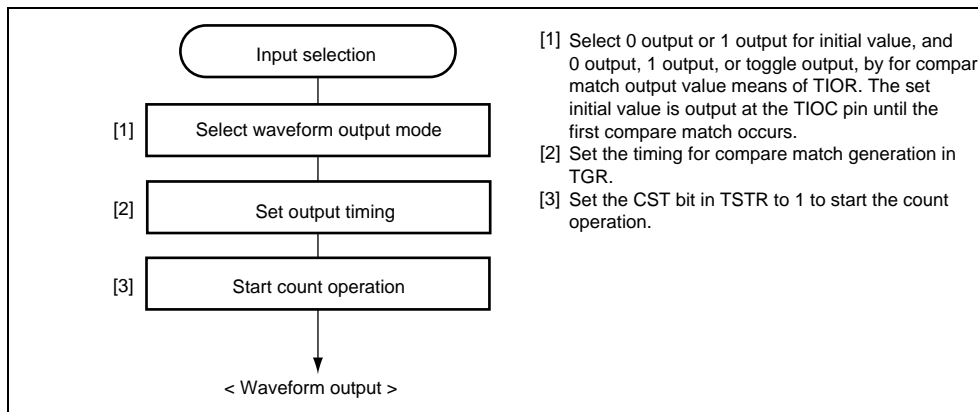


Figure 12.8 Example of Setting Procedure for Waveform Output by Compare Match

(b) Examples of Waveform Output Operation

Figure 12.9 shows an example of 1 output.

In this example, TCNT has been designated as a free-running counter, and settings have been made such that 1 is output by compare match A. When the set level and the pin level match, the pin level does not change.

Figure 12.10 shows an example of toggle output.

In this example, TCNT has been designated as a periodic counter (with counter clearing compare match A), and settings have been made such that the output is toggled by compare match A.

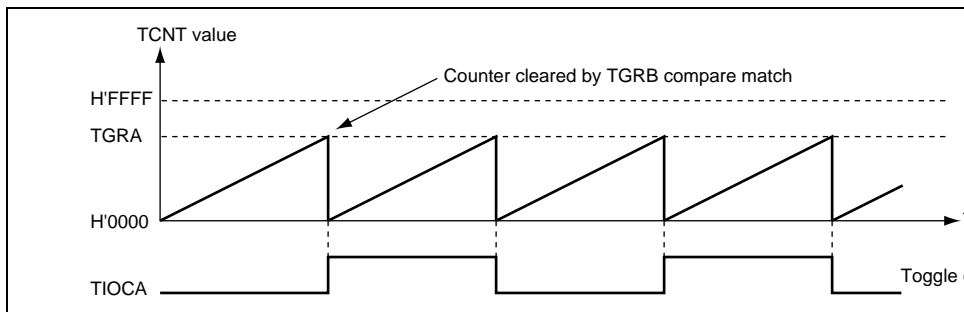


Figure 12.10 Example of Toggle Output Operation

(3) Input Capture Function

The TCNT value can be transferred to TGR on detection of the TIOC pin input edge.

Rising edge, falling edge, or both edges can be selected as the detected edge.

(a) Example of Input Capture Operation Setting Procedure

Figure 12.11 shows an example of the setting procedure for input capture operation.

(b) Example of Input Capture Operation

Figure 12.12 shows an example of input capture operation.

In this example, both rising and falling edges have been selected as the input capture input pin, the falling edge has been selected as the input capture input edge of the T pin, and counter clearing by TGRB input capture has been designated for TCNT.

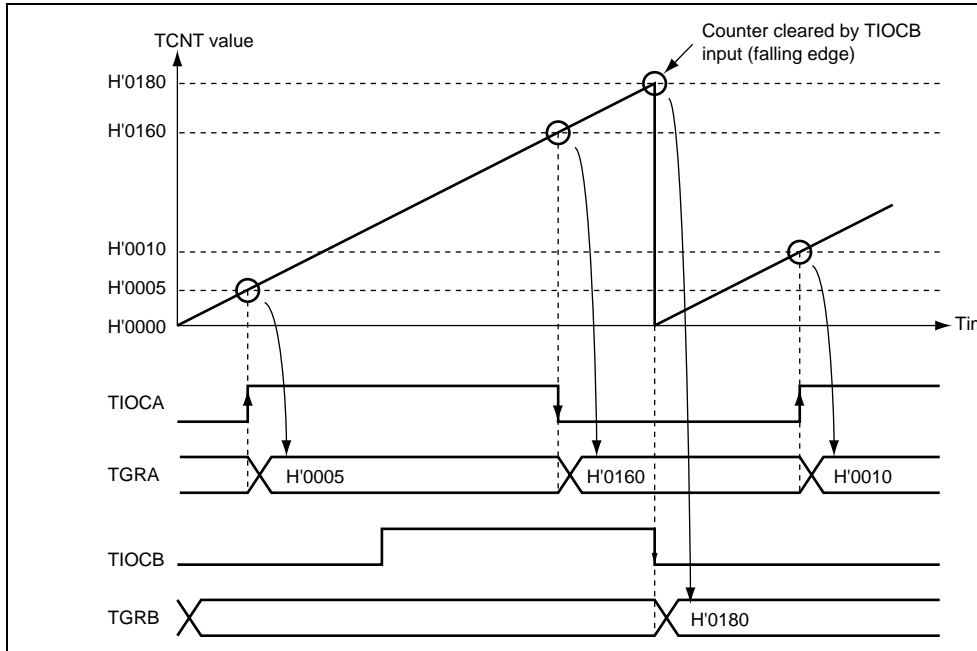


Figure 12.12 Example of Input Capture Operation

Figure 12.13 shows an example of the synchronous operation setting procedure.

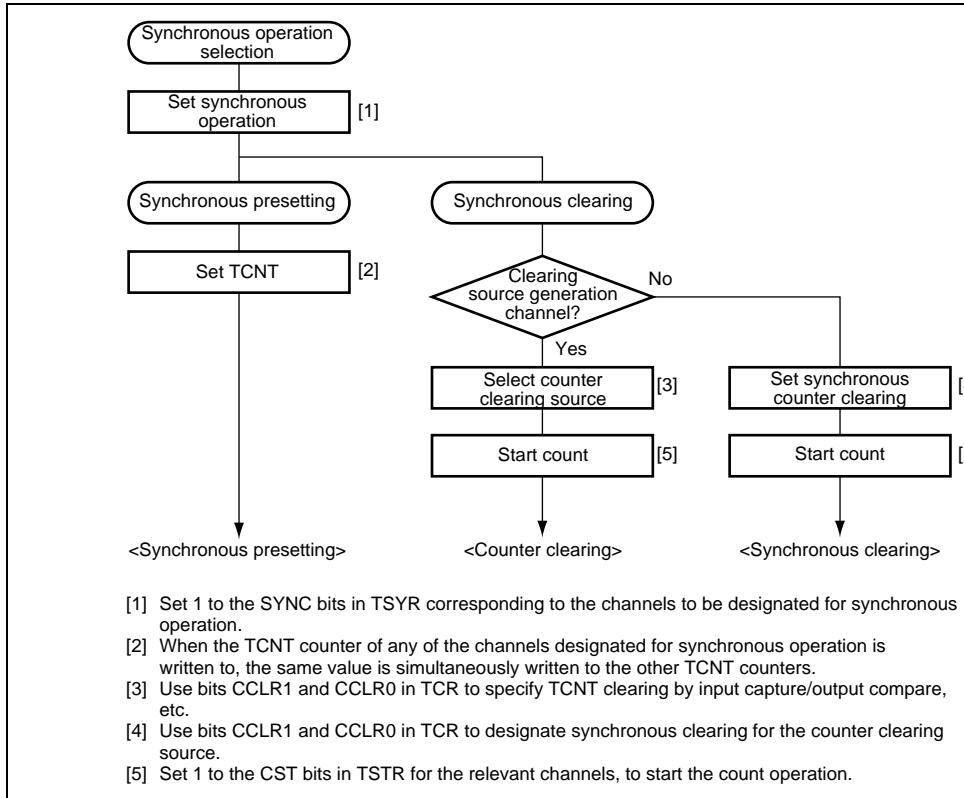


Figure 12.13 Example of Synchronous Operation Setting Procedure

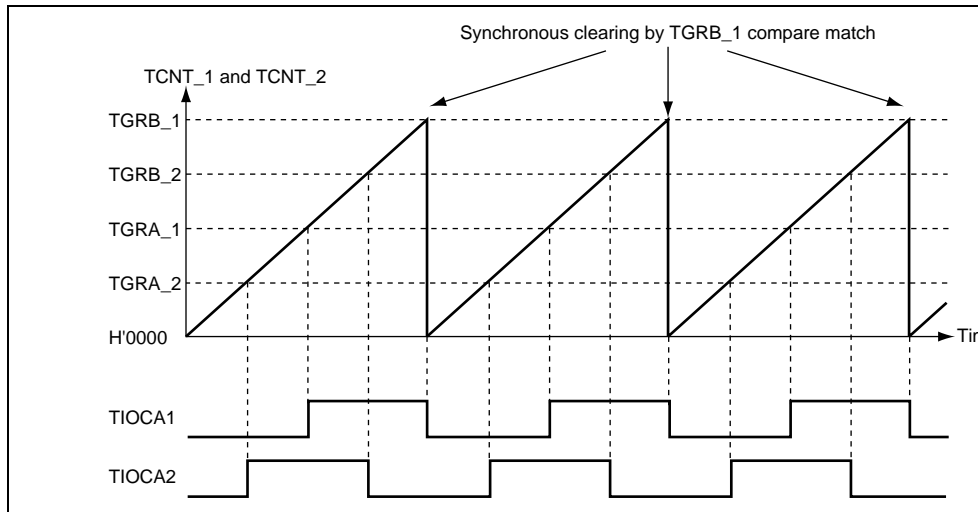


Figure 12.14 Example of Synchronous Operation

(1) Setting Procedure for Operation with Cascaded Connection

Figure 12.15 shows the setting procedure for cascaded connection operation.

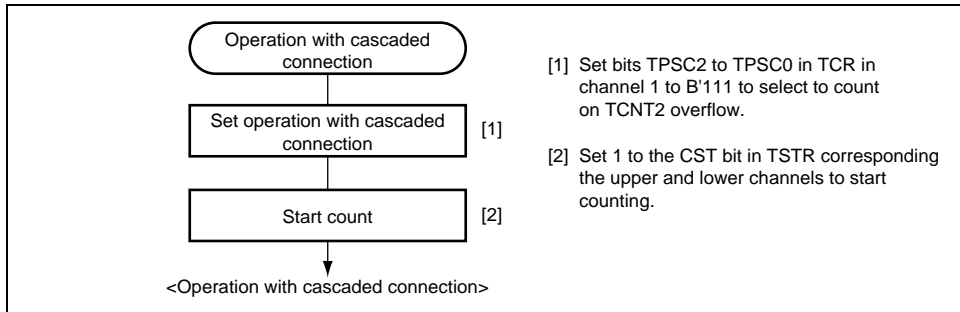


Figure 12.15 Setting Procedure for Operation with Cascaded Operation

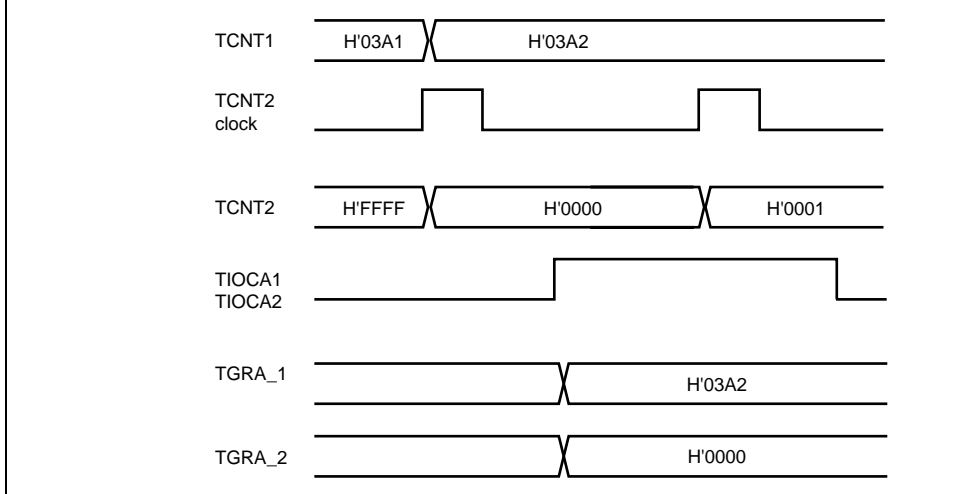


Figure 12.16 Example of Operation with Cascaded Connection

(1) PWM Mode 1

PWM output is generated from the TIOCA pin by pairing TGRA with TGRB. The level by bits IOA0 to IOA3 in TIOR is output from the TIOCA pin at compare match A, and specified by bits IOB0 to IOB3 in TIOR is output at compare match B. The initial output the value set in TGRA. If the set values of paired TGRs are identical, the output value does not change even if a compare match occurs.

In PWM mode 1, PWM output is enabled up to 2 phases.

(2) PWM Mode 2

PWM output is generated using one TGR as the cycle register and the others as duty register. The output specified in TIOR is performed by means of compare matches. Upon counter clear or synchronization register compare match, the output value of each pin is the initial value specified in TIOR. If the set values of the cycle and duty registers are identical, the output value does not change even if a compare match occurs.

In PWM mode 2, PWM output is enabled up to 2 phases.

The correspondence between PWM output pins and registers is shown in table 12.12.

(3) Example of PWM Mode Setting Procedure

Figure 12.17 shows an example of the PWM mode setting procedure.

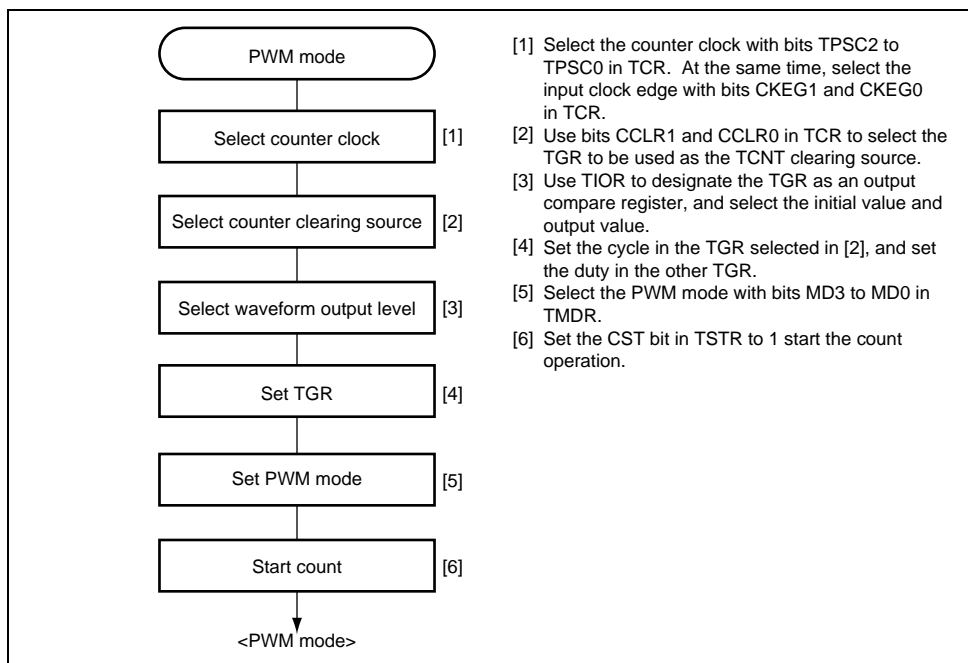


Figure 12.17 Example of PWM Mode Setting Procedure

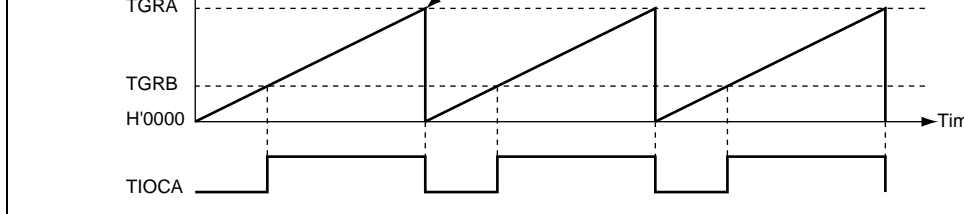


Figure 12.18 Example of PWM Mode Operation (1)

Figure 12.19 shows an example of PWM mode 2 operation. In this example, synchronous operation is designated for channels 1 and 2, TGRB_2 compare match is set as the TCNT source, and 0 is set for the initial output value and 1 for the output value of the other TG (TGRA_1, TGRB_1, and TGRA_2), outputting a 2-phase PWM waveform.

In this case, the value set in TGRB_2 is used as the cycle, and the values set in the other TG are used as the duty levels.

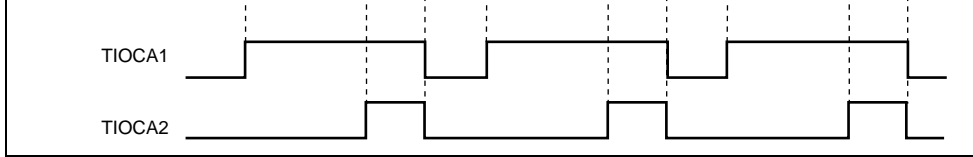


Figure 12.19 Example of PWM Mode Operation (2)

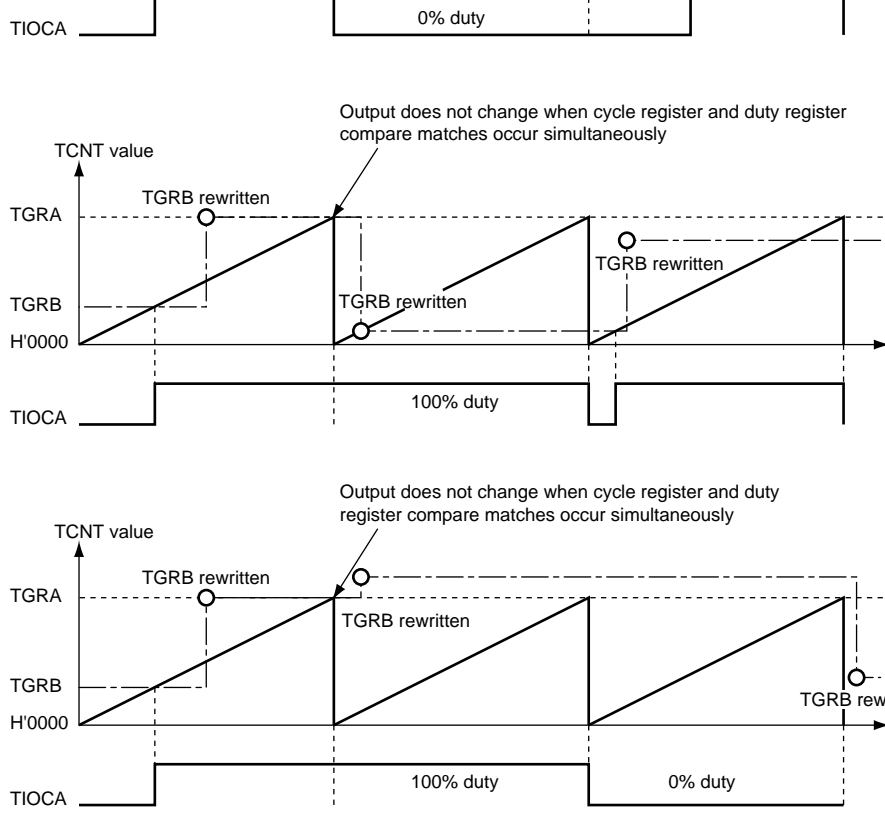


Figure 12.20 Example of PWM Mode Operation (3)

is fixed. For details, see section 4, Interrupt Controller.

Table 12.13 lists the TPU interrupt sources.

Table 12.13 TPU Interrupts

Channel	Name	Interrupt Source	Interrupt Flag	Priority
1	TGI1A	TGRA_1 input capture/compare match	TGFA_1	High ↑
	TGI1B	TGRB_1 input capture/compare match	TGFB_1	
	TCI1V	TCNT_1 overflow	TCFV_1	
2	TGI2A	TGRA_2 input capture/compare match	TGFA_2	Low
	TGI2B	TGRB_2 input capture/compare match	TGFB_2	
	TCI2V	TCNT_2 overflow	TCFV_2	

(1) Input Capture/Compare Match Interrupt

An interrupt is requested if the TGIE bit in TIER is set to 1 when the TGF flag in TSR is set to 1 by the occurrence of a TGR input capture/compare match on a particular channel. The interrupt request is cleared by clearing the TGF flag to 0. The TPU has a total of four input capture/compare match interrupts, two for each channel.

(2) Overflow Interrupt

An interrupt is requested if the TCIEV bit in TIER is set to 1 when the TCFV flag in TSR is set to 1 by the occurrence of TCNT overflow on a channel. The interrupt request is cleared by clearing the TCFV flag to 0. The TPU has a total of two overflow interrupts, one for each channel.

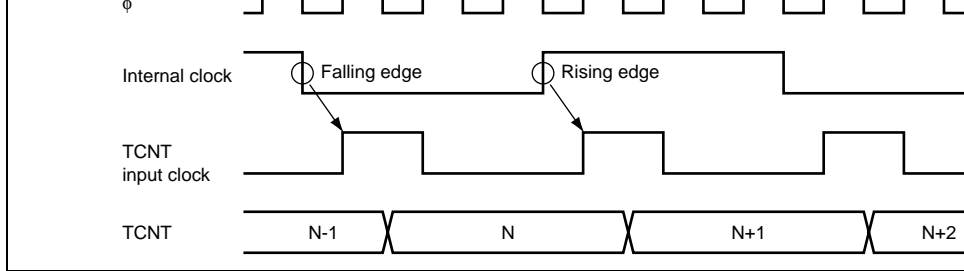


Figure 12.21 Count Timing in Internal Clock Operation

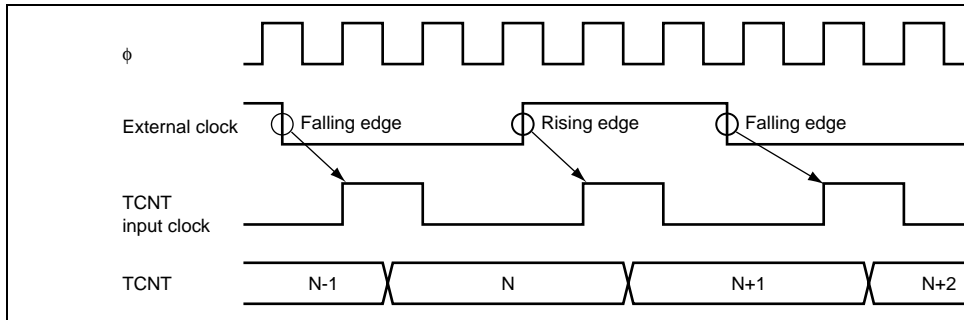


Figure 12.22 Count Timing in External Clock Operation

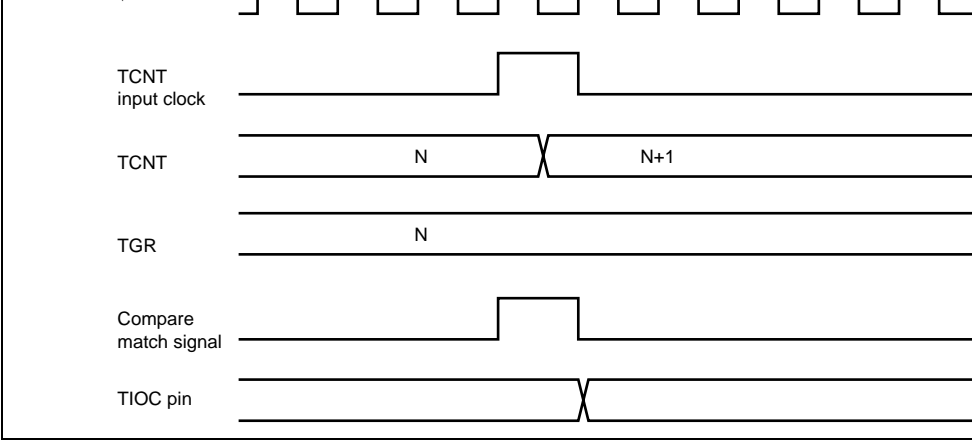


Figure 12.23 Output Compare Output Timing

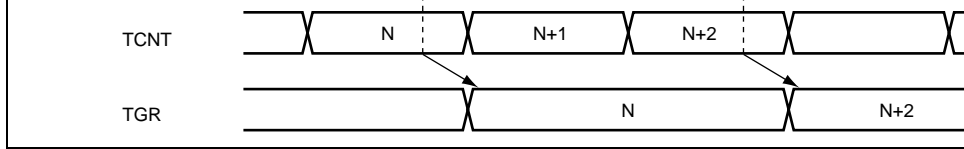


Figure 12.24 Input Capture Input Signal Timing

(4) Timing for Counter Clearing by Compare Match/Input Capture

Figure 12.25 shows the timing when counter clearing on compare match is specified, and Figure 12.26 shows the timing when counter clearing on input capture is specified.

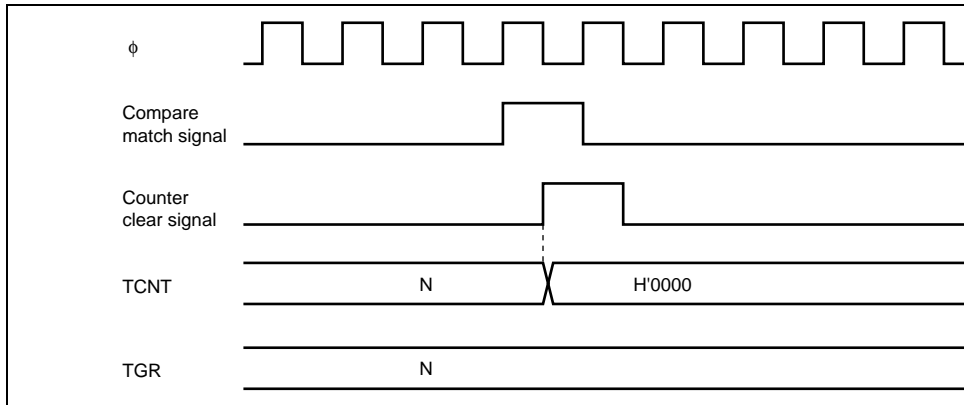


Figure 12.25 Counter Clear Timing (Compare Match)

12.7.2 Interrupt Signal Timing

(1) TGF Flag Setting Timing in Case of Compare Match

Figure 12.27 shows the timing for setting of the TGF flag in TSR on compare match, and interrupt request signal timing.

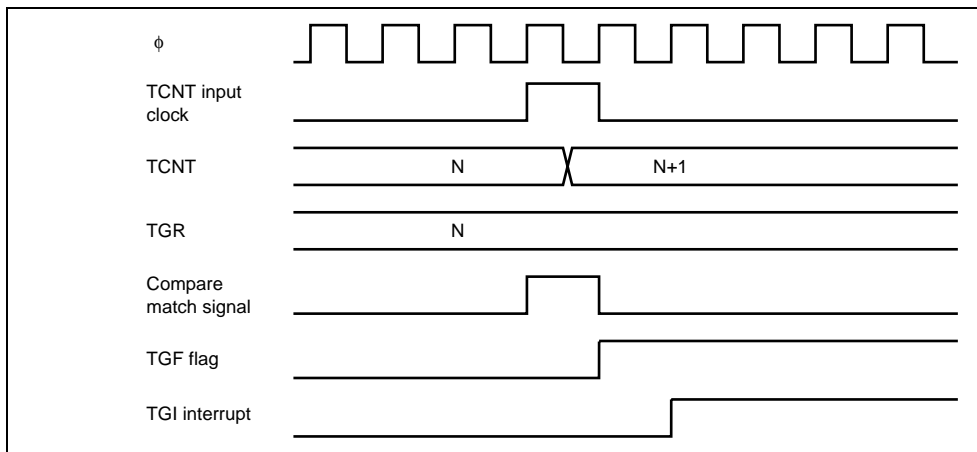


Figure 12.27 TGI Interrupt Timing (Compare Match)

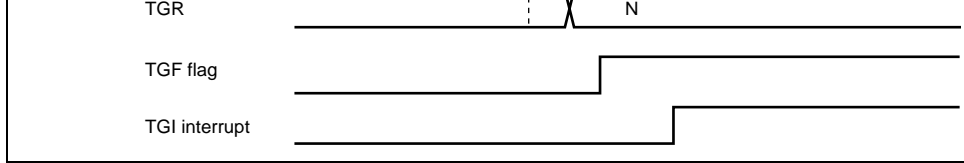


Figure 12.28 TGI Interrupt Timing (Input Capture)

(3) TCFV Flag Setting Timing

Figure 12.29 shows the timing for setting of the TCFV flag in TSR on overflow, and TCIV interrupt request signal timing.

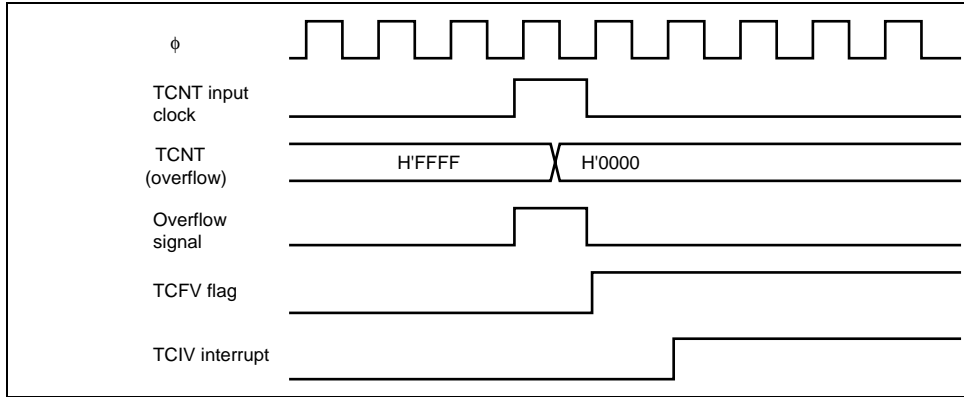


Figure 12.29 TCIV Interrupt Setting Timing

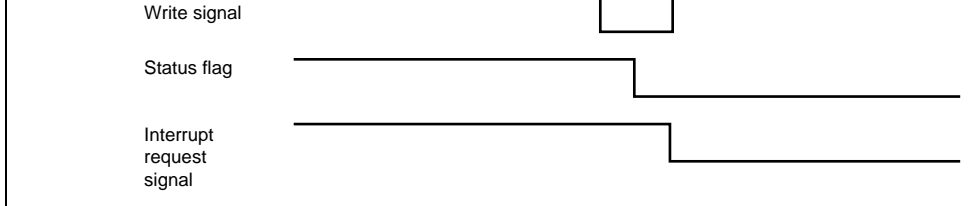


Figure 12.30 Timing for Status Flag Clearing by CPU

12.8 Usage Notes

12.8.1 Module Standby Function Setting

TPU operation can be disabled or enabled using the clock stop register. The initial setting of the clock stop register disables the TPU. Register access is enabled by clearing the module standby function. For details, refer to section 6.4, Module Standby Function.

12.8.2 Input Clock Restrictions

The input clock pulse width must be at least 1.5 states in the case of single-edge detection and at least 2.5 states in the case of both-edge detection. The TPU will not operate properly at narrow pulse widths.

12.8.4 Contention between TCNT Write and Clear Operation

If the counter clear signal is generated in the T2 state of a TCNT write cycle, TCNT clear priority and the TCNT write is not performed.

Figure 12.31 shows the timing in this case.

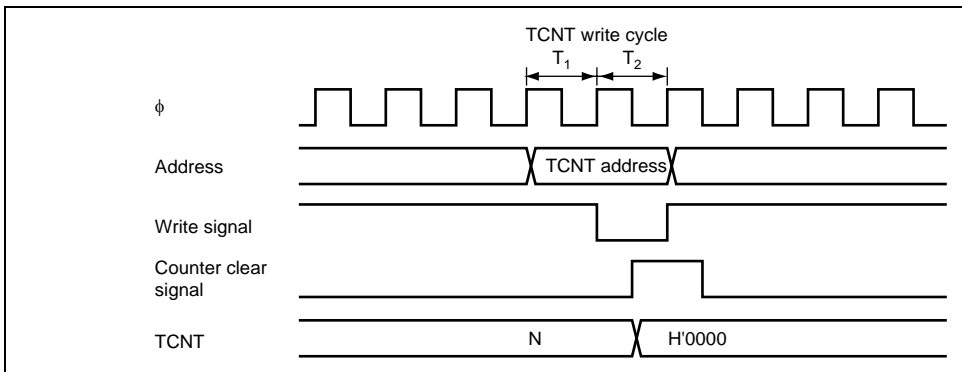


Figure 12.31 Contention between TCNT Write and Clear Operation

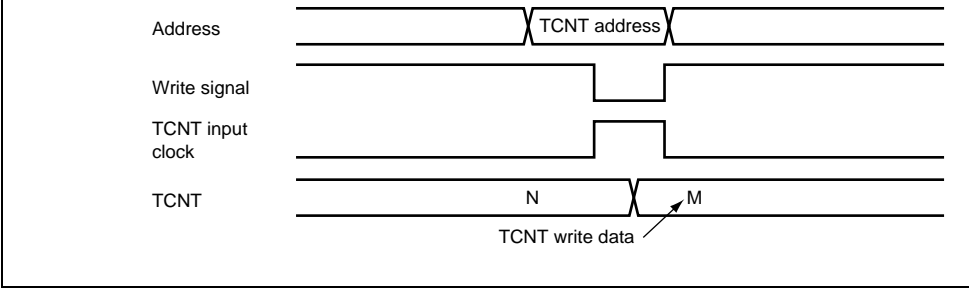


Figure 12.32 Contention between TCNT Write and Increment Operation

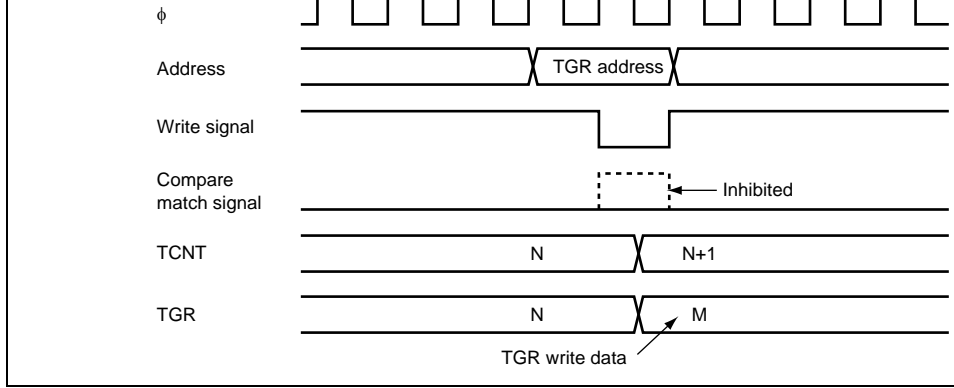


Figure 12.33 Contention between TGR Write and Compare Match

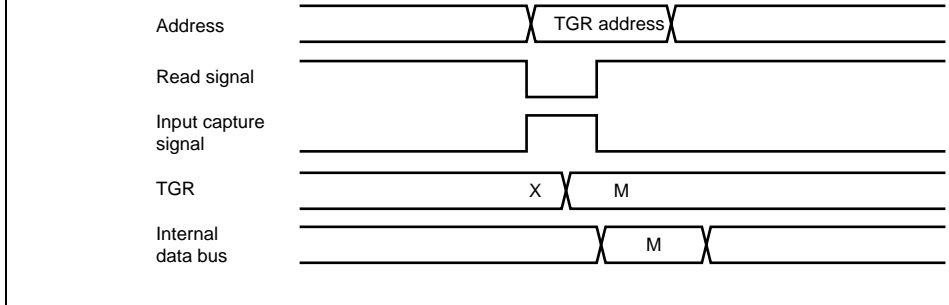


Figure 12.34 Contention between TGR Read and Input Capture

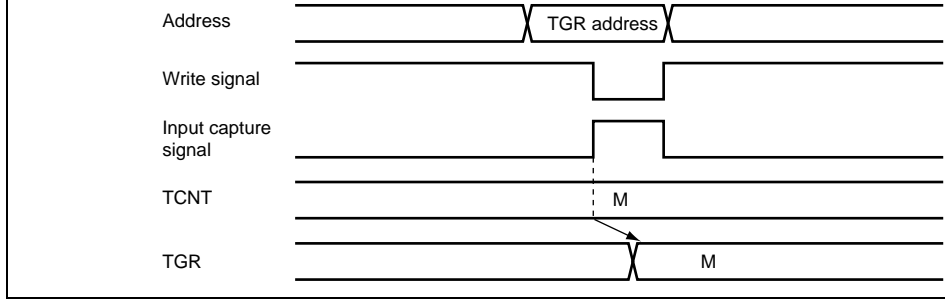


Figure 12.35 Contention between TGR Write and Input Capture

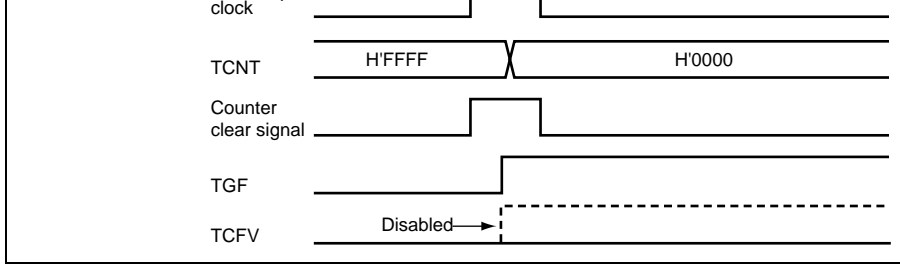


Figure 12.36 Contention between Overflow and Counter Clearing

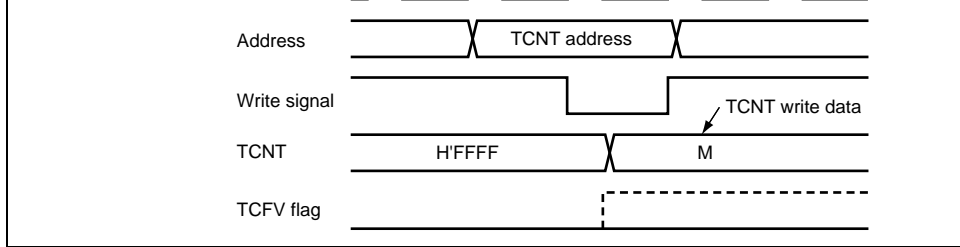


Figure 12.37 Contention between TCNT Write and Overflow

12.8.11 Multiplexing of I/O Pins

The TIOCA1 I/O pin is multiplexed with the TCLKA input pin, the TIOCB1 I/O pin with the TCLKB input pin, and the TIOCA2 I/O pin with the TCLKC input pin. When an external input, compare match output should not be performed from a multiplexed pin.

12.8.12 Interrupts when Module Standby Function is Used

If the module standby function is used when an interrupt has been requested, it will not clear the CPU interrupt source. Interrupts should therefore be disabled before using the module standby function.

clocks (ϕ) or subclocks (ϕ_{SUB}).

- Can be used as two-channel independent 8-bit event counter or single-channel independent 8-bit event counter.
- Event/clock input is enabled when IRQAEC goes high or event counter PWM output (IECPWM) goes high.
- Both edge sensing can be used for IRQAEC or event counter PWM output (IECPWM) interrupts. When the asynchronous counter is not used, they can be used as independent interrupts.
- When an event counter PWM is used, event clock input enabling/disabling can be controlled by a constant cycle.
- Selection of four clock sources
Three internal clocks ($\phi/2$, $\phi/4$, or $\phi/8$) or external event can be selected.
- Both edge counting is possible for the AEVL and AEVH pins.
- Counter resetting and halting of the count-up function can be controlled by software.
- Automatic interrupt generation on detection of an event counter overflow
- Use of module standby mode enables this module to be placed in standby mode independent of the system standby mode when not used. (For details, refer to section 6.4, Module Standby Function.)
- The IRQAEC pin can select the on-chip oscillator and the system clock oscillator during a reset, though this function does not apply to a reset by the watchdog timer. (Supported only in the masked ROM version.)

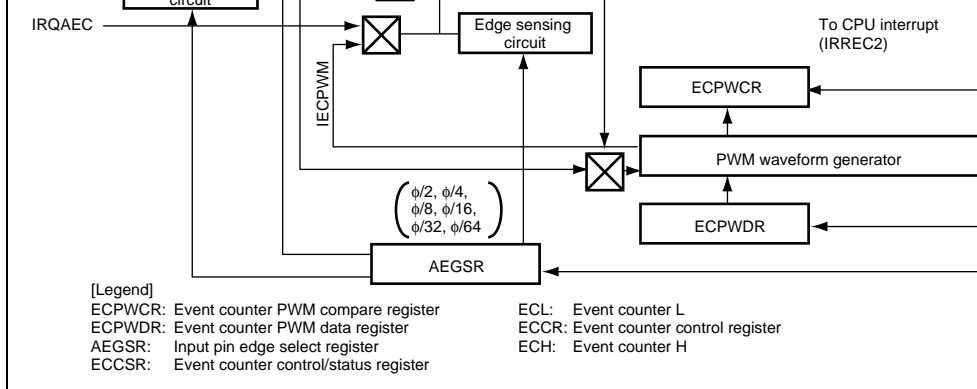


Figure 13.1 Block Diagram of Asynchronous Event Counter

13.2 Input/Output Pins

Table 13.1 shows the pin configuration of the asynchronous event counter.

Table 13.1 Pin Configuration

Name	Abbreviation	I/O	Function
Asynchronous event input H	AEVH	Input	Event input pin for input to event counter H
Asynchronous event input L	AEVL	Input	Event input pin for input to event counter L
Event input enable interrupt input	IRQAEC	Input	Input pin for interrupt enabling event input Input pin to select the on-chip oscillator system clock oscillator (supported only masked ROM version)

- Event counter L (ECL)

13.3.1 Event Counter PWM Compare Register (ECPWCR)

ECPWCR sets the one conversion period of the event counter PWM waveform.

Always read or write to this register in word size.

Bit	Bit Name	Initial Value	R/W	Description
15	ECPWCR15	1	R/W	One Conversion Period of Event Counter PWM Waveform
14	ECPWCR14	1	R/W	
13	ECPWCR13	1	R/W	When the ECPWME bit in AEGSR is 1, the event counter PWM is operating and therefore ECPWCR should not be modified.
12	ECPWCR12	1	R/W	
11	ECPWCR11	1	R/W	When changing the conversion period, the event counter PWM must be halted by clearing the ECPWME bit in AEGSR to 0 before modifying ECPWCR.
10	ECPWCR10	1	R/W	
9	ECPWCR9	1	R/W	
8	ECPWCR8	1	R/W	
7	ECPWCR7	1	R/W	
6	ECPWCR6	1	R/W	
5	ECPWCR5	1	R/W	
4	ECPWCR4	1	R/W	
3	ECPWCR3	1	R/W	
2	ECPWCR2	1	R/W	
1	ECPWCR1	1	R/W	
0	ECPWCR0	1	R/W	

12	ECPWDR12	0	W
11	ECPWDR11	0	W
10	ECPWDR10	0	W
9	ECPWDR9	0	W
8	ECPWDR8	0	W
7	ECPWDR7	0	W
6	ECPWDR6	0	W
5	ECPWDR5	0	W
4	ECPWDR4	0	W
3	ECPWDR3	0	W
2	ECPWDR2	0	W
1	ECPWDR1	0	W
0	ECPWDR0	0	W

counter PWM is operating and therefore ECPWDR should not be modified.

When changing the conversion cycle, the even PWM must be halted by clearing the ECPWME AEGSR to 0 before modifying ECPWDR.

				01: Rising edge on AEVH pin is sensed 10: Both edges on AEVH pin are sensed 11: Setting prohibited
5	ALEGS1	0	R/W	AEC Edge Select L
4	ALEGS0	0	R/W	Select rising, falling, or both edge sensing for pin. 00: Falling edge on AEVL pin is sensed 01: Rising edge on AEVL pin is sensed 10: Both edges on AEVL pin are sensed 11: Setting prohibited
3	AIEGS1	0	R/W	IRQAEC Edge Select
2	AIEGS0	0	R/W	Select rising, falling, or both edge sensing for IRQAEC pin. 00: Falling edge on IRQAEC pin is sensed 01: Rising edge on IRQAEC pin is sensed 10: Both edges on IRQAEC pin are sensed 11: Setting prohibited
1	ECPWME	0	R/W	Event Counter PWM Enable Controls operation of event counter PWM and of IRQAEC. 0: AEC PWM halted, IRQAEC selected 1: AEC PWM enabled, IRQAEC not selected
0	—	0	R/W	Reserved This bit can be read from or written to. However, it should not be set to 1.

				10: $\phi/4$ 11: $\phi/8$
5	ACKL1	0	R/W	AEC Clock Select L
4	ACKL0	0	R/W	Select the clock used by ECL. 00: AEVL pin input 01: $\phi/2$ 10: $\phi/4$ 11: $\phi/8$
3	PWCK2	0	R/W	Event Counter PWM Clock Select
2	PWCK1	0	R/W	Select the event counter PWM clock.
1	PWCK0	0	R/W	000: $\phi/2$ 001: $\phi/4$ 010: $\phi/8$ 011: $\phi/16$ 1X0: $\phi/32$ 1X1 $\phi/64$
0	—	0	R/W	Reserved This bit can be read from or written to. However should not be set to 1.

[Legend] X: Don't care.

				[Clearing condition] When this bit is written to 0 after reading OVH
6	OVL	0	R/W*	Counter Overflow L This is a status flag indicating that ECL has overflowed. [Setting condition] When ECL overflows from H'FF to H'00 while the counter value is 1. [Clearing condition] When this bit is written to 0 after reading OVL
5	—	0	R/W	Reserved Although this bit is readable/writable, it should always be set to 1.
4	CH2	0	R/W	Channel Select Selects how ECH and ECL event counters are used. 0: ECH and ECL are used together as a single 16-bit event counter 1: ECH and ECL are used as two-channel 8-bit event counters
3	CUEH	0	R/W	Count-Up Enable H Enables event clock input to ECH. 0: ECH event clock input is disabled (ECH value is retained) 1: ECH event clock input is enabled

1: ECH reset is cleared and count-up function is enabled

0	CRCL	0	R/W	Counter Reset Control L Controls resetting of ECL. 0: ECL is reset 1: ECL reset is cleared and count-up function is
---	------	---	-----	--

Note: * Only 0 can be written to clear the flag.

5	ECH5	0	R	ECH can be cleared to H'00 by clearing CRCL ESSCR to 0.
4	ECH4	0	R	
3	ECH3	0	R	
2	ECH2	0	R	
1	ECH1	0	R	
0	ECH0	0	R	

13.3.7 Event Counter L (ECL)

ECL is an 8-bit read-only up-counter that operates as an independent 8-bit event counter. It also operates as the upper 8-bit up-counter of a 16-bit event counter configured in combination with ECH.

Bit	Bit Name	Initial Value	R/W	Description
7	ECL7	0	R	Either the external asynchronous event AEVL $\phi/4$, or $\phi/8$ can be selected as the input clock source.
6	ECL6	0	R	ECL can be cleared to H'00 by clearing CRCL to 0.
5	ECL5	0	R	
4	ECL4	0	R	
3	ECL3	0	R	
2	ECL2	0	R	
1	ECL1	0	R	
0	ECL0	0	R	

Note that the input clock is enabled when REQ16C is high or IECPWM is high. When IECPWM is low or IECPWM is low, the input clock is not input to the counter, which therefore does not operate. Figure 13.2 shows the software procedure when ECH and ECL are used as a 16-bit counter.

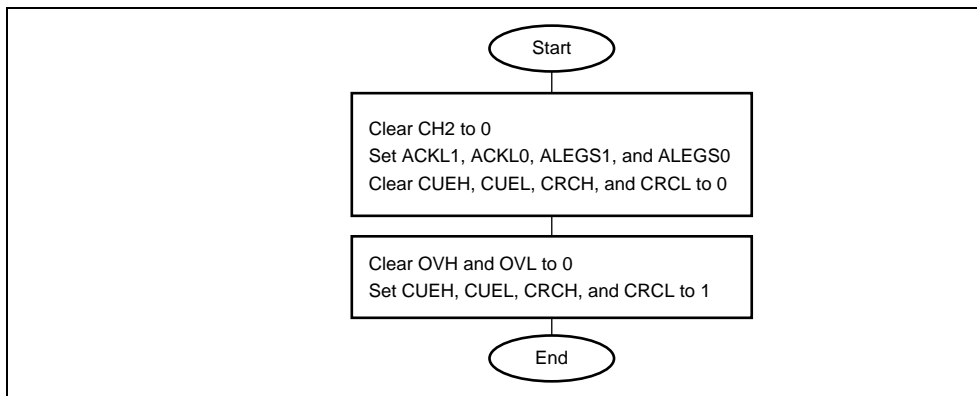


Figure 13.2 Software Procedure when Using ECH and ECL as 16-Bit Event Co

As CH2 is cleared to 0 by a reset, ECH and ECL operate as a 16-bit event counter after a reset. When ACKL1 and ACKL0 are cleared to B'00, the operating clock is asynchronous event counter clock from the AEVL pin (using falling edge sensing).

When the next clock is input after the count value reaches H'FF in both ECH and ECL, ECH and ECL overflow from H'FFFF to H'0000, the OVH flag is set to 1 in ECCSR, the ECH and ECL count values each return to H'00, and counting up is restarted. When an overflow occurs, the IRREC bit is set to 1 in IRR2. If the IENEC bit in IENR2 is 1 at this time, an interrupt request is sent to the CPU.

low or IECPWM is low, the input clock is not input to the counter, which therefore does not operate. Figure 13.3 shows the software procedure when ECH and ECL are used as 8-bit counters.

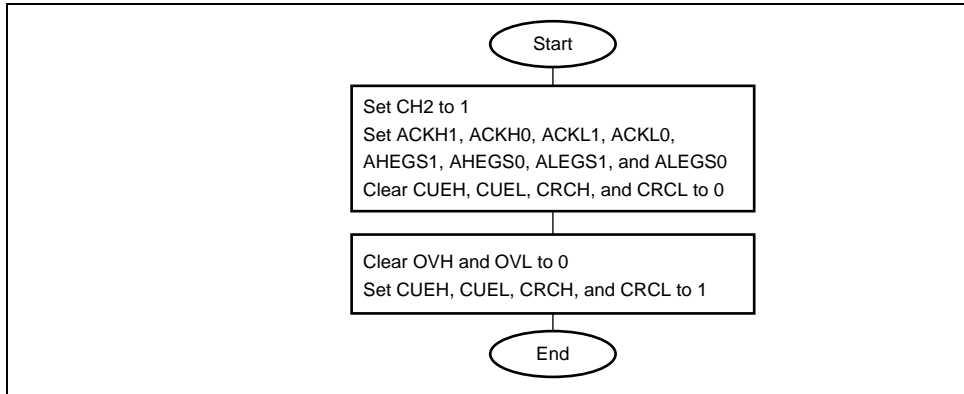


Figure 13.3 Software Procedure when Using ECH and ECL as 8-Bit Event Counters

When the next clock is input after the ECH count value reaches H'FF, ECH overflows, the OVH flag is set to 1 in ECCSR, the ECH count value returns to H'00, and counting up is restarted. Similarly, when the next clock is input after the ECL count value reaches H'FF, ECL overflows, the OVL flag is set to 1 in ECCSR, the ECL count value returns to H'00, and counting up is restarted. When an overflow occurs, the IRREC bit is set to 1 in IRR2. If the IENEC bit is 1 at this time, an interrupt request is sent to the CPU.

Rising, falling, or both edge sensing can be selected for the IRQAEC input pin with bits α and AIAGS0 in AEGSR.

13.4.4 Event Counter PWM Operation

When the ECPWME bit in AEGSR is 1, the ECH and ECL input clocks are enabled when counter PWM output (IECPWM) is high. When IECPWM is low, the input clocks are not enabled for the counters, and so ECH and ECL do not count. ECH and ECL count operations can then be controlled cyclically from outside by controlling event counter PWM. In this case, ECH and ECL cannot be controlled individually.

IECPWM can also operate as an interrupt source.

Interrupt enabling is controlled by IENEC2 in IENR1. When an IECPWM interrupt is generated, the IRR1 interrupt request flag IRREC2 is set to 1. If IENEC2 in IENR1 is set to 1 at this time, an interrupt request is sent to the CPU.

Rising, falling, or both edge detection can be selected for IECPWM interrupt sensing with bits AIAGS1 and AIAGS0 in AEGSR.

Figure 13.4 and table 13.2 show examples of event counter PWM operation.

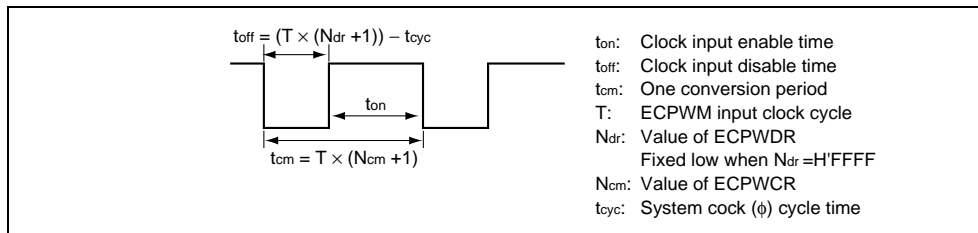


Figure 13.4 Event Counter Operation Waveform

$\phi/4$	1 μs	D'31249	D'5859	5.85975 ms	31.25 ms	25.3
$\phi/8$	2 μs			11.71975 ms	62.5 ms	50.7
$\phi/16$	4 μs			23.43975 ms	125.0 ms	101.
$\phi/32$	8 μs			46.87975 ms	250.0 ms	203.
$\phi/64$	16 μs			93.75975 ms	500.0 ms	406.

Note: * toff minimum width

13.4.5 Operation of Clock Input Enable/Disable Function

The clock input to the event counter can be controlled by the IRQAEC pin when ECPWME in AEGSR is 0, and by the event counter PWM output, IIECPWM when ECPWME in AEGSR is 1. As this function forcibly terminates the clock input by each signal, a maximum error of one clock period will occur depending on the IRQAEC or IIECPWM timing. Figure 13.5 shows an example of this operation.

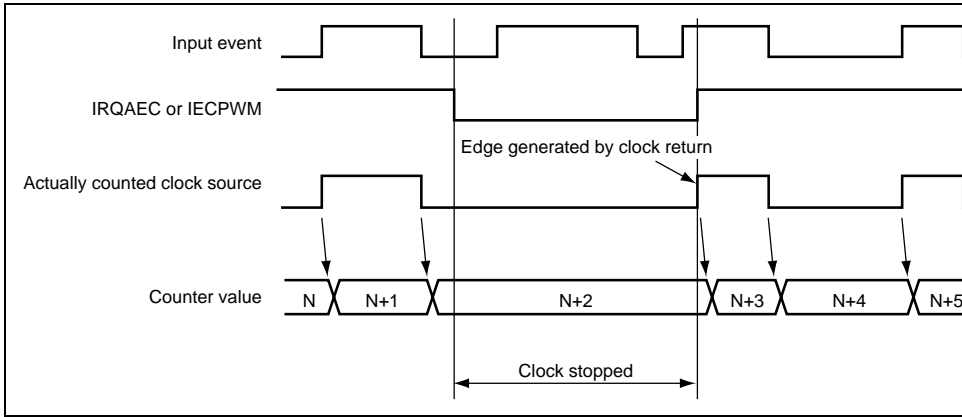


Figure 13.5 Example of Clock Control Operation

ECH	Reset	Functions	Functions	Functions* ¹ * ²	Functions* ²	Functions* ²	Functions* ¹ * ²
ECL	Reset	Functions	Functions	Functions* ¹ * ²	Functions ²	Functions* ²	Functions* ¹ * ²
IRQAEC	Reset	Functions	Functions	Retained* ³	Functions	Functions	Retained* ³
Event counter PWM	Reset	Functions	Functions	Retained	Retained	Retained	Retained

- Notes:
1. When an asynchronous external event is input, the counter increments. However, an interrupt request is issued when the counter overflows.
 2. Functions when asynchronous external events are selected; halted and retained otherwise.
 3. Clock control by IRQAEC operates, but interrupts do not.
 4. As the clock is stopped in module standby mode, IRQAEC has no effect.

Table 13.4 shows a maximum clock frequency.

Table 13.4 Maximum Clock Frequency

Mode		Maximum Clock Frequency Input to AEVH/AEVL
Active (high-speed), sleep (high-speed)		10 MHz
Active (medium-speed), sleep (medium-speed)	$(\phi_{osc}/8)$	$2 \cdot f_{osc}$
	$(\phi_{osc}/16)$	f_{osc}
	$(\phi_{osc}/32)$	$1/2 \cdot f_{osc}$
	$(\phi_{osc}/64)$	$1/4 \cdot f_{osc}$
Watch, subactive, subsleep, standby	$(\phi_w/2)$	1000 kHz
	$(\phi_w/4)$	500 kHz
$\phi_w = 32.768 \text{ kHz or } 38.4 \text{ kHz}$	$(\phi_w/8)$	250 kHz

- When AEC uses with 16-bit mode, set CUEH in ECCSR to 1 first, set CRCH in ECCR to 1 second, or set both CUEH and CRCH to 1 at same time before clock input. When AEC is operating on 16-bit mode, do not change CUEH. Otherwise, ECH will be miscounted.
- When ECPWME in AEGSR is 1, the event counter PWM is operating and therefore ECH and ECPWDR should not be modified.
When changing the data, clear the ECPWME bit in AEGSR to 0 (halt the event counter) before modifying these registers.
- The event counter PWM data register and event counter PWM compare register must satisfy that event counter PWM data register < event counter PWM compare register. If they do not satisfy this condition, do not set ECPWME to 1 in AEGSR.

The WDT features are described below.

- Selectable from nine counter input clocks
Eight internal clock sources ($\phi/64$, $\phi/128$, $\phi/256$, $\phi/512$, $\phi/1024$, $\phi/2048$, $\phi/4096$, and $\phi/8192$) or the WDT on-chip oscillator can be selected as the timer-counter clock.
- Watchdog timer mode
If the counter overflows, this LSI is internally reset.
- Interval timer mode
If the counter overflows, an interval timer interrupt is generated.
- Use of module standby mode enables this module to be placed in standby mode independent of the LSI when not used. (For details, refer to section 6.4, Module Standby Function.)

Figure 14.1 shows a block diagram of the WDT.

TCSRWD2: Timer control/status register WD2
TCWD: Timer counter WD
TMWD: Timer mode register WD
PSS: Prescaler S

Interrupt reques

Figure 14.1 Block Diagram of Watchdog Timer

14.2 Register Descriptions

The watchdog timer has the following registers.

- Timer control/status register WD1 (TCSRWD1)
- Timer control/status register WD2 (TCSRWD2)
- Timer counter WD (TCWD)
- Timer mode register WD (TMWD)

				This bit is always read as 1.
6	TCWE	0	R/W	<p>Timer Counter WD Write Enable</p> <p>TCWD can be written when the TCWE bit is set to 1.</p> <p>When writing data to this bit, the write value for TCWD must be 0.</p>
5	B4WI	1	R/W	<p>Bit 4 Write Inhibit</p> <p>The TCSRWE bit can be written only when the value of the B4WI bit is 0. This bit is always read as 1.</p>
4	TCSRWE	0	R/W	<p>Timer Control/Status Register WD Write Enable</p> <p>The WDON and WRST bits can be written when the TCSRWE bit is set to 1.</p> <p>When writing data to this bit, the write value for TCSRWE must be 0.</p>
3	B2WI	1	R/W	<p>Bit 2 Write Inhibit</p> <p>The WDON bit can be written only when the value of the B2WI bit is 0. This bit is always read as 1.</p>

- When 0 is written to the WDON bit and 0 to the B2WI bit while the TCSRWE bit is 1

1	B0WI	1	R/W	Bit 0 Write Inhibit The WRST bit can be written only when the value of the B0WI bit is 0. This bit is always read as 1
0	WRST	0	R/W	Watchdog Timer Reset [Setting condition] When TCWD overflows and an internal reset signal is generated [Clearing conditions] <ul style="list-style-type: none"> • Reset by \overline{RES} pin • When 0 is written to the WRST bit and 0 to the B0WI bit while the TCSRWE bit is 1

Note: * When transitioning to the watch mode or standby mode while the main internal clock source is selected (CKS3 = 1) using timer mode register WD (TMWD), make sure to clear WRST to 0 to halt operation of TCWD.

[Setting condition]
 When TCWD overflows (changes from H'FF to H'00), the bit is set.
 When internal reset request generation is selected in watchdog timer mode, this bit is cleared automatically by the internal reset after it has been set.
 [Clearing condition]

- When TCSRWD2 is read when OVF = 1, the bit is written to OVF*⁴

6	B5WI	1	R/(W)* ²	Bit 5 Write Inhibit The WT/ $\overline{\text{IT}}$ bit can be written only when the value of the B5WI bit is 0. This bit is always read as 0.
5	WT/ $\overline{\text{IT}}$	0	R/(W)* ³	Timer Mode Select Selects whether the WDT is used as a watchdog timer or interval timer. 0: Watchdog timer mode 1: Interval timer mode
4	B3WI	1	R/(W)* ²	Bit 3 Write Inhibit The IEOVF bit can be written only when the value of the B3WI bit is 0. This bit is always read as 0.
3	IEOVF	0	R/(W)* ³	Overflow Interrupt Enable Enables or disables an overflow interrupt request when the interval timer mode is selected. 0: Disables an overflow interrupt 1: Enables an overflow interrupt

Bit	Bit Name	Value	R/W	Description
7 to 4	—	All 1	—	Reserved These bits are always read as 1.
3	CKS3	1	R/W	Clock Select 3 to 0
2	CKS2	1	R/W	Select the clock to be input to TCWD.
1	CKS1	1	R/W	1000: Internal clock: counts on $\phi/64$
0	CKS0	1	R/W	1001: Internal clock: counts on $\phi/128$ 1010: Internal clock: counts on $\phi/256$ 1011: Internal clock: counts on $\phi/512$ 1100: Internal clock: counts on $\phi/1024$ 1101: Internal clock: counts on $\phi/2048$ 1110: Internal clock: counts on $\phi/4096$ 1111: Internal clock: counts on $\phi/8192$ 0XXX: WDT on-chip oscillator For the WDT on-chip oscillator overflow period, see section 24, Electrical Characteristics. In active (medium-speed) mode or sleep (medium-speed) mode, the setting of B'0XXX and internal clock mode is disabled.

[Legend] X: Don't care.

reset signal is output for a period of $256 \phi_{osc}$ clock cycles. TCWD is a writable counter, and its value is set in TCWD, the count-up starts from that value. An overflow period in the range of 256 input clock cycles can therefore be set, according to the TCWD set value.

Figure 14.2 shows an example of watchdog timer operation.

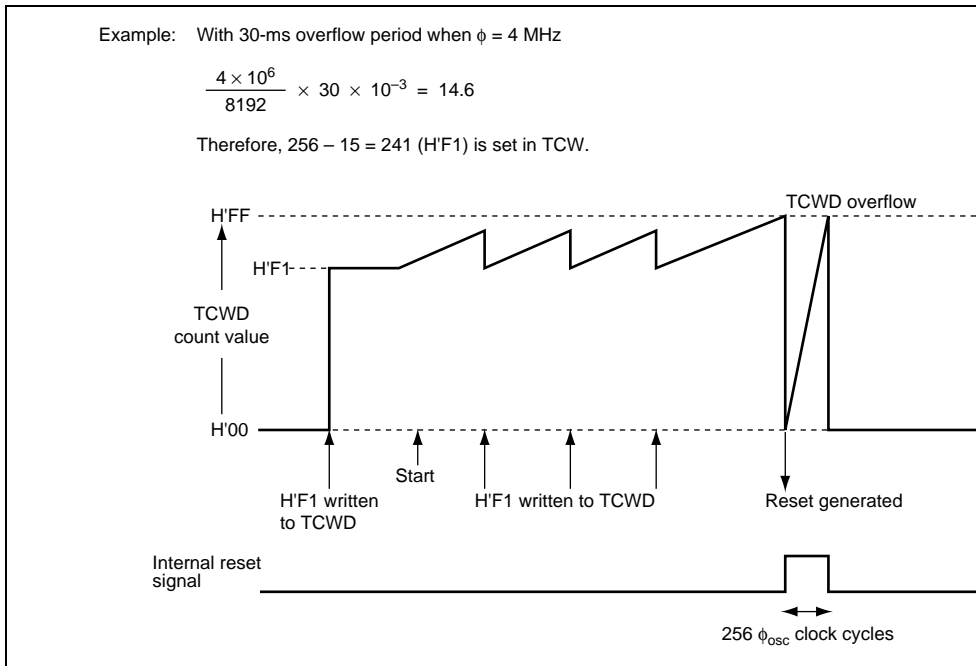


Figure 14.2 Example of Watchdog Timer Operation

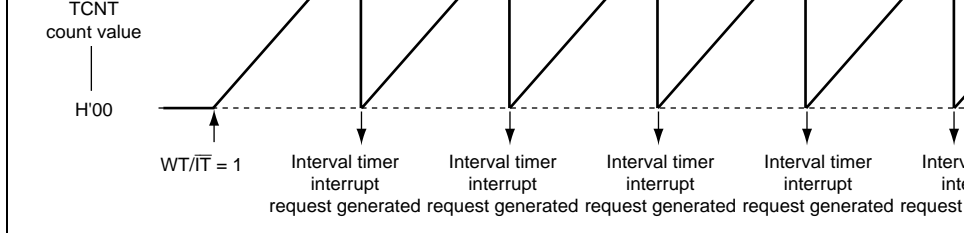


Figure 14.3 Interval Timer Mode Operation

14.3.3 Timing of Overflow Flag (OVF) Setting

Figure 14.4 shows the timing of the OVF flag setting. The OVF flag in TCSRWD2 is set when TCNT overflows. At the same time, a reset signal is output in watchdog timer mode and an interval timer interrupt is generated in interval timer mode.

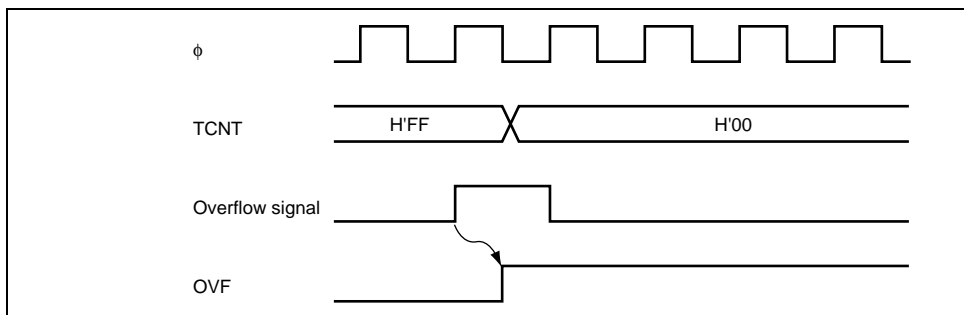


Figure 14.4 Timing of OVF Flag Setting

If the mode is switched between watchdog timer and interval timer, while the WDT is operating, errors could occur in the incrementation. Software must stop the watchdog timer (by clearing the WDON bit to 0) before switching the mode.

14.5.2 Module Standby Mode Control

The WDCKSTP bit in CKSTPR2 is valid when the WDON bit in the timer control/status register 1 (TCSRWD1) is cleared to 0. The WDCKSTP bit can be cleared to 0 while the WDON bit is set to 1 (while the watchdog timer is operating). However, the watchdog timer does not enter standby mode but continues operating. When the WDON bit is cleared to 0 by software and the watchdog timer stops operating, the WDCKSTP bit is valid at the same time and the watchdog timer enters module standby mode.

15.1 Features

- Choice of asynchronous or clocked synchronous serial communication mode
- Full-duplex communication capability

The transmitter and receiver are mutually independent, enabling transmission and reception to be executed simultaneously.

Double-buffering is used in both the transmitter and the receiver, enabling continuous transmission and continuous reception of serial data.

- On-chip baud rate generator allows any bit rate to be selected
- On-chip baud rate generator, internal clock, or external clock can be selected as a transmission clock source.
- Six interrupt sources
Transmit-end, transmit-data-empty, receive-data-full, overrun error, framing error, and parity error.
- Use of module standby mode enables this module to be placed in standby mode independently when not used. (For details, refer to section 6.4, Module Standby Function.)

Asynchronous mode

- Data length: 7, 8, or 5 bits
- Stop bit length: 1 or 2 bits
- Parity: Even, odd, or none
- Receive error detection: Parity, overrun, and framing errors
- Break detection: Break can be detected by reading the RXD32 pin level directly in the case of a framing error

Note: When using serial communication interface 3 in the masked ROM version, do not use the on-chip oscillator.

			TDR3_1	H'FF9B
			SSR3_1	H'FF9C
			RDR3_1	H'FF9D
			RSR3_1	—
			TSR3_1	—
			IrCR	H'FFA7
Channel 2	SCI3_2	SCK32	SMR3_2	H'FFA8
		RXD32	BRR3_2	H'FFA9
		TXD32	SCR3_2	H'FFAA
			TDR3_2	H'FFAB
			SSR3_2	H'FFAC
			RDR3_2	H'FFAD
			RSR3_2	—
			TSR3_2	—

- Notes: 1. Pin names SCK3, RXD3, and TXD3 are used in the text for all channels, omitting channel designation.
2. In the text, channel description is omitted for registers and bits.

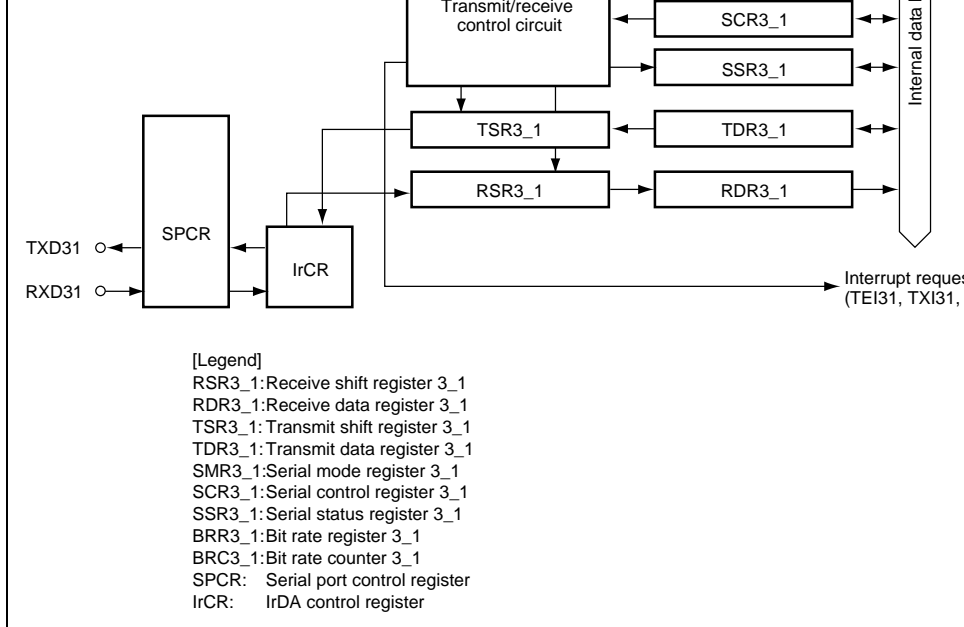


Figure 15.1 (1) Block Diagram of SCI3_1

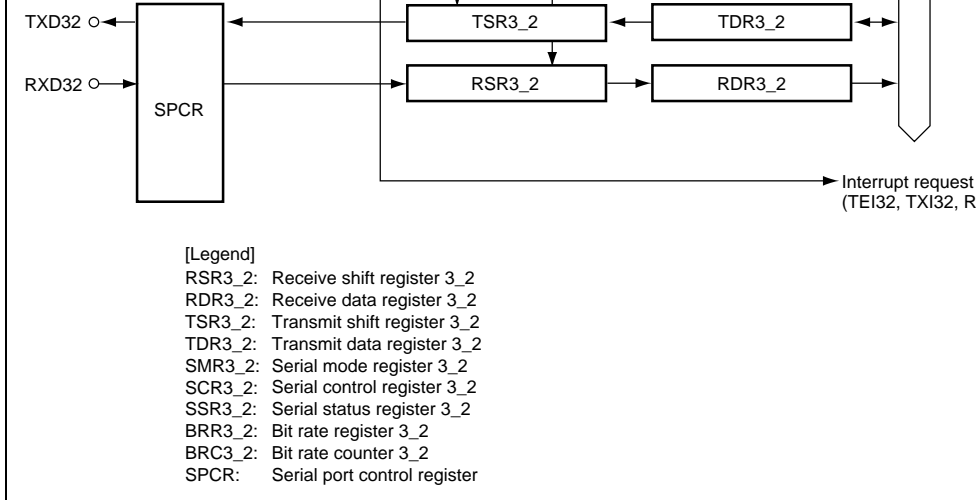


Figure 15.1 (2) Block Diagram of SCI3_2

input	RXD32		
SCI3 transmit data output	TXD31, TXD32	Output	SCI3 transmit data output

15.3 Register Descriptions

The SCI3 has the following registers for each channel.

- Receive shift register 3 (RSR3)*
- Receive data register 3 (RDR3)*
- Transmit shift register 3 (TSR3)*
- Transmit data register 3 (TDR3)*
- Serial mode register 3 (SMR3)*
- Serial control register 3 (SCR3)*
- Serial status register 3 (SSR3)*
- Bit rate register 3 (BRR3)*
- Serial port control register (SPCR)
- IrDA control register (IrCR)

Note: * These register names are abbreviated to RSR, RDR, TSR, TDR, SMR, SCR, BRR in the text.

receive-enabled. As RSR and RDR function as a double buffer in this way, continuous receive operations are possible. After confirming that the RDRF bit in SSR is set to 1, read RDR once. RDR cannot be written to by the CPU. RDR is initialized to H'00.

RDR is initialized to H'00 by a reset or in standby mode, watch mode, or module standby mode.

15.3.3 Transmit Shift Register (TSR)

TSR is a shift register that transmits serial data. To perform serial data transmission, the SCI3 transfers transmit data from TDR to TSR automatically, then sends the data that starts from the LSB to the TXD31 or TXD32 pin. Data transfer from TDR to TSR is not performed if no data has been written to TDR (if the TDRE bit in SSR is set to 1). TSR cannot be directly accessed by the CPU.

15.3.4 Transmit Data Register (TDR)

TDR is an 8-bit register that stores data for transmission. When the SCI3 detects that TSR is empty, it transfers the transmit data written in TDR to TSR and starts transmission. The double-buffered structure of TDR and TSR enables continuous serial transmission. If the next transmit data has already been written to TDR during transmission of one-frame data, the SCI3 transfers the written data to TSR to continue transmission. To achieve reliable serial transmission, write transmit data to TDR only once after confirming that the TDRE bit in SSR is set to 1. TDR is initialized to H'FF.

TDR is initialized to H'FF by a reset or in standby mode, watch mode, or module standby mode.

				1: Clocked synchronous mode
6	CHR	0	R/W	<p>Character Length (enabled only in asynchronous mode)</p> <p>0: Selects 8 or 5 bits as the data length.</p> <p>1: Selects 7 or 5 bits as the data length.</p> <p>When 7-bit data is selected, the MSB (bit 7) is not transmitted. To select 5 bits as the data length, set 1 to both the PE and MP bits. The three most significant bits (bits 7, 6, and 5) in TDR are not transmitted. In clocked synchronous mode, the character length is fixed to 8 bits regardless of the CHR bit setting.</p>
5	PE	0	R/W	<p>Parity Enable (enabled only in asynchronous mode)</p> <p>When this bit is set to 1, the parity bit is added to the transmit data before transmission, and the parity is checked in reception. In clocked synchronous mode, parity bit addition and checking is not performed regardless of the PE bit setting.</p>

an even number.

When odd parity is selected, a parity bit is added to the transmission so that the total number of 1 bits in the transmitted data plus the parity bit is an odd number. At reception, a check is carried out to confirm that the number of 1 bits in the received data plus the parity bit is an odd number.

If parity bit addition and checking is disabled in synchronous mode and asynchronous mode, the parity bit setting is invalid.

3	STOP	0	R/W	<p>Stop Bit Length (enabled only in asynchronous mode)</p> <p>Selects the stop bit length in transmission.</p> <p>0: 1 stop bit 1: 2 stop bits</p> <p>For reception, only the first stop bit is checked, regardless of the value in the bit. If the second stop bit is 0, it is treated as the start bit of the next transmitted character.</p>
2	MP	0	R/W	<p>5-Bit Communication</p> <p>When this bit is set to 1, the 5-bit communication format is enabled. When writing 1 to this bit, also write 1 to bit 5 (RE) at the same time. In addition, 0 must be written to bit 3 (MPIE) in the serial control register (SCR) before writing 1 to this bit.</p>

speed/high-speed) mode and sleep (medium-speed/high-speed) mode $\phi_w/2$ clock is set. In mode and subsleep mode, ϕ_w clock is set. The enabled only, when $\phi_w/2$ is selected for the C operating clock.

For the relationship between the bit rate register and the baud rate, see section 15.3.8, Bit Rate Register (BRR). n is the decimal representation of n in BRR (see section 15.3.8, Bit Rate Register (BRR)).

request is enabled. TXI (TXI32) can be released by clearing the TDRE bit or TI bit to 0.

6	RIE	0	R/W	<p>Receive Interrupt Enable</p> <p>When this bit is set to 1, RXI and ERI interrupts are enabled.</p> <p>RXI (RXI32) and ERI (ERI32) can be released by clearing the RDRF bit or the FER, PER, or OER flag to 0, or by clearing the RIE bit to 0.</p>
5	TE	0	R/W	<p>Transmit Enable</p> <p>When this bit is set to 1, transmission is enabled. When this bit is 0, the TDRE bit in SSR is fixed at 1. When transmit data is written to TDR while this bit is 1, TDRE in SSR is cleared to 0 and serial data transmission is started. Be sure to carry out SMR settings, and setting of bit SPC31 or SPC32 in advance to decide the transmission format before setting this bit to 1.</p>
4	RE	0	R/W	<p>Receive Enable</p> <p>When this bit is set to 1, reception is enabled. In the idle state, serial data reception is started when a start bit is detected in asynchronous mode or serial clock is detected in clocked synchronous mode. Be sure to carry out the SMR settings to decide the reception format before setting bit RE to 1.</p> <p>Note that the RDRF, FER, PER, and OER flags are not affected when bit RE is cleared to 0, and they remain in their previous state.</p>

Asynchronous mode.

00: Internal baud rate generator (SCK31 or SCK32 pin functions as an I/O port)

01: Internal baud rate generator (Outputs a clock with the same frequency as the bit rate from the SCK31 or SCK32 pin)

10: External clock (Inputs a clock with a frequency that is 2 times the bit rate from the SCK31 or SCK32 pin)

11: Reserved

Clocked synchronous mode:

00: Internal clock (SCK31 or SCK32 pin functions as a clock output)

01: Reserved

10: External clock (SCK31 or SCK32 pin functions as a clock input)

11: Reserved

[Setting conditions]

- When the TE bit in SCR is 0
- When data is transferred from TDR to TSR

[Clearing conditions]

- When 0 is written to TDRE after reading TD
- When the transmit data is written to TDR

6	RDRF	0	R/(W)*	Receive Data Register Full
---	------	---	--------	----------------------------

Indicates that the received data is stored in RDR.

[Setting condition]

- When serial reception ends normally and received data is transferred from RSR to RDR

[Clearing conditions]

- When 0 is written to RDRF after reading RDR

When data is read from RDR

If an error is detected in reception, or if the REACK bit in SCR has been cleared to 0, RDR and bit RDRF are not affected and retain their previous state.

Note that if data reception is completed while bit RDRF is still set to 1, an overrun error (OER) will occur and the receive data will be lost.

data it held before the overrun error occurred. Reception cannot be continued after the error is lost. Reception cannot be continued with bit OER set to 1, and in clocked synchronous mode, transmission cannot be continued either.

4	FER	0	R/(W)*	<p>Framing Error</p> <p>[Setting condition]</p> <ul style="list-style-type: none">When a framing error occurs in reception <p>[Clearing condition]</p> <ul style="list-style-type: none">When 0 is written to FER after reading FER <p>When bit RE in SCR is cleared to 0, bit FER is not affected and retains its previous state.</p> <p>Note that, in 2-stop-bit mode, only the first stop bit is checked for a value of 1, and the second stop bit is not checked. When a framing error occurs, the received data is transferred to RDR but bit RDRF is not set. Reception cannot be continued with bit FER set to 1. In clocked synchronous mode, neither transmission nor reception is possible when bit FER is set to 1.</p>
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still transferred to RDR, but bit RDRF is not set. Reception cannot be continued with bit PER = 1. In clocked synchronous mode, neither transmission nor reception is possible when PER is set to 1.

2	TEND	1	R	<p>Transmit End</p> <p>[Setting conditions]</p> <ul style="list-style-type: none"> • When the TE bit in SCR is 0 • When TDRE = 1 at transmission of the last 1-byte serial transmit character <p>[Clearing conditions]</p> <ul style="list-style-type: none"> • When 0 is written to TDRE after reading TDR • When the transmit data is written to TDR
1	MPBR	0	R	<p>Reserved</p> <p>This bit is read-only and reserved. It cannot be written to.</p>
0	MPBT	0	R/W	<p>Reserved</p> <p>The write value should always be 0.</p>

Note: * Only 0 can be written to clear the flag.

[Asynchronous Mode]

Active (medium-speed/high-speed) or sleep (medium-speed/high-speed)

$$N = \frac{\text{OSC}}{32 \times 2^{2n} \times B} - 1$$

$$\text{Error (\%)} = \frac{B \text{ (bit rate obtained from } n, N, \phi) - R \text{ (bit rate in left-hand column in table 15.3)}}{R \text{ (bit rate in left-hand column in table 15.3)}}$$

Subactive or subsleep

$$N = \frac{\text{OSC}}{64 \times 2^{2n} \times B} - 1$$

[Legend] B: Bit rate (bit/s)

N: BRR setting for baud rate generator ($0 \leq N \leq 255$)

OSC: ϕ_{osc} value (Hz)

n: Baud rate generator input clock number ($n = 0, 2, \text{ or } 3$)

(The relation between n and the clock is shown in table 15.3)

600	—	—	—	0	0	0.00	0	103	0.16	0	108
1200	—	—	—	—	—	—	0	51	0.16	0	54
2400	—	—	—	—	—	—	0	25	0.16	0	26
4800	—	—	—	—	—	—	0	12	0.16	0	13
9600	—	—	—	—	—	—	—	—	—	0	6
19200	—	—	—	—	—	—	—	—	—	—	—
31250	—	—	—	—	—	—	0	1	0.00	—	—
38400	—	—	—	—	—	—	—	—	—	—	—

600	3	1	0.00	0	155	0.16	3	2	0.00	0	207
1200	3	0	0.00	0	77	0.16	2	5	0.00	0	103
2400	2	1	0.00	0	38	0.16	2	2	0.00	0	51
4800	2	0	0.00	0	19	-2.34	0	23	0.00	0	25
9600	0	7	0.00	0	9	-2.34	0	11	0.00	0	12
19200	0	3	0.00	0	4	-2.34	0	5	0.00	—	—
31250	—	—	—	0	2	0.00	—	—	—	0	3
38400	0	1	0.00	—	—	—	0	2	0.00	—	—

600	3	3	0.00	0	255	1.73	3	4	-2.34	3	4
1200	3	1	0.00	0	129	0.16	0	155	0.16	2	9
2400	3	0	0.00	0	64	0.16	0	77	0.16	2	4
4800	2	1	0.00	0	32	-1.36	0	38	0.16	0	39
9600	2	0	0.00	2	0	1.73	0	19	-2.34	0	19
19200	0	7	0.00	0	7	1.73	0	9	-2.34	0	9
31250	0	4	-1.70	0	4	0.00	0	5	0.00	0	5
38400	0	3	0.00	0	3	1.73	0	4	-2.34	0	4

600	3	5	0.00	2	25	0.16	3	7	0.00	2	32
1200	3	2	0.00	2	12	0.16	3	3	0.00	2	15
2400	2	5	0.00	0	103	0.16	3	1	0.00	0	129
4800	2	2	0.00	0	51	0.16	3	0	0.00	0	64
9600	0	23	0.00	0	25	0.16	2	1	0.00	0	32
19200	0	11	0.00	0	12	0.16	2	0	0.00	0	15
31250	—	—	—	0	7	0.00	0	9	-1.70	0	9
38400	0	5	0.00	—	—	—	0	7	0.00	0	7

Table 15.4 Relation between n and Clock

n	Clock	SMR Setting	
		CKS1	CKS0
0	ϕ	0	0
0	$\phi_W/2^{*1}/\phi_W^{*2}$	0	1
2	$\phi/16$	1	0
3	$\phi/64$	1	1

Notes: 1. $\phi_W/2$ clock in active (medium-speed/high-speed) mode and sleep (medium-speed) mode

2. ϕ_W clock in subactive mode and subsleep mode

In subactive or subsleep mode, the SCI3 can be operated only when CPU cl

3.6864	115200	0	0
4	125000	0	0
4.9152	153595	0	0
5	156250	0	0
6	187500	0	0
6.144	192000	0	0
7.3728	230400	0	0
8	250000	0	0
9.8304	307200	0	0
10	312500	0	0

Note: * When CKS1 = 0 and CKS0 = 1 in SMR

2.5k	—	—	—	—	—	—	0	199	0.0
5k	—	—	—	—	—	—	0	99	0.0
10k	—	—	—	—	—	—	0	49	0.0
25k	—	—	—	—	—	—	0	19	0.0
50k	—	—	—	—	—	—	0	9	0.0
100k	—	—	—	—	—	—	0	4	0.0
250k	—	—	—	—	—	—	0	1	0.0
500k	—	—	—	—	—	—	0*	0*	0.0
1M	—	—	—	—	—	—	—	—	—

Note: * Continuous transmission/reception is not possible.

2.5k	2	24	0.00	2	49	0.00	2	62	-0.7
5k	0	199	0.00	2	24	0.00	2	30	0.8
10k	0	99	0.00	0	199	0.00	2	15	-2.3
25k	0	39	0.00	0	79	0.00	0	99	0.0
50k	0	19	0.00	0	39	0.00	0	49	0.0
100k	0	9	0.00	0	19	0.00	0	24	0.0
250k	0	3	0.00	0	7	0.00	0	9	0.0
500k	0	1	0.00	0	3	0.00	0	4	0.0
1M	0*	0*	0.00*	0	1	0.00	—	—	—

Note: * Continuous transmission/reception is not possible.

The value set in BRR is given by the following formula:

Active (medium-speed/high-speed) or sleep (medium-speed/high-speed)

$$N = \frac{\text{OSC}}{4 \times 2^{2n} \times B} - 1$$

Subactive or subsleep

$$N = \frac{\text{OSC}}{8 \times 2^{2n} \times B} - 1$$

B: Bit rate (bit/s)

N: BRR setting for baud rate generator ($0 \leq N \leq 255$)

OSC: ϕ_{osc} value (Hz)

n: Baud rate generator input clock number ($n = 0, 2, \text{ or } 3$)

(The relation between n and the clock is shown in table 15.7.)

2. ϕ_w clock in subactive or subsleep mode

In subactive or subsleep mode, the SCI3_1 and SCI3_2 can be operated only if the CPU clock is $\phi_w/2$.

15.3.9 Serial Port Control Register (SPCR)

SPCR selects the functions of the TXD32 and TXD31 pins.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Reserved
6	—	1	—	These bits are always read as 1 and cannot be modified.
5	SPC32	0	R/W	P32/TXD33 Pin Function Switch Selects whether pin P32/TXD32 is used as P32 or TXD32. 0: P32 I/O pin 1: TXD32 output pin Set the TE32 bit in SCR32 after setting this bit to 1.
4	SPC31	0	R/W	P42/TXD31 Pin Function Switch Selects whether pin P42/TXD31 is used as P42 or TXD31. 0: P42 I/O pin 1: TXD31 output pin Set the TE bit in SCR after setting this bit to 1.

				0: Output data of RXD32 pin is not inverted. 1: Output data of RXD32 pin is inverted.
1	SCINV1	0	R/W	TXD31 Pin Output Data Inversion Switch Selects whether the polarity of output data of the TXD31 pin is inverted or not. 0: Output data of TXD31 pin is not inverted. 1: Output data of TXD31 pin is inverted.
0	SCINV0	0	R/W	RXD31 Pin Input Data Inversion Switch Selects whether the polarity of input data of the pin is inverted or not. 0: Input data of RXD31 pin is not inverted. 1: Input data of RXD31 pin is inverted.

Note: When the serial port control register is modified, the data being input or output up to that point is inverted immediately after the modification, and an invalid data change is in output. When modifying the serial port control register, modification must be made in which data changes are invalidated.

6	IrCKS2	0	R/W	IrDA Clock Select
5	IrCKS1	0	R/W	If the IrDA function is enabled, these bits set the pulse width when encoding the IrTXD output
4	IrCKS0	0	R/W	000: Bit rate $\times 3/16$ 001: $\phi/2$ 010: $\phi/4$ 011: $\phi/8$ 100: $\phi/16$ 101: Setting prohibited 11x: Setting prohibited
3 to 0	—	0	—	Reserved These bits are always read as 0 and cannot be modified.

[Legend] x: Don't care.

transfer formats that can be set in asynchronous mode. The format is selected by the setting of SMR as shown in table 15.9.

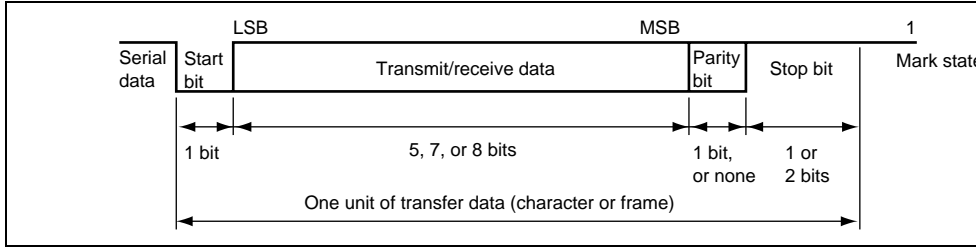


Figure 15.2 Data Format in Asynchronous Communication

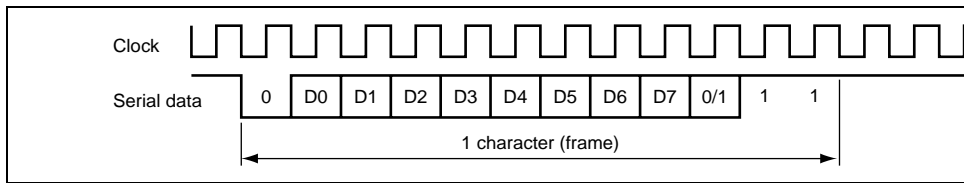
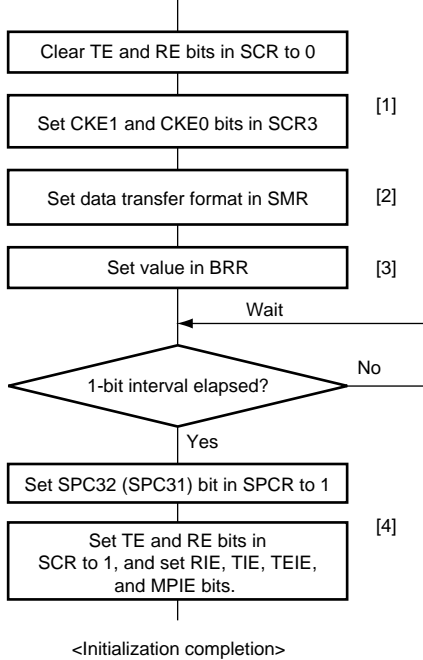


Figure 15.3 Relationship between Output Clock and Transfer Data Phase (Asynchronous Mode) (Example with 8-Bit Data, Parity, Two Stop Bits)

				1					
			1	0					Yes
				1					
0	1	0	0	0				Setting prohibited	
				1					
			1	0				5-bit data	No
				1					
1		0	0	0				Setting prohibited	
				1					
			1	0				5-bit data	Yes
				1					
1	*	0	*	*		Clocked synchronous mode	8-bit data		No

[Legend] *: Don't care.

1	0	0	Clocked synchronous mode	Internal	Outputs serial clock
	1	0		External	Inputs serial clock
0	1	1	Reserved (Do not specify these combinations)		
1	0	1			
1	1	1			



When the clock output is selected in asynchronous mode, clock is output immediately after CKE1 and CKE0 settings are made. When the clock output is selected at reception in clocked synchronous mode, clock is output immediately after CKE1, CKE0, and RE are set to 1.

[2] Set the data transfer format in SMR.

[3] Write a value corresponding to the bit rate to BRR. Not necessary if an external clock is used.

[4] Wait at least one bit interval, then set the TE bit or RE bit in SCR to 1. Setting bits TE and RE enables the TXD31 (TXD32) and RXD31 (RXD32) pins to be used. Also set the RIE, TIE, and TEIE bits, depending on whether interrupts are required. In asynchronous mode, the bits are marked at transmission and idled at reception to wait for the start bit.

Figure 15.4 Sample SCI3 Initialization Flowchart

writes next transmit data to TDR before transmission of the current transmit data has completed.

3. The SCI3 checks the TDRE flag at the timing for sending the stop bit.
4. If the TDRE flag is 0, the data is transferred from TDR to TSR, the stop bit is sent, and serial transmission of the next frame is started.
5. If the TDRE flag is 1, the TEND flag in SSR is set to 1, the stop bit is sent, and then the state "idle" is entered, in which 1 is output. If the TEIE bit in SCR is set to 1 at this time, an interrupt request is generated.
6. Figure 15.6 shows a sample flowchart for transmission in asynchronous mode.

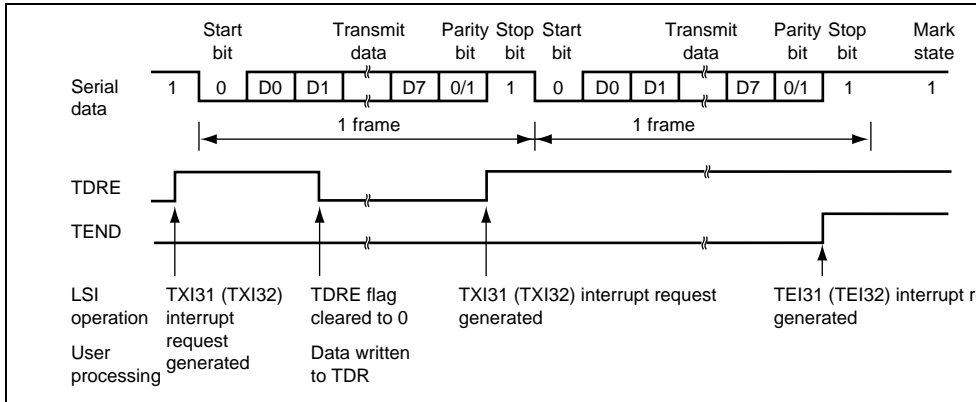
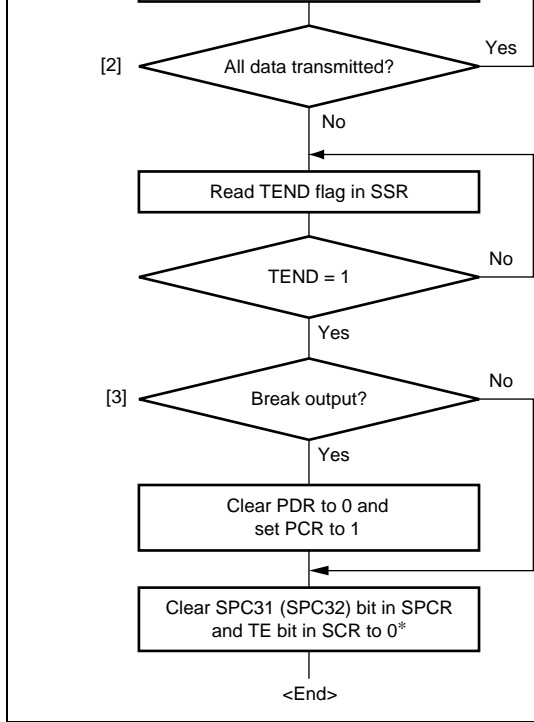


Figure 15.5 Example SCI3 Operation in Transmission in Asynchronous Mode (8-Bit Data, Parity, One Stop Bit)



then write data to TDR. When data is written to TDR, the TDRE flag is automatically cleared to 0.

[3] To output a break in serial transmission, after setting PCR to 1 and PDR to 0, clear the SPC31 (SPC32) bit in SPCR and the TE bit in SCR to 0.

Figure 15.6 Sample Serial Transmission Flowchart (Asynchronous Mode)

- Stop bit check
The SCI3 checks that the stop bit is 1. If two stop bits are used, only the first is checked.
 - Status check
The SCI3 checks that bit RDRF is set to 0, indicating that the receive data can be transferred from RSR to RDR.
2. If an overrun error occurs (when reception of the next data is completed while the RDRF bit is still set to 1), the OER bit in SSR is set to 1. If the RIE bit in SCR is set to 1 at this time, an ERI31 (ERI32) interrupt request is generated. Receive data is not transferred to RDR.
 3. If a parity error is detected, the PER bit in SSR is set to 1 and receive data is transferred to RDR. If the RIE bit in SCR is set to 1 at this time, an ERI31 (ERI32) interrupt request is generated.
 4. If a framing error is detected (when the stop bit is 0), the FER bit in SSR is set to 1 and receive data is transferred to RDR. If the RIE bit in SCR is set to 1 at this time, an ERI31 (ERI32) interrupt request is generated.
 5. If reception is completed successfully, the RDRF bit in SSR is set to 1, and receive data is transferred to RDR. If the RIE bit in SCR is set to 1 at this time, an RXI31 (RXI32) interrupt request is generated. Continuous reception is possible because the RXI31 (RXI32) interrupt routine reads the receive data transferred to RDR before reception of the next receive data has been completed.

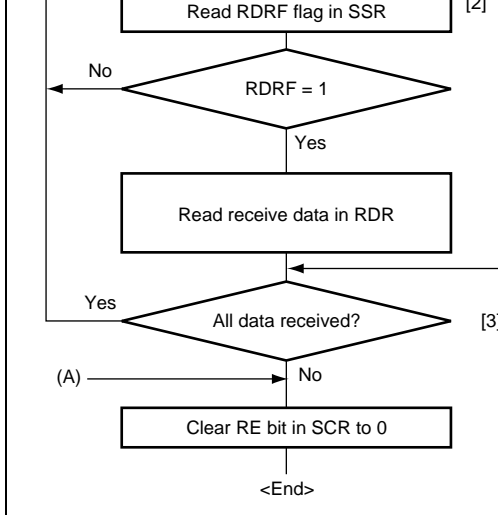
**Figure 15.7 Example SCI3 Operation in Reception in Asynchronous Mode
(8-Bit Data, Parity, One Stop Bit)**

Table 15.11 shows the states of the SSR status flags and receive data handling when a receive error is detected. If a receive error is detected, the RDRF flag retains its state before receiving data. Reception cannot be resumed while a receive error flag is set to 1. Accordingly, clear the OER, FER, PER, and RDRF bits to 0 before resuming reception. Figure 15.8 shows a sample flowchart for serial data reception.

Table 15.11 SSR Status Flags and Receive Data Handling

SSR Status Flag				Receive Data	Receive Error Type
RDRF*	OER	FER	PER		
1	1	0	0	Lost	Overflow error
0	0	1	0	Transferred to RDR	Framing error
0	0	0	1	Transferred to RDR	Parity error
1	1	1	0	Lost	Overflow error + framing error
1	1	0	1	Lost	Overflow error + parity error
0	0	1	1	Transferred to RDR	Framing error + parity error
1	1	1	1	Lost	Overflow error + framing error + parity error

Note: * The RDRF flag retains the state it had before data reception. However, note that the RDRF flag is read after an overflow error has occurred in a frame because reading of the RDRF flag is delayed, the RDRF flag will be cleared to 0.



the error. After performing the appropriate error processing, ensure that the OER, PER, and FER flags are all cleared to 0. Reception cannot be resumed if any of these flags are 1. In the case of a framing error break can be detected by reading the value of the input port corresponding to the RXD31 (RXD32) pin.

Figure 15.8 Sample Serial Data Reception Flowchart (Asynchronous Mode)

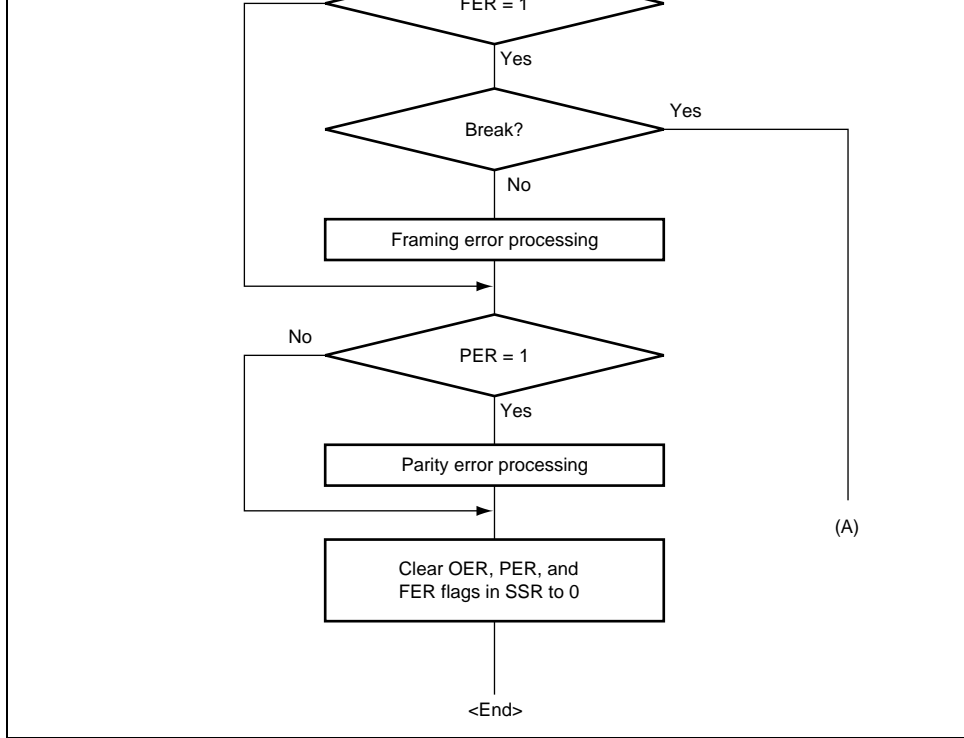


Figure 15.8 Sample Serial Data Reception Flowchart (Asynchronous Mode)

through the use of a common clock. Both the transmitter and the receiver also have a double-buffered structure, so data can be read or written during transmission or reception, enabling continuous data transfer.

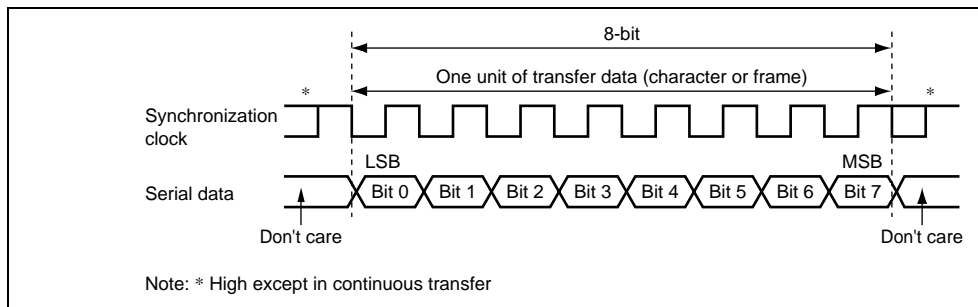


Figure 15.9 Data Format in Clocked Synchronous Communication

15.5.1 Clock

Either an internal clock generated by the on-chip baud rate generator or an external synchronization clock input at the SCK31 (SCK32) pin can be selected, according to the COM bit in SMR and CKE0 and CKE1 bits in SCR. When the SCI3 is operated on an external clock, the serial clock is output from the SCK31 (SCK32) pin. Eight serial clock pulses are output during the transfer of one character, and when no transfer is performed the clock is fixed high.

15.5.2 SCI3 Initialization

Before transmitting and receiving data, the SCI3 should be initialized as described in a flowchart in figure 15.4.

output clock mode has been specified, and synchronized with the input clock when the external clock has been specified. Serial data is transmitted sequentially from the LSI from the TXD31 (TXD32) pin.

4. The SCI checks the TDRE flag at the timing for sending the MSB (bit 7).
5. If the TDRE flag is cleared to 0, data is transferred from TDR to TSR, and serial transmission of the next frame is started.
6. If the TDRE flag is set to 1, the TEND flag in SSR is set to 1, and the TDRE flag matches the output state of the last bit. If the TEIE bit in SCR is set to 1 at this time, a TEI31 (TEI32) interrupt is generated.
7. The SCK31 (SCK32) pin is fixed high.

Figure 15.11 shows a sample flowchart for serial data transmission. Even if the TDRE flag is cleared to 0, transmission will not start while a receive error flag (OER, FER, or PER) is set. Make sure that the receive error flags are cleared to 0 before starting transmission.

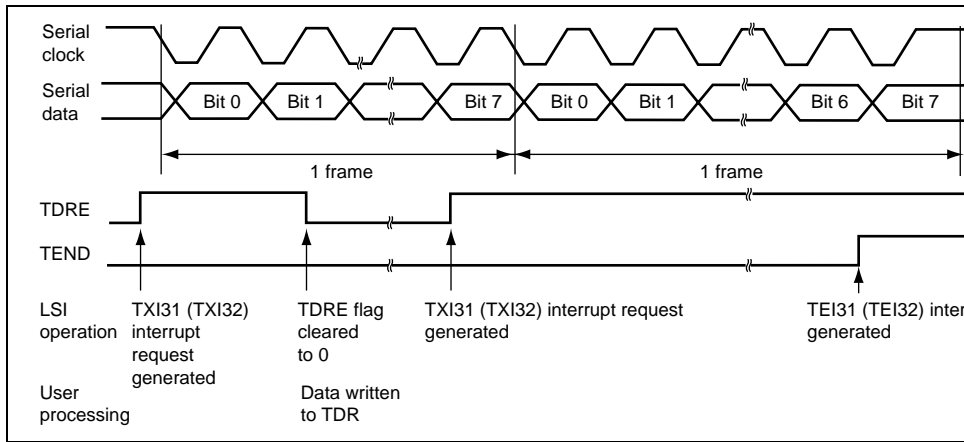


Figure 15.10 Example of SCI3 Operation in Transmission in Clocked Synchronous Mode

When data is written to TDR, the TDRE flag is automatically cleared to 0.

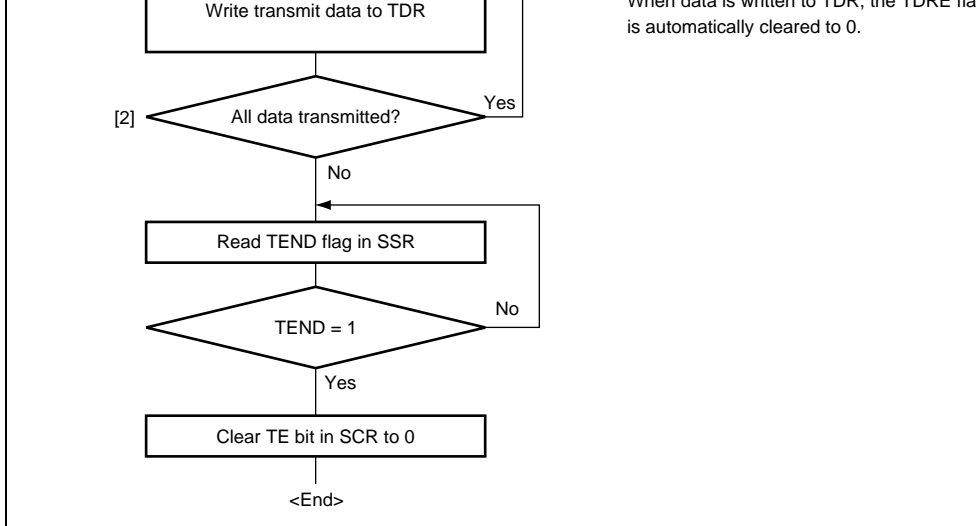


Figure 15.11 Sample Serial Transmission Flowchart (Clocked Synchronous Mode)

time, an RXI31 (RXI32) interrupt request is generated, receive data is not transferred to RDR, and the RDRF remains to be set to 1.

4. If reception is completed successfully, the RDRF bit in SSR is set to 1, and receive data is transferred to RDR. If the RIE bit in SCR is set to 1 at this time, an RXI31 (RXI32) interrupt request is generated.

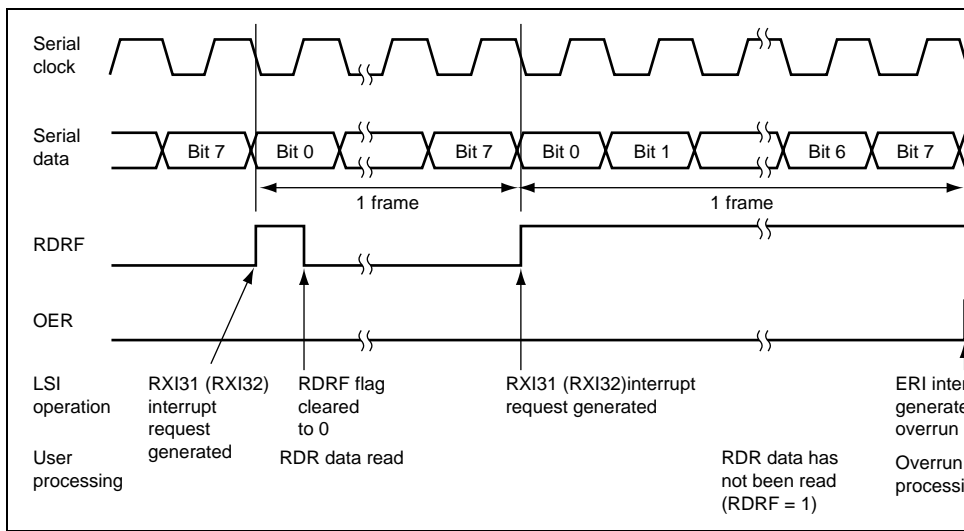
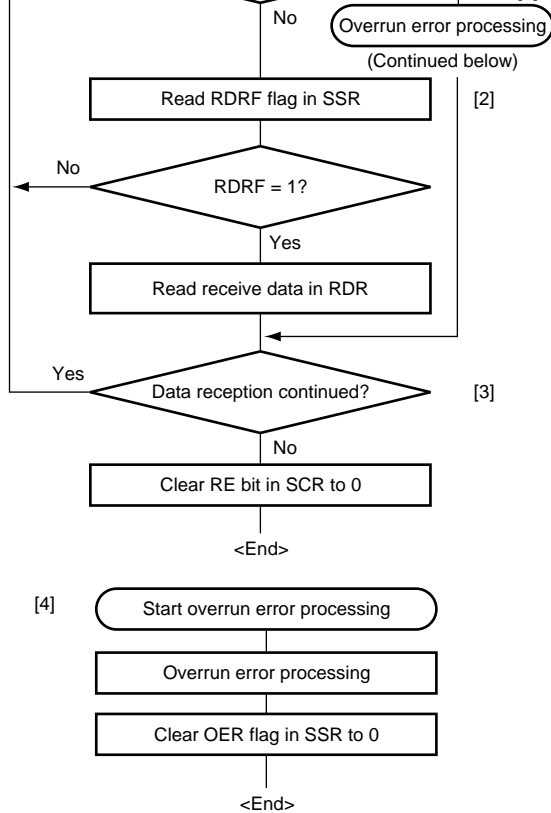


Figure 15.12 Example of SCI3 Reception Operation in Clocked Synchronous



MSB (bit 7) of the current frame is received. After reading the RDRF flag and reading RDR, the RDRF flag is automatically cleared to 0.

[4] If an overrun error occurs, read the OER flag in SSR, and after performing the appropriate error processing, clear the OER flag to 0. Reception cannot be resumed until the OER flag is set to 1.

Figure 15.13 Sample Serial Reception Flowchart (Clocked Synchronous Mode)

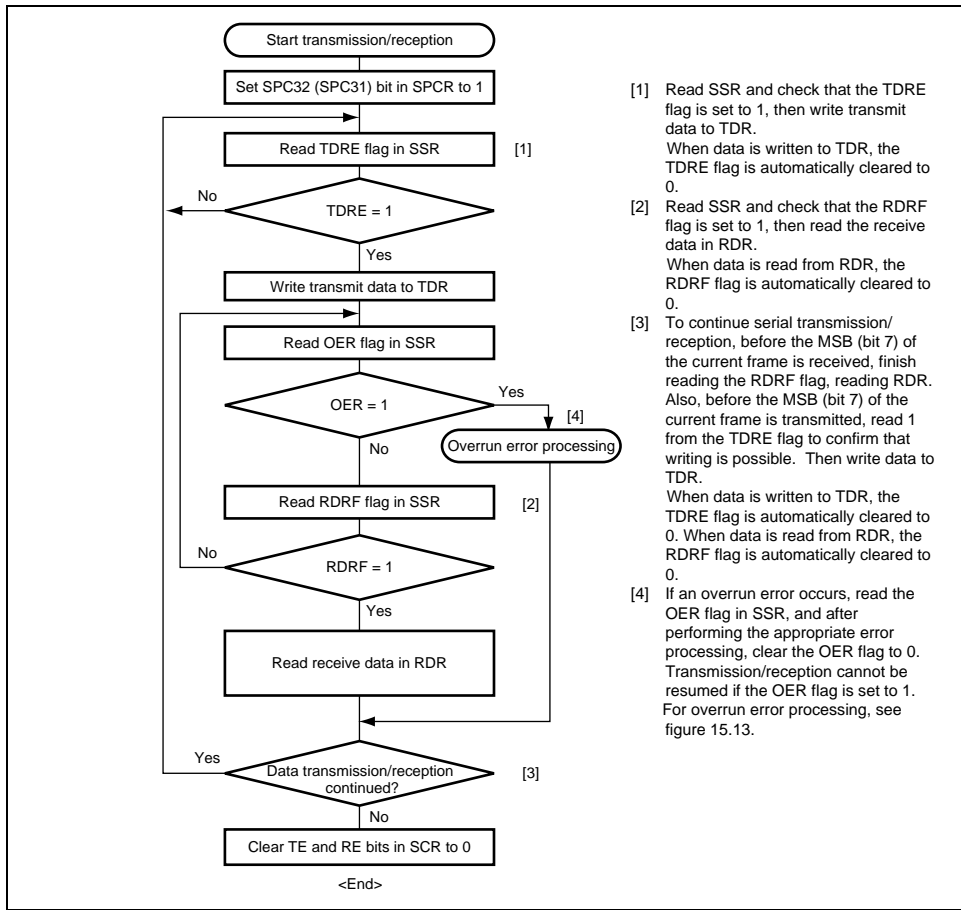


Figure 15.14 Sample Flowchart of Simultaneous Serial Transmit and Receive Operation (Clocked Synchronous Mode)

of 9600 bps, which can be modified as required. The IrDA interface provided by this LSI incorporate the capability of automatic modification of the transfer rate; the transfer rate is modified through programming.

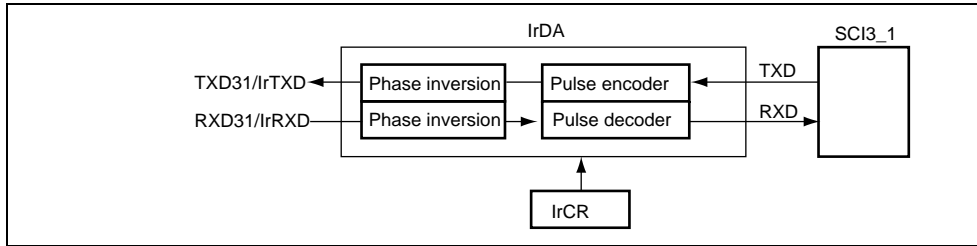


Figure 15.15 IrDA Block Diagram

15.6.1 Transmission

During transmission, the output signals from the SCI (UART frames) are converted to IR using the IrDA interface (see figure 15.16).

For serial data of level 0, a high-level pulse having a width of 3/16 of the bit rate (1-bit in output (initial setting)). The high-level pulse can be selected using the IrCKS2 to IrCKS0 and IrCR.

The high-level pulse width is defined to be 1.41 μ s at minimum and $(3/16 + 2.5\%) \times \text{bit rate}$ ($3/16 \times \text{bit rate}$) + 1.08 μ s at maximum. For example, when the frequency of system clock is 10 MHz, a high-level pulse width of at least 1.41 μ s to 1.6 μ s can be specified.

For serial data of level 1, no pulses are output.

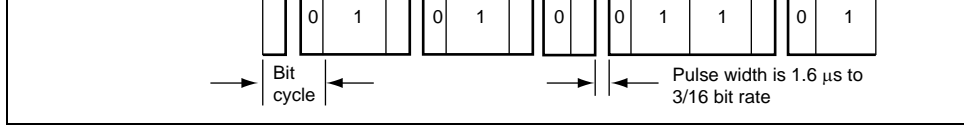


Figure 15.16 IrDA Transmission and Reception

15.6.2 Reception

During reception, IR frames are converted to UART frames using the IrDA interface by inputting to the SCI3_1.

Data of level 0 is output each time a high-level pulse is detected and data of level 1 is output if no pulse is detected in a bit cycle. If a pulse has a high-level width of less than 1.41 μs, minimum width allowed, the pulse is recognized as level 0.

2	010	010	010	010
2.097152	010	010	010	010
2.4576	010	010	010	010
3	011	011	011	011
3.6864	011	011	011	011
4.9152	011	011	011	011
5	011	011	011	011
6	100	100	100	100
6.144	100	100	100	100
7.3728	100	100	100	100
8	100	100	100	100
9.8304	100	100	100	100
10	100	100	100	100

Transmission End	TEI	Setting TEND in SSR
Receive Error	ERI	Setting OER, FER, and PER in SSR

Each interrupt request can be enabled or disabled by means of bits TIE and RIE in SCR.

When the TDRE bit in SSR is set to 1, a TXI31 (TXI32) interrupt is requested. When the TEIE bit in SSR is set to 1, a TEI31 (TEI32) interrupt is requested. These two interrupts are generated during transmission.

The initial value of the TDRE flag in SSR is 1. Thus, when the TIE bit in SCR is set to 1 before transferring the transmit data to TDR, a TXI31 (TXI32) interrupt request is generated even if the transmit data is not ready. The initial value of the TEND flag in SSR is 1. Thus, when the TEIE bit in SCR is set to 1 before transferring the transmit data to TDR, a TEI31 (TEI32) interrupt request is generated even if the transmit data has not been sent. It is possible to make use of these interrupt requests efficiently by transferring the transmit data to TDR in the interrupt request. To prevent the generation of these interrupt requests (TXI31 and TEI31), set the enable bits (TIE and TEIE) that correspond to these interrupt requests to 1, after transferring the transmit data to TDR.

When the RDRF bit in SSR is set to 1, an RXI31 (RXI32) interrupt is requested, and if the OER, PER, and FER is set to 1, an ERI31 (ERI32) interrupt is requested. These two interrupt requests are generated during reception.

The SCI3 can carry out continuous reception using an RXI31 (RXI32) and continuous transmission using a TXI31 (TXI32).

These interrupts are shown in table 15.14.

(TXI32)	TIE	(on completion of the previous transmission) and the transmit data placed in TDR is transferred to TSR, bit TDRE is set to 1. If bit TIE is set to 1 at this time, a TXI31 (TXI32) is enabled and an interrupt is requested. (See figure 15.17 (b).)	routine writes the next transmit data to TDR and clears bit TDRE to 0. Continuous transmission can be performed by repeating the above operations until the transmit character has been transferred to TSR has been transmitted.
TEI31 (TEI32)	TEND TEIE	When the last bit of the character in TSR is transmitted, if bit TDRE is set to 1, bit TEND is set to 1. If bit TEIE is set to 1 at this time, a TEI31 (TEI32) is enabled and an interrupt is requested. (See figure 15.17 (c).)	A TEI31 (TEI32) indicates that the next transmit data has not yet been written to TDR when the character is transmitted.

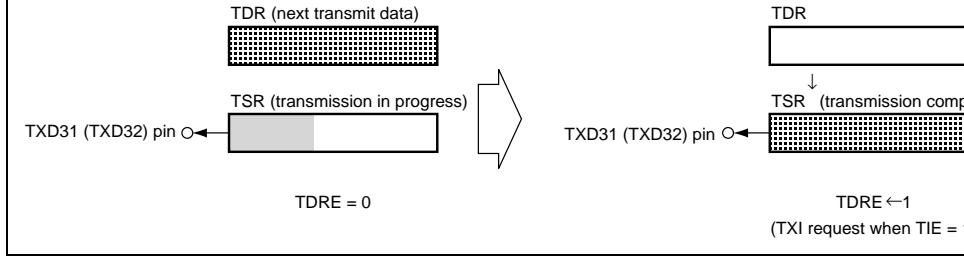


Figure 15.17 (b) TDRE Setting and TXI Interrupt

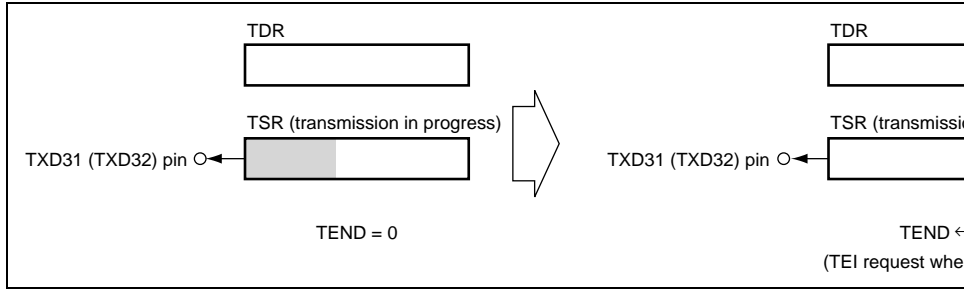


Figure 15.17 (c) TEND Setting and TEI Interrupt

Regardless of the value of TE, when the SPCR31 (SPCR32) bit in SPCR is cleared to 0, the TXD31 (TXD32) pin is used as an I/O port whose direction (input or output) and level are determined by PCR and PDR. This can be used to set the TXD31 (TXD32) pin to mark state (level) or send a break during serial data transmission. To maintain the communication line in state (1) until SPCR31 (SPCR32) in SPCR is set to 1, set both PCR and PDR to 1. As SPCR31 (SPCR32) in SPCR is cleared to 0 at this point, the TXD31 (TXD32) pin becomes an I/O port and 1 is output from the TXD31 (TXD32) pin. To send a break during serial transmission, first set PCR to 1 and PDR to 0, and then clear SPCR31 (SPCR32) and TE to 0. If TE is cleared to 0 immediately after SPCR31 (SPCR32) is cleared to 0, the transmitter is initialized regardless of the current transmission state after TE is cleared, and when SPCR31 (SPCR32) is cleared to 0, the TXD31 (TXD32) pin becomes an I/O port and 0 is output from it.

15.8.3 Receive Error Flags and Transmit Operations (Clocked Synchronous Mode)

Transmission cannot be started when a receive error flag (OER, PER, or FER) is set to 1, and the TDRE flag is cleared to 0. Be sure to clear the receive error flags to 0 before starting transmission. Note also that receive error flags cannot be cleared to 0 even if the RE bit is cleared to 0.

- Where N: Ratio of bit rate to clock (N = 16)
- D: Clock duty (D = 0.5 to 1.0)
- L: Frame length (L = 9 to 12)
- F: Absolute value of clock rate deviation

Assuming values of F (absolute value of clock rate deviation) = 0 and D (clock duty) = 0.5, using formula (1), the reception margin can be given by the formula.

$$M = \{0.5 - 1/(2 \times 16)\} \times 100 [\%] = 46.875\%$$

However, this is only the computed value, and a margin of 20% to 30% should be allowed in system design.

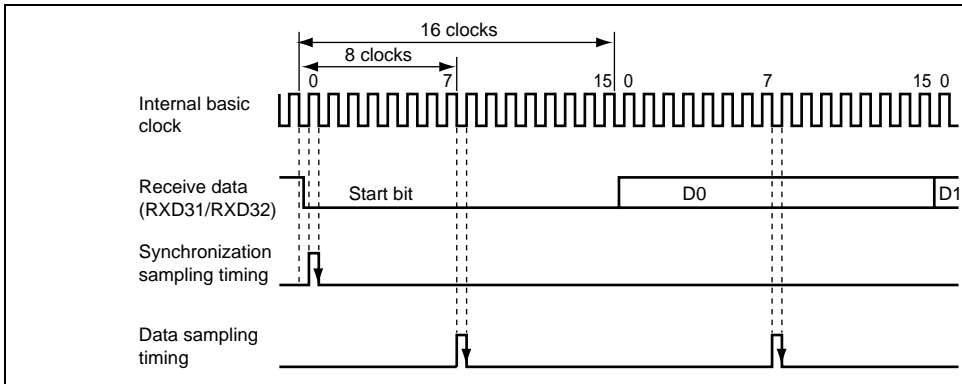


Figure 15.18 Receive Data Sampling Timing in Asynchronous Mode

CKE1 and CKE0 in SCR to 1 and 0, respectively.

In this case, bit COM in SMR should be left 1. The above prevents the SCK31 (SCK32) pin from being used as a general input/output pin. To avoid an intermediate level of voltage from being applied to the SCK31 (SCK32) pin, the line connected to the SCK31 (SCK32) pin should be pulled up to the V_{cc} level via a resistor, or supplied with output from an external device.

(2) When SCK31 (SCK32) Function is Switched from Clock Output to General Input/Output

When stopping data transfer,

1. Issue one instruction to clear bits TE and RE to 0 and to set bits CKE1 and CKE0 in SCR to 1 and 0, respectively.
2. Clear bit COM in SMR to 0
3. Clear bits CKE1 and CKE0 in SCR to 0. Note that special care is also needed here to avoid an intermediate level of voltage from being applied to the SCK31 (SCK32) pin.

15.8.6 Relation between Writing to TDR and Bit TDRE

Bit TDRE in the serial status register (SSR) is a status flag that indicates that data for serial transmission has not been prepared in TDR. When data is written to TDR, bit TDRE is cleared to 0 automatically. When the SCI3 transfers data from TDR to TSR, bit TDRE is set to 1.

Data can be written to TDR irrespective of the state of bit TDRE, but if new data is written to TDR while bit TDRE is cleared to 0, the data previously stored in TDR will be lost if it has not been transferred to TSR. Accordingly, to ensure that serial transmission is performed dependably, you should first check that bit TDRE is set to 1, then write the transmit data to TDR only once (or two or more times).

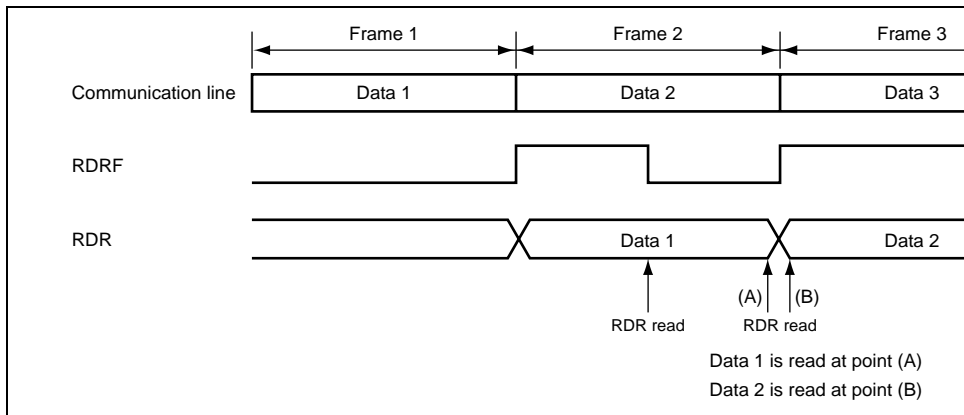


Figure 15.19 Relation between RDR Read Timing and Data

In this case, only a single RDR read operation (not two or more) should be performed after checking that bit RDRF is set to 1. If two or more reads are performed, the data read the first time should be transferred to RAM, etc., and the RAM contents used. Also, ensure that there is a sufficient margin in an RDR read operation before reception of the next frame is complete. In terms of timing, the RDR read should be completed before bit 7 is transferred in synchronous mode, or before the STOP bit is transferred in asynchronous mode.

15.8.8 Transmit and Receive Operations when Making State Transition

Make sure that transmit and receive operations have completely finished before carrying out state transition processing.

Version).

selected as a clock source.

- Receive error detection: Overrun errors detected
- Four interrupt sources

Transmit-end, transmit-data-empty, receive-data-full, and overrun error

- Full-duplex communication capability

Buffering is used in both the transmitter and the receiver, enabling continuous transmission and continuous reception of serial data.

- When the on-chip emulator debugger etc. is not used, the SCI4 is available for the user.
- Use of module standby mode enables this module to be placed in standby mode independently when not used. (For details, refer to section 6.4, Module Standby Function.)

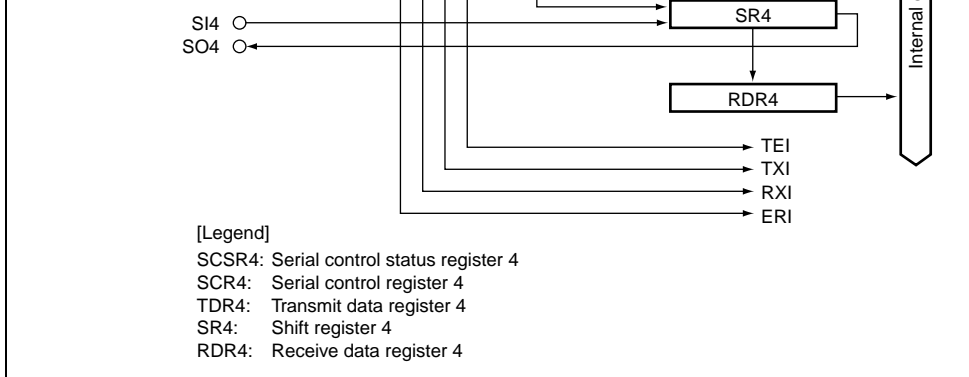


Figure 16.1 Block Diagram of SCI4

16.2 Input/Output Pins

Table 16.1 shows the SCI4 pin configuration.

Table 16.1 Pin Configuration

Pin Name	Abbreviation	I/O	Function
SCI4 clock	SCK4	I/O	SCI4 clock input/output
SCI4 data input	SI4	Input	SCI4 receive data input
SCI4 data output	SO4	Output	SCI4 transmit data output

16.3.1 Serial Control Register 4 (SCR4)

SCR4 enables or disables interrupt requests and controls SCI4 transfer operations.

Bit	Bit Name	Initial Value	R/W	Description
7	TIE	0	R/W	<p>Transmit Interrupt Enable</p> <p>Enables or disables a transmit data empty interrupt (TXI) request when serial transmit data is transferred from TDR4 to SR4 and the TDRE flag in SCSR4 is set to 1. TXI can be cleared by clearing the TDRE flag in SCSR4 to 0 after the flag is read as 1 or cleared to 0.</p> <p>0: Transmit data empty interrupt (TXI) request disabled 1: Transmit data empty interrupt (TXI) request enabled</p>
6	RIE	0	R/W	<p>Receive Interrupt Enable</p> <p>Enables or disables a receive data full interrupt (RXI) request and receive error interrupt (ERI) request when serial receive data is transferred from SR4 to RDR4 and the RDRF flag in SCSR4 is set to 1. RXI and ERI can be cleared by clearing the RDRF or ORER flag in SCSR4 to 0 after the flag is read as 1 or cleared to 0.</p> <p>0: Receive data full interrupt (RXI) request and receive error interrupt (ERI) request disabled 1: Receive data full interrupt (RXI) request and receive error interrupt (ERI) request enabled</p>

Sets the output level of the SO4 pin. When this bit is read, the output level of the SO4 pin is read. The output level of the SO4 pin retains the value of the last bit of data after transmission is completed. However, if the output level is changed before or after transmission, the output level of the SO4 pin can be changed. When the output level of the SO4 pin is changed, the SOLP bit should be cleared to 0 and the MOV instruction should be executed. Note that this bit should not be changed during transmission because incorrect operation may occur.

[When reading]

0: The output level of the SO4 pin is low.

1: The output level of the SO4 pin is high.

[When writing]

0: The output level of the SO4 pin is changed to low.

1: The output level of the SO4 pin is changed to high.

3	SOLP	1	R/W	<p>SOL Write Protect</p> <p>Controls change of the output level of the SO4 pin to the change of the SOL bit. When the output level of the SO4 pin is changed, the setting of SOL = 1 and SOLP = 0 or SOL = 0 and SOLP = 0 is made by the MOV instruction. This bit is always read as 1.</p> <p>0: When writing, the output level is changed according to the value of the SOL pin.</p> <p>1: When reading, this bit is always read as 1 and cannot be modified.</p>
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1: Internal sequencer is forcibly reset

1	TE	0	R/W	<p>Transmit Enable</p> <p>Enables or disables start of the SCI4 serial transmission. When this bit is cleared to 0, the flag in SCSR4 is fixed to 1. When transmit data is written to TDR4 while this bit is set to 1, the TDR4 in SCSR4 is automatically cleared to 0 and serial transmission is started.</p> <p>0: Transmission disabled (SO4 pin functions as data pin)</p> <p>1: Transmission enabled (SO4 pin functions as data pin)</p>
0	RE	0	R/W	<p>Receive Enable</p> <p>Enables or disables start of the SCI4 serial reception. Note that the RDRF and ORER flags in SCSR4 are not affected even if this bit is cleared to 0, and return to previous state. Serial data reception is started when synchronous clock input is detected while this bit is set to 1 (when an external clock is selected). When the internal clock is selected, the synchronous clock output and serial data reception is started.</p> <p>0: Reception disabled (SI4 pin functions as I/O pin)</p> <p>1: Reception enabled (SI4 pin functions as reception pin)</p>

Indicates that data is transferred from TDR4 to
the next serial transmit data can be written to T

[Setting conditions]

- When the TE bit in SCR4 is 0
- When data is transferred from TDR4 to SR4
data can be written to TDR4

[Clearing conditions]

- When 0 is written to TDRE after reading TD
- When data is written to TDR4

6	RDRF	0	R/(W)*	Receive Data Full
---	------	---	--------	-------------------

Indicates that the receive data is stored in RDR

[Setting condition]

- When serial reception ends normally and re
data is transferred from SR4 to RDR4

[Clearing conditions]

- When 0 is written to RDRF after reading RD
- When data is read from RDR4

continued either.

[Setting condition]

- When the next serial reception is complete
RDRF = 1

[Clearing condition]

- When 0 is written to ORER after reading C

4	TEND	0	R/(W)*	Transmit End Indicates that the TDRE flag has been set to 1 at the end of transmission of the last bit of transmit data. [Setting condition] <ul style="list-style-type: none">• When TDRE = 1 at transmission of the last bit of transmit data [Clearing conditions] <ul style="list-style-type: none">• When 0 is written to TEND after reading TDR4• When data is written to TDR4 with an instruction
3	CKS3	1	R/W	Clock Source Select and Pin Function
2	CKS2	0	R/W	Select the clock source to be supplied and set the pin as input/output for the SCK4 pin. The prescaler divider ratio and transfer clock cycle when an internal clock is selected are shown in table 16.2. When an external clock is selected, the external clock cycle should be at least $4/\phi$.
1	CKS1	0	R/W	
0	CKS0	0	R/W	

Note: * Only 0 can be written to clear the flag.

0	0	1	0	$\phi/64$	12.8 μs	25.6 μs	Internal clock	SC ou
0	0	1	1	$\phi/32$	6.4 μs	12.8 μs	Internal clock	SC ou
0	1	0	0	$\phi/16$	3.2 μs	6.4 μs	Internal clock	SC ou
0	1	0	1	$\phi/8$	1.6 μs	3.2 μs	Internal clock	SC ou
0	1	1	0	$\phi/4$	0.8 μs	1.6 μs	Internal clock	SC ou
0	1	1	1	$\phi/2$	—	0.8 μs	Internal clock	SC ou
1	0	0	0	—	—	—	I/O port (initial	
1	0	0	1	—	—	—	I/O port	
1	0	1	0	—	—	—	I/O port	
1	0	1	1	—	—	—	I/O port	
1	1	0	0	—	—	—	I/O port	
1	1	0	1	—	—	—	I/O port	
1	1	1	0	—	—	—	I/O port	
1	1	1	1	—	—	—	External clock	SC pin

RDR4 is an 8-bit register that stores receive data. When the SCI4 has received one byte of data, it transfers the received serial data from SR4 to RDR4, where it is stored. Then the operation is completed. After this, SR4 is receive-enabled. RDR4 cannot be written to by the CPU. RDR4 is initialized to H'00.

16.3.5 Shift Register 4 (SR4)

SR4 is a register that receives or transmits serial data. SR4 cannot be directly read from or written to by the CPU.

The eight internal clocks or an external clock can be selected as a transfer clock. When the external clock is selected, the SCK4 pin is a clock input pin. When the internal clock is selected, the SCK4 pin is a synchronous clock output pin. The synchronous clock is output eight pulses per 1-character transmission or reception. While neither transmission nor reception is being performed, the signal is fixed high.

When the internal clock or external clock is not selected according to the combination of CKS3 to CKS0 bits in SCSR4, the SCK4 pin functions as an I/O port.

16.4.2 Data Transfer Format

Figure 16.2 shows the SCI4 transfer format.

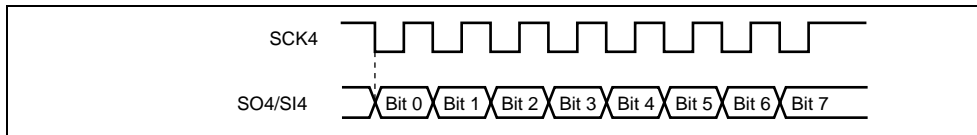


Figure 16.2 Data Transfer Format

In clocked synchronous communication, data on the communication line is output from the rising edge to the next falling edge of the synchronous clock. The data is guaranteed to be settled at the rising edge of the synchronous clock. One character starts with the LSB and ends with the MSB. After transmitting the MSB, the communication line retains the MSB level.

The SCI4 latches data at the rising edge of the synchronous clock on reception. The data format is fixed to 8-bit data. While transmission is stopped, the output level on the SO4 pin is changed by the SOL setting in SCR4.

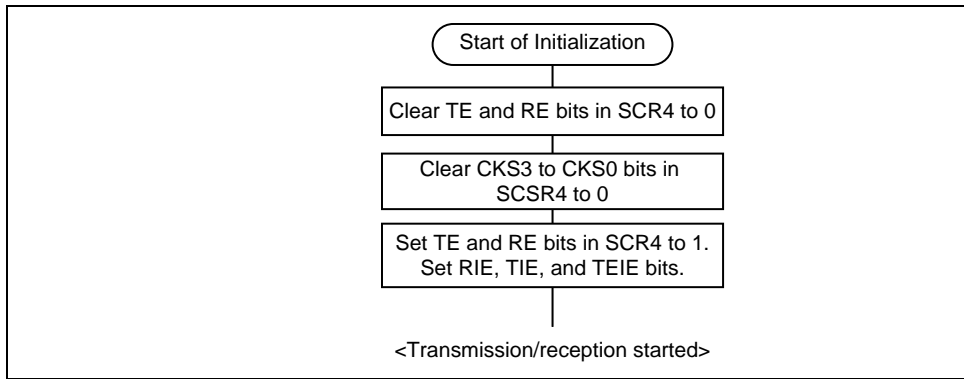


Figure 16.3 Flowchart Example of SCI4 Initialization

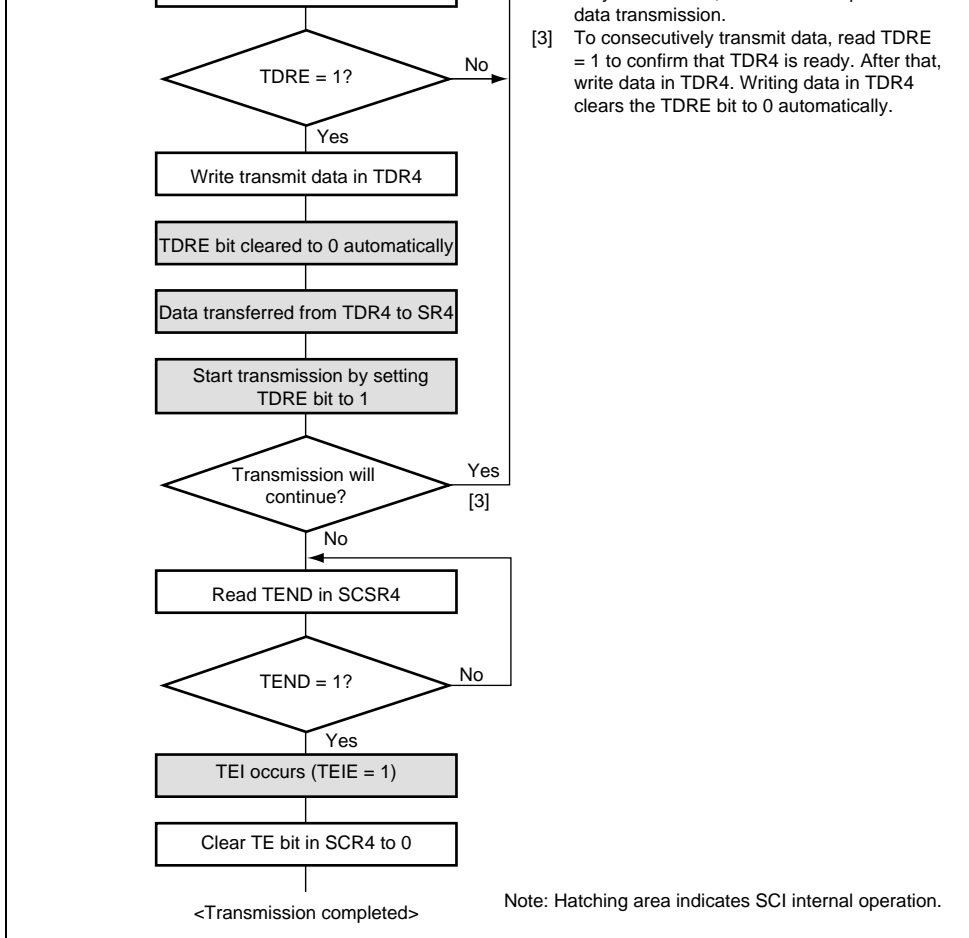


Figure 16.4 Flowchart Example of Data Transmission

after transmitting the MSB (bit 7). At this time, when the TEIE bit in SCR4 is set to 1, the TXEIE flag is generated.

5. After the transmission, the output level on pin SCK4 is fixed high.

Note: Transmission cannot be performed when the error flag (ORER) which indicates reception status is set to 1. Before transmission, confirm that the ORER flag is cleared to 0.

Figure 16.5 shows the example of transmission operation.

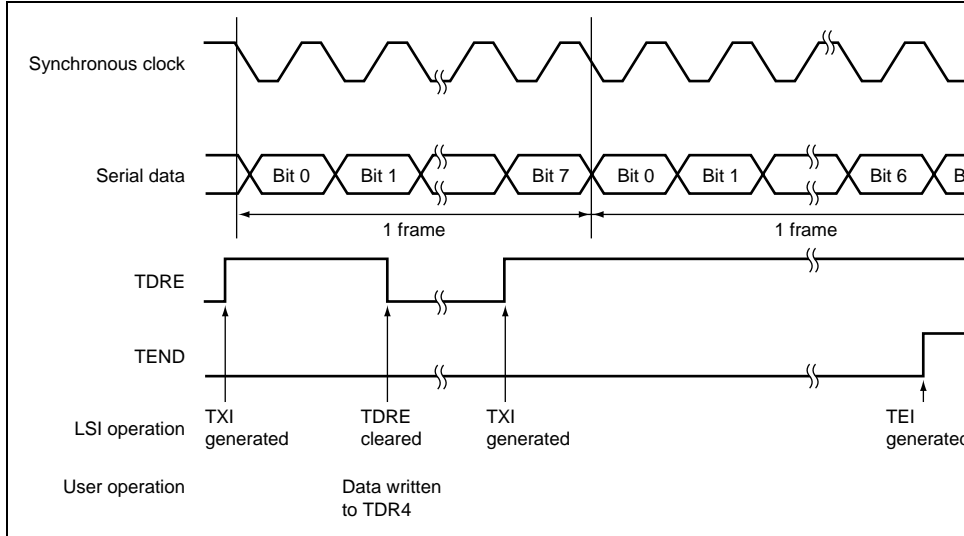
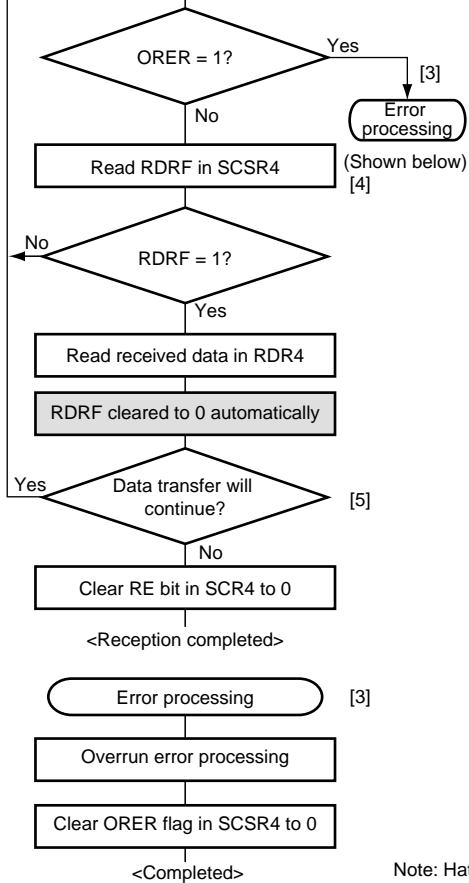


Figure 16.5 Transmit Operation Example



[4] After reading SCSR4 and confirming RDRF, read the receive data in RDR4. The RDRF is automatically cleared to 0. Changes in the RDRF flag from 0 to 1 can be notified by an interrupt.

[5] To consecutively receive data, reading the flag and RDR4 must be completed before receiving the MSB (bit 7) of the current frame.

Note: Hatching area indicates SCI internal operation.

Figure 16.6 Flowchart Example of Data Reception

generated.

- An overrun error is detected when the next data reception is completed with the RDRF and SCSR4 set to 1. The received data is not transferred from SR4 to RDR4.

Note: Reception cannot be performed when the error flag is set to 1. Before reception, that the ORE and RDRF flags are cleared to 0.

Figure 16.7 shows an operation example of reception.

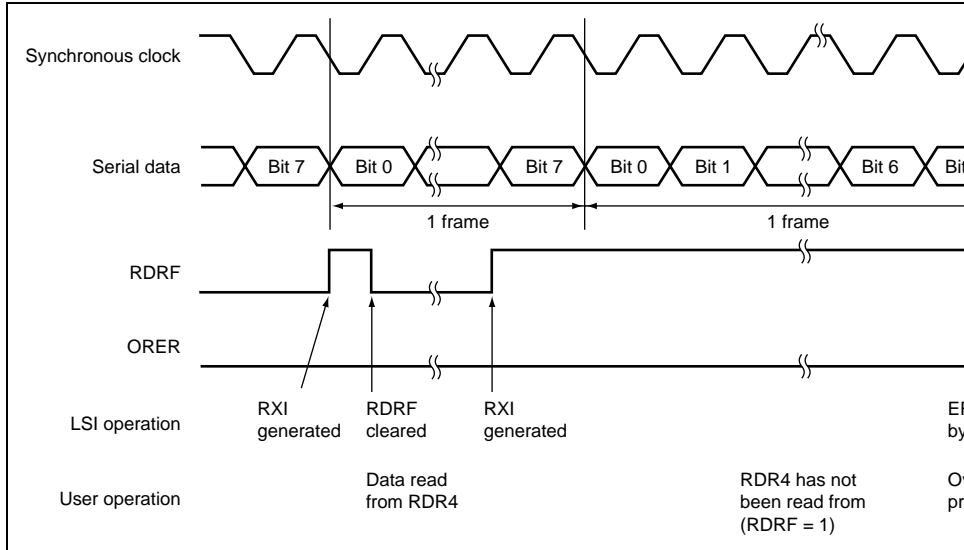
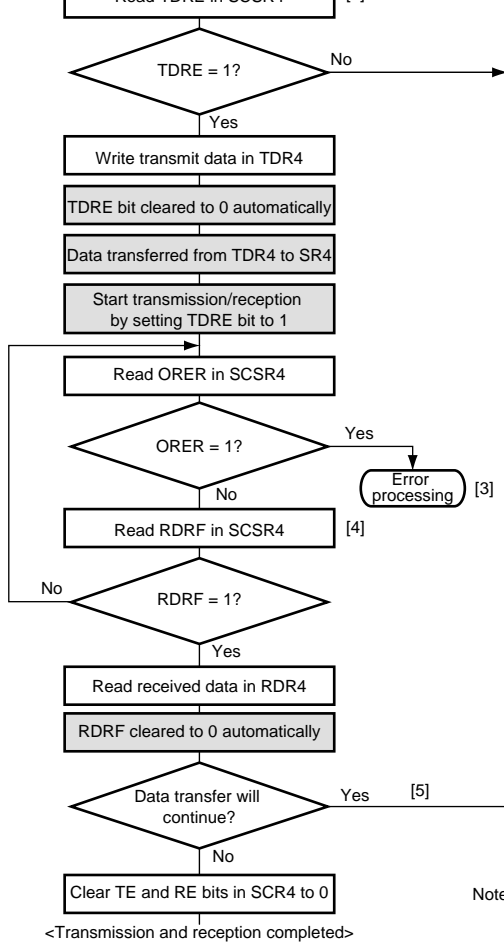


Figure 16.7 Receive Operation Example



- [3] When a reception error occurs, read the ORER flag in SCSR4 and then clear the ORER flag to 0 after executing the error processing. When the ORER flag is set to 1, both transmission and reception cannot be restarted.
- [4] After reading SCSR4 and confirming RDRF = 1, read receive data in RDR4 and clear the RDRF flag to 0. An RXI interrupt can also be used to confirm that the RDRF flag value has been cleared from 0 to 1.
- [5] To consecutively transmit and receive data, the following operation must be completed: read the RDRF flag and reading RDR4 before receiving the MSB (bit 7) of the current frame: confirming that TDR4 is ready for writing by reading TDRE = 1 before transmitting the MSB (bit 7) and writing data to TDR4 to clear the TDRE flag to 0.

Note: Hatching area indicates SCI internal operation.

Figure 16.8 Flowchart Example of Simultaneous Transmission and Reception



Table 16.3 lists the descriptions of the interrupt sources.

Table 16.3 SCI4 Interrupt Sources

Abbreviation	Condition	Interrupt Source
RXI	RIE = 1	Receive data full (RDRF)
TXI	TIE = 1	Transmit data empty (TDRE)
TEI	TEIE = 1	Transmit end (TEND)
ERI	RIE = 1	Receive error (ORER)

The interrupt requests can be enabled/disabled by the TIE and RIE bits in SCR4.

When the TDRE flag in SCSR4 is set to 1, a TXI is generated. When the TEND bit in SCSR4 is set to 1, a TEI is generated. These two interrupt requests are generated during transmission.

The TDRE flag in SCSR4 is initialized to 1. Therefore, if a TXI request is enabled by setting the TIE bit in SCR4 to 1 before transmit data is transferred to TDR4, a TXI is generated even if transmit data is not ready.

If transmit data is transferred to TDR4 in the interrupt handling routine, these interrupt requests can be effectively used.

To avoid the occurrence of the interrupt requests (TXI and TEI), clear the corresponding enable bits (TIE and TEIE) to 0 after transmit data is transferred to TDR4.

When the RDRF bit in SCSR4 is set to 1, an RXI is generated. When the ORER flag in SCSR4 is set to 1, an ERI is generated. These two interrupt requests are generated during reception.

Data is written to TDR4 regardless of the TDRE flag value. However, if data is written to TDR4 with TDRE = 0, the previous data is lost unless the previous data has been transferred to TDR5. Accordingly, to ensure transmission, writing transmit data to TDR4 must be performed only after confirming that the TDRE flag has been set to 1. (Do not write more than once.)

16.6.2 Receive Error Flag and Transmission

While the receive error flag (ORER) is set to 1, transmission cannot be started even if the TDRE flag is cleared to 0. To start transmission, the ORER flag must be cleared to 0.

Note that the ORER flag cannot be cleared to 0 even if the RE bit is cleared to 0.

16.6.3 Relationship between Reading RDR4 and RDRF

The SCI4 always checks the RDRF flag status during reception. When the RDRF flag is cleared to 0 at the end of a frame, the reception is completed without error. When the RDRF flag is set to 1, it indicates that an overrun has occurred.

Since reading RDR4 clears the RDRF flag to 0 automatically, if RDR4 is read twice or more, the data is read with the RDRF flag cleared to 0. In this case, when the timing of the read operation matches that of the data reception of the next frame, the read data may be the next frame data. Figure 16.9 shows this operation.

Figure 16.9 Relationship between Reading RDR4 and RDRF

In this case, RDR4 must be read only once after confirming RDRF = 1. If reading RDR4 more, store the read data in the RAM, and use the stored data. In addition, there should be a margin from the timing of reading RDR4 to completion of the next frame reception. (Reading RDR4 should be completed before the bit 7 transfer.)

16.6.4 SCK4 Output Waveform when Internal Clock of $\phi/2$ is Selected

When the internal clock of $\phi/2$ is selected by the CKS3 to CKS0 bits in SCSR4 and communication transmission or reception is performed, one pulse of high period is lengthened after eight clock cycles. The clock has been output as shown in figure 16.10.

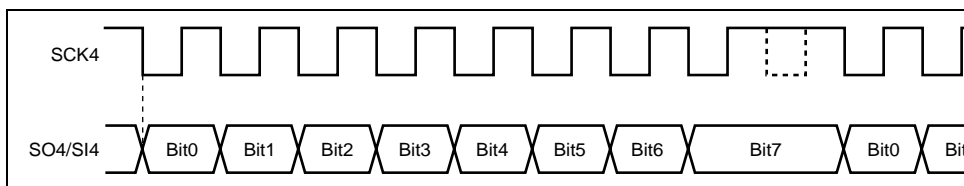


Figure 16.10 Transfer Format when Internal Clock of $\phi/2$ is Selected

A conversion period of $131,072/\phi$ with a minimum modulation width of $8/\phi$, a conversion period of $65,536/\phi$ with a minimum modulation width of $4/\phi$, a conversion period of $32,768/\phi$ with a minimum modulation width of $2/\phi$, or a conversion period of $16,384/\phi$ with a modulation width of $1/\phi$, can be selected.

- Pulse division method for less ripple
- Use of module standby mode enables this module to be placed in standby mode independently when not used. (For details, refer to section 6.4, Module Standby Function.)
- The standard PWM or pulse-division type PWM can be selected by software.

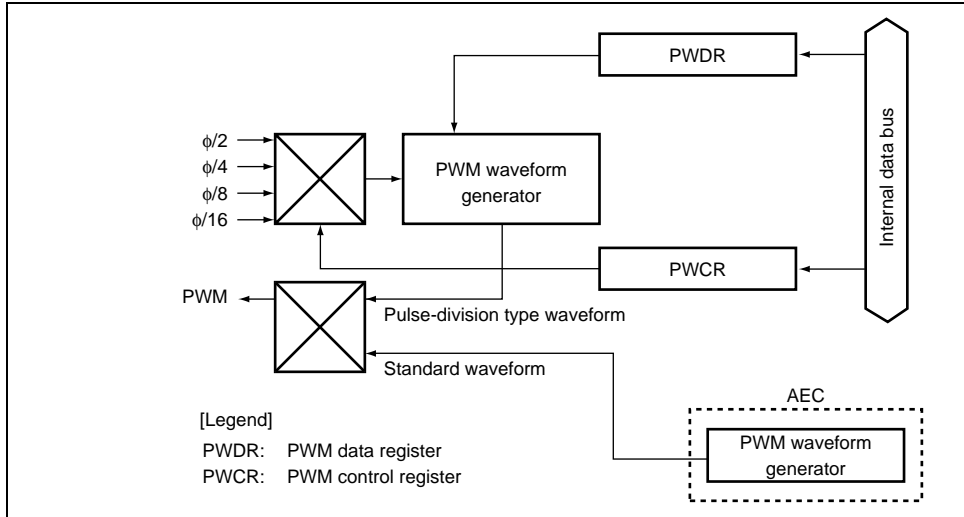


Figure 17.1 Block Diagram of 14-Bit PWM

17.3 Register Descriptions

The 14-bit PWM has the following registers.

- PWM1 control register (PWCR1)
- PWM1 data register (PWDR1)
- PWM2 control register (PWCR2)
- PWM2 data register (PWDR2)

17.3.1 PWM Control Register (PWCR)

PWCR selects the input clocks and selects whether the standard PWM or pulse-division type PWM is used.

Bit	Bit Name	Initial Value	R/W	Description
7 to 3	—	All 1	—	Reserved These bits are always read as 1 and cannot be modified.
2	PWCRm2	0	W	PWM Output Waveform Select Selects whether the standard PWM waveform or pulse-division type PWM waveform is output. 0: Pulse-division type PWM waveform is output 1: Standard PWM waveform is output

10: The input clock is $\phi/8$ ($t\phi^* = 8/\phi$)

— A conversion period is $65,536/\phi$, with a modulation width of $4/\phi$

11: The input clock is $\phi/16$ ($t\phi^* = 16/\phi$)

— A conversion period is $131,072/\phi$, with a minimum modulation width of $8/\phi$

Note: * $t\phi$: Period of PWM clock input
m = 2 or 1

17.3.2 PWM Data Register (PWDR)

PWDR is a 14-bit write-only register. PWDR indicates high level width in one PWM wave cycle when the pulse-division type PWM is selected.

When data is written to the lower 14 bits of PWDR, the contents are latched in the PWM waveform generator and the PWM waveform generation data is updated.

The initial value of PWDR is 0, and it is always read as H'FFFF.

Always write to this register in word size.

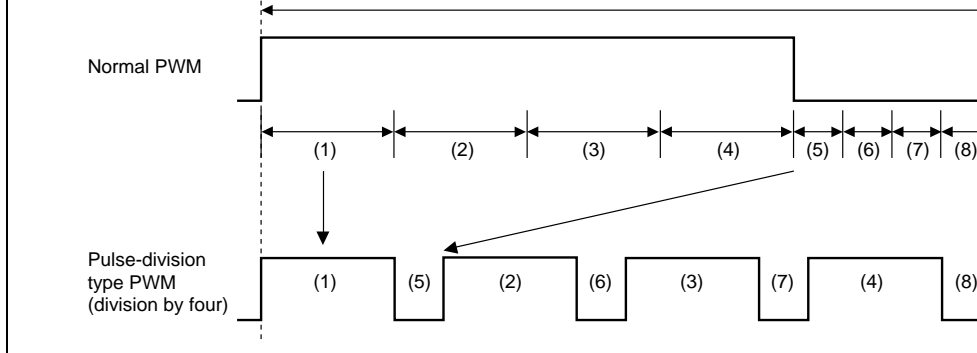


Figure 17.2 Example of Pulse-Division Type PWM Using Division by Four

17.4.2 Pulse-Division Type PWM Setting Method

When using the pulse-division type PWM, set the registers in this sequence:

1. Set the PWM1 or PWM2 bit in PMR9 (corresponding to the PWM channel used) to 1 and the P90/PWM1 or P91/PWM2 pin to function as a PWM pin.
2. Set PWCR to define one conversion period.
3. Set the output waveform data in PWDR. When the data is written to PWDR, the content is latched in the PWM waveform generator, and the PWM waveform generation data is

17.4.3 Pulse-Division Type PWM Operating

One conversion period consists of 64 pulses, as shown in figure 17.3. The total high-level time during this period (T_H) corresponds to the data in PWDR. Table 17.2 shows this relation.

Table 17.2 Correspondence Between PWCR, PWRD, and Output Waveform

PWCRm Setting Value		One Conversion Period [tcyc]	T _H [tcyc]	t _{rn(n=} [tcyc]
PWCRm1	PWCRm0			
0	0	16384	(PWDRm+64) * 1	256
0	1	32768	(PWDRm+64) * 2	512
1	0	65536	(PWDRm+64) * 4	1024
1	1	131072	(PWDRm+64) * 8	2048

Note: m = 2, 1

17.4.4 Setting for Standard PWM Operation

When using the standard PWM, set the registers in this sequence:

1. Set the PWM1 or PWM2 bit in PMR9 (according to the PWM channel used) to 1 to P90/PWM1 or P91/PWM2 pin to function as a PWM pin.
2. Set PWCRm2 to 1 to select the standard PWM waveform. (m = 2 or 1)
3. Set the event counter PWM in the asynchronous event counter. For the setting method, see the description of the event counter PWM operation in the asynchronous event counter.
4. The PWM pin outputs the PWM waveform set by the event counter.

Note: When the standard waveform is used, 16-bit counter operation, 8-bit counter operation, and IRQAEC operation for the asynchronous event counter are not available because the standard PWM for the asynchronous event counter is used.

When the IECPWM signal of the asynchronous event counter goes high, ECH starts to increment. However, when the signal goes low, these counters stop. (For details, see section 13.4, Operation.)

17.6 Usage Notes

17.6.1 Timing of Effect on PWM Waveform After Writing to PWDR

If PWDR is rewritten during PWM waveform output, the effects on the PWM waveform follows, depending on the timing of the write operation:

- (1) Write performed during low-level output.
 - New setting takes effect from next pulse.
- (2) Write performed during low-level output.
 - a. Duty increased.
 - New setting takes effect immediately after write.
 - b. Duty decreased.
 - High width at time of write exceeds PWDR high width after write.
 - High-level output for one pulse period.
 - High width at time of write does not exceed PWDR high width after write.
 - New setting takes effect immediately after write.

- High-speed conversion: 12.4 μ s per channel (at 5-MHz operation)
- Sample and hold function
- Conversion start method
A/D conversion can be started by software and external trigger.
- Interrupt source
An A/D conversion end interrupt request can be generated.
- Use of module standby mode enables this module to be placed in standby mode independent of the CPU when not used. (For details, refer to section 6.4, Module Standby Function.)

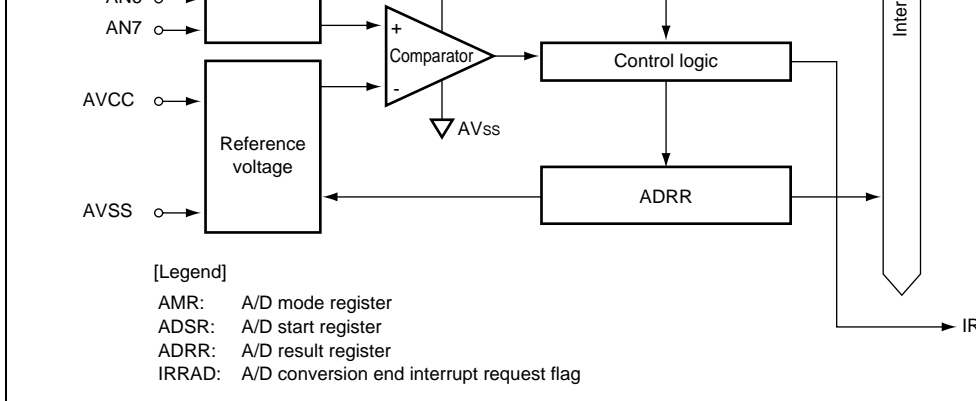


Figure 18.1 Block Diagram of A/D Converter

Analog input pin 0	AN0	Input	Analog input pins
Analog input pin 1	AN1	Input	
Analog input pin 2	AN2	Input	
Analog input pin 3	AN3	Input	
Analog input pin 4	AN4	Input	
Analog input pin 5	AN5	Input	
Analog input pin 6	AN6	Input	
Analog input pin 7	AN7	Input	
External trigger input pin	ADTRG	Input	External trigger input that controls A/D conversion start.

18.3 Register Descriptions

The A/D converter has the following registers.

- A/D result register (ADRR)
- A/D mode register (AMR)
- A/D start register (ADSR)

18.3.1 A/D Result Register (ADRR)

ADRR is a 16-bit read-only register that stores the results of A/D conversion. The upper 6 bits of the data are stored in ADRR. ADRR can be read by the CPU at any time, but the ADRR value during A/D conversion is undefined. After A/D conversion is completed, the conversion result is stored as 10-bit data, and this data is retained until the next conversion operation starts. The value of ADRR is undefined.

Always read this register in word size.

6	TRGE	0	R/W	External Trigger Select Enables or disables the A/D conversion start by external trigger input. 0: Disables the A/D conversion start by the external trigger input. 1: Starts A/D conversion at the rising or falling edge of the $\overline{\text{ADTRG}}$ pin The edge of the $\overline{\text{ADTRG}}$ pin is selected by the $\overline{\text{ADTRGNEG}}$ bit in IEGR.
5	—	1	—	Reserved
4	—	1	—	These bits are always read as 1 and cannot be modified.
3	CH3	0	R/W	Channel Select 3 to 0
2	CH2	0	R/W	Select the analog input channel.
1	CH1	0	R/W	00xx: No channel selected
0	CH0	0	R/W	0100: AN0 0101: AN1 0110: AN2 0111: AN3 1000: AN4 1001: AN5 1010: AN6 1011: AN7 11xx: Using prohibited The channel selection should be made while the bit is cleared to 0.

[Legend] x: Don't care.

18.4 Operation

The A/D converter operates by successive approximation with 10-bit resolution. When starting the conversion time or analog input channel, in order to prevent incorrect operation, first set bit ADSF to 0 in ADSR.

18.4.1 A/D Conversion

1. A/D conversion is started from the selected channel when the ADSF bit in ADSR is set to 1 according to software.
2. When A/D conversion is completed, the result is transferred to the A/D result register.
3. On completion of conversion, the IRRAD flag in IRR2 is set to 1. If the IENAD bit in IEN2 is set to 1 at this time, an A/D conversion end interrupt request is generated.
4. The ADSF bit remains set to 1 during A/D conversion. When A/D conversion ends, the ADSF bit is automatically cleared to 0 and the A/D converter enters the wait state.

the ADTRG pin, reset should be cleared while the 0-fixed or 1-fixed signal is the TEST pin. Then the ADTSTCHG bit should be set to 1 after the TEST signal is fixed.

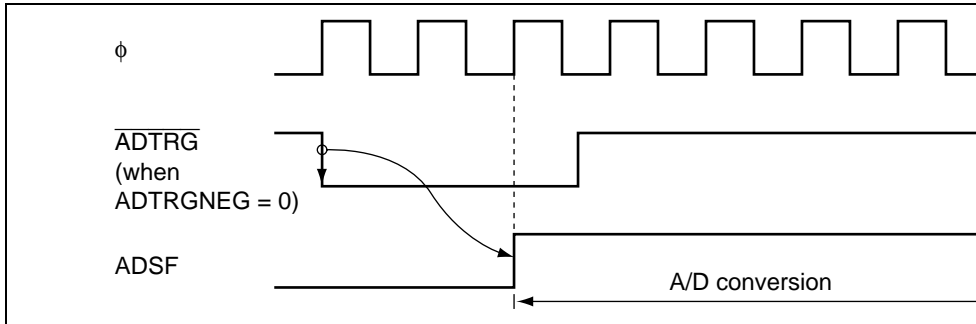


Figure 18.2 External Trigger Input Timing

18.4.3 Operating States of A/D Converter

Table 18.2 shows the operating states of the A/D converter.

Table 18.2 Operating States of A/D Converter

Operating Mode	Reset	Active	Sleep	Watch	Sub-active	Sub-sleep	Standby	M	S
AMR	Reset	Functions	Functions	Retained	Retained	Retained	Retained	R	S
ADSR	Reset	Functions	Functions	Retained	Retained	Retained	Retained	R	S
ADRR	Retained*	Functions	Functions	Retained	Retained	Retained	Retained	R	S

Note: * Undefined at a power-on reset.

3. Bit IENAD = 1, so an A/D conversion end interrupt is requested.
4. The A/D interrupt handling routine starts.
5. The A/D conversion result is read and processed.
6. The A/D interrupt handling routine ends.

If bit ADSF is set to 1 again afterward, A/D conversion starts and steps 2 through 6 take place again. Figures 18.4 and 18.5 show flowcharts of procedures for using the A/D converter.

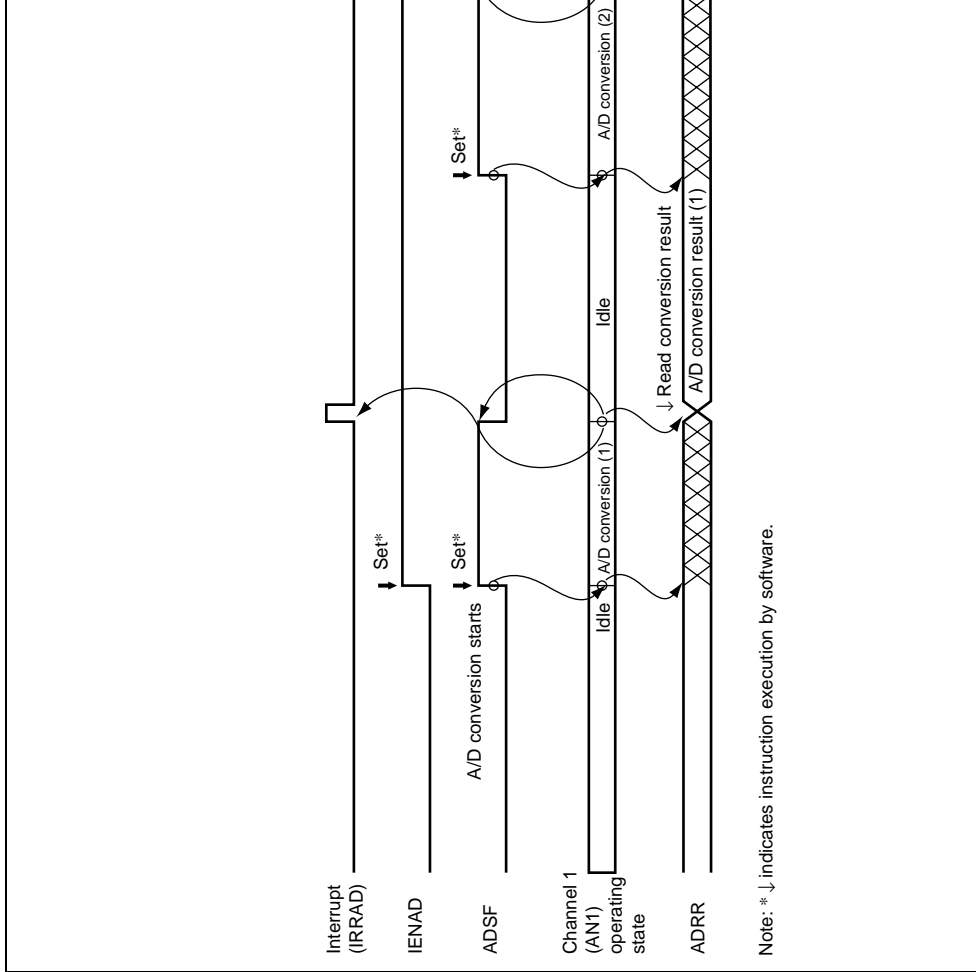


Figure 18.3 Example of A/D Conversion Operation

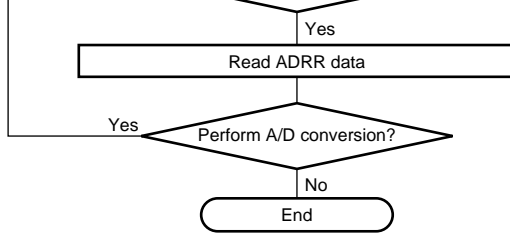


Figure 18.4 Flowchart of Procedure for Using A/D Converter (Polling by Software)

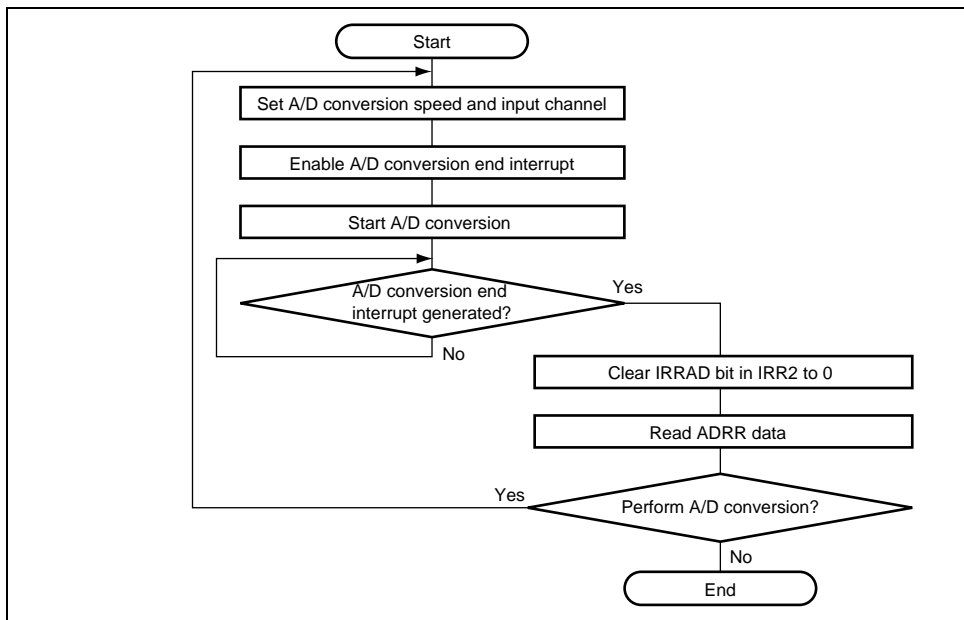


Figure 18.5 Flowchart of Procedure for Using A/D Converter (Interrupts Used)

when the digital output changes from the minimum voltage value 0000000000 to 0000000001 (see figure 18.7).

- Full-scale error

The deviation of the analog input voltage value from the ideal A/D conversion characteristic when the digital output changes from 1111111110 to 1111111111 (see figure 18.7).

- Nonlinearity error

The error with respect to the ideal A/D conversion characteristics between zero voltage and full-scale voltage. Does not include offset error, full-scale error, or quantization error.

- Absolute accuracy

The deviation between the digital value and the analog input value. Includes offset error, full-scale error, quantization error, and nonlinearity error.

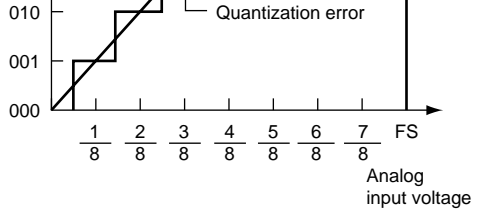


Figure 18.6 A/D Conversion Accuracy Definitions (1)

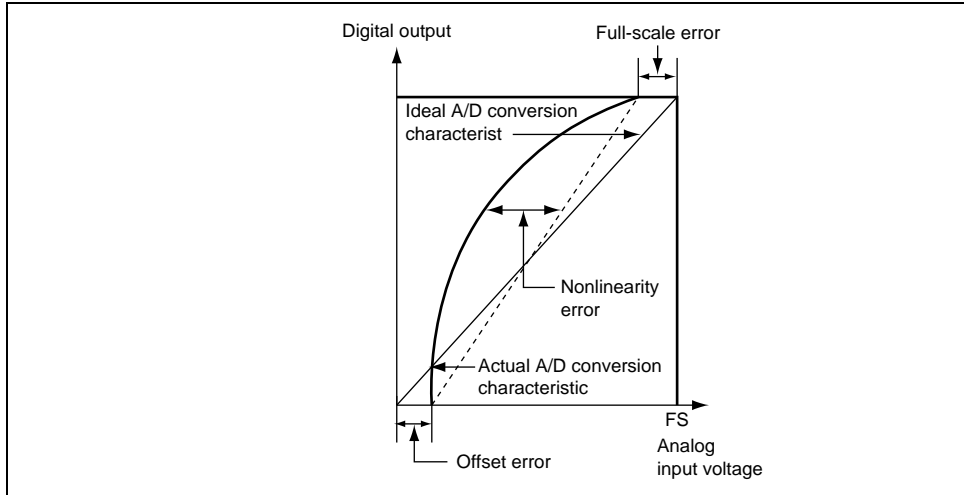


Figure 18.7 A/D Conversion Accuracy Definitions (2)

and the signal source impedance can be ignored. However, as a low-pass filter effect is observed in this case, it may not be possible to follow an analog signal with a large differential coefficient (e.g., 5 mV/ μ s or greater) (see figure 18.8).

When converting a high-speed analog signal, a low-impedance buffer should be inserted.

18.7.2 Influences on Absolute Accuracy

Adding capacitance results in coupling with GND, and therefore noise in GND may adversely affect absolute accuracy. Be sure to make the connection to an electrically stable GND.

Care is also required to ensure that filter circuits do not interfere with digital signals or act as antennas on the mounting board.

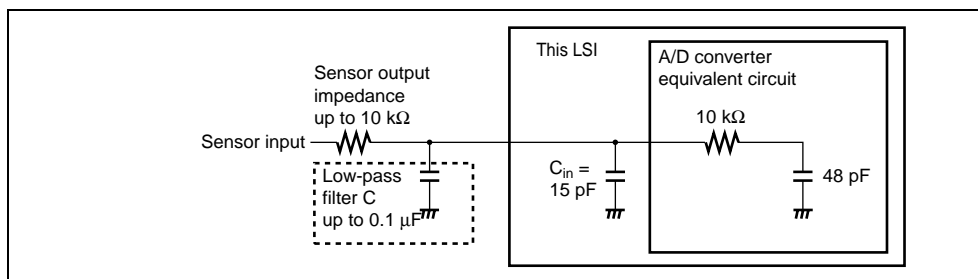


Figure 18.8 Example of Analog Input Circuit

cleared to 0 in CKSTPR1.



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REJ09

Static	32 SEG
1/2	32 SEG
1/3	32 SEG
1/4	32 SEG

- LCD RAM capacity
8 bits × 16 bytes (128 bits)
- Word access to LCD RAM
- The segment output pins can be used as ports.
SEG32 to SEG1 pins can be used as ports in groups of four.
- Common output pins not used because of the duty cycle can be used for common driver buffering (parallel connection).
With 1/2 duty, parallel connection of COM1 to COM2, and of COM3 to COM4, can be used.
In static mode, parallel connection of COM1 to COM2, COM3, and COM4 can be used.
- Choice of 11 frame frequencies
- A or B waveform selectable by software
- On-chip power supply split-resistor
- Display possible in operating modes other than standby mode
- On-chip 3-V constant-voltage power supply circuit
This power circuit can constantly supply 3 V to LCD drive power supply without using an external voltage.
- Output of the 3-V constant-voltage power supply circuit adjustable
- Use of module standby mode enables this module to be placed in standby mode independently when not used. (For details, refer to section 6.4, Module Standby Function.)

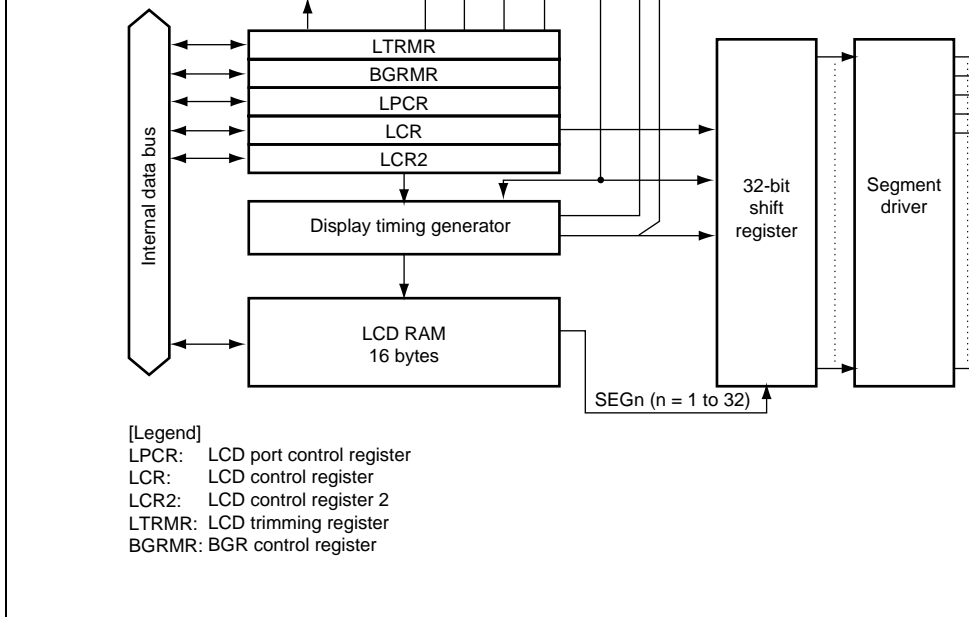


Figure 19.1 Block Diagram of LCD Controller/Driver

pins			Pins can be used in parallel with static 1/2 duty
LCD power supply pins	V1, V2, V3	—	Used when a bypass capacitor is connected externally, and when an external power circuit is used
LCD step-up capacitance pins	C1, C2	—	Capacitance pins for stepping up the power supply

19.3 Register Descriptions

The LCD controller/driver has the following registers.

- LCD port control register (LPCR)
- LCD control register (LCR)
- LCD control register 2 (LCR2)
- LCD trimming register (LTRMR)
- BGR control register (BGRMR)
- LCDRAM

increase the common drive power when not all common pins are used because of the duty selection. For details, see table 19.2.

4	—	—	W	Reserved Only 0 can be written to this bit.
3	SGS3	0	R/W	Segment Driver Select 3 to 0
2	SGS2	0	R/W	Select the segment drivers to be used.
1	SGS1	0	R/W	For details, see table 19.3.
0	SGS0	0	R/W	

Table 19.2 Duty Cycle and Common Function Selection

Bit 7: DTS1	Bit 6: DTS0	Bit 5: CMX	Duty Cycle	Common Drivers	Notes*
0	0	0	Static	COM1	Leave COM4, COM3, and COM2 in open drain state
		1		COM4 to COM1	COM4, COM3, and COM2 output the same waveform as COM1
	1	0	1/2 duty	COM2 to COM1	Leave COM4 and COM3 in open drain state
		1		COM4 to COM1	COM4 outputs the same waveform as COM2 COM2 outputs the same waveform as COM1
1	0	0	1/3 duty	COM3 to COM1	Leave COM4 in open drain state
		1		COM4 to COM1	Leave COM4 in open drain state
	1	0	1/4 duty	COM4 to COM1	—
		1			

Note: * If SGS3 to SGS0 are set to B'0000, the power supply voltage level of PA0 to PA3 and COM1 to COM4 is Vcc. If the setting of SGS3 to SGS0 is other than B'0000, the power supply voltage level of PA0 to PA3 and COM1 to COM4 is the LCD drive power supply voltage level.

		1	0	Port	Port	SEG	SEG	SEG	SEG	SEG
			1	Port	SEG	SEG	SEG	SEG	SEG	SEG
1	0	0	0	SEG	SEG	SEG	SEG	SEG	SEG	SEG
			1	SEG	SEG	SEG	SEG	SEG	SEG	SEG
		1	0	SEG	SEG	SEG	SEG	SEG	SEG	Port
			1	SEG	SEG	SEG	SEG	SEG	Port	Port
	1	0	0	SEG	SEG	SEG	SEG	Port	Port	Port
			1	SEG	SEG	SEG	Port	Port	Port	Port
		1	0	SEG	SEG	Port	Port	Port	Port	Port
			1	SEG	Port	Port	Port	Port	Port	Port

19.3.2 LCD Control Register (LCR)

LCR controls LCD drive power supply and display data, and selects the frame frequency.

Bit	Bit Name	Initial Value	R/W	Description
7	—	1	—	Reserved This bit is always read as 1 and cannot be modified.
6	PSW	0	R/W	LCD Drive Power Supply Control Can be used to turn off the LCD drive power supply when LCD display is not required in power-down mode or when an external power supply is used. When the ACT bit is cleared to 0 or in standby mode, the LCD drive power supply is turned off regardless of the value of this bit. 0: LCD drive power supply is turned off 1: LCD drive power supply is turned on

Specifies whether the LCD RAM contents are 0 or blank data is displayed regardless of the LCD RAM contents.

0: Blank data is displayed

1: LCD RAM data is displayed

3	CKS3	0	R/W	Frame Frequency Select 3 to 0
2	CKS2	0	R/W	Select the operating clock and the frame frequency. However, in subactive mode, watch mode, and subsleep mode, the system clock (ϕ) is halted. Therefore display operations are not performed.
1	CKS1	0	R/W	When the clock divider from $\phi/2$ to $\phi/256$ is selected. If LCD data is required in these modes, ϕ_w , $\phi_w/2$, or $\phi_w/4$ must be selected as the operating clock.
0	CKS0	0	R/W	For details, see table 19.4.

		1	$\phi/16$	244 Hz	30.5 Hz
1	0	0	$\phi/32$	122 Hz	—
		1	$\phi/64$	61 Hz	—
	1	0	$\phi/128$	30.5 Hz	—
		1	$\phi/256$	—	—

[Legend]

X: Don't care

- Notes:
1. When 1/3 duty is selected, the frame frequency is 4/3 times the value shown.
 2. This is the frame frequency when $\phi_w = 32.768$ kHz.
 3. This is the frame frequency in active (medium-speed, $\phi_{osc}/8$) mode when ϕ_{osc}

19.3.3 LCD Control Register 2 (LCR2)

LCR2 controls switching between the A waveform and B waveform, selection of the split resistor for the 3-V constant-voltage circuit, connection with the LCD power-supply split resistor, and turning on or off 3-V constant-voltage power supply.

voltage power supply circuit. The step up clock is obtained by dividing the clock selected by the CKS0 bits in LCR into 4 or 8.

0: Divided into 4

1: Divided into 8

5	CHG	0	R/W	Connection Control of LCD Power-Supply Split Selects whether an LCD power-supply split resistor is disconnected or connected from or to LCD driver supply. 0: Disconnected 1: Connected
4	SUPS	0	R/W	3-V Constant-Voltage Power Supply Control Can be used to turn off the 3-V constant-voltage power supply when LCD display is not required in power mode, or when an external power supply is used. When the BGRSTPN bit in BGRMR is cleared to 0 or in standby mode, the 3-V constant-voltage power supply is turned off regardless of the setting of this bit. 0: 3-V constant-voltage power supply is turned off 1: 3-V constant-voltage power supply is turned on
3 to 0	—	—	W	Reserved Only 0 can be written to these bits.

4	TRM0	0	R/W	3 V. Following values* indicate the voltage of pin. Set this register so that the voltage on the should be 3 V. 0000: ±0 V 1000: 0.48 V 0001: -0.06 V 1001: 0.42 V 0010: -0.12 V 1010: 0.36 V 0011: -0.15 V 1011: 0.30 V 0100: -0.21 V 1100: 0.24 V 0101: -0.24 V 1101: 0.18 V 0110: -0.30 V 1110: 0.12 V 0111: -0.33 V 1111: 0.06 V
3	—	1	—	Reserved This bit is always read as 1 and cannot be mo

010: 0.18 V
011: 0.27 V
100: -0.36 V
101: -0.27 V
110: -0.18 V
111: -0.09 V

Notes: Setting Method for LCD Trimming Register (LTRMR)
Assuming the following definitions,

V1 initial state voltage: A

LTRMR register TRM3 to TRM0: B

CTRM2 to CTRM0: C

rough guidelines for the voltages after trimming are as follows:

V1 voltage = $A + B + C$

V2 voltage = $(A + B + C) \times 2/3$

V3 voltage = $(A + B + C) / 3$

After monitoring voltage A, set B and C so the V1 voltage is 3 V.

* These are approximate values and are not guaranteed. Therefore these values be used as reference values.

0: Band-gap reference circuit halts

1: Band-gap reference circuit operates

6 to 3	—	All 1	—	Reserved
				These bits are always read as 1 and cannot be modified.
2 to 0	—	All 0	R/W	Reserved
				This bit is always read as 0, and only 0 can be written to it.

When 1/2 duty is used, interconnect pins V2 and V3 as shown in figure 19.2.

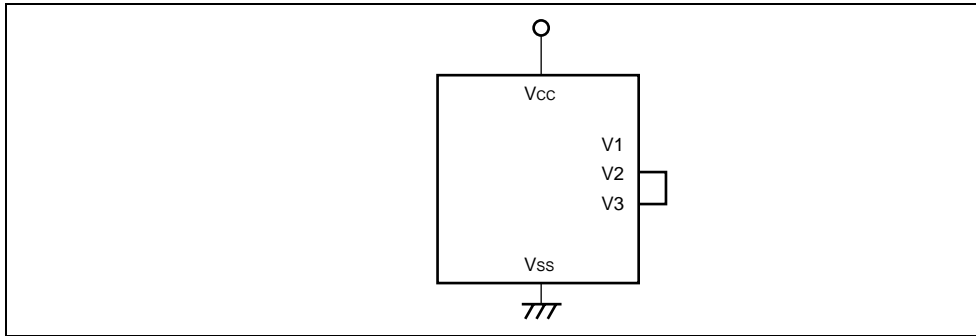


Figure 19.2 Handling of LCD Drive Power Supply when Using 1/2 Duty

(b) Large-Panel Display

As the impedance of the on-chip power supply split-resistor is large, it may not be suitable for driving a panel which requires a current more than the current value calculated by the on-chip power supply split-resistor and voltage of the LCD power supply. If the display lacks sharpness when using a large panel, refer to section 19.4.5, Boosting LCD Drive Power Supply and Contrast Adjustment. When static or 1/2 duty is selected, the common output drive capability can be increased. Set CMX to 1 when selecting the duty cycle. In this mode, with a static duty cycle, COM4 to COM1 output the same waveform, and with 1/2 duty the COM1 waveform is output from pins COM2 and COM1, and the COM2 waveform is output from pins COM4 and COM1.

(c) LCD Drive Power Supply Setting

With this LSI, there are two ways of providing LCD power: by using the on-chip power supply circuit, or by using an external power supply circuit.

The segment drivers to be used can be selected with bits SGS5 to SGS0.

(c) Frame Frequency Selection

The frame frequency can be selected by setting bits CKS3 to CKS0. The frame frequency can be selected in accordance with the LCD panel specification. For the clock selection method in watch mode, subactive mode, and subsleep mode, see section 19.4.4, Operation in Power Modes.

(d) A or B Waveform Selection

Either the A or B waveform can be selected as the LCD waveform to be used by means of the LCDAB bit.

(e) LCD Drive Power Supply Selection

When an external power supply circuit is used, turn the LCD drive power supply off with the LCDPS bit.

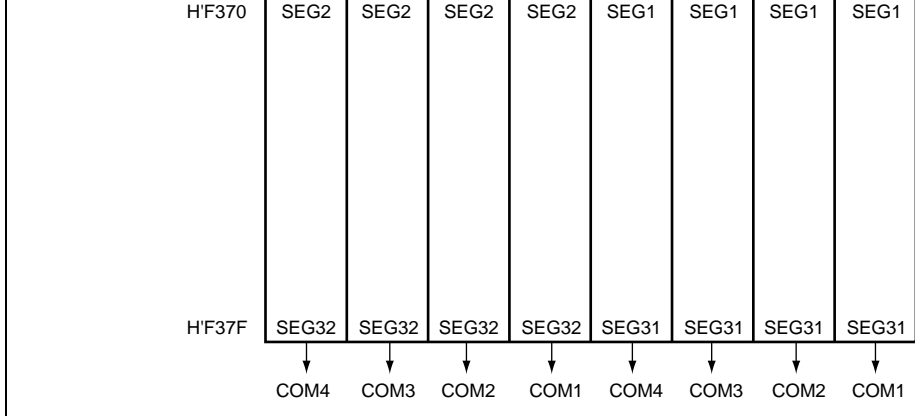


Figure 19.3 LCD RAM Map (1/4 Duty)

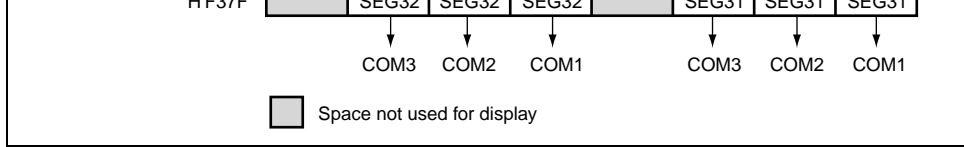


Figure 19.4 LCD RAM Map (1/3 Duty)

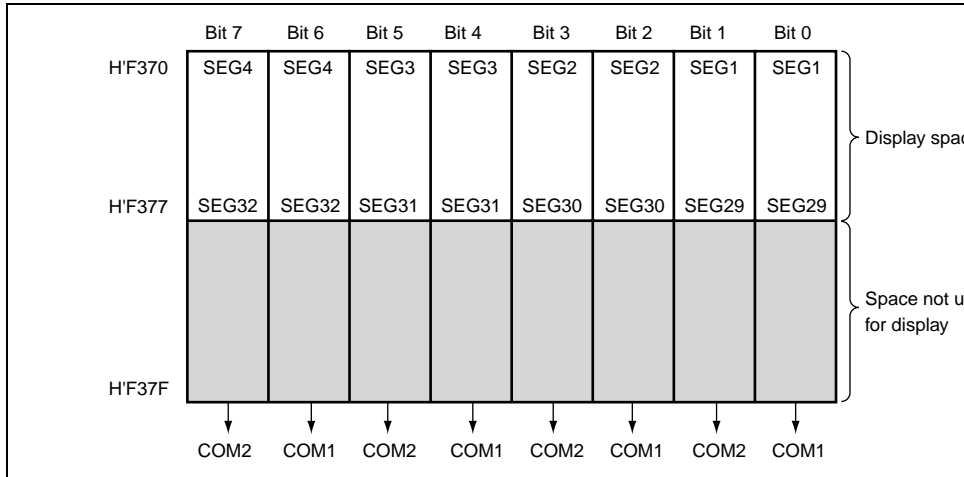


Figure 19.5 LCD RAM Map (1/2 Duty)

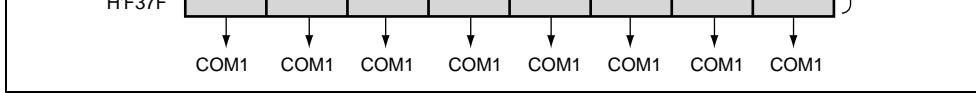


Figure 19.6 LCD RAM Map (Static Mode)

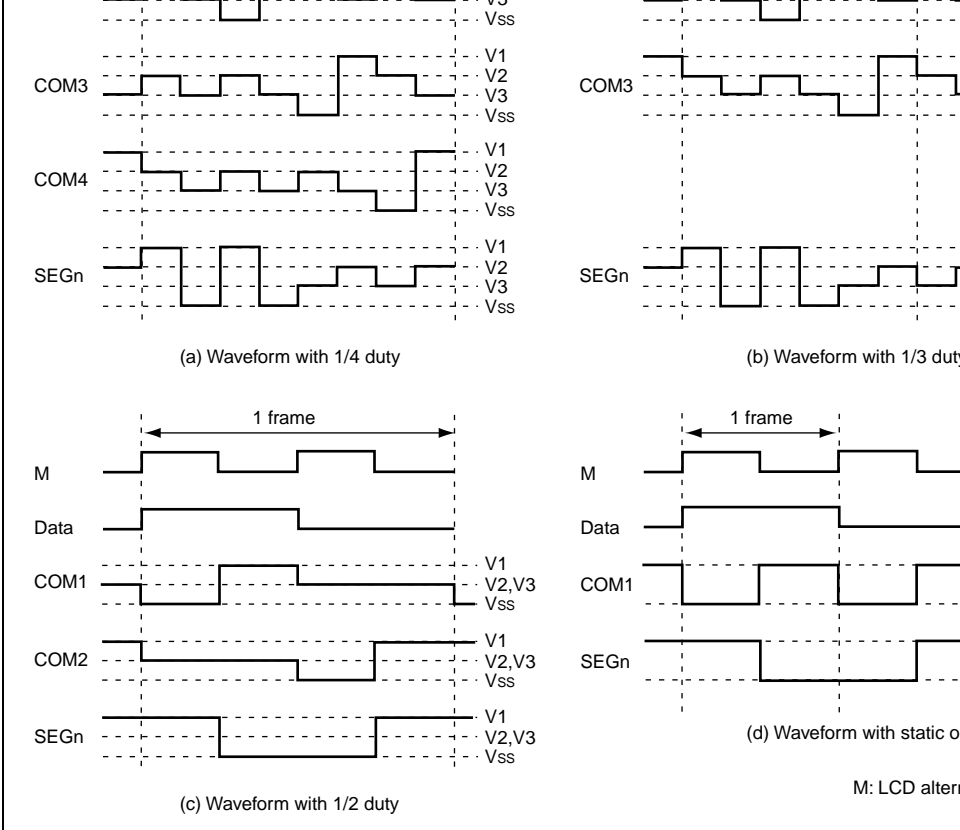


Figure 19.7 Output Waveforms for Each Duty Cycle (A Waveform)

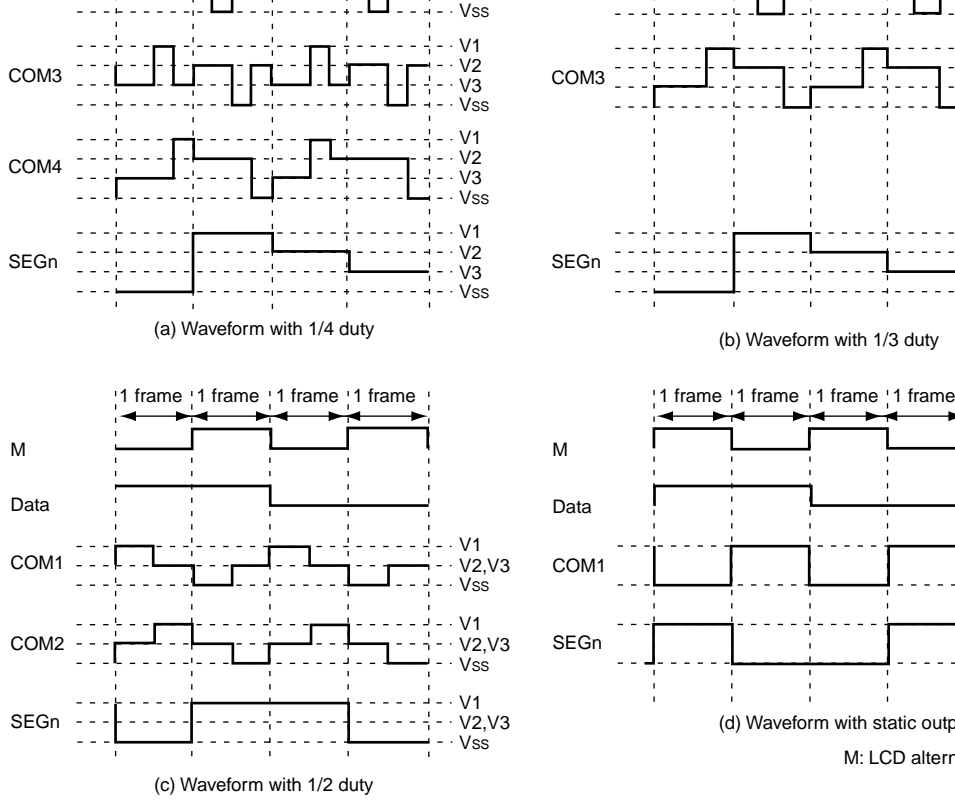


Figure 19.8 Output Waveforms for Each Duty Cycle (B Waveform)

1/3 duty	Common output	V3	V2	V1	VSS
	Segment output	V2	V3	VSS	V1
1/4 duty	Common output	V3	V2	V1	VSS
	Segment output	V2	V3	VSS	V1

M: LCD alternation signal

19.4.3 3-V Constant-Voltage Power Supply Circuit

This LSI incorporates a 3-V constant-voltage power supply circuit consisting of a band gap reference circuit (BGR), a triple step-up circuit, etc. This allows the 3 V constant voltage LCD driver independently of Vcc.

Before activating a step-up circuit, LCD controller/driver operates and set the duty cycle function of the LCD driver or I/O, display data, frame frequencies, etc. Insert a capacitor of 0.1 μF between the C1 pin and C2 pin, and connect a capacitance of 0.1 μF to each of V1, V2, and V3 pins. (See figure 19.9.)

After this setting, setting the BGRSTPN bit in the BGR control register (BGRMR) to 1 activates the band gap reference circuit, generating 1 V constant voltage (V_{LCD3}) at the V3 pin. Further, selecting the step-up circuit clock of the LCD control register 2 (LCR2) and setting the STPN bit to 1 activates the triple step-up circuit, generating 2 V constant voltage, twice V_{LCD3} , at the V2 pin and generating 3 V constant voltage, triple V_{LCD3} , at the V1 pin.

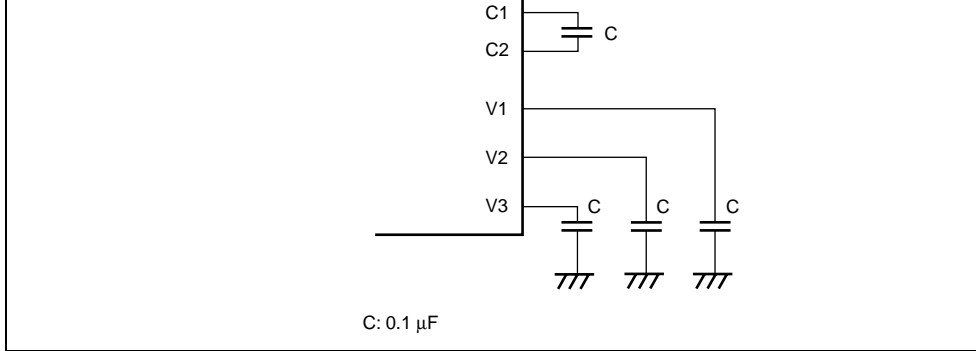


Figure 19.9 Capacitance Connection when Using 3-V Constant-Voltage Power Supply Circuit

19.4.4 Operation in Power-Down Modes

In this LSI, the LCD controller/driver can be operated even in the power-down modes. The operating state of the LCD controller/driver in the power-down modes is summarized in Table 19.6.

In subactive mode, watch mode, and subsleep mode, the system clock oscillator stops, and therefore, unless ϕ_w , $\phi_w/2$, or $\phi_w/4$ has been selected by bits CKS3 to CKS0, the clock will not be supplied and display will halt. The subclock can be turned on or off by setting the 32KST bit in the SUB32K control register (SUB32CR). When it is turned off, display will halt. Since there is a possibility that a direct current will be applied to the LCD panel in this case, it is essential to ensure that the subclock is turned on and ϕ_w , $\phi_w/2$, or $\phi_w/4$ is selected.

In active (medium-speed) mode, the system clock is switched, and therefore bits CKS3 to CKS0 must be modified to ensure that the frame frequency does not change.

3. Display operation is performed only if ϕ_w , $\phi_w/2$, or $\phi_w/4$ is selected as the open clock.
4. The clock supplied to the LCD stops.
5. When the 32KSTOP bit in SUB32CR is set to 1, the subclock ϕ_w halts and display operation halts.

19.4.5 Boosting LCD Drive Power Supply and Fine Adjustment

When a large panel is driven, the on-chip power supply capacity may be insufficient. In this case, the power supply impedance must be reduced. This can be done by connecting bypass capacitors of around 0.1 to 0.3 μF to pins V1 to V3, as shown in figure 19.10, or by adding a split resistor externally. The voltage on the V1 pin can further be adjusted by connecting a variable resistor (VR) between the V_{cc} and V1 pins.

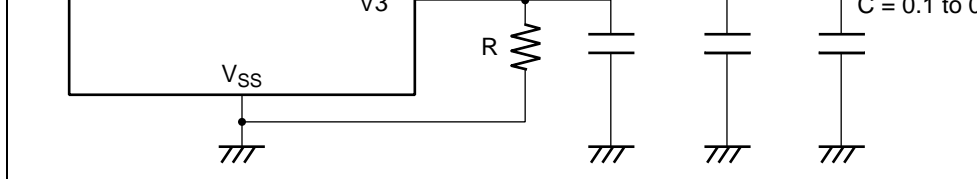


Figure 19.10 Connection of External Split Resistor

19.5 Usage Notes

19.5.1 Pin Processing when No LCD Controller/Driver Is Used

(1) V1, V2, V3

Connect to GND. In this case, CHG in LCR2 should not be changed from its initial value (LCD power-supply split resistor disconnected).

(2) C1, C2

Leave open.

19.5.2 Pin Processing when No 3 V Constant Voltage Circuit Is Used

Leave pins C1 and C2 open.

- Continuous transmission/reception
Since the shift register, transmit data register, and receive data register are independent of each other, the continuous transmission/reception can be performed.
- Use of module standby mode enables this module to be placed in standby mode independently when not used. (For details, refer to section 6.4, Module Standby Function.)

I²C bus format

- Start and stop conditions generated automatically in master mode
- Selection of acknowledge output levels when receiving
- Automatic loading of acknowledge bit when transmitting
- Bit synchronization/wait function

In master mode, the state of SCL is monitored per bit, and the timing is synchronized automatically.

If transmission/reception is not yet possible, set the SCL to low until preparations are completed.

- Six interrupt sources

Transmit data empty (including slave-address match), transmit end, receive data full (including slave-address match), arbitration lost, NACK detection, and stop condition detection

- Direct bus drive

Two pins, SCL and SDA pins, function as CMOS outputs in normal operation (when port/serial function is selected) and NMOS outputs when the bus drive function is selected.

Clocked synchronous format

- Four interrupt sources

Transmit-data-empty, transmit-end, receive-data-full, and overrun error

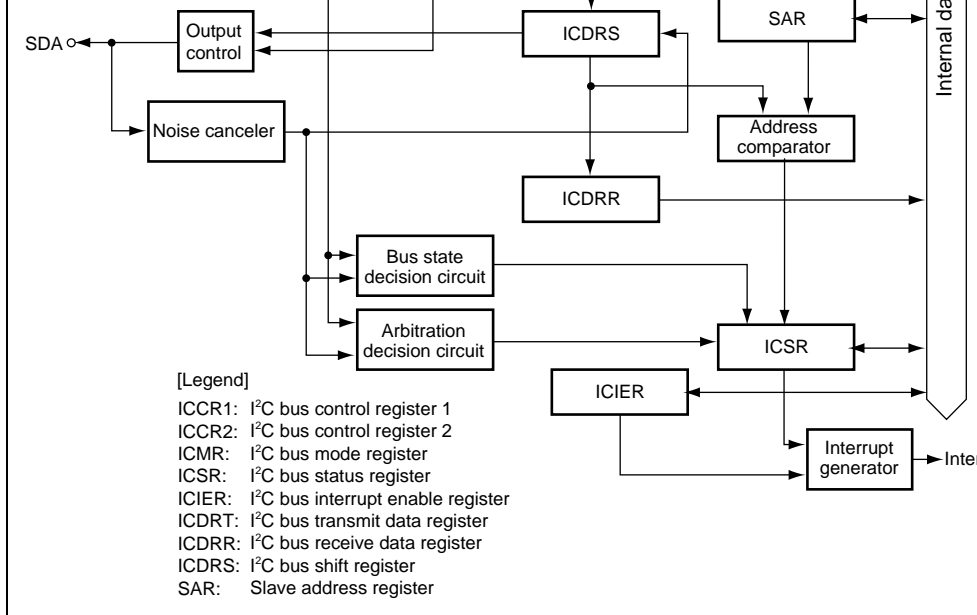


Figure 20.1 Block Diagram of I²C Bus Interface 2

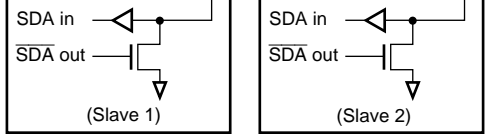


Figure 20.2 External Circuit Connections of I/O Pins

20.2 Input/Output Pins

Table 20.1 summarizes the input/output pins used by the I²C bus interface 2.

Table 20.1 Pin Configuration

Name	Abbreviation	I/O	Function
Serial clock pin	SCL	I/O	IIC serial clock input/output
Serial data pin	SDA	I/O	IIC serial data input/output

- I²C bus transmit data register (ICDRT)
- I²C bus receive data register (ICDRR)
- I²C bus shift register (ICDRS)

20.3.1 I²C Bus Control Register 1 (ICCR1)

ICCR1 enables or disables the I²C bus interface 2, controls transmission or reception, and master or slave mode, transmission or reception, and transfer clock frequency in master mode.

Bit	Bit Name	Initial Value	R/W	Description
7	ICE	0	R/W	<p>I2C Bus Interface Enable</p> <p>0: This module is halted. (SCL and SDA pins are in high impedance state.)</p> <p>1: This bit is enabled for transfer operations. (SCL and SDA pins are bus drive state.)</p>
6	RCVD	0	R/W	<p>Reception Disable</p> <p>This bit enables or disables the next operation. When TRS is 0 and ICDRR is read.</p> <p>0: Enables next reception</p> <p>1: Disables next reception</p>

agree with the slave address that is set to 0. If the eighth bit is 1, TRS is automatically set to 1. If an overrun error occurs in master mode with the synchronous serial format, MST is cleared to 0. In slave receive mode is entered.

Operating modes are described below according to the MST and TRS combination. When clocked synchronous serial format is selected and MST is 1, clock is

00: Slave receive mode

01: Slave transmit mode

10: Master receive mode

11: Master transmit mode

3	CKS3	0	R/W	Transfer Clock Select 3 to 0
2	CKS2	0	R/W	In master mode, set these bits according to the necessary transfer rate (see table 20.2, Transfer Rate). In slave mode, these bits are used to secure the data setup time in transmission mode. When CKS3 = 0, data setup time is 10 t _{cy} and when CKS3 = 1, data setup time is 20 t _{cy} .
1	CKS1	0	R/W	
0	CKS0	0	R/W	

		1	0	$\phi/112$	17.9 kHz	44.6 kHz	89.3
			1	$\phi/128$	15.6 kHz	39.1 kHz	78.1
1	0	0	0	$\phi/56$	35.7 kHz	89.3 kHz	179
			1	$\phi/80$	25.0 kHz	62.5 kHz	125
		1	0	$\phi/96$	20.8 kHz	52.1 kHz	104
			1	$\phi/128$	15.6 kHz	39.1 kHz	78.1
	1	0	0	$\phi/160$	12.5 kHz	31.3 kHz	62.5
			1	$\phi/200$	10.0 kHz	25.0 kHz	50.0
		1	0	$\phi/224$	8.9 kHz	22.3 kHz	44.6
			1	$\phi/256$	7.8 kHz	19.5 kHz	39.1

format, this bit has no meaning. With the I2C format, this bit is set to 1 when the SDA level from high to low under the condition of SCL = assuming that the start condition has been issued. This bit is cleared to 0 when the SDA level changes from low to high under the condition of SCL = high, assuming that the stop condition has been issued. Write 1 in BBSY and 0 to SCP to issue a start condition. Write 0 in BBSY and 1 to SCP to issue a stop condition. This procedure when also re-transmitting a start condition. Write 0 in BBSY and 0 in SCP to issue a start condition. Write 1 in BBSY and 1 in SCP to issue a stop condition. To issue start/stop conditions, use the I2C instruction.

6	SCP	1	R/W	<p>Start/Stop Issue Condition Disable</p> <p>The SCP bit controls the issue of start/stop conditions in master mode.</p> <p>To issue a start condition, write 1 in BBSY and 0 in SCP. A retransmit start condition is issued in master mode. To issue a stop condition, write 0 in BBSY and 1 in SCP. This bit is always read as 1. If 1 is written, start/stop data is not stored.</p>
5	SDAO	1	R/W	<p>SDA Output Value Control</p> <p>This bit is used with SDAOP when modifying the output level of SDA. This bit should not be manipulated during data transfer.</p> <p>0: When reading, SDA pin outputs low. When writing, SDA pin is changed to output high.</p> <p>1: When reading, SDA pin outputs high. When writing, SDA pin is changed to output low. (outputs high by external pull-up resistance)</p>

2	—	1	—	Reserved
This bit is always read as 1, and cannot be mo				
1	IICRST	0	R/W	IIC Control Part Reset
This bit resets the control part except for I2C re				
If this bit is set to 1 when hang-up occurs beca				
communication failure during I2C operation, I2				
part can be reset without setting ports and initia				
registers.				
0	—	1	—	Reserved
This bit is always read as 1, and cannot be mo				

6	WAIT	0	R/W	<p>Wait Insertion Bit</p> <p>In master mode with the I2C bus format, this bit controls whether to insert a wait after data transfer except after the acknowledge bit. When WAIT is set to 1, after the clock for the final data bit, low period is extended for two transfer clocks. If WAIT is cleared to 0, data and acknowledge bits are transferred consecutively without wait inserted.</p> <p>The setting of this bit is invalid in slave mode with the I2C bus format or with the clocked synchronous serial mode.</p>
5, 4	—	All 1	—	<p>Reserved</p> <p>These bits are always read as 1, and cannot be modified.</p>
3	BCWP	1	R/W	<p>BC Write Protect</p> <p>This bit controls the BC2 to BC0 modifications. When modifying BC2 to BC0, this bit should be cleared and use the MOV instruction. In clock synchronous serial mode, BC should not be modified.</p> <p>0: When writing, values of BC2 to BC0 are set. 1: When reading, 1 is always read.</p> <p>When writing, settings of BC2 to BC0 are invalid.</p>

the clock synchronous serial format, these bits not be modified.

I2C Bus Format	Clock Synchronous Serial
000: 9 bits	000: 8 bits
001: 2 bits	001: 1 bits
010: 3 bits	010: 2 bits
011: 4 bits	011: 3 bits
100: 5 bits	100: 4 bits
101: 6 bits	101: 5 bits
110: 7 bits	110: 6 bits
111: 8 bits	111: 7 bits

disabled.

1: Transmit data empty interrupt request (TXI) enabled.

6	TEIE	0	R/W	<p>Transmit End Interrupt Enable</p> <p>This bit enables or disables the transmit end interrupt request (TEI) at the rising of the ninth clock while the transmit data empty interrupt request (TXI) is enabled in ICSR is 1. TEI can be canceled by clearing the TXI bit or the TEIE bit to 0.</p> <p>0: Transmit end interrupt request (TEI) is disabled.</p> <p>1: Transmit end interrupt request (TEI) is enabled.</p>
5	RIE	0	R/W	<p>Receive Interrupt Enable</p> <p>This bit enables or disables the receive data full interrupt request (RXI) and the overrun error interrupt request (ERI) with the clocked synchronous format when a receive data is transferred from ICDR to ICDRR and the RDRF bit in ICSR is set to 1. RXI and ERI can be canceled by clearing the RDRF or RIE bit to 0.</p> <p>0: Receive data full interrupt request (RXI) and the overrun error interrupt request (ERI) with the clocked synchronous format are disabled.</p> <p>1: Receive data full interrupt request (RXI) and the overrun error interrupt request (ERI) with the clocked synchronous format are enabled.</p>

3	STIE	0	R/W	<p>Stop Condition Detection Interrupt Enable</p> <p>0: Stop condition detection interrupt request (S disabled).</p> <p>1: Stop condition detection interrupt request (S enabled).</p>
2	ACKE	0	R/W	<p>Acknowledge Bit Judgment Select</p> <p>0: The value of the receive acknowledge bit is and continuous transfer is performed.</p> <p>1: If the receive acknowledge bit is 1, continuous transfer is halted.</p>
1	ACKBR	0	R	<p>Receive Acknowledge</p> <p>In transmit mode, this bit stores the acknowledge that are returned by the receive device. This bit can be modified.</p> <p>0: Receive acknowledge = 0</p> <p>1: Receive acknowledge = 1</p>
0	ACKBT	0	R/W	<p>Transmit Acknowledge</p> <p>In receive mode, this bit specifies the bit to be sent at the acknowledge timing.</p> <p>0: 0 is sent at the acknowledge timing.</p> <p>1: 1 is sent at the acknowledge timing.</p>

- When TRS is set
- When a start condition (including re-transfer) has been issued
- When transmit mode is entered from receive slave mode

[Clearing conditions]

- When 0 is written in TDRE after reading TDR
- When data is written to ICDRT with an instruction

6	TEND	0	R/W
---	------	---	-----

Transmit End

[Setting conditions]

- When the ninth clock of SCL rises with the 1st format while the TDRE flag is 1
- When the final bit of transmit frame is sent with clock synchronous serial format

[Clearing conditions]

- When 0 is written in TEND after reading TEND
- When data is written to ICDRT with an instruction

5	RDRF	0	R/W
---	------	---	-----

Receive Data Register Full

[Setting condition]

- When a receive data is transferred from ICDRT to ICDRR

[Clearing conditions]

- When 0 is written in RDRF after reading RDRF
 - When ICDRR is read with an instruction
-

- When a stop condition is detected after completing a frame transfer in master mode
- When a stop condition is detected after the final slave address and SAR match following a general call and detection of a start condition in slave mode

[Clearing condition]

- When 0 is written to STOP after reading 1

2	AL/OVE	0	R/W
---	--------	---	-----

Arbitration Lost Flag/Overrun Error Flag

This flag indicates that arbitration was lost in master mode with the I²C bus format and that the final bit has been received while RDRF = 1 with the clocked synchronous format.

When two or more master devices attempt to seize the bus at nearly the same time, if the I²C bus interface detects data differing from the data it sent, it sets this flag to indicate that the bus has been taken by another master.

[Setting conditions]

- If the internal SDA and SDA pin disagree at the start of the SCL in master transmit mode
- When the SDA pin outputs high in master mode and a start condition is detected
- When the final bit is received with the clocked synchronous format while RDRF = 1

[Clearing condition]

- When 0 is written in AL/OVE after reading AL
-

				receive mode. [Clearing condition] <ul style="list-style-type: none"> When 0 is written in AAS after reading AAS=
0	ADZ	0	R/W	General Call Address Recognition Flag This bit is valid in I ² C bus format slave receive m [Setting condition] <ul style="list-style-type: none"> When the general call address is detected in receive mode [Clearing conditions] <ul style="list-style-type: none"> When 0 is written in ADZ after reading ADZ=

20.3.6 Slave Address Register (SAR)

SAR selects the communication format and sets the slave address. When the chip is in slave mode with the I²C bus format, if the upper 7 bits of SAR match the upper 7 bits of the first frame received after a start condition, the chip operates as the slave device.

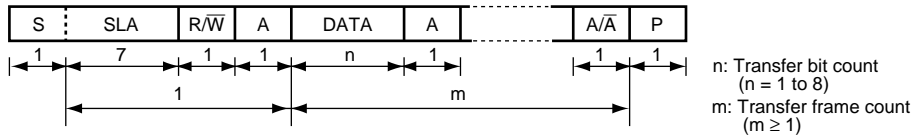
Bit	Bit Name	Initial Value	R/W	Description
7 to 1	SVA6 to SVA0	All 0	R/W	Slave Address 6 to 0 These bits set a unique address in bits SVA6 to SVA0, differing from the addresses of other slave devices connected to the I ² C bus.
0	FS	0	R/W	Format Select 0: I ² C bus format is selected. 1: Clocked synchronous serial format is selected.

ICDRR is an 8-bit register that stores the receive data. When data of one byte is received, transfers the receive data from ICDRS to ICDRR and the next data can be received. ICDRR is a receive-only register, therefore the CPU cannot write to this register. The initial value of ICDRR is H'FF.

20.3.9 I²C Bus Shift Register (ICDRS)

ICDRS is a register that is used to transfer/receive data. In transmission, data is transferred from ICDRS to ICDRT and the data is sent from the SDA pin. In reception, data is transferred from ICDRR to ICDRS after data of one byte is received. This register cannot be read directly by the CPU.

(a) I²C bus format (FS = 0)



(b) I²C bus format (Start condition retransmission, FS = 0)

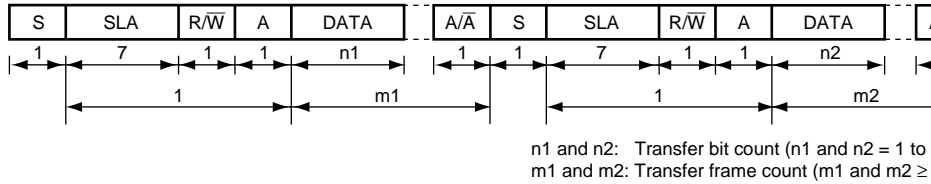


Figure 20.3 I²C Bus Formats

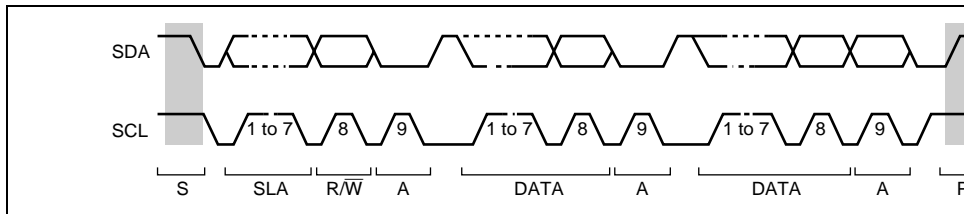


Figure 20.4 I²C Bus Timing

In master transmit mode, the master device outputs the transmit clock and transmit data, and the slave device returns an acknowledge signal. For master transmit mode operation timing, refer to figures 20.5 and 20.6. The transmission procedure and operations in master transmit mode are described below.

1. Set the ICE bit in ICCR1 to 1. Set the MLS and WAIT bits in ICMR and the CKS3 to CKS0 bits in ICCR1 to 1. (Initial setting)
2. Read the BBSY flag in ICCR2 to confirm that the bus is free. Set the MST and TRS bits in ICCR1 to select master transmit mode. Then, write 1 to BBSY and 0 to SCP using MOV instruction. (Start condition issued) This generates the start condition.
3. After confirming that TDRE in ICSR has been set, write the transmit data (the first byte shows the slave address and R/\overline{W}) to ICDRT. At this time, TDRE is automatically cleared and data is transferred from ICDRT to ICDRS. TDRE is set again.
4. When transmission of one byte data is completed while TDRE is 1, TEND in ICSR is set at the rise of the 9th transmit clock pulse. Read the ACKBR bit in ICIER, and confirm that the slave device has been selected. Then, write second byte data to ICDRT. When ACKBR is 0, the slave device has not been acknowledged, so issue the stop condition. To issue the stop condition, write 0 to BBSY and SCP using MOV instruction. SCL is fixed low until the transmit data is prepared or the stop condition is issued.
5. The transmit data after the second byte is written to ICDRT every time TDRE is set.
6. Write the number of bytes to be transmitted to ICDRT. Wait until TEND is set (the end of byte data transmission) while TDRE is 1, or wait for NACK (NACKF in ICSR = 1) from the receive device while ACKE in ICIER is 1. Then, issue the stop condition to clear TEND and NACKF.
7. When the STOP bit in ICSR is set to 1, the operation returns to the slave receive mode.

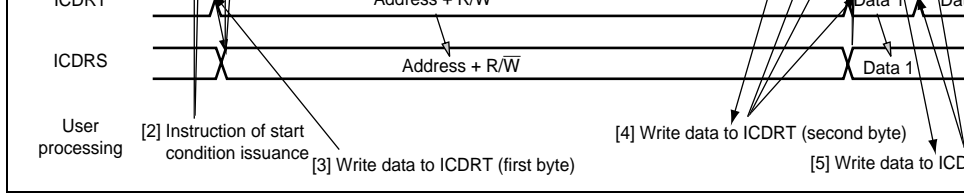


Figure 20.5 Master Transmit Mode Operation Timing (1)

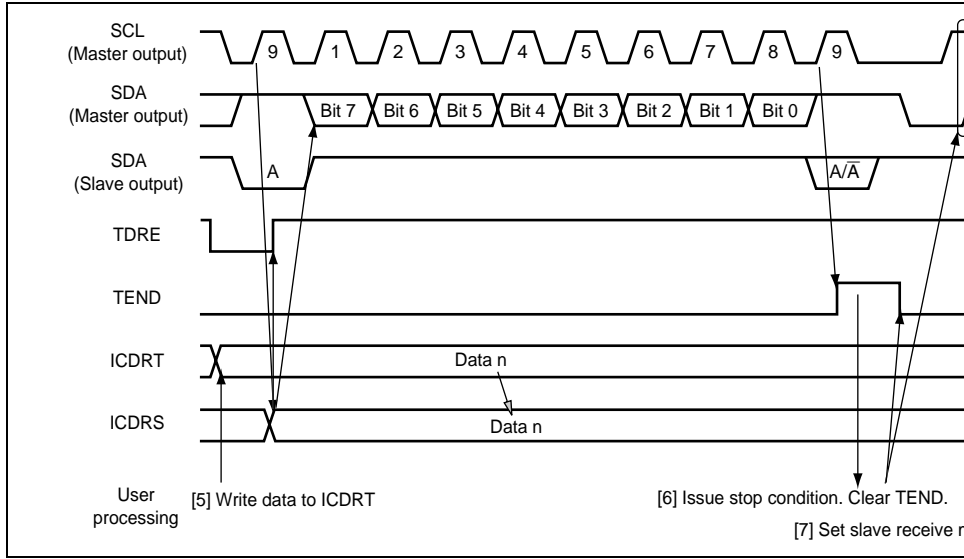


Figure 20.6 Master Transmit Mode Operation Timing (2)

2. When ICDRR is read (dummy data read), reception is started, and the receive clock is and data received, in synchronization with the internal clock. The master device outputs level specified by ACKBT in ICIER to SDA, at the 9th receive clock pulse.
3. After the reception of first frame data is completed, the RDRF bit in ICST is set to 1 at the rise of 9th receive clock pulse. At this time, the receive data is read by reading ICDRR, and RDRF is cleared to 0.
4. The continuous reception is performed by reading ICDRR every time RDRF is set. If RDRF is set, the receive clock pulse falls after reading ICDRR by the other processing while RDRF is fixed low until ICDRR is read.
5. If next frame is the last receive data, set the RCVD bit in ICCR1 and set the ACKBT in ICIER. to 1 before reading ICDRR. This enables the issuance of the stop condition after the next reception.
6. When the RDRF bit is set to 1 at rise of the 9th receive clock pulse, and clearing the STOP bit in ICSR issue the stage condition.
7. When the STOP bit in ICSR is set to 1, read ICDRR. Then clear the RCVD bit to 0.
8. Clear the MST bit in ICCR1 and then, the operation returns to the slave receive mode.

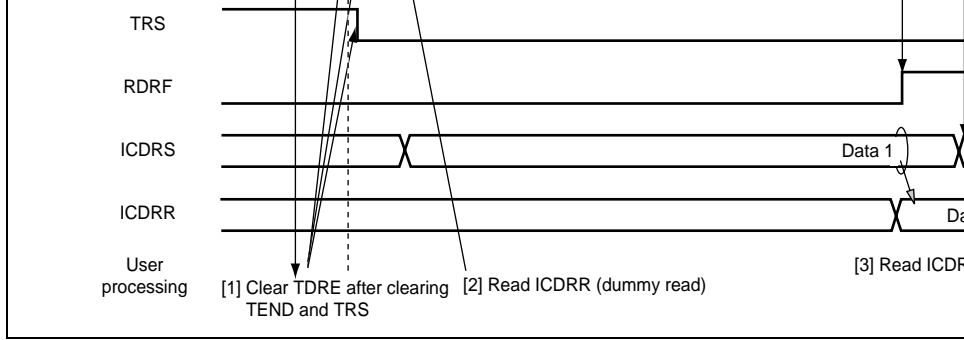


Figure 20.7 Master Receive Mode Operation Timing (1)

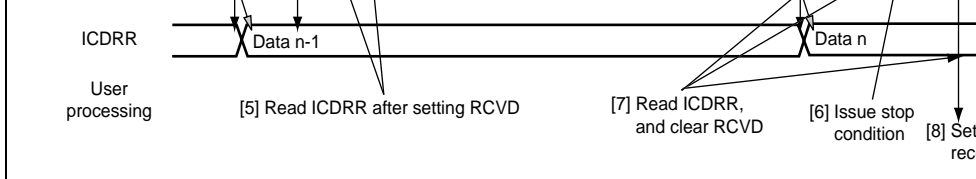


Figure 20.8 Master Receive Mode Operation Timing (2)

2. When the slave address matches in the first frame following detection of the start condition, the slave device outputs the level specified by ACKBT in ICIER to SDA, at the rise of the clock pulse. At this time, if the 8th bit data (R/\overline{W}) is 1, the TRS and ICSR bits in ICDRT are set to 1, and the mode changes to slave transmit mode automatically. The continuous transmission is performed by writing transmit data to ICDRT every time TDRE is set.
3. If TDRE is set after writing last transmit data to ICDRT, wait until TEND in ICSR is set with TDRE = 1. When TEND is set, clear TEND.
4. Clear TRS for the end processing, and read ICDRR (dummy read). SCL is free.
5. Clear TDRE.

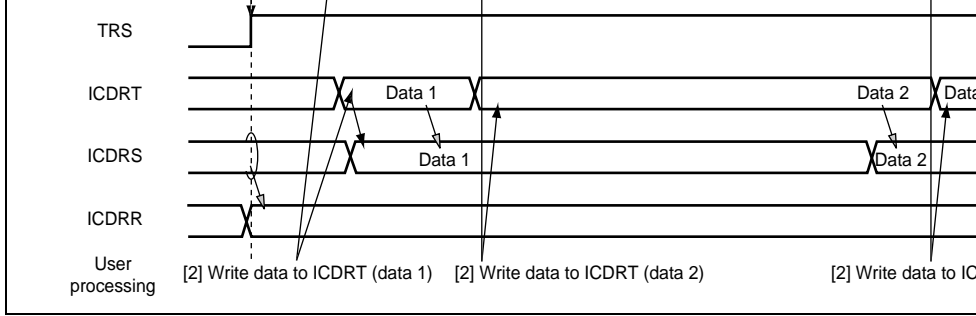


Figure 20.9 Slave Transmit Mode Operation Timing (1)

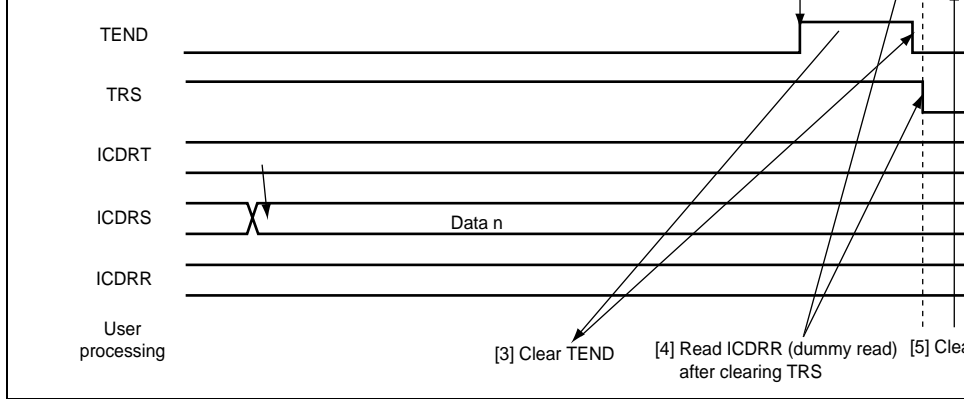


Figure 20.10 Slave Transmit Mode Operation Timing (2)

20.4.5 Slave Receive Operation

In slave receive mode, the master device outputs the transmit clock and transmit data, and the slave device returns an acknowledge signal. For slave receive mode operation timing, refer to figures 20.11 and 20.12. The reception procedure and operations in slave receive mode are described below.

1. Set the ICE bit in ICCR1 to 1. Set the MLS and WAIT bits in ICMR and the CKS3 bits in ICCR1 to 1. (Initial setting) Set the MST and TRS bits in ICCR1 to select slave mode, and wait until the slave address matches.
2. When the slave address matches in the first frame following detection of the start condition, the slave device outputs the level specified by ACKBT in ICIER to SDA, at the rise of the clock pulse. At the same time, RDRF in ICSR is set to read ICDRR (dummy read). (When reading data, the read data show the slave address and $\overline{R/\overline{W}}$, it is not used.)

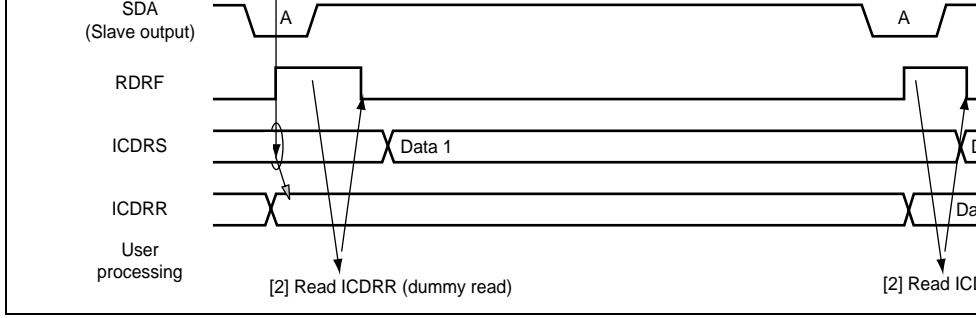


Figure 20.11 Slave Receive Mode Operation Timing (1)

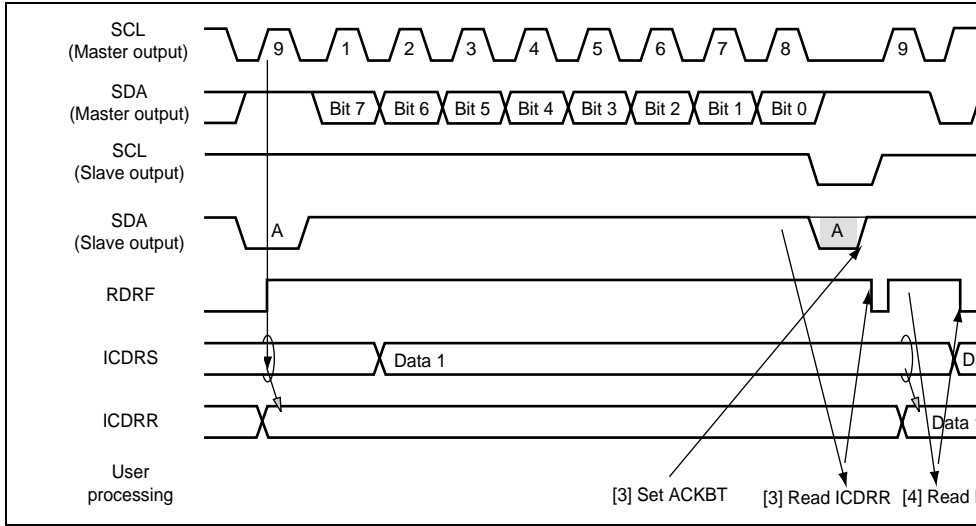


Figure 20.12 Slave Receive Mode Operation Timing (2)

of the SCL clock is guaranteed. The MLS bit in ICMR sets the order of data transfer, in MSB first or LSB first. The output level of SDA can be changed during the transfer wait SDAO bit in ICCR2.

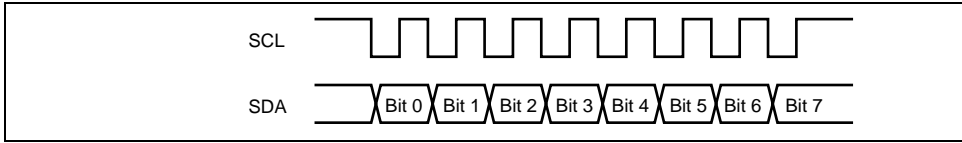


Figure 20.13 Clocked Synchronous Serial Transfer Format

transferred from ICDRT to ICDRS, and TDRE is set automatically. The continuous transmission is performed by writing data to ICDRT every time TDRE is set. When changing from transmit mode to receive mode, clear TRS while TDRE is 1.

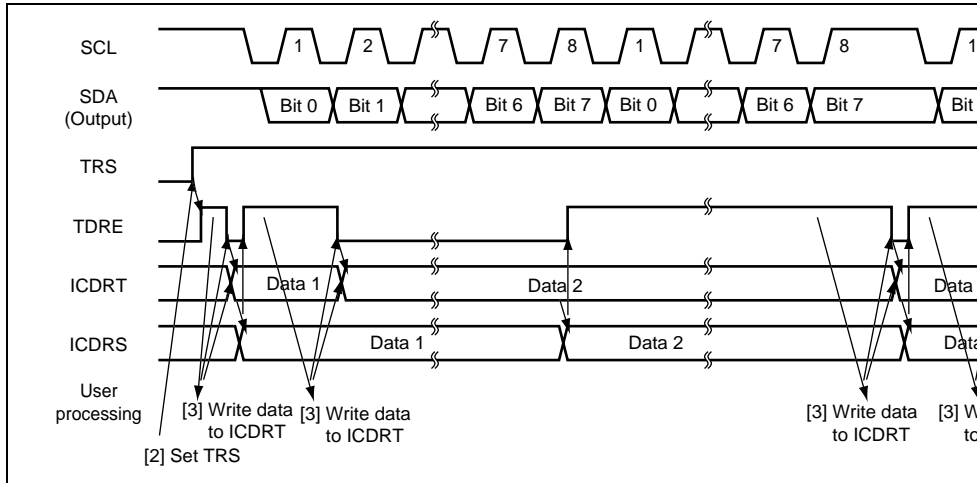


Figure 20.14 Transmit Mode Operation Timing

continually output. The continuous reception is performed by reading ICDRR every time RDRF is set. When the 8th clock is risen while RDRF is 1, the overrun is detected and AL/OVE in ICSR is set. At this time, the previous reception data is retained in ICDRR.

- To stop receiving when $MST = 1$, set RCVD in ICCR1 to 1, then read ICDRR. Then, RDRF is fixed high after receiving the next byte data.

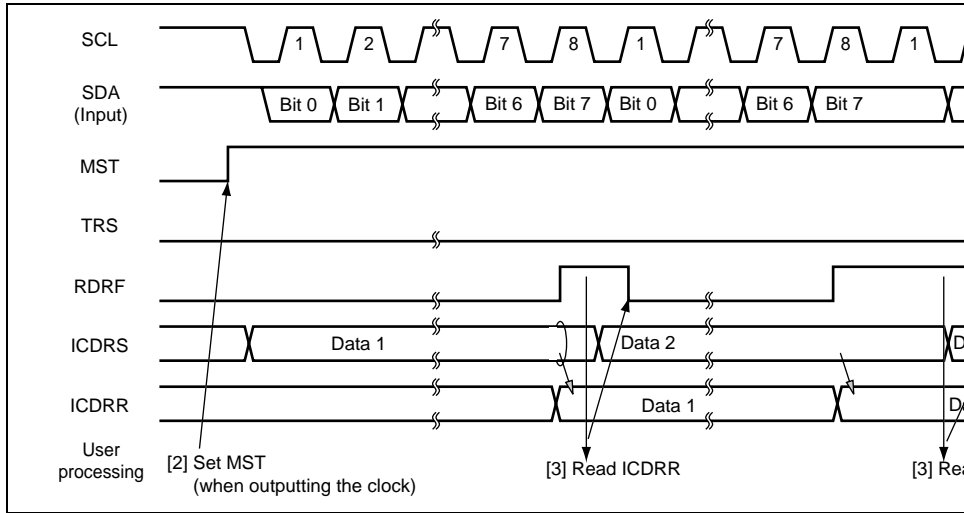


Figure 20.15 Receive Mode Operation Timing

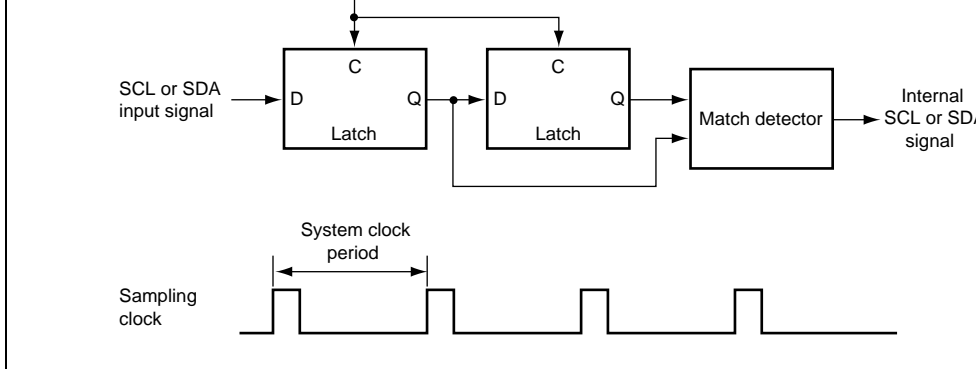


Figure 20.16 Block Diagram of Noise Concener

20.4.8 Example of Use

Flowcharts in respective modes that use the I²C bus interface are shown in figures 20.17 t

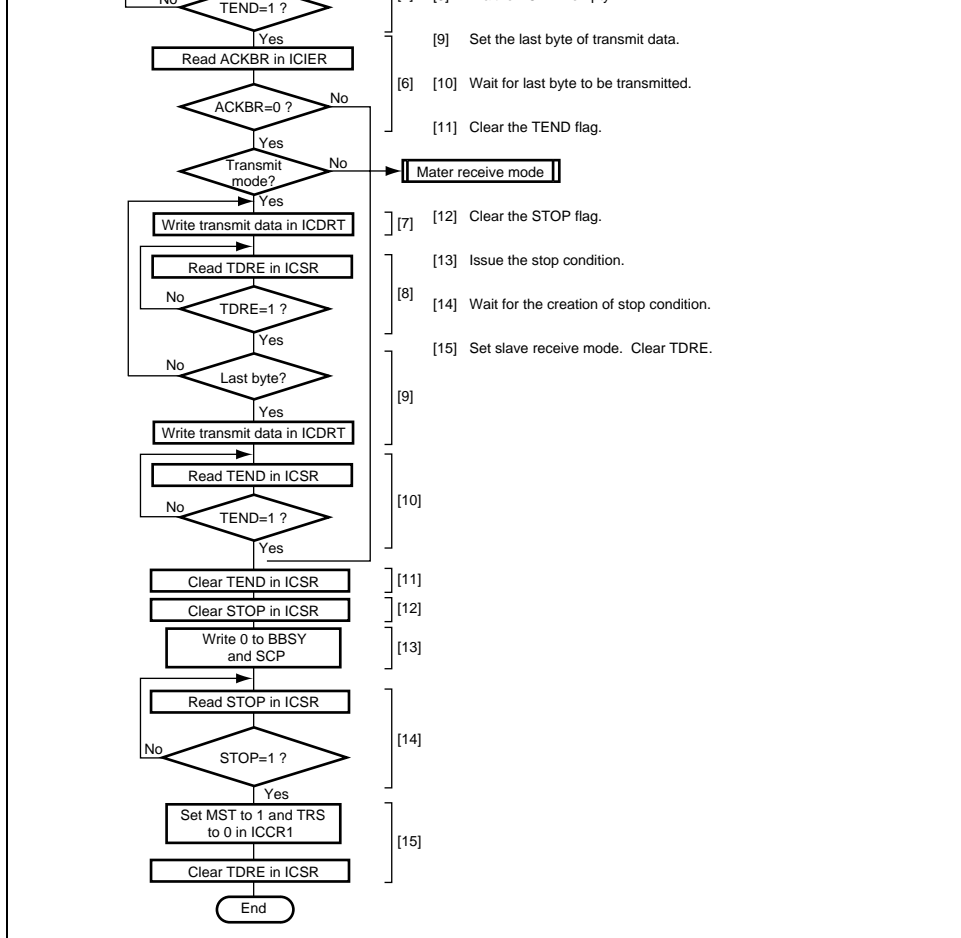


Figure 20.17 Sample Flowchart for Master Transmit Mode

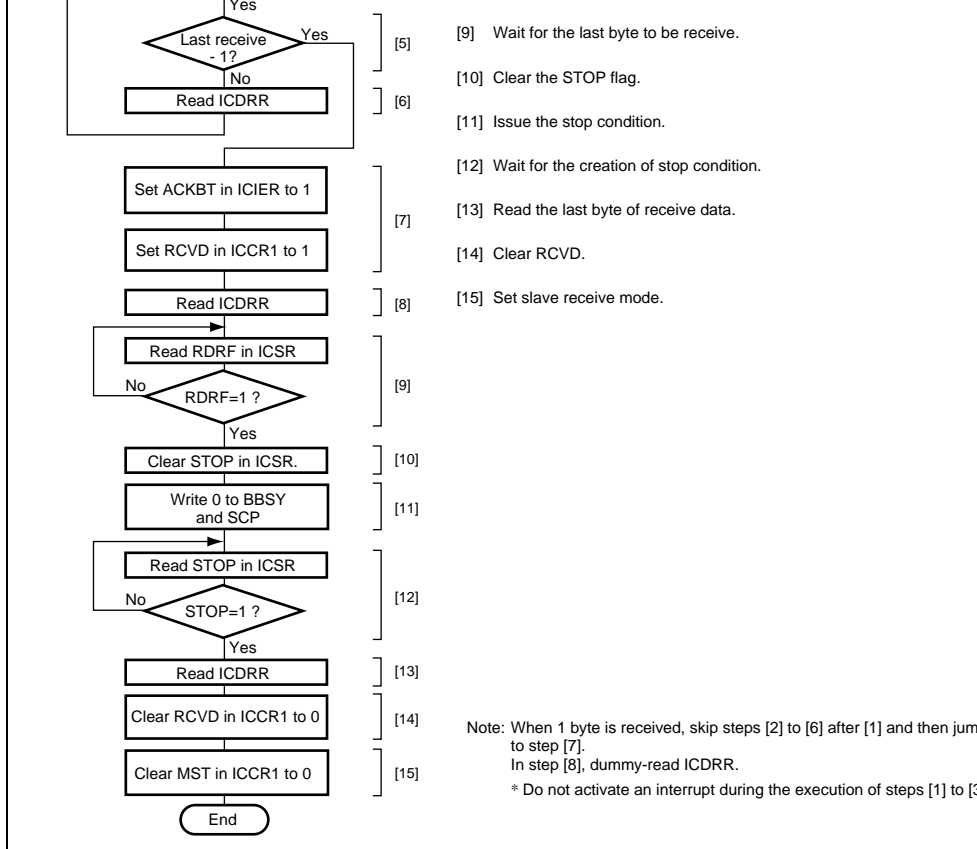


Figure 20.18 Sample Flowchart for Master Receive Mode

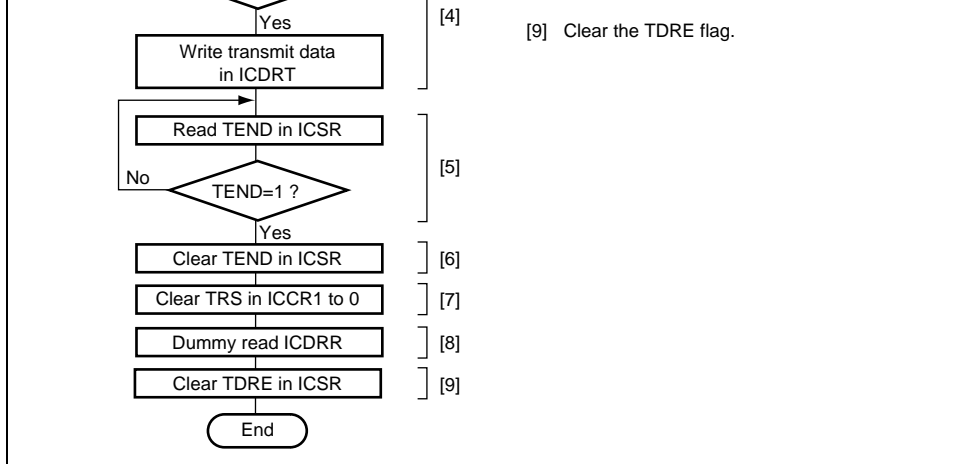


Figure 20.19 Sample Flowchart for Slave Transmit Mode

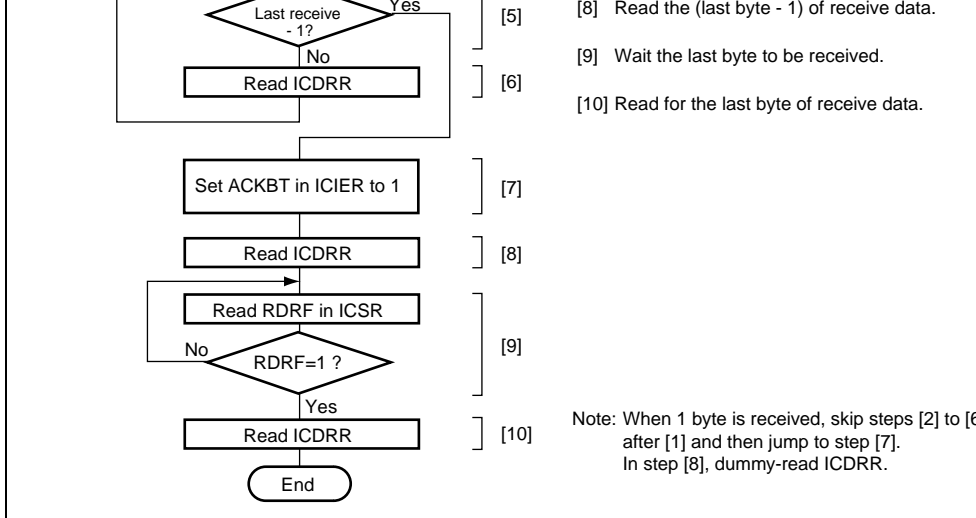


Figure 20.20 Sample Flowchart for Slave Receive Mode

Transmit Data Empty	TXI	$(TDRE=1) \cdot (TIE=1)$	○	○
Transmit End	TEI	$(TEND=1) \cdot (TEIE=1)$	○	○
Receive Data Full	RXI	$(RDRF=1) \cdot (RIE=1)$	○	○
STOP Recognition	STPI	$(STOP=1) \cdot (STIE=1)$	○	×
NACK Receive	NAKI	$\{(NACKF=1)+(AL=1)\} \cdot (NAKIE=1)$	○	×
Arbitration Lost/Overrun			○	○

When interrupt conditions described in table 20.3 are 1 and the I bit in CCR is 0, the CPU executes interrupt exception processing. Interrupt sources should be cleared in the exception processing. TDRE and TEND are automatically cleared to 0 by writing the transmit data to ICDRT. RDRF are automatically cleared to 0 by reading ICDRR. TDRE is set to 1 again at the same time when transmit data is written to ICDRT. When TDRE is cleared to 0, then another data of one byte may be transmitted.

Figure 20.21 shows the timing of the bit synchronous circuit and table 20.4 shows the time for monitoring SCL output changes from low to Hi-Z then SCL is monitored.

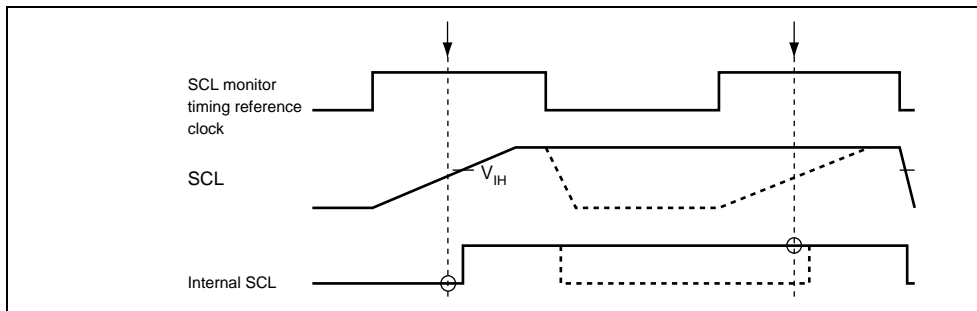


Figure 20.21 Timing of Bit Synchronous Circuit

Table 20.4 Time for Monitoring SCL

CKS3	CKS2	Time for Monitoring SCL
0	0	7.5 tcyc
	1	19.5 tcyc
1	0	17.5 tcyc
	1	41.5 tcyc

during the eighth clock.

2. The WAIT bit in the I2C bus mode register (ICMR) must be held 0.

If the WAIT bit is set to 1, when a slave device holds the SCL signal low more than one transfer clock cycle during the eighth clock, the high level period of the ninth clock must be shorter than a given period.

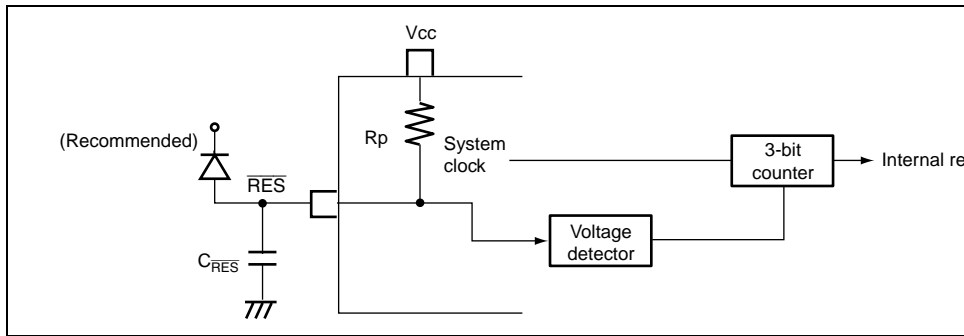


Figure 21.1 Power-On Reset Circuit

If the $\overline{\text{RES}}$ pin rising time is t , the capacitance ($C_{\overline{\text{RES}}}$) connected to the $\overline{\text{RES}}$ pin can be calculated using the formula below. For information about the on-chip resistor (R_p), see section 24, Characteristics. The power supply rising time should not exceed half the $\overline{\text{RES}}$ rising time. $\overline{\text{RES}}$ rising time (t) should also equal or exceed the oscillation stabilization time (trc).

$$C_{\overline{\text{RES}}} = \frac{t}{R_p} \quad (t > trc, t > t_{vtr} \times 2)$$

Note: Adjust the capacitor connected to the $\overline{\text{RES}}$ pin so that $t_{vtr} \times 2$ exceeds the oscillation stabilization time.

Note that the power supply voltage (V_{cc}) must fall below $V_{por} = 100 \text{ mV}$ and rise after the $\overline{\text{RES}}$ pin is removed. To remove charge on the $\overline{\text{RES}}$ pin, it is recommended that the diode should be placed near V_{cc} . If the power supply voltage (V_{cc}) rises from the point above V_{por} , power-on reset may not occur.

Figure 21.2 Power-On Reset Circuit Operation Timing

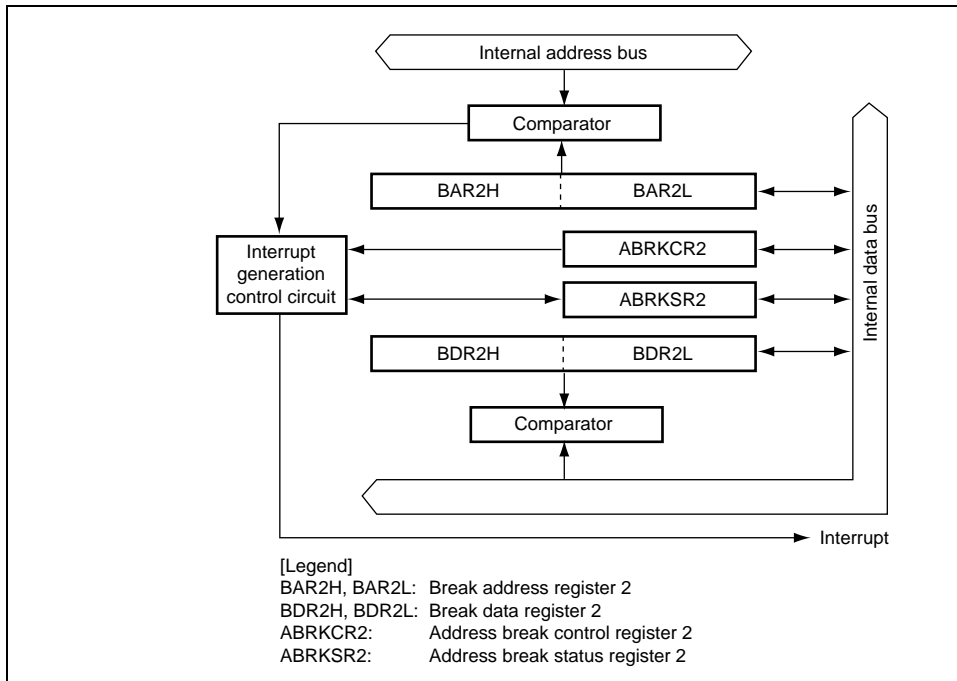


Figure 22.1 Block Diagram of Address Break

ABRKCR2 sets address break conditions.

Bit	Bit Name	Initial Value	R/W	Description
7	RTINTE2	1	R/W	RTE Interrupt Enable When this bit is 0, the interrupt immediately after executing RTE is masked and then one instruction can be executed. When this bit is 1, the interrupt is masked.
6	CSEL21	0	R/W	Condition Select 1 and 0
5	CSEL20	0	R/W	These bits set address break conditions. 00: Instruction execution cycle (no data comparison) 01: CPU data read cycle 10: CPU data write cycle 11: CPU data read/write cycle
4	ACMP22	0	R/W	Address Compare Condition Select 2 to 0
3	ACMP21	0	R/W	These bits set the comparison condition between the address set in BAR2 and the internal address.
2	ACMP20	0	R/W	000: Compares 16-bit addresses 001: Compares upper 12-bit addresses 010: Compares upper 8-bit addresses 011: Compares upper 4-bit addresses 1xx: Setting prohibited

[Legend] x: Don't care.

When an address break is set in the data read cycle or data write cycle, the data bus used depend on the combination of the byte/word access and address. Table 22.1 shows the data bus used. When an I/O register space with an 8-bit data bus width is accessed in word access, a byte access is generated twice. For details on data widths of each register, see section 23 (Register Addresses (Address Order)).

Table 22.1 Access and Data Bus Used

	Word Access		Byte Access	
	Even Address	Odd Address	Even Address	Odd Address
ROM space	Upper 8 bits	Lower 8 bits	Upper 8 bits	Upper 8 bits
RAM space	Upper 8 bits	Lower 8 bits	Upper 8 bits	Upper 8 bits
I/O register with 8-bit data bus width	Upper 8 bits	Upper 8 bits	Upper 8 bits	Upper 8 bits
I/O register with 16-bit data bus width* ¹	Upper 8 bits	Lower 8 bits	—	—
I/O register with 16-bit data bus width* ²	Upper 8 bits	Lower 8 bits	Upper 8 bits	Upper 8 bits

Notes: 1. Registers whose addresses do not range from H'FF96 and H'FF97, and H'FF98 and H'FF99, and H'FFA0 and H'FFA1, and H'FFB0 and H'FFB1, and H'FFB2 and H'FFB3, and H'FFB4 and H'FFB5, and H'FFB6 and H'FFB7, and H'FFB8 and H'FFB9, and H'FFC0 and H'FFC1, and H'FFC2 and H'FFC3, and H'FFC4 and H'FFC5, and H'FFC6 and H'FFC7, and H'FFC8 and H'FFC9, and H'FFD0 and H'FFD1, and H'FFD2 and H'FFD3, and H'FFD4 and H'FFD5, and H'FFD6 and H'FFD7, and H'FFD8 and H'FFD9, and H'FFE0 and H'FFE1, and H'FFE2 and H'FFE3, and H'FFE4 and H'FFE5, and H'FFE6 and H'FFE7, and H'FFE8 and H'FFE9, and H'FFF0 and H'FFF1, and H'FFF2 and H'FFF3, and H'FFF4 and H'FFF5, and H'FFF6 and H'FFF7, and H'FFF8 and H'FFF9 with 16-bit data bus width.

2. Registers whose addresses range from H'FF96 and H'FF97, and H'FFB8 to H'FFB9, and H'FFC8 to H'FFC9, and H'FFD8 to H'FFD9, and H'FFE8 to H'FFE9, and H'FFF8 to H'FFF9.

6	ABIE2	0	R/W	Address Break Interrupt Enable When this bit is 1, an address break interrupt is enabled.
5 to 0	—	All 1	—	Reserved These bits are always read as 1.

22.1.3 Break Address Registers 2 (BAR2H, BAR2L)

BAR2H and BAR2L are 16-bit read/write registers that set the address for generating an address break interrupt. When setting the address break condition to the instruction execution cycle, the register sets the first byte address of the instruction. The initial value of this register is H'FFFF.

22.1.4 Break Data Registers 2 (BDR2H, BDR2L)

BDR2H and BDR2L are 16-bit read/write registers that set the data for generating an address break interrupt. BDR2H is compared with the upper 8-bit data bus. BDR2L is compared with the lower 8-bit data bus. When memory or registers are accessed by byte, the upper 8-bit data bus is used for even and odd addresses in the data transmission. Therefore, comparison data must be set in BDR2H for byte access. For word access, the data bus used depends on the address. See Section 22.1.1, Address Break Control Register 2 (ABRKCR2), for details. The initial value of this register is undefined.

Register setting

- ABRKCR2 = H'80
- BAR2 = H'025A

Program

```

0258  NOP
* 025A  NOP
025C  MOV.W @H'025A,R0
0260  NOP
0262  NOP
:      :
    
```

Underline indicates the address to be stacked.

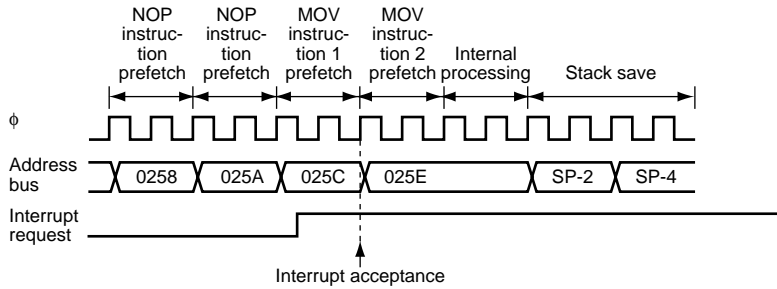


Figure 22.2 Address Break Interrupt Operation Example (1)

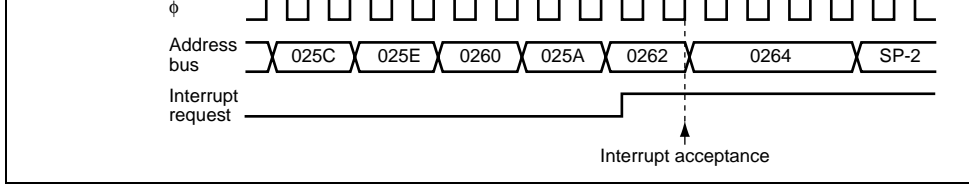


Figure 22.2 Address Break Interrupt Operation Example (2)

22.3 Operating States of Address Break

The operating states of the address break are shown in table 22.2.

Table 22.2 Operating States of Address Break

Operating Mode	Reset	Active	Sleep	Watch	Sub-active	Sub-sleep	Standby	M S
ABRKCR2	Reset	Functions	Retained	Retained	Functions	Retained	Retained	R
ABRKSr2	Reset	Functions	Retained	Retained	Functions	Retained	Retained	R
BAR2H	Reset	Functions	Retained	Retained	Functions	Retained	Retained	R
BAR2L	Reset	Functions	Retained	Retained	Functions	Retained	Retained	R
BDR2H	Retained*	Functions	Retained	Retained	Functions	Retained	Retained	R
BDR2L	Retained*	Functions	Retained	Retained	Functions	Retained	Retained	R

Note: * Undefined at a power-on reset

- The number of access states is indicated.
2. Register bits
 - Bit configurations of the registers are described in the same order as the register address.
 - Reserved bits are indicated by — in the bit name column.
 - When registers consist of 16 bits, bits are described from the MSB side.
 3. Register states in each operating mode
 - Register states are described in the same order as the register addresses.
 - The register states described here are for the basic operating modes. If there is a special mode for an on-chip peripheral module, refer to the section on that on-chip peripheral module.

Transmit data register 4	TDR4	8	H'F00E	SCI4	8
Receive data register 4	RDR4	8	H'F00F	SCI4	8
Flash memory control register 1	FLMCR1	8	H'F020	ROM	8
Flash memory control register 2	FLMCR2	8	H'F021	ROM	8
Flash memory power control register	FLPWCR	8	H'F022	ROM	8
Erase block register1	EBR1	8	H'F023	ROM	8
Flash memory enable register	FENR	8	H'F02B	ROM	8
Timer start register	TSTR	8	H'F030	TPU	8
Timer synchro register	TSYR	8	H'F031	TPU	8
Timer control register_1	TCR_1	8	H'F040	TPU_1	8
Timer mode register_1	TMDR_1	8	H'F041	TPU_1	8
Timer I/O control register_1	TIOR_1	8	H'F042	TPU_1	8
Timer interrupt enable register_1	TIER_1	8	H'F044	TPU_1	8
Timer status register_1	TSR_1	8	H'F045	TPU_1	8
Timer counter_1	TCNT_1	16	H'F046	TPU_1	16
Timer general register A_1	TGRA_1	16	H'F048	TPU_1	16
Timer general register B_1	TGRB_1	16	H'F04A	TPU_1	16
Timer control register_2	TCR_2	8	H'F050	TPU_2	8
Timer mode register_2	TMDR_2	8	H'F051	TPU_2	8
Timer I/O control register_2	TIOR_2	8	H'F052	TPU_2	8
Timer interrupt enable register_2	TIER_2	8	H'F054	TPU_2	8
Timer status register_2	TSR_2	8	H'F055	TPU_2	8
Timer counter_2	TCNT_2	16	H'F056	TPU_2	16

Day-of-week data register	RWKDR	8	H'F06B	RTC	8
RTC control register 1	RTCCR1	8	H'F06C	RTC	8
RTC control register 2	RTCCR2	8	H'F06D	RTC	8
SUB32k control register	SUB32CR	8	H'F06E	Clock pulse generator	8
Clock source select register	RTCCSR	8	H'F06F	RTC	8
I ² C bus control register 1	ICCR1	8	H'F078	IIC2	8
I ² C bus control register 2	ICCR2	8	H'F079	IIC2	8
I ² C bus mode register	ICMR	8	H'F07A	IIC2	8
I ² C bus interrupt enable register	ICIER	8	H'F07B	IIC2	8
I ² C bus status register	ICSR	8	H'F07C	IIC2	8
Slave address register	SAR	8	H'F07D	IIC2	8
I ² C bus transmit data register	ICDRT	8	H'F07E	IIC2	8
I ² C bus receive data register	ICDRR	8	H'F07F	IIC2	8
Interrupt priority register A	IPRA	8	H'F080	Interrupts	8
Interrupt priority register B	IPRB	8	H'F081	Interrupts	8
Interrupt priority register C	IPRC	8	H'F082	Interrupts	8
Interrupt priority register D	IPRD	8	H'F083	Interrupts	8
Interrupt priority register E	IPRE	8	H'F084	Interrupts	8
Address break control register 2	ABRKCR2	8	H'F096	Address break	8
Address break status register 2	ABRKS2	8	H'F097	Address break	8

Event counter PWM compare register	ECPWCR	16	H'FF8C	AEC* ¹	16
Event counter PWM data register	ECPWDR	16	H'FF8E	AEC* ¹	16
Wakeup edge select register	WEGR	8	H'FF90	Interrupts	8
Serial port control register	SPCR	8	H'FF91	SCI3	8
Input pin edge select register	AEGSR	8	H'FF92	AEC* ¹	8
Event counter control register	ECCR	8	H'FF94	AEC* ¹	8
Event counter control/status register	ECCSR	8	H'FF95	AEC* ¹	8
Event counter H	ECH	8	H'FF96	AEC* ¹	8/16
Event counter L	ECL	8	H'FF97	AEC* ¹	8/16
Serial mode register 3_1	SMR3_1	8	H'FF98	SCI3_1	8
Bit rate register 3_1	BRR3_1	8	H'FF99	SCI3_1	8
Serial control register 3_1	SCR3_1	8	H'FF9A	SCI3_1	8
Transmit data register 3_1	TDR3_1	8	H'FF9B	SCI3_1	8
Serial status register 3_1	SSR3_1	8	H'FF9C	SCI3_1	8
Receive data register 3_1	RDR3_1	8	H'FF9D	SCI3_1	8
LCD port control register	LPCR	8	H'FFA0	LCD* ³	8
LCD control register	LCR	8	H'FFA1	LCD* ³	8
LCD control register 2	LCR2	8	H'FFA2	LCD* ³	8
LCD trimming register	LTRMR	8	H'FFA3	LCD* ³	8
BGR control register	BGRMR	8	H'FFA4	LCD* ³	8
IrDA control register	IrCR	8	H'FFA7	IrDA	8
Serial mode register 3_2	SMR3_2	8	H'FFA8	SCI3_2	8
Bit rate register 3_2	BRR3_2	8	H'FFA9	SCI3_2	8

Timer counter WD	TCWD	8	H'FFB3	WDT*2	8
Timer control register F	TCRF	8	H'FFB6	Timer F	8
Timer control/status register F	TCSRF	8	H'FFB7	Timer F	8
8-bit timer counter FH	TCFH	8	H'FFB8	Timer F	8/16
8-bit timer counter FL	TCFL	8	H'FFB9	Timer F	8/16
Output compare register FH	OCRFH	8	H'FFBA	Timer F	8/16
Output compare register FL	OCRFL	8	H'FFBB	Timer F	8/16
A/D result register	ADRR	16	H'FFBC	A/D converter	16
A/D mode register	AMR	8	H'FFBE	A/D converter	8
A/D start register	ADSR	8	H'FFBF	A/D converter	8
Port mode register 1	PMR1	8	H'FFC0	I/O ports	8
Oscillator Control Register	OSCCR	8	H'FFC1	Clock pulse generator	8
Port mode register 3	PMR3	8	H'FFC2	I/O ports	8
Port mode register 4	PMR4	8	H'FFC3	I/O ports	8
Port mode register 5	PMR5	8	H'FFC4	I/O ports	8
Port mode register 9	PMR9	8	H'FFC8	I/O ports	8
Port mode register B	PMRB	8	H'FFCA	I/O ports	8
PWM2 control register	PWCR22	8	H'FFCD	14-bit PWM	8
PWM2 data register	PWDR2	16	H'FFCE	14-bit PWM	16
PWM1 control register	PWCR1	8	H'FFD0	14-bit PWM	8
PWM1 data register	PWDR1	16	H'FFD2	14-bit PWM	16

Port data register 9	PDR9	8	H'FFDC	I/O ports	8
Port data register A	PDRA	8	H'FFDD	I/O ports	8
Port data register B	PDRB	8	H'FFDE	I/O ports	8
Port pull-up control register 1	PUCR1	8	H'FFE0	I/O ports	8
Port pull-up control register 3	PUCR3	8	H'FFE1	I/O ports	8
Port pull-up control register 5	PUCR5	8	H'FFE2	I/O ports	8
Port pull-up control register 6	PUCR6	8	H'FFE3	I/O ports	8
Port control register 1	PCR1	8	H'FFE4	I/O ports	8
Port control register 3	PCR3	8	H'FFE6	I/O ports	8
Port control register 4	PCR4	8	H'FFE7	I/O ports	8
Port control register 5	PCR5	8	H'FFE8	I/O ports	8
Port control register 6	PCR6	8	H'FFE9	I/O ports	8
Port control register 7	PCR7	8	H'FFEA	I/O ports	8
Port control register 8	PCR8	8	H'FFEB	I/O ports	8
Port control register 9	PCR9	8	H'FFEC	I/O ports	8
Port control register A	PCRA	8	H'FFED	I/O ports	8
System control register 1	SYSCR1	8	H'FFF0	System	8
System control register 2	SYSCR2	8	H'FFF1	System	8
IRQ edge select register	IEGR	8	H'FFF2	Interrupts	8
Interrupt enable register 1	IENR1	8	H'FFF3	Interrupts	8
Interrupt enable register 2	IENR2	8	H'FFF4	Interrupts	8
Interrupt mask register	INTM	8	H'FFF5	Interrupts	8

FLMCR1	—	SWE	ESU	PSU	EV	PV	E	P
FLMCR2	FLER	—	—	—	—	—	—	—
FLPWCR	PDWND	—	—	—	—	—	—	—
EBR1	—	EB6	EB5	EB4	EB3	EB2	EB1	EB0
FENR	FLSHE	—	—	—	—	—	—	—
TSTR	—	—	—	—	—	CST2	CST1	—
TSYR	—	—	—	—	—	SYNC2	SYNC1	—
TCR_1	—	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0
TMDR_1	—	—	—	—	—	—	MD1	MD0
TIOR_1	IOB3	IOB2	IOB1	IOB0	IOA3	IOA2	IOA1	IOA0
TIER_1	—	—	—	TCIEV	—	—	TGIEB	TGIEA
TSR_1_	—	—	—	TCFV	—	—	TGFB	TGFA
TCNT_1	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TGRA_1	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TGRB_1	Bit15	Bit14	Bit13	Bit12	Bit11	Bit10	Bit9	Bit8
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
TCR_2	—	CCLR1	CCLR0	CKEG1	CKEG0	TPSC2	TPSC1	TPSC0
TMDR_2	—	—	—	—	—	—	MD1	MD0
TIOR_2	IOB3	IOB2	IOB1	IOB0	IOA3	IOA2	IOA1	IOA0
TIER_2	—	—	—	TCIEV	—	—	TGIEB	TGIEA
TSR_2	—	—	—	TCFV	—	—	TGFB	TGFA

RMINDR	BSY	MN12	MN11	MN10	MN03	MN02	MN01	MN00
RHRDR	BSY	—	HR11	HR10	HR03	HR02	HR01	HR00
RWKDR	BSY	—	—	—	—	WK2	WK1	WK0
RTCCR1	RUN	12/24	PM	RST	—	—	—	—
RTCCR2	FOIE	WKIE	DYIE	HRIE	MNIE	1SEIE	05SEIE	025SEIE
SUB32CR	32KSTOP	—	—	—	—	—	—	—
RTCCSR	—	RCS6	RCS5	SUB32K	RCS3	RCS2	RCS1	RCS0
ICCR1	ICE	RCVD	MST	TRS	CKS3	CKS2	CKS1	CKS0
ICCR2	BBSY	SCP	SDAO	SDAOP	SCLO	—	IICRST	—
ICMR	MLS	WAIT	—	—	BCWP	BC2	BC1	BC0
ICIER	TIE	TEIE	RIE	NAKIE	STIE	ACKE	ACKBR	ACKBT
ICSR	TDRE	TEND	RDRF	NACKF	STOP	AL/OVE	AAS	ADZ
SAR	SVA6	SVA5	SVA4	SVA3	SVA2	SVA1	SVA0	FS
ICDRT	ICDRT7	ICDRT6	ICDRT5	ICDRT4	ICDRT3	ICDRT2	ICDRT1	ICDRT0
ICDRR	ICDRR7	ICDRR6	ICDRR5	ICDRR4	ICDRR3	ICDRR2	ICDRR1	ICDRR0
IPRA	IPRA7	IPRA6	IPRA5	IPRA4	IPRA3	IPRA2	IPRA1	IPRA0
IPRB	IPRB7	IPRB6	IPRB5	IPRB4	IPRB3	IPRB2	IPRB1	IPRB0
IPRC	IPRC7	IPRC6	IPRC5	IPRC4	IPRC3	IPRC2	IPRC1	IPRC0
IPRD	IPRD7	IPRD6	IPRD5	IPRD4	IPRD3	IPRD2	IPRD1	IPRD0
IPRE	IPRE7	IPRE6	IPRE5	IPRE4	—	—	—	—

ECPWDR	ECPWDR15	ECPWDR14	ECPWDR13	ECPWDR12	ECPWDR11	ECPWDR10	ECPWDR9	ECPWDR8
	ECPWDR7	ECPWDR6	ECPWDR5	ECPWDR4	ECPWDR3	ECPWDR2	ECPWDR1	ECPWDR0
WEGR	WKEGS7	WKEGS6	WKEGS5	WKEGS4	WKEGS3	WKEGS2	WKEGS1	WKEGS0
SPCR	—	—	SPC32	SPC31	SCINV3	SCINV2	SCINV1	SCINV0
AEGSR	AHEGS1	AHEGS0	ALEGS1	ALEGS0	AIEGS1	AIEGS0	ECPWME	—
ECCR	ACKH1	ACKH0	ACKL1	ACKL0	PWCK2	PWCK1	PWCK0	—
ECCSR	OVH	OVL	—	CH2	CUEH	CUEL	CRCH	CRCL
ECH	ECH7	ECH6	ECH5	ECH4	ECH3	ECH2	ECH1	ECH0
ECL	ECL7	ECL6	ECL5	ECL4	ECL3	ECL2	ECL1	ECL0
SMR3_1	COM	CHR	PE	PM	STOP	MP	CKS1	CKS0
BRR3_1	BRR7	BRR6	BRR5	BRR4	BRR3	BRR2	BRR1	BRR0
SCR3_1	TIE	RIE	TE	RE	MPIE	TEIE	CKE1	CKE0
TDR3_1	TDR7	TDR6	TDR5	TDR4	TDR3	TDR2	TDR1	TDR0
SSR3_1	TDRE	RDRF	OER	FER	PER	TEND	MPBR	MPBT
RDR3_1	RDR7	RDR6	RDR5	RDR4	RDR3	RDR2	RDR1	RDR0
LPCR	DTS1	DTS0	CMX	—	SGS3	SGS2	SGS1	SGS0
LCR	—	PSW	ACT	DISP	CKS3	CKS2	CKS1	CKS0
LCR2	LCDAB	HCKS	CHG	SUPS	—	—	—	—
LTRMR	TRM3	TRM2	TRM1	TRM0	—	CTRM2	CTRM1	CTRM0
BGRMR	BGRSTPN	—	—	—	—	BTRM2	BTRM1	BTRM0
IrCR	IrE	IrCKS2	IrCKS1	IrCKS0	—	—	—	—

TCSRWD2	OVF	B5WI	WT/IT	B3WI	IEOVF	—	—	—
TCWD	TCW7	TCW6	TCW5	TCW4	TCW3	TCW2	TCW1	TCW0
TCRF	TOLH	CKSH2	CKSH1	CKSH0	TOLL	CKSL2	CKSL1	CKSL0
TCSRFB	OVFB	CMFB	OVIEH	CCLRH	OVFL	CMFL	OVIEL	CCLRL
TCFH	TCFH7	TCFH6	TCFH5	TCFH4	TCFH3	TCFH2	TCFH1	TCFH0
TCFL	TCFL7	TCFL6	TCFL5	TCFL4	TCFL3	TCFL2	TCFL1	TCFL0
OCRFH	OCRFH7	OCRFH6	OCRFH5	OCRFH4	OCRFH3	OCRFH2	OCRFH1	OCRFH0
OCRFL	OCRFL7	OCRFL6	OCRFL5	OCRFL4	OCRFL3	OCRFL2	OCRFL1	OCRFL0
ADRR	ADR9	ADR8	ADR7	ADR6	ADR5	ADR4	ADR3	ADR2
	ADR1	ADR0	—	—	—	—	—	—
AMR	CKS	TRGE	—	—	CH3	CH2	CH1	CH0
ADSR	ADSF	—	—	—	—	—	—	—
PMR1	—	—	—	—	—	—	AEVL	AEVH
OSCCR	—	—	—	—	—	IRQAECF	OSCF	—
PMR3	—	—	—	—	—	—	—	TMOW
PMR4	—	—	—	—	—	TMOFH	TMOFL	TMIF
PMR5	WKP7	WKP6	WKP5	WKP4	WKP3	WKP2	WKP1	WKP0
PMR9	—	—	—	—	—	IRQ4	PWM2	PWM1
PMRB	—	—	—	ADTSTCHG	—	IRQ3	IRQ1	IRQ0

PDR4	—	—	—	—	—	P42	P41	P40
PDR5	P57	P56	P55	P54	P53	P52	P51	P50
PDR6	P67	P66	P65	P64	P63	P62	P61	P60
PDR7	P77	P76	P75	P74	P73	P72	P71	P70
PDR8	P87	P86	P85	P84	P83	P82	P81	P80
PDR9	—	—	—	—	P93	P92	P91	P90
PDRA	—	—	—	—	PA3	PA2	PA1	PA0
PDRB	PB7	PB6	PB5	PB4	PB3	PB2	PB1	PB0
PUCR1	—	PUCR16	PUCR15	PUCR14	PUCR13	PUCR12	PUCR11	PUCR10
PUCR3	PUCR37	PUCR36	—	—	—	—	—	PUCR30
PUCR5	PUCR57	PUCR56	PUCR55	PUCR54	PUCR53	PUCR52	PUCR51	PUCR50
PUCR6	PUCR67	PUCR66	PUCR65	PUCR64	PUCR63	PUCR62	PUCR61	PUCR60
PCR1	—	PCR16	PCR15	PCR14	PCR13	PCR12	PCR11	PCR10
PCR3	PCR37	PCR36	—	—	—	PCR32	PCR31	PCR30
PCR4	—	—	—	—	—	PCR42	PCR41	PCR40
PCR5	PCR57	PCR56	PCR55	PCR54	PCR53	PCR52	PCR51	PCR50
PCR6	PCR67	PCR66	PCR65	PCR64	PCR63	PCR62	PCR61	PCR60
PCR7	PCR77	PCR76	PCR75	PCR74	PCR73	PCR72	PCR71	PCR70
PCR8	PCR87	PCR86	PCR85	PCR84	PCR83	PCR82	PCR81	PCR80
PCR9	—	—	—	—	PCR93	PCR92	PCR91	PCR90
PCRA	—	—	—	—	PCRA3	PCRA2	PCRA1	PCRA0
SYSCR1	SSBY	STS2	STS1	STS0	LS0N	TMA3	MA1	MA0
SYSCR2	—	—	—	NESEL	DT0N	MS0N	SA1	SA0

-
- Notes:
1. AEC: Asynchronous event counter
 2. WDT: Watchdog timer
 3. LCD: LCD controller/driver
 4. This bit is available only for the flash memory version. In the masked ROM version, this bit is reserved.

FLPWCR	Initialized	—	—	—	—	—	—	
EBR1	Initialized	—	—	—	—	—	—	Initialized
FENR	Initialized	—	—	—	—	—	—	
TSTR	Initialized	—	—	—	—	—	—	TPU
TSYR	Initialized	—	—	—	—	—	—	
TCR_1	Initialized	—	—	—	—	—	—	TPU
TMDR_1	Initialized	—	—	—	—	—	—	
TIOR_1	Initialized	—	—	—	—	—	—	
TIER_1	Initialized	—	—	—	—	—	—	
TSR_1_	Initialized	—	—	—	—	—	—	
TCNT_1	Initialized	—	—	—	—	—	—	
TGRA_1	Initialized	—	—	—	—	—	—	
TGRB_1	Initialized	—	—	—	—	—	—	
TCR_2	Initialized	—	—	—	—	—	—	TPU
TMDR_2	Initialized	—	—	—	—	—	—	
TIOR_2	Initialized	—	—	—	—	—	—	
TIER_2	Initialized	—	—	—	—	—	—	
TSR_2	Initialized	—	—	—	—	—	—	
TCNT_2	Initialized	—	—	—	—	—	—	
TGRA_2	Initialized	—	—	—	—	—	—	
TGRB_2	Initialized	—	—	—	—	—	—	

RTCCSR	Initialized	—	—	—	—	—	—	ge
ICCR1	Initialized	—	—	—	—	—	—	RT
ICCR2	Initialized	—	—	—	—	—	—	IIC
ICMR	Initialized	—	—	—	—	—	—	
ICIER	Initialized	—	—	—	—	—	—	
ICSR	Initialized	—	—	—	—	—	—	
SAR	Initialized	—	—	—	—	—	—	
ICDRT	Initialized	—	—	—	—	—	—	
ICDRR	Initialized	—	—	—	—	—	—	
IPRA	Initialized	—	—	—	—	—	—	Int
IPRB	Initialized	—	—	—	—	—	—	
IPRC	Initialized	—	—	—	—	—	—	
IPRD	Initialized	—	—	—	—	—	—	
IPRE	Initialized	—	—	—	—	—	—	
ABRKCR2	Initialized	—	—	—	—	—	—	Ad
ABRKSR2	Initialized	—	—	—	—	—	—	
BAR2H	Initialized	—	—	—	—	—	—	
BAR2L	Initialized	—	—	—	—	—	—	
BDR2H	—	—	—	—	—	—	—	
BDR2L	—	—	—	—	—	—	—	
ECPWCR	Initialized	—	—	—	—	—	—	AE
ECPWDR	Initialized	—	—	—	—	—	—	

BRR3_1	Initialized	—	—	Initialized	—	—	Initialized	
SCR3_1	Initialized	—	—	Initialized	—	—	Initialized	
TDR3_1	Initialized	—	—	Initialized	—	—	Initialized	
SSR3_1	Initialized	—	—	Initialized	—	—	Initialized	
RDR3_1	Initialized	—	—	Initialized	—	—	Initialized	
LPCR	Initialized	—	—	—	—	—	—	LCD
LCR	Initialized	—	—	—	—	—	—	
LCR2	Initialized	—	—	—	—	—	—	
LTRMR	Initialized	—	—	—	—	—	—	
BGRMR	Initialized	—	—	—	—	—	—	
IrCR	Initialized	—	—	Initialized	—	—	Initialized	IrDA
SMR3_2	Initialized	—	—	Initialized	—	—	Initialized	SCI
BRR3_2	Initialized	—	—	Initialized	—	—	Initialized	
SCR3_2	Initialized	—	—	Initialized	—	—	Initialized	
TDR3_2	Initialized	—	—	Initialized	—	—	Initialized	
SSR3_2	Initialized	—	—	Initialized	—	—	Initialized	
RDR3_2	Initialized	—	—	Initialized	—	—	Initialized	
TMWD	Initialized	—	—	—	—	—	—	WD
TCSRWD1	Initialized	—	—	—	—	—	—	
TCSRWD2	Initialized	—	—	—	—	—	—	
TCWD	Initialized	—	—	—	—	—	—	

ADSR	Initialized	—	—	—	—	—	—	
PMR1	Initialized	—	—	—	—	—	—	I/O
PMR3	Initialized	—	—	—	—	—	—	
PMR4	Initialized	—	—	—	—	—	—	
PMR5	Initialized	—	—	—	—	—	—	
PMR9	Initialized	—	—	—	—	—	—	
PMRB	Initialized	—	—	—	—	—	—	
PWCR2	Initialized	—	—	—	—	—	—	14
PWDR2	Initialized	—	—	—	—	—	—	
PWCR1	Initialized	—	—	—	—	—	—	
PWDR1	Initialized	—	—	—	—	—	—	
PDR1	Initialized	—	—	—	—	—	—	I/O
OSCCR	Initialized	—	—	—	—	—	—	Cl ge
PDR3	Initialized	—	—	—	—	—	—	I/O
PDR4	Initialized	—	—	—	—	—	—	
PDR5	Initialized	—	—	—	—	—	—	
PDR6	Initialized	—	—	—	—	—	—	
PDR7	Initialized	—	—	—	—	—	—	
PDR8	Initialized	—	—	—	—	—	—	
PDR9	Initialized	—	—	—	—	—	—	
PDRA	Initialized	—	—	—	—	—	—	
PDRB	Initialized	—	—	—	—	—	—	

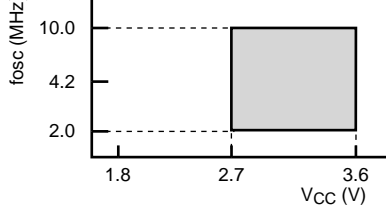
PCR6	Initialized	—	—	—	—	—	—	
PCR7	Initialized	—	—	—	—	—	—	
PCR8	Initialized	—	—	—	—	—	—	
PCR9	Initialized	—	—	—	—	—	—	
PCRA	Initialized	—	—	—	—	—	—	
SYSCR1	Initialized	—	—	—	—	—	—	System
SYSCR2	Initialized	—	—	—	—	—	—	
IEGR	Initialized	—	—	—	—	—	—	Interrupt
IENR1	Initialized	—	—	—	—	—	—	
IENR2	Initialized	—	—	—	—	—	—	
INTM	Initialized	—	—	—	—	—	—	
IRR1	Initialized	—	—	—	—	—	—	
IRR2	Initialized	—	—	—	—	—	—	
IWPR	Initialized	—	—	—	—	—	—	
CKSTPR1	Initialized	—	—	—	—	—	—	System
CKSTPR2	Initialized	—	—	—	—	—	—	

Notes: — is not initialized.

1. AEC: Asynchronous event counter
2. WDT: Watchdog timer
3. LCD: LCD controller/driver

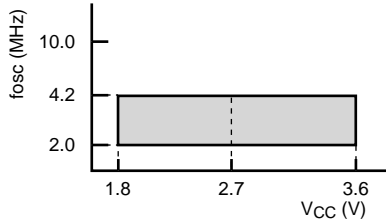
Analog power supply voltage		AV_{cc}	-0.3 to +4.3	V
Input voltage	Other than port B	V_{in}	-0.3 to $V_{cc} + 0.3$	V
	Port B	AV_{in}	-0.3 to $AV_{cc} + 0.3$	V
Operating temperature		T_{opr}	-20 to +75 (regular specifications)* ²	°C
			-40 to +85 (wide-range specifications)* ²	
			+75 (products shipped as chips)* ³	
Storage temperature		T_{stg}	-55 to +125	°C

- Notes:
1. Permanent damage may occur to the chip if absolute maximum ratings are exceeded. Normal operation should be under the conditions specified in Electrical Characteristics. Exceeding these values can result in incorrect operation and reduced reliability.
 2. When the operating voltage (V_{cc}) for reading the flash memory is from 2.7 V to 1.8 V, the operating temperature (T_a) for programming/erasing ranges from -20 to +75°C. When the operating voltage (V_{cc}) for reading the flash memory is from 1.8 V to 1.2 V, the operating temperature (T_a) for programming/erasing ranges from -20 to +75°C.
 3. Power may be applied when the temperature is between -20 to +75°C.

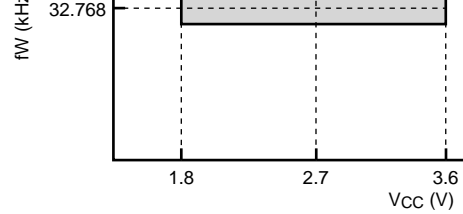


- Active (high-speed) mode
- Sleep (high-speed) mode
- Refer to no.1 in the note.

[4-MHz version]

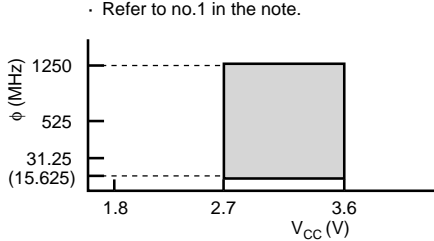


- Active (high-speed) mode
- Sleep (high-speed) mode
- Refer to no.1 in the note.

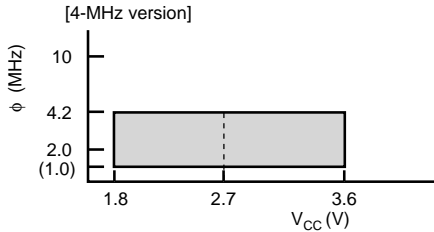


- All operating mode
- Refer to no. 2 in the note.

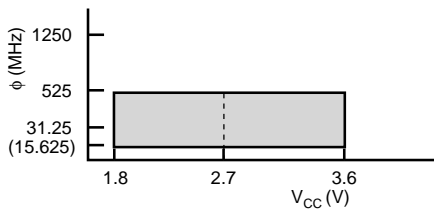
Notes: 1. The f_{osc} values are those when a resonator is used; when an external clock is used, the minimum value of f_{osc} is 2 MHz.
 2. When a resonator is used, hold V_{CC} at 2.2 V to 3.6 V from power-on until the oscillation settling time has elapsed.



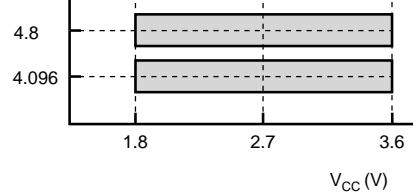
- Active (medium-speed) mode
- Sleep (medium-speed) mode (except A/D converter)
- Refer to no.2 in the note.



- Active (high-speed) mode
- Sleep (high-speed) mode (except CPU)
- Refer to no.1 in the note.



- Active (medium-speed) mode
- Sleep (medium-speed) mode (except A/D converter)
- Refer to no.2 in the note.



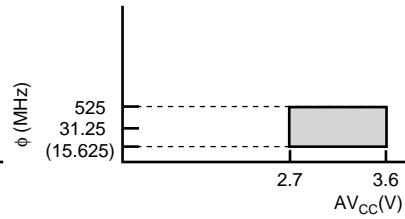
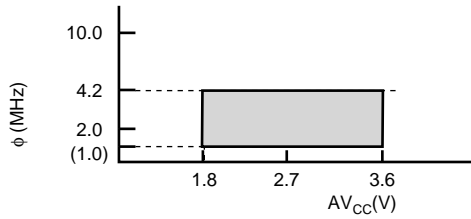
- Subactive mode
- Subsleep mode (except CPU)
- Watch mode (except CPU)

- Notes: 1. The value in parentheses is the minimum operating frequency when an external clock is input using a resonator, the minimum operating frequency (ϕ) is 2 MHz.
2. The value in parentheses is the minimum operating frequency when an external clock is input using a resonator, the minimum operating frequency (ϕ) is 31.25 kHz.

- Sleep (high-speed) mode
- Refer to no.1 in the note.

- Sleep (medium-speed) mode
- Refer to no.2 in the note.

[4-MHz version]



- Active (high-speed) mode
- Sleep (high-speed) mode
- Refer to no.1 in the note.

- Active (medium-speed) mode
- Sleep (medium-speed) mode
- Refer to no.2 in the note.

Notes: 1. The minimum operating frequency (ϕ) is 2 MHz when using a resonator;
and 1 MHz when using an external clock.

2. The minimum operating frequency (ϕ) is 31.25 kHz when using a resonator;
and 15.625 kHz when using an external clock.

voltage

to WKP7, IRQ4,
AEVL, AEVH,
TMIF, ADTRG,
SCK32, SCK31,
SCK4

$\overline{\text{IRQ0}}, \overline{\text{IRQ1}}, \overline{\text{IRQ3}}$		$0.9V_{\text{cc}}$	—	$AV_{\text{cc}} + 0.3$
RXD32, RXD31		$0.8V_{\text{cc}}$	—	$V_{\text{cc}} + 0.3$
OSC1		$0.9V_{\text{cc}}$	—	$V_{\text{cc}} + 0.3$
X1	$V_{\text{cc}} = 2.7 \text{ to } 3.6 \text{ V}$	$0.9V_{\text{cc}}$	—	$V_{\text{cc}} + 0.3$
P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P93, PA0 to PA3, TCLKA, TCLKB, TCLKC, TIOCA1, TIOCA2, TIOCB1, TIOCB2, SCL, SDA		$0.8V_{\text{cc}}$	—	$V_{\text{cc}} + 0.3$
PB0 to PB7		$0.8V_{\text{cc}}$	—	$AV_{\text{cc}} + 0.3$
IRQAEC		$0.9V_{\text{cc}}$	—	$V_{\text{cc}} + 0.3$

	OSC1		-0.3	—	0.1V _{cc}		
	X1	V _{cc} = 2.7 to 3.6 V	-0.3	—	0.1V _{cc}		
	P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P93, PA0 to PA3, TCLKA, TCLKB, TCLKC, TIOCA1, TIOCB1, TIOCA2, TIOCB2, SCL, SDA, PB0 to PB7		-0.3	—	0.2V _{cc}		
Output high voltage	V _{OH}	P10, P16, P30 to P32, P36, P37 P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, PA0 to PA3	-I _{OH} = 1.0 mA V _{cc} = 2.7 to 3.6 V	V _{cc} - 1.0	—	—	V
		P90 to P93	-I _{OH} = 0.1 mA	V _{cc} - 0.3	—	—	
			I _{OH} = 1.0 mA V _{cc} = 2.7 to 3.6 V	V _{cc} - 1.0	—	—	
			I _{OH} = 0.1 mA	V _{cc} - 0.3	—	—	

			$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$				
			$I_{OL} = 10 \text{ mA}$, $V_{CC} = 2.2 \text{ to } 3.6 \text{ V}$	—	—	0.5	
			$I_{OL} = 8 \text{ mA}$ $V_{CC} = 1.8 \text{ to } 3.6 \text{ V}$	—	—	0.5	
		SCL, SDA	$V_{CC} = 2.0 \text{ to } 3.6 \text{ V}$ $I_{OL} = 3.0 \text{ mA}$	—	—	0.4	
			$V_{CC} = 1.8 \text{ to } 2.0 \text{ V}$ $I_{OL} = 3.0 \text{ mA}$	—	—	$0.2V_{CC}$	
Input/output leakage current	$ I_L $	NMI* ³ , OSC1, X1, P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, IRQAEC, PA0 to PA3, P90 to P93	$V_{IN} = 0.5 \text{ V to } V_{CC} - 0.5 \text{ V}$	—	—	1.0	μA
		PB0 to PB7	$V_{IN} = 0.5 \text{ V to } AV_{CC} - 0.5 \text{ V}$	—	—	1.0	
Pull-up MOS current	$-I_p$	P10 to P16, P30, P36, P37, P50 to P57, P60 to P67	$V_{CC} = 3.0 \text{ V}$, $V_{IN} = 0 \text{ V}$	30	—	180	μA

			$V_{CC} = 3.0\text{ V}$, $f_{OSC} = 4\text{ MHz}$						
			Active (high-speed) mode, $V_{CC} = 3.0\text{ V}$, $f_{OSC} = 10\text{ MHz}$	—	6.6	10			
	I_{OPEZ}	V_{CC}	Active (medium-speed) mode, $V_{CC} = 1.8\text{ V}$, $f_{OSC} = 2\text{ MHz}$, $\phi_{OSC}/64$	—	0.4	—		mA	
			Active (medium-speed) mode, $V_{CC} = 3.0\text{ V}$, $f_{OSC} = 4\text{ MHz}$, $\phi_{OSC}/64$	—	0.7	—			
			Active (medium-speed) mode, $V_{CC} = 3.0\text{ V}$, $f_{OSC} = 10\text{ MHz}$, $\phi_{OSC}/64$	—	1.1	1.8			
Sleep mode current consumption	I_{SLEEP}	V_{CC}	$V_{CC} = 1.8\text{ V}$, $f_{OSC} = 2\text{ MHz}$	—	0.7	—		mA	
			$V_{CC} = 3.0\text{ V}$, $f_{OSC} = 4\text{ MHz}$	—	1.7	—			
			$V_{CC} = 3.0\text{ V}$, $f_{OSC} = 10\text{ MHz}$	—	3.5	5.0			

mode current consumption			LCD on, 32-KHz crystal resonator ($\phi_{SUB} = \phi_W/2$)				
Watch mode current consumption	I_{WATCH}	V_{CC}	$V_{CC} = 1.8\text{ V}$, $T_a = 25^\circ\text{C}$, 32-kHz crystal resonator, LCD not used	—	0.4	—	μA
			$V_{CC} = 2.7\text{ V}$, 32-kHz crystal resonator, LCD not used	—	2.0	6.0	
Standby mode current consumption	I_{STBY}	V_{CC}	$V_{CC} = 1.8\text{ V}$, $T_a = 25^\circ\text{C}$, 32-kHz crystal resonator not used	—	0.4	—	μA
			$V_{CC} = 3.0\text{ V}$, $T_a = 25^\circ\text{C}$, 32-kHz crystal resonator not used	—	0.6	—	
			32-kHz crystal resonator not used	—	1.0	5.0	
			$V_{CC} = 3.0\text{ V}$, 32KSTOP = 1	—	0.3	—	
RAM data retaining voltage	V_{RAM}	V_{CC}		1.5	—	—	V
Allowable output low current (per pin)	I_{OL}	Output pins except port 9		—	—	0.5	mA
		P90 to P93		—	—	15.0	

Notes: 1. Pin states during current measurement.

Mode	RES		Other Pins	LCD Power Supply	Oscillator P
	Pin	Internal State			
Active (high-speed) mode (I_{OPE1})	V_{CC}	Only CPU operates	V_{CC}	Halted	System clock crystal reson
Active (medium-speed) mode (I_{OPE2})		On-chip WDT oscillator is off			
Sleep mode	V_{CC}	Only on-chip timers operate On-chip WDT oscillator is off	V_{CC}	Halted	Subclock osc Pin X1 = GND
Subactive mode	V_{CC}	Only CPU operates On-chip WDT oscillator is off	V_{CC}	Halted	System clock crystal reson
Subsleep mode	V_{CC}	Only on-chip timers operate, CPU stops On-chip WDT oscillator is off	V_{CC}	Halted	Subclock osc crystal reson
Watch mode	V_{CC}	Only time base operates, CPU stops On-chip WDT oscillator is off	V_{CC}	Halted	
Standby mode	V_{CC}	CPU and timers both stop On-chip WDT oscillator is off	V_{CC}	Halted	System clock crystal reson Subclock osc Pin X1 = GND (32KSTOP =

2. Excludes current in pull-up MOS transistors and output buffers.
3. Used for the determination of user mode or boot mode when the reset is released.
4. Except for the package for the TLP-85V.
5. Only for 4-MHz version.

System clock oscillation frequency	f_{osc}	OSC1, OSC2	$V_{cc} = 2.7$ to 3.6 V	2.0	—	10.0	MHz
			$V_{cc} = 1.8$ to 3.6 V	2.0	—	4.2	
OSC clock (ϕ_{osc}) cycle time	t_{osc}	OSC1, OSC2	$V_{cc} = 2.7$ to 3.6 V	100	—	500 (1000)	ns
			$V_{cc} = 1.8$ to 3.6 V	238	—	500 (1000)	
System clock (ϕ) cycle time	t_{cyc}			1	—	64	t_{osc}
				—	—	64	μs
Subclock oscillation frequency	f_w	X1, X2		—	32.768 or 38.4	—	kHz
Watch clock (ϕ_w) cycle time	t_w	X1, X2		—	30.5 or 26.0	—	μs
Subclock (ϕ_{sub}) cycle time	t_{subcyc}			2	—	8	t_w
Instruction cycle time				2	—	—	t_{cyc} t_{subcyc}
Oscillation stabilization time	t_c	OSC1, OSC2	Crystal resonator ($V_{cc} = 2.7$ to 3.6 V)	—	0.8	2.0	ms
			Crystal resonator ($V_{cc} = 2.2$ to 3.6 V)	—	1.2	3	
			Ceramic resonator ($V_{cc} = 2.2$ to 3.6 V)	—	20	45	μs
			Ceramic resonator (other than above)	—	80	—	
			Other than above	—	—	50	ms
		$\times 1, \times 2$	$V_{cc} = 2.2$ to 3.6 V	—	—	2.0	s
			Other than above	—	4	—	

		$V_{CC} = 1.8 \text{ to } 3.6 \text{ V}$		93	—	—		
		X1		—	15.26	—	μs	
					or			
					13.02			
External clock F time	t_{CPr}	OSC1	$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$	—	—	10	ns	
			$V_{CC} = 1.8 \text{ to } 3.6 \text{ V}$	—	—	24		
		X1		—	—	55.0		
External clock fall time	t_{CPf}	OSC1	$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$	—	—	10	ns	
			$V_{CC} = 1.8 \text{ to } 3.6 \text{ V}$	—	—	24		
		X1		—	—	55.0		
RES pin low width	t_{REL}	RES		10	—	—	t_{oyc}	
Input pin high width	t_{IH}	$\overline{\text{IRQ0}}$, $\overline{\text{IRQ1}}$, $\overline{\text{NMI}}$, $\overline{\text{IRQ3}}$, $\overline{\text{IRQ4}}$, $\overline{\text{IRQAEC}}$, $\overline{\text{WKP0}}$ to $\overline{\text{WKP7}}$, $\overline{\text{TMIF}}$, $\overline{\text{ADTRG}}$		2	—	—	t_{oyc}	
								t_{suboyc}
			AEVL, AEVH	$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$	50	—	—	ns
				$V_{CC} = 1.8 \text{ to } 3.6 \text{ V}$	110	—	—	
			t_{TCKWH}	TCLKA, TCLKB, TCLKC, TIOCA1, TIOCB1, TIOCA2, TIOCB2	Single edge specified	1.5	—	—
		Both edges specified	2.5	—	—			

TCLKC,
TIOCA1,
TIOCB1,
TIOCA2,
TIOCB2

Both edges 2.5 — —
specified

- Notes: 1. Selected with the SA1 and SA0 bits in the system control register 2 (SYSCR2)
2. The value in parentheses is t_{OSC} (max.) when an external clock is used.
3. For details on the power-on reset characteristics, refer to table 24.8 and figure 24.10.

Table 24.4 Serial Interface Timing

$V_{CC} = 1.8\text{ V to }3.6\text{ V}$, $AV_{CC} = 1.8\text{ V to }3.6\text{ V}$, $V_{SS} = AV_{SS} = 0.0\text{ V}$, unless otherwise specified

Item	Symbol	Test Condition	Values			Unit
			Min.	Typ.	Max.	
Input clock cycle	Asynchronous	t_{syc}	4	—	—	t_{cyc} or t_{subcyc}
	Clocked synchronous		6	—	—	t_{subcyc}
Input clock pulse width	t_{SCKW}	0.4	0.4	—	0.6	t_{syc}
Transmit data delay time (clocked synchronous)	t_{TXD}	—	—	—	1	t_{cyc} or t_{subcyc}
Receive data setup time (clocked synchronous)	t_{RXS}		238	—	—	ns
		$V_{CC} = 2.7\text{ to }3.6\text{ V}$	100			
Receive data hold time (clocked synchronous)	t_{RXH}		238	—	—	ns
		$V_{CC} = 2.7\text{ to }3.6\text{ V}$	100			

SCL and SDA input spike pulse removal time	t_{SP}	—	—	$1t_{cyc}$	ns
SDA input bus-free time	t_{BUF}	$5t_{cyc}$	—	—	ns
Start condition input hold time	t_{STAH}	$3t_{cyc}$	—	—	ns
Retransmission start condition input setup time	t_{STAS}	$3t_{cyc}$	—	—	ns
Setup time for stop condition input	t_{STOS}	$3t_{cyc}$	—	—	ns
Data-input setup time	t_{SDAS}	$1t_{cyc} + 20$	—	—	ns
Data-input hold time	t_{SDAH}	0	—	—	ns
Capacitive load of SCL and SDA	C_b	0	—	400	pF
SCL and SDA output fall time	t_{Sf}	—	—	300	ns

24.2.4 A/D Converter Characteristics

Table 24.6 lists the A/D converter characteristics.

	I_{STOP2}	V_{CC}	—	—	5	μA
Analog input capacitance	C_{AIN}	AN0 to AN7	—	—	15.0	pF
Allowable signal source impedance	R_{AIN}		—	—	10.0	k Ω
Resolution (data length)			—	—	10	bits
Nonlinearity error		$V_{CC} = 2.7 V$ to $3.6 V$ $V_{CC} = 2.7 V$ to $3.6 V$	—	—	± 3.5	LSB
		$V_{CC} = 2.0 V$ to $3.6 V$ $V_{CC} = 2.0 V$ to $3.6 V$	—	—	± 5.5	
		Other than above	—	—	± 7.5	
Quantization error			—	—	± 0.5	LSB
Absolute accuracy		$V_{CC} = 2.7 V$ to $3.6 V$ $V_{CC} = 2.7 V$ to $3.6 V$	—	—	± 4.0	LSB
		$V_{CC} = 2.0 V$ to $3.6 V$ $V_{CC} = 2.0 V$ to $3.6 V$	—	—	± 6.0	
		Other than above	—	—	± 8.0	
Conversion time		$V_{CC} = 2.7 V$ to $3.6 V$ $V_{CC} = 2.7 V$ to $3.6 V$	6.2	—	124	μs
		$V_{CC} = 2.0 V$ to $3.6 V$ $V_{CC} = 2.0 V$ to $3.6 V$	14.7	—	124	
		Other than above	31	—	124	

Notes: 1. Set $V_{CC} = V_{CC}$ when the A/D converter is not used.

2. I_{STOP1} is the current in active and sleep modes while the A/D converter is idle.

3. I_{STOP2} is the current at a reset and in standby, watch, subactive, and subsleep while the A/D converter is idle.

4. Conversion time = 31 μs

Common driver drop voltage	V_{DC}	COM1 to COM4	$I_D = 2 \mu A$ $V1 = 2.7 V$ to $3.6 V$	—	—	0.3	V
LCD power supply split-resistance	R_{LCD}		Between V1 and V_{SS}	1.5	3.0	7.0	M Ω
LCD display voltage	V_{LCD}	V1		2.2	—	3.6	V
V3 power supply voltage	V_{LCD3}	V3	Between V3 and V_{SS}	0.9	1.0	1.1	V
V2 power supply voltage	V_{LCD2}	V2	Between V2 and V_{SS}	—	2.0 ($V_{LCD3} \times 2$)	—	V
V1 power supply voltage	V_{LCD1}	V1	Between V1 and V_{SS}	—	3.0 ($V_{LCD3} \times 3$)	—	V
3-V constant voltage LCD power supply circuit current consumption	I_{LCD}	Vcc	Vcc = 3.0 V Booster clock: 125 kHz	—	20	—	μA

- Notes:
1. The voltage drop from power supply pins V1, V2, V3, and V_{SS} to each segment common pin.
 2. When the LCD display voltage is supplied from an external power source, ensure the following relationship is maintained: $V1 \geq V2 \geq V3 \geq V_{SS}$.
 3. The value when the LCD power supply split-resistor is separated and 3-V constant voltage power supply circuit is driven.
 4. For details on the register (BGRMR) setting range when the voltage of the V3 is set to 1.0 V, refer to section 19.3.5, BGR Control Register (BGRMR).
 5. Includes the current consumption of the band-gap reference circuit (BGR) (operating current).

Item	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Reset voltage	V _{rst}		0.7V _{cc}	0.8V _{cc}	0.9V _{cc}	V
Power supply rise time	t _{vtr}		The V _{cc} rise time should be shorter than half the $\overline{\text{RES}}$ rise time.			
Reset count time	t _{out}		0.8	—	8.0	μs
Count start time	t _{cr}		Adjustable by the value of the external capacitor of the $\overline{\text{RES}}$ pin.			
On-chip pull-up resistance	R _p	V _{cc} = 3.0 V	60	100	—	kΩ

24.2.7 Watchdog Timer Characteristics

Table 24.9 Watchdog Timer Characteristics

V_{cc} = 1.8 V to 3.6 V, AV_{cc} = 1.8 V to 3.6 V, V_{ss} = AV_{ss} = 0.0 V,
 Ta = -20 to +75°C (regular specifications), Ta = -40 to +85°C (wide-range specification)
 unless otherwise specified.

Item	Symbol	Applicable		Values			Unit
		Pins	Test Condition	Min.	Typ.	Max.	
On-chip oscillator overflow time	t _{ovf}			0.2	0.4	—	s

Condition B:

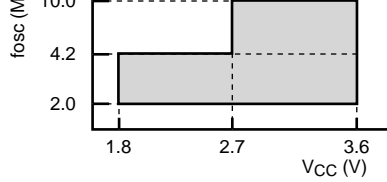
$AV_{CC} = 1.8 \text{ V to } 3.6 \text{ V}$, $DV_{CC} = 2.2 \text{ V to } 3.6 \text{ V}$, $V_{SS} = AV_{SS} = 0.0 \text{ V}$, $V_{CC} = 1.8 \text{ V to } 3.6 \text{ V}$ (voltage range in reading), $V_{CC} = 3.0 \text{ V to } 3.6 \text{ V}$ (operating voltage range in programming/erasing), $T_a = -20 \text{ to } +50^\circ\text{C}$ (operating temperature range in programming/erasing: regular specifications/wide-range specifications)

Item	Symbol	Test Condition	Values			
			Min.	Typ.	Max.	
Programming time (per 128 bytes)*1*2*4	t_p		—	7	200	
Erase time (per block)*1*3*6	t_E		—	100	1200	
Maximum number of reprogrammings	N_{WEC}		1000*8*11	10000*9	—	
			100*8*12	10000*9	—	
Data retention time	t_{DRP}		10^{*10}	—	—	
Programming	Wait time after SWE bit setting*1	x	1	—	—	
	Wait time after PSU bit setting*1	y	50	—	—	
	Wait time after P bit setting*1*4	z1	$1 \leq n \leq 6$	28	30	32
		z2	$7 \leq n \leq 1000$	198	200	202
		z3	Additional-programming	8	10	12
	Wait time after P bit clear*1	α		5	—	—
	Wait time after PSU bit clear*1	β		5	—	—
	Wait time after PV bit setting*1	γ		4	—	—
	Wait time after dummy write*1	ε		2	—	—
	Wait time after PV bit clear*1	η		2	—	—
Wait time after SWE bit clear*1	θ		100	—	—	
Maximum programming count*1*4*5	N		—	—	1000	

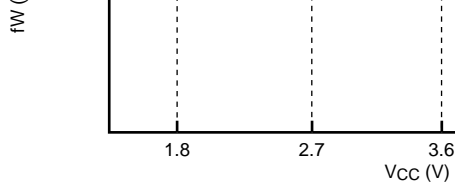
- Notes:
1. Make the time settings in accordance with the program/erase algorithms.
 2. The programming time for 128 bytes. (Indicates the total time for which the flash memory control register 1 (FLMCR1) is set. The program-verify time is included.)
 3. The time required to erase one block. (Indicates the total time for which the flash memory control register 1 (FLMCR1) is set. The erase-verify time is included.)
 4. Programming time maximum value (t_p (max.)) = wait time after P bit setting (z1, z2, and z3) × maximum number of programmings (N)
 5. Set the maximum number of programmings (N) according to the actual set value of z1, z2, and z3, so that it does not exceed the programming time maximum value (t_p (max.)). The wait time after P bit setting (z1, z2) should be changed as follows according to the value of the number of programmings (n).
 Number of programmings (n)
 $1 \leq n \leq 6 \quad z1 = 30 \mu s$
 $7 \leq n \leq 1000 \quad z2 = 200 \mu s$
 6. Erase time maximum value (t_e (max.)) = wait time after E bit setting (z) × maximum number of erases (N)
 7. Set the maximum number of erases (N) according to the actual set value of z, so that it does not exceed the erase time maximum value (t_e (max.)).
 8. The minimum number of times in which all characteristics are guaranteed for reprogramming. (The guarantee covers the range from 1 to the minimum value.)
 9. Reference value at 25°C. (Guideline showing number of reprogrammings over which the functionality will be retained under normal circumstances.)
 10. Data retention characteristics within the range indicated in the specifications and the minimum value for reprogrammings.
 11. Applies to an operating voltage range when reading data of 2.7 to 3.6 V.
 12. Applies to an operating voltage range when reading data of 1.8 to 3.6 V.

Operating temperature	T_{opr}	-20 to $+75$ (regular specifications) <hr/> -40 to $+85$ (wide-range specifications) <hr/> $+75$ (products shipped as chips)* ²	°C
Storage temperature	T_{stg}	-55 to $+125$	°C

- Notes: 1. Permanent damage may occur to the chip if absolute maximum ratings are exceeded. Normal operation should be under the conditions specified in Electrical Characteristics. Exceeding these values can result in incorrect operation and reduced reliability.
2. Power may be applied when the temperature is between -20 and $+75$ °C.

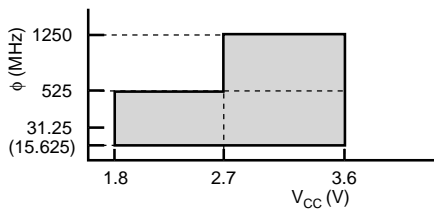


- Active (high-speed) mode
- Sleep (high-speed) mode
- Refer to no.1 in the note.

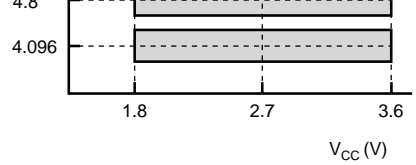


- All operating mode
- Refer to no.2 in the note.

Notes: 1. The f_{osc} values are those when a resonator is used; when an external clock is used, the minimum value of f_{osc} is 1 MHz.
 2. When a resonator is used, hold V_{CC} at 2.2 V to 3.6 V from power-on until oscillation settling time has elapsed.



- Active (medium-speed) mode
- Sleep (medium-speed) mode (except A/D converter)
- Refer to no.2 in the note.



- Subactive mode
- Subsleep mode (except CPU)
- Watch mode (except CPU)

- Notes: 1. The value in parentheses is the minimum operating frequency when an external clock is input using a resonator, the minimum operating frequency (ϕ) is 2 MHz.
2. The value in parentheses is the minimum operating frequency when an external clock is input using a resonator, the minimum operating frequency (ϕ) is 31.25 kHz.

Refer to no.1 in the note.

Notes: 1. The minimum operating frequency (ϕ) is 2 MHz when using a resonator;
and 1 MHz when using an external clock.

2. The minimum operating frequency (ϕ) is 31.25 kHz when using a resonator;
and 15.625 kHz when using an external clock.

voltage

WKP7, IRQ4,
AEVL, AEVH,
TMIF, $\overline{\text{ADTRG}}$,
SCK32, SCK31

IRQ0, IRQ1, IRQ3		$0.9V_{cc}$	—	$AV_{cc} + 0.3$
RXD32, RXD31		$0.8V_{cc}$	—	$V_{cc} + 0.3$
OSC1		$0.9V_{cc}$	—	$V_{cc} + 0.3$
X1	$V_{cc} = 2.7 \text{ to } 3.6 \text{ V}$	$0.9V_{cc}$	—	$V_{cc} + 0.3$
P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P93, PA0 to PA3, TCLKA, TCLKB, TCLKC, TIOCA1, TIOCA2, TIOCB1, TIOCB2, SCL, SDA		$0.8V_{cc}$	—	$V_{cc} + 0.3$
PB0 to PB7		$0.8V_{cc}$	—	$AV_{cc} + 0.3$
IRQAEC		$0.9V_{cc}$	—	$V_{cc} + 0.3$

		X1	$V_{cc} = 2.7 \text{ to } 3.6 \text{ V}$	-0.3	—	$0.1V_{cc}$	
		P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, P90 to P93, PA0 to PA3, TCLKA, TCLKB, TCLKC, TIOCA1, TIOCB1, TIOCA2, TIOCB2, SCL, SDA, PB0 to PB7					
Output high voltage	V_{OH}	P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, PA0 to PA3	$-I_{OH} = 1.0 \text{ mA}$ $V_{cc} = 2.7 \text{ to } 3.6 \text{ V}$	$V_{cc} - 1.0$	—	—	V
		P90 to P93	$-I_{OH} = 0.1 \text{ mA}$	$V_{cc} - 0.3$	—	—	
		P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, PA0 to PA3	$-I_{OH} = 1.0 \text{ mA}$ $V_{cc} = 2.7 \text{ to } 3.6 \text{ V}$	$V_{cc} - 1.0$	—	—	
		P90 to P93	$-I_{OH} = 0.1 \text{ mA}$	$V_{cc} - 0.3$	—	—	

			$V_{CC} = 2.7$ to 3.6 V				
			$I_{OL} = 10$ mA	—	—	0.5	
			$V_{CC} = 2.2$ to 3.6 V				
			$I_{OL} = 8.0$ mA	—	—	0.5	
			$V_{CC} = 1.8$ to 3.6 V				
		SCL, SDA	$V_{CC} = 2.0$ to 3.6 V	—	—	0.4	V
			$I_{OL} = 3.0$ mA				
			$V_{CC} = 1.8$ to 2.0 V	—	—	$0.2V_{CC}$	
			$I_{OL} = 3.0$ mA				
Input/output leakage current	$ I_L $	\overline{NMI} , OSC1, X1, P10 to P16, P30 to P32, P36, P37, P40 to P42, P50 to P57, P60 to P67, P70 to P77, P80 to P87, IRQAEC, PA0 to PA3, P90 to P93	$V_{IN} = 0.5$ V to $V_{CC} - 0.5$ V	—	—	1.0	μ A
		PB0 to PB7	$V_{IN} = 0.5$ V to $A V_{CC} - 0.5$ V	—	—	1.0	
Pull-up MOS current	$-I_p$	P10 to P16, P30, P36, P37, P50 to P57, P60 to P67	$V_{CC} = 3$ V, $V_{IN} = 0$ V	30	—	180	μ A
Input capacitance ^{*3}	C_{IN}	All input pins except power supply pin	$f = 1$ MHz, $V_{IN} = 0$ V, $T_a = 25^\circ$ C	—	—	15.0	pF

$V_{CC} = 3.0 \text{ V}$,
 $f_{OSC} = 10 \text{ MHz}$

	I_{OPE2}	V_{CC}					
			Active (medium-speed) mode, $V_{CC} = 1.8 \text{ V}$, $f_{OSC} = 2 \text{ MHz}$, $\phi_{OSC}/64$	—	0.2	—	mA
			Active (medium-speed) mode, $V_{CC} = 3.0 \text{ V}$, $f_{OSC} = 4 \text{ MHz}$, $\phi_{OSC}/64$	—	0.4	—	
			Active (medium-speed) mode, $V_{CC} = 3.0 \text{ V}$, $f_{OSC} = 10 \text{ MHz}$, $\phi_{OSC}/64$	—	0.8	1.8	
Sleep mode current consumption	I_{SLEEP}	V_{CC}	$V_{CC} = 1.8 \text{ V}$, $f_{OSC} = 2 \text{ MHz}$	—	0.3	—	mA
			$V_{CC} = 3.0 \text{ V}$, $f_{OSC} = 4 \text{ MHz}$	—	1.2	—	
			$V_{CC} = 3.0 \text{ V}$, $f_{OSC} = 10 \text{ MHz}$	—	3.0	5.0	

Subsleep mode current consumption	I_{SUBSP}	V_{CC}	$V_{\text{CC}} = 2.7 \text{ V}$, LCD on, 32-kHz crystal resonator ($\phi_{\text{SUB}} = \phi_{\text{W}}/2$)	—	4.5	10	μA
Watch mode current consumption	I_{WATCH}	V_{CC}	$V_{\text{CC}} = 1.8 \text{ V}$, $T_{\text{a}} = 25^{\circ}\text{C}$, 32-kHz crystal resonator, LCD not used	—	0.5	—	μA
			$V_{\text{CC}} = 2.7 \text{ V}$, 32-kHz crystal resonator, LCD not used	—	1.6	6.0	
Standby mode current consumption	I_{STBY}	V_{CC}	$V_{\text{CC}} = 1.8 \text{ V}$, $T_{\text{a}} = 25^{\circ}\text{C}$, 32-kHz crystal resonator not used	—	0.4	—	μA
			$V_{\text{CC}} = 3.0 \text{ V}$, $T_{\text{a}} = 25^{\circ}\text{C}$, 32-kHz crystal resonator not used	—	0.6	—	
			32-kHz crystal resonator not used	—	1.0	5.0	
			$V_{\text{CC}} = 3.0 \text{ V}$, 32KSTOP = 1	—	0.3	—	
RAM data retaining voltage	V_{RAM}	V_{CC}		1.5	—	—	V
Allowable output low current (per pin)	I_{OL}	Output pins except port 9		—	—	0.5	mA
		P90 to P93		—	—	15.0	

Notes: 1. Pin states during current measurement.

Mode	RES		Other Pins	LCD Power Supply	Oscillator
	Pin	Internal State			
Active (high-speed) mode (I_{OPE1})	V_{CC}	Only CPU operates On-chip WDT oscillator is off	V_{CC}	Halted	System clock crystal resonator
Active (medium-speed) mode (I_{OPE2})					Subclock oscillator Pin X1 = GND
Sleep mode	V_{CC}	Only on-chip timers operate On-chip WDT oscillator is off	V_{CC}	Halted	
Subactive mode	V_{CC}	Only CPU operates On-chip WDT oscillator is off	V_{CC}	Halted	System clock crystal resonator
Subsleep mode	V_{CC}	Only on-chip timers operate, CPU stops On-chip WDT oscillator is off	V_{CC}	Halted	Subclock oscillator crystal resonator
Watch mode	V_{CC}	Only time base operates, CPU stops On-chip WDT oscillator is off TCSRWD1 (WDON) = 0	V_{CC}	Halted	
Standby mode	V_{CC}	CPU and timers both stop On-chip WDT oscillator is off TCSRWD1 (WDON) = 0	V_{CC}	Halted	System clock crystal resonator Subclock oscillator Pin X1 = GND (32KSTOP)

2. Excludes current in pull-up MOS transistors and output buffers.
3. Except for the package for the TLP-85V.

System clock oscillation frequency	t_{OSC}	OSC1, OSC2	$V_{CC} = 2.7$ to 3.6 V	2.0	—	10.0	MHz	*
On-chip oscillator oscillation frequency	R_{OSC}		$V_{CC} = 1.8$ to 3.6 V	2.0	—	4.2		
			When on-chip oscillator is selected $V_{CC} = 2.7$ to 3.6 V	1.0	—	10.0		*
			$V_{CC} = 1.8$ to 3.6 V	2.0	—	4.2		
			When on-chip oscillator is selected $V_{CC} = 1.8$ to 2.7 V	0.5	—	4.2		
OSC clock (ϕ_{OSC}) cycle time	t_{OSC}	OSC1, OSC2	$V_{CC} = 2.7$ to 3.6 V	100	—	500 (1000)	ns	F
			$V_{CC} = 1.8$ to 3.6 V	238	—	500 (1000)		*
On-chip oscillator clock (ϕ_{OSC}) cycle time	t_{ROSC}		When on-chip oscillator is selected $V_{CC} = 2.7$ to 3.6 V	100	—	1000		*
			When on-chip oscillator is selected $V_{CC} = 1.8$ to 2.7 V	238	—	2000		
System clock (ϕ) cycle time	t_{cyc}			1	—	64	t_{OSC}	
				—	—	64	μs	
Subclock oscillation frequency	f_W	X1, X2		—	32.768 or 38.4	—	kHz	F
Watch clock (ϕ_W) cycle time	t_W	X1, X2		—	30.5 or 26.0	—	μs	F
Subclock (ϕ_{SUB}) cycle time	t_{subcyc}			2	—	8	t_W	*
Instruction cycle time				2	—	—	t_{cyc} t_{subcyc}	

			Other than above	—	—	50	ns
			When on-chip oscillator is selected	—	—	100	μ s
		X1, X2	$V_{CC} = 2.2$ to 3.6 V	—	—	2.0	s
			Other than above	—	4	—	
External clock high width	t_{CPH}	OSC1	$V_{CC} = 2.7$ to 3.6 V	40	—	—	ns
			$V_{CC} = 1.8$ to 3.6 V	95	—	—	
		X1		—	15.26 or 13.02	—	μ s
External clock low width	t_{CPL}	OSC1	$V_{CC} = 2.7$ to 3.6 V	40	—	—	ns
			$V_{CC} = 1.8$ to 3.6 V	95	—	—	
		X1		—	15.26 or 13.02	—	μ s
External clock rise time	t_{CPR}	OSC1	$V_{CC} = 2.7$ to 3.6 V	—	—	10	ns
			$V_{CC} = 1.8$ to 3.6 V	—	—	24	
		X1		—	—	55.0	ns
External clock fall time	t_{CPF}	OSC1	$V_{CC} = 2.7$ to 3.6 V	—	—	10	ns
			$V_{CC} = 1.8$ to 3.6 V	—	—	24	
		X1		—	—	55.0	ns
\overline{RES} pin low width	t_{REL}	\overline{RES}		10	—	—	t_{cyc}

TIOCA1,
TIOCB1,
TIOCA2,
TIOCB2

			Both edges specified	2.5	—	—	
Input pin low width	t_{IL}	$\overline{IRQ0}$, $\overline{IRQ1}$, \overline{NMI} , $\overline{IRQ3}$, $\overline{IRQ4}$, \overline{IRQAEC} , $\overline{WKP0}$ to $\overline{WKP7}$, \overline{TMIF} , \overline{ADTRG}		2	—	—	t_{cyc} t_{subcyc}
		AEVL, AEVH	$V_{CC} = 2.7$ to 3.6 V	50	—	—	ns
			$V_{CC} = 1.8$ to 3.6 V	110	—	—	
	t_{TCKWL}	TCLKA, TCLKB, TCLKC, TIOCA1, TIOCB1, TIOCA2, TIOCB2	Single edge specified	1.5	—	—	t_{cyc}
			Both edges specified	2.5	—	—	

- Notes: 1. Selected with the SA1 and SA0 bits in the system control register 2 (SYSCR2)
2. The value in parentheses is t_{osc} (max.) when an external clock is used.
3. For details on the power-on reset characteristics, refer to table 24.18 and figure 24.19.
4. Characteristics vary due to variations in factors such as temperature, power supply voltage, and production lot. When designing the system, give due consideration to actual usage conditions. For actual data on this product, please contact a Renesas representative.

(clocked synchronous)						
Receive data setup time (clocked synchronous)	t_{RXS}	238	—	—	ns	Fig
		$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$	100			
Receive data hold time (clocked synchronous)	t_{RXH}	238	—	—	ns	Fig
		$V_{CC} = 2.7 \text{ to } 3.6 \text{ V}$	100			

SCL and SDA input spike pulse removal time	t_{SP}	—	—	$1t_{cyc}$	ns
SDA input bus-free time	t_{BUF}	$5t_{cyc}$	—	—	ns
Start condition input hold time	t_{STAH}	$3t_{cyc}$	—	—	ns
Retransmission start condition input setup time	t_{STAS}	$3t_{cyc}$	—	—	ns
Setup time for stop condition input	t_{STOS}	$3t_{cyc}$	—	—	ns
Data-input setup time	t_{SDAS}	$1t_{cyc} + 20$	—	—	ns
Data-input hold time	t_{SDAH}	0	—	—	ns
Capacitive load of SCL and SDA	C_b	0	—	400	pF
SCL and SDA output fall time	t_{Sf}	—	—	300	ns

voltage							
Analog input voltage	AV_{IN}	AN0 to AN7		-0.3	—	$AV_{CC} + 0.3$	V
Analog power supply current	AI_{OPE}	AV_{CC}	$AV_{CC} = 3.0$ V	—	—	1.0	mA
	AI_{STOP1}	AV_{CC}		—	600	—	μ A
	AI_{STOP2}	AV_{CC}		—	—	5	μ A
Analog input capacitance	C_{AIN}	AN0 to AN7		—	—	15.0	pF
Allowable signal source impedance	R_{AIN}			—	—	10.0	k Ω
Resolution (data length)				—	—	10	bits
Nonlinearity error			$AV_{CC} = 2.7$ V to 3.6 V $V_{CC} = 2.7$ V to 3.6 V	—	—	± 3.5	LSB
			$AV_{CC} = 2.0$ V to 3.6 V $V_{CC} = 2.0$ V to 3.6 V	—	—	± 5.5	
			Other than above	—	—	± 7.5	
				—	—		
Quantization error				—	—	± 0.5	LSB
Absolute accuracy			$AV_{CC} = 2.7$ V to 3.6 V $V_{CC} = 2.7$ V to 3.6 V	—	—	± 4.0	LSB
			$AV_{CC} = 2.0$ V to 3.6 V $V_{CC} = 2.0$ V to 3.6 V	—	—	± 6.0	
			Other than above	—	—	± 8.0	
				—	—		

while the A/D converter is idle.

4. Conversion time = 62 μ s

voltage		SEG32	$V1 = 2.7 \text{ V to } 3.6 \text{ V}$					
Common driver drop voltage	V_{DC}	COM1 to COM4	$I_D = 2 \mu\text{A}$ $V1 = 2.7 \text{ V to } 3.6 \text{ V}$	—	—	0.3	V	
LCD power supply split-resistance	R_{LCD}		Between $V1$ and V_{SS}	1.5	3.0	7.0	M Ω	
LCD display voltage	V_{LCD}	V1		2.2	—	3.6	V	
V3 power supply voltage	V_{LCD3}	V3	Between $V3$ and V_{SS}	0.9	1.0	1.1	V	
V2 power supply voltage	V_{LCD2}	V2	Between $V2$ and V_{SS}	—	2.0 ($V_{LCD3} \times 2$)	—	V	
V1 power supply voltage	V_{LCD1}	V1	Between $V1$ and V_{SS}	—	3.0 ($V_{LCD3} \times 3$)	—	V	
3-V constant voltage LCD power supply circuit current consumption	I_{LCD}	V_{CC}	$V_{CC} = 3.0 \text{ V}$ Booster clock: 125 kHz	—	20	—	μA	

- Notes:
1. The voltage drop from power supply pins $V1$, $V2$, $V3$, and V_{SS} to each segment common pin.
 2. When the LCD display voltage is supplied from an external power source, the following relationship is maintained: $V1 \geq V2 \geq V3 \geq V_{SS}$.
 3. The value when the LCD power supply split-resistor is separated and 3-V constant voltage power supply circuit is driven.
 4. For details on the register (BGRMR) setting range when the voltage of the $V3$ is to 1.0 V, refer to section 19.3.5, BGR Control Register (BGRMR).
 5. Includes the current consumption of the band-gap reference circuit (BGR) (op

Item	Symbol	Test Condition	Min.	Typ.	Max.	Unit	Fi	
Reset voltage	V_rst		0.7V _{cc}	0.8V _{cc}	0.9V _{cc}	V	Fi	
Power supply rise time	t_vtr		The V _{cc} rise time should be shorter than half the $\overline{\text{RES}}$ rise time.					
Reset count time	t_out		0.8	—	4.0	μs		
Count start time	t_cr		Adjustable by the value of the external capacitor of the $\overline{\text{RES}}$ pin.					
On-chip pull-up resistance	R _p	V _{cc} = 3.0 V	60	100	—	k Ω	Fi	

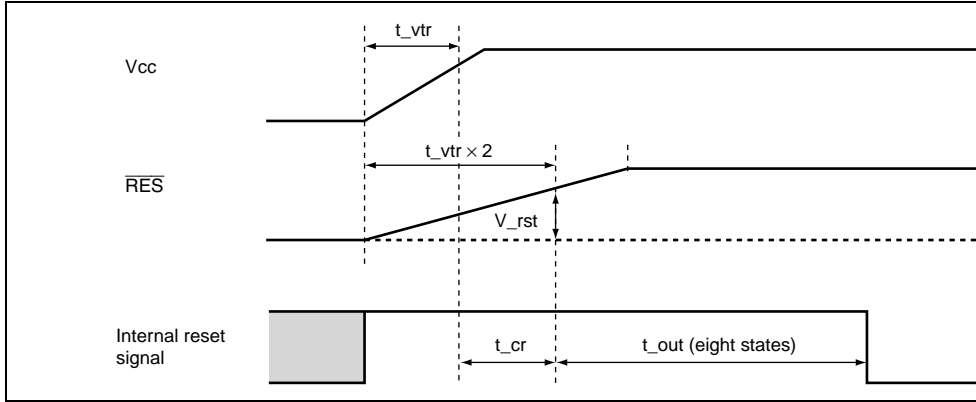


Figure 24.1 Power-On Reset Circuit Reset Timing

24.5 Operation Timing

Figures 24.2 to 24.7 show operation timings.

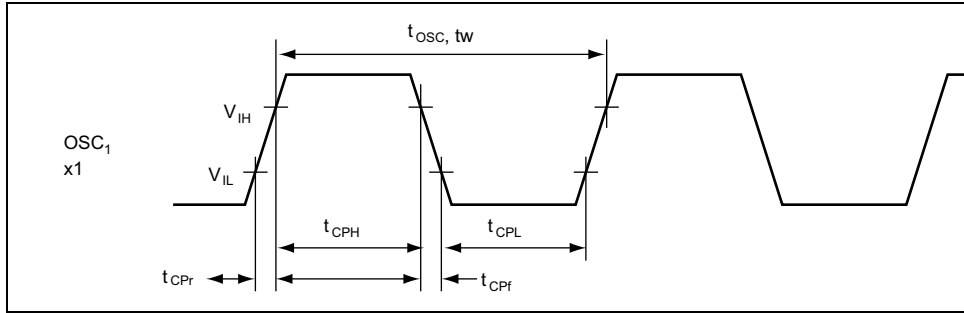


Figure 24.2 Clock Input Timing

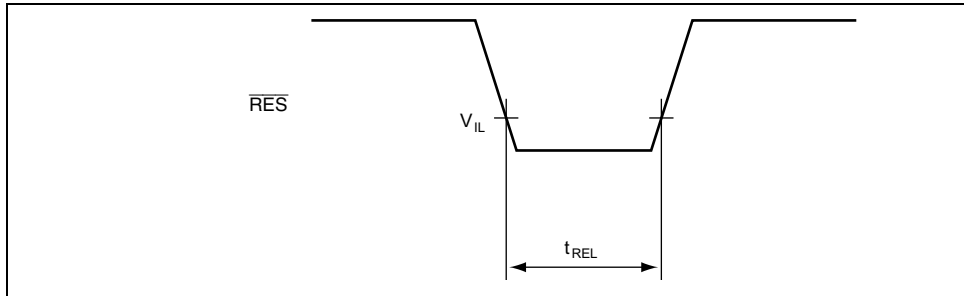


Figure 24.3 \overline{RES} Low Width Timing

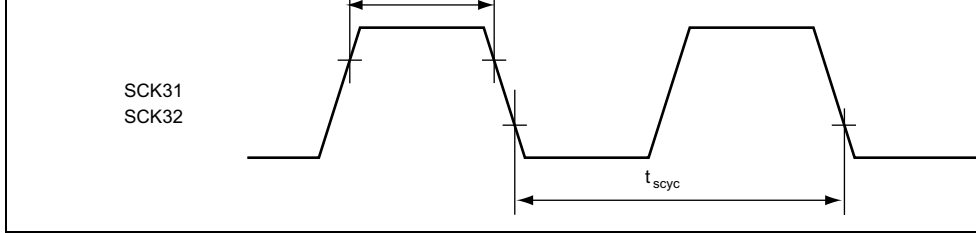


Figure 24.5 SCK3 Input Clock Timing

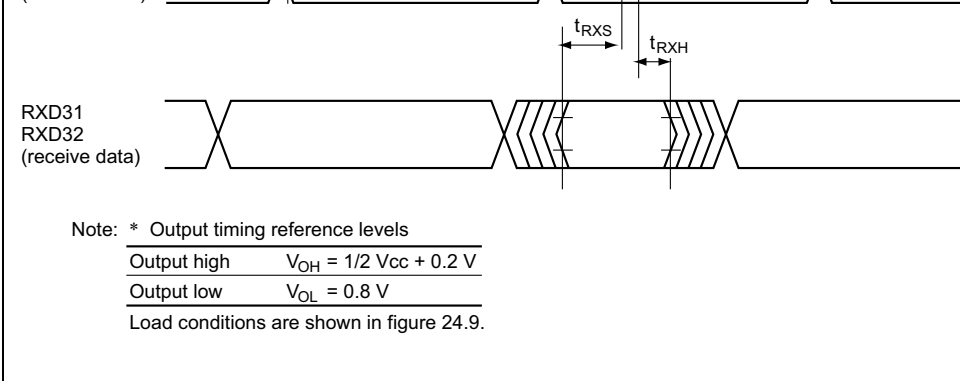


Figure 24.6 SCI3 Input/Output Timing in Clocked Synchronous Mode

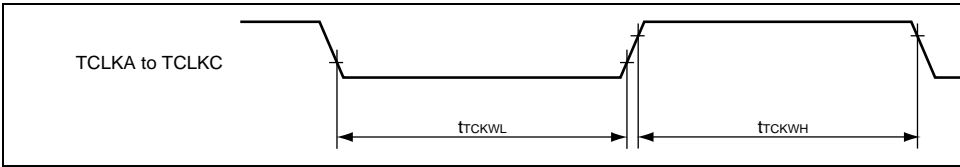


Figure 24.7 Clock Input Timing for TCLKA to TCLKC Pins

Note: * S, P, and Sr represent the following:
S: Start condition
P: Stop condition
Sr: Retransmission start condition

Figure 24.8 I²C Bus Interface Input/Output Timing

24.6 Output Load Circuit

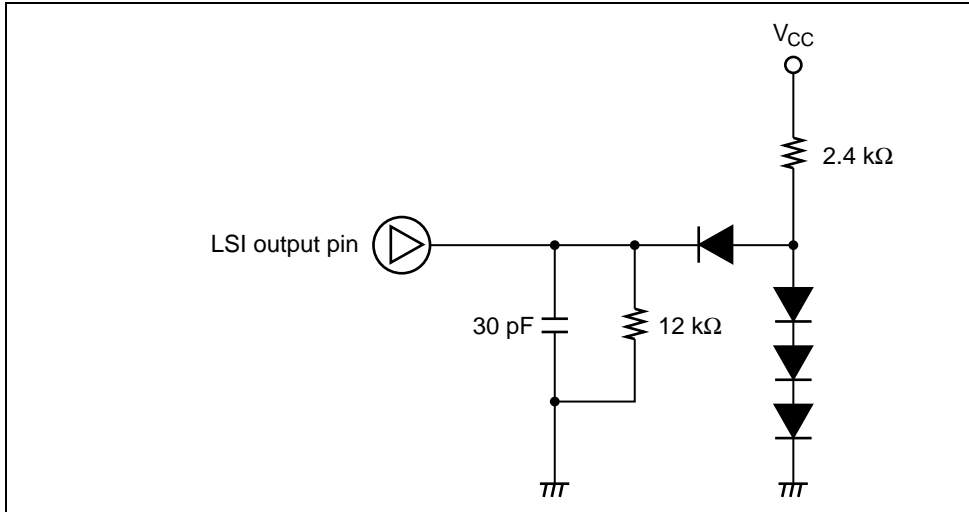


Figure 24.9 Output Load Condition

Frequency (MHz)	Manufacturer	Product Type
2	Murata Manufacturing Co., Ltd.	CSTCC2M00G53-B0
	Murata Manufacturing Co., Ltd.	CSTCC2M00G56-B0
4.194	Murata Manufacturing Co., Ltd.	CSTLS4M19G53-B0
	Murata Manufacturing Co., Ltd.	CSTLS4M19G56-B0
10	Murata Manufacturing Co., Ltd.	CSTLS10M0G53-B0
	Murata Manufacturing Co., Ltd.	CSTLS10M0G56-B0

24.8 Usage Note

The F-ZTAT and masked ROM versions satisfy the electrical characteristics shown in the manual, but actual electrical characteristic values, operating margins, noise margins, and properties may vary due to differences in manufacturing process, on-chip ROM, layout, and so on.

When system evaluation testing is carried out using the F-ZTAT version, the same evaluation testing should also be conducted for the masked ROM version when changing over to the

Rs	General source register
Rn	General register
ERd	General destination register (address register or 32-bit register)
ERs	General source register (address register or 32-bit register)
ERn	General register (32-bit register)
(EAd)	Destination operand
(EAs)	Source operand
PC	Program counter
SP	Stack pointer
CCR	Condition-code register
N	N (negative) flag in CCR
Z	Z (zero) flag in CCR
V	V (overflow) flag in CCR
C	C (carry) flag in CCR
disp	Displacement
→	Transfer from the operand on the left to the operand on the right, or transfer the state on the left to the state on the right
+	Addition of the operands on both sides
–	Subtraction of the operand on the right from the operand on the left
×	Multiplication of the operands on both sides
÷	Division of the operand on the left by the operand on the right
^	Logical AND of the operands on both sides
∨	Logical OR of the operands on both sides
⊕	Logical exclusive OR of the operands on both sides

*	Undetermined (no guaranteed value)
0	Cleared to 0
1	Set to 1
—	Not affected by execution of the instruction
Δ	Varies depending on conditions, described in notes

MOV.B @ERs, Rd	B		2			@ERs → Rd8	—	—	↕	↕	0
MOV.B @(d:16, ERs), Rd	B		4			@(d:16, ERs) → Rd8	—	—	↕	↕	0
MOV.B @(d:24, ERs), Rd	B		8			@(d:24, ERs) → Rd8	—	—	↕	↕	0
MOV.B @ERs+, Rd	B			2		@ERs → Rd8 ERs32+1 → ERs32	—	—	↕	↕	0
MOV.B @aa:8, Rd	B			2		@aa:8 → Rd8	—	—	↕	↕	0
MOV.B @aa:16, Rd	B			4		@aa:16 → Rd8	—	—	↕	↕	0
MOV.B @aa:24, Rd	B			6		@aa:24 → Rd8	—	—	↕	↕	0
MOV.B Rs, @ERd	B		2			Rs8 → @ERd	—	—	↕	↕	0
MOV.B Rs, @(d:16, ERd)	B		4			Rs8 → @(d:16, ERd)	—	—	↕	↕	0
MOV.B Rs, @(d:24, ERd)	B		8			Rs8 → @(d:24, ERd)	—	—	↕	↕	0
MOV.B Rs, @-ERd	B			2		ERd32-1 → ERd32 Rs8 → @ERd	—	—	↕	↕	0
MOV.B Rs, @aa:8	B			2		Rs8 → @aa:8	—	—	↕	↕	0
MOV.B Rs, @aa:16	B			4		Rs8 → @aa:16	—	—	↕	↕	0
MOV.B Rs, @aa:24	B			6		Rs8 → @aa:24	—	—	↕	↕	0
MOV.W #xx:16, Rd	W	4				#xx:16 → Rd16	—	—	↕	↕	0
MOV.W Rs, Rd	W		2			Rs16 → Rd16	—	—	↕	↕	0
MOV.W @ERs, Rd	W		2			@ERs → Rd16	—	—	↕	↕	0
MOV.W @(d:16, ERs), Rd	W		4			@(d:16, ERs) → Rd16	—	—	↕	↕	0
MOV.W @(d:24, ERs), Rd	W		8			@(d:24, ERs) → Rd16	—	—	↕	↕	0
MOV.W @ERs+, Rd	W			2		@ERs → Rd16 ERs32+2 → @ERd32	—	—	↕	↕	0
MOV.W @aa:16, Rd	W			4		@aa:16 → Rd16	—	—	↕	↕	0
MOV.W @aa:24, Rd	W			6		@aa:24 → Rd16	—	—	↕	↕	0
MOV.W Rs, @ERd	W		2			Rs16 → @ERd	—	—	↕	↕	0
MOV.W Rs, @(d:16, ERd)	W		4			Rs16 → @(d:16, ERd)	—	—	↕	↕	0
MOV.W Rs, @(d:24, ERd)	W		8			Rs16 → @(d:24, ERd)	—	—	↕	↕	0

	MOV.L ERs, ERd	L			4					ERs32 → ERd32	—	—	↕	↕	0	—
	MOV.L @(d:16, ERs), ERd	L			6					@(d:16, ERs) → ERd32	—	—	↕	↕	0	—
	MOV.L @(d:24, ERs), ERd	L			10					@(d:24, ERs) → ERd32	—	—	↕	↕	0	—
	MOV.L @ERs+, ERd	L			4					@ERs → ERd32 ERs32+4 → ERs32	—	—	↕	↕	0	—
	MOV.L @aa:16, ERd	L			6					@aa:16 → ERd32	—	—	↕	↕	0	—
	MOV.L @aa:24, ERd	L			8					@aa:24 → ERd32	—	—	↕	↕	0	—
	MOV.L ERs, @ERd	L		4						ERs32 → @ERd	—	—	↕	↕	0	—
	MOV.L ERs, @(d:16, ERd)	L		6						ERs32 → @(d:16, ERd)	—	—	↕	↕	0	—
	MOV.L ERs, @(d:24, ERd)	L		10						ERs32 → @(d:24, ERd)	—	—	↕	↕	0	—
	MOV.L ERs, @-ERd	L		4						ERd32-4 → ERd32 ERs32 → @ERd	—	—	↕	↕	0	—
	MOV.L ERs, @aa:16	L		6						ERs32 → @aa:16	—	—	↕	↕	0	—
	MOV.L ERs, @aa:24	L		8						ERs32 → @aa:24	—	—	↕	↕	0	—
POP	POP.W Rn	W							2	@SP → Rn16 SP+2 → SP	—	—	↕	↕	0	—
	POP.L ERn	L							4	@SP → ERn32 SP+4 → SP	—	—	↕	↕	0	—
PUSH	PUSH.W Rn	W							2	SP-2 → SP Rn16 → @SP	—	—	↕	↕	0	—
	PUSH.L ERn	L							4	SP-4 → SP ERn32 → @SP	—	—	↕	↕	0	—
MOVFPE	MOVFPE @aa:16, Rd	B			4					Cannot be used in this LSI	Cannot be used in this LSI					
MOVTPPE	MOVTPPE Rs, @aa:16	B			4					Cannot be used in this LSI	Cannot be used in this LSI					

	ADD.L #xx:32, ERd	L	6															ERd32+#xx:32 → ERd32	—	(2)	↕	↕	↕
	ADD.L ERs, ERd	L	2															ERd32+ERs32 → ERd32	—	(2)	↕	↕	↕
ADDX	ADDX.B #xx:8, Rd	B	2															Rd8+#xx:8 +C → Rd8	—	↕	↕	(3)	↕
	ADDX.B Rs, Rd	B	2															Rd8+Rs8 +C → Rd8	—	↕	↕	(3)	↕
ADDS	ADDS.L #1, ERd	L	2															ERd32+1 → ERd32	—	—	—	—	—
	ADDS.L #2, ERd	L	2															ERd32+2 → ERd32	—	—	—	—	—
	ADDS.L #4, ERd	L	2															ERd32+4 → ERd32	—	—	—	—	—
INC	INC.B Rd	B	2															Rd8+1 → Rd8	—	—	↕	↕	↕
	INC.W #1, Rd	W	2															Rd16+1 → Rd16	—	—	↕	↕	↕
	INC.W #2, Rd	W	2															Rd16+2 → Rd16	—	—	↕	↕	↕
	INC.L #1, ERd	L	2															ERd32+1 → ERd32	—	—	↕	↕	↕
	INC.L #2, ERd	L	2															ERd32+2 → ERd32	—	—	↕	↕	↕
DAA	DAA Rd	B	2															Rd8 decimal adjust → Rd8	—	*	↕	↕	*
SUB	SUB.B Rs, Rd	B	2															Rd8-Rs8 → Rd8	—	↕	↕	↕	↕
	SUB.W #xx:16, Rd	W	4															Rd16-#xx:16 → Rd16	—	(1)	↕	↕	↕
	SUB.W Rs, Rd	W	2															Rd16-Rs16 → Rd16	—	(1)	↕	↕	↕
	SUB.L #xx:32, ERd	L	6															ERd32-#xx:32 → ERd32	—	(2)	↕	↕	↕
	SUB.L ERs, ERd	L	2															ERd32-ERs32 → ERd32	—	(2)	↕	↕	↕
SUBX	SUBX.B #xx:8, Rd	B	2															Rd8-#xx:8-C → Rd8	—	↕	↕	(3)	↕
	SUBX.B Rs, Rd	B	2															Rd8-Rs8-C → Rd8	—	↕	↕	(3)	↕
SUBS	SUBS.L #1, ERd	L	2															ERd32-1 → ERd32	—	—	—	—	—
	SUBS.L #2, ERd	L	2															ERd32-2 → ERd32	—	—	—	—	—
	SUBS.L #4, ERd	L	2															ERd32-4 → ERd32	—	—	—	—	—
DEC	DEC.B Rd	B	2															Rd8-1 → Rd8	—	—	↕	↕	↕
	DEC.W #1, Rd	W	2															Rd16-1 → Rd16	—	—	↕	↕	↕
	DEC.W #2, Rd	W	2															Rd16-2 → Rd16	—	—	↕	↕	↕

	AND.L #xx:32, ERd	L	6												ERd32 \wedge #xx:32 \rightarrow ERd32	—	—	\updownarrow	\updownarrow	0
	AND.L ERs, ERd	L	4												ERd32 \wedge ERs32 \rightarrow ERd32	—	—	\updownarrow	\updownarrow	0
OR	OR.B #xx:8, Rd	B	2												Rd8 \vee #xx:8 \rightarrow Rd8	—	—	\updownarrow	\updownarrow	0
	OR.B Rs, Rd	B	2												Rd8 \vee Rs8 \rightarrow Rd8	—	—	\updownarrow	\updownarrow	0
	OR.W #xx:16, Rd	W	4												Rd16 \vee #xx:16 \rightarrow Rd16	—	—	\updownarrow	\updownarrow	0
	OR.W Rs, Rd	W	2												Rd16 \vee Rs16 \rightarrow Rd16	—	—	\updownarrow	\updownarrow	0
	OR.L #xx:32, ERd	L	6												ERd32 \vee #xx:32 \rightarrow ERd32	—	—	\updownarrow	\updownarrow	0
	OR.L ERs, ERd	L	4												ERd32 \vee ERs32 \rightarrow ERd32	—	—	\updownarrow	\updownarrow	0
XOR	XOR.B #xx:8, Rd	B	2												Rd8 \oplus #xx:8 \rightarrow Rd8	—	—	\updownarrow	\updownarrow	0
	XOR.B Rs, Rd	B	2												Rd8 \oplus Rs8 \rightarrow Rd8	—	—	\updownarrow	\updownarrow	0
	XOR.W #xx:16, Rd	W	4												Rd16 \oplus #xx:16 \rightarrow Rd16	—	—	\updownarrow	\updownarrow	0
	XOR.W Rs, Rd	W	2												Rd16 \oplus Rs16 \rightarrow Rd16	—	—	\updownarrow	\updownarrow	0
	XOR.L #xx:32, ERd	L	6												ERd32 \oplus #xx:32 \rightarrow ERd32	—	—	\updownarrow	\updownarrow	0
	XOR.L ERs, ERd	L	4												ERd32 \oplus ERs32 \rightarrow ERd32	—	—	\updownarrow	\updownarrow	0
NOT	NOT.B Rd	B	2												\neg Rd8 \rightarrow Rd8	—	—	\updownarrow	\updownarrow	0
	NOT.W Rd	W	2												\neg Rd16 \rightarrow Rd16	—	—	\updownarrow	\updownarrow	0
	NOT.L ERd	L	2												\neg Rd32 \rightarrow Rd32	—	—	\updownarrow	\updownarrow	0

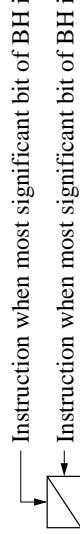
	BSET Rn, @ERd	B		4					(Rn8 of @ERd) ← 1	—	—	—	—
	BSET Rn, @aa:8	B				4			(Rn8 of @aa:8) ← 1	—	—	—	—
BCLR	BCLR #xx:3, Rd	B	2						(#xx:3 of Rd8) ← 0	—	—	—	—
	BCLR #xx:3, @ERd	B		4					(#xx:3 of @ERd) ← 0	—	—	—	—
	BCLR #xx:3, @aa:8	B				4			(#xx:3 of @aa:8) ← 0	—	—	—	—
	BCLR Rn, Rd	B	2						(Rn8 of Rd8) ← 0	—	—	—	—
	BCLR Rn, @ERd	B		4					(Rn8 of @ERd) ← 0	—	—	—	—
	BCLR Rn, @aa:8	B					4		(Rn8 of @aa:8) ← 0	—	—	—	—
BNOT	BNOT #xx:3, Rd	B	2						(#xx:3 of Rd8) ← ¬ (#xx:3 of Rd8)	—	—	—	—
	BNOT #xx:3, @ERd	B		4					(#xx:3 of @ERd) ← ¬ (#xx:3 of @ERd)	—	—	—	—
	BNOT #xx:3, @aa:8	B				4			(#xx:3 of @aa:8) ← ¬ (#xx:3 of @aa:8)	—	—	—	—
	BNOT Rn, Rd	B	2						(Rn8 of Rd8) ← ¬ (Rn8 of Rd8)	—	—	—	—
	BNOT Rn, @ERd	B		4					(Rn8 of @ERd) ← ¬ (Rn8 of @ERd)	—	—	—	—
	BNOT Rn, @aa:8	B					4		(Rn8 of @aa:8) ← ¬ (Rn8 of @aa:8)	—	—	—	—
BTST	BTST #xx:3, Rd	B	2						¬ (#xx:3 of Rd8) → Z	—	—	—	↑
	BTST #xx:3, @ERd	B		4					¬ (#xx:3 of @ERd) → Z	—	—	—	↑
	BTST #xx:3, @aa:8	B				4			¬ (#xx:3 of @aa:8) → Z	—	—	—	↑
	BTST Rn, Rd	B	2						¬ (Rn8 of @Rd8) → Z	—	—	—	↑
	BTST Rn, @ERd	B		4					¬ (Rn8 of @ERd) → Z	—	—	—	↑
	BTST Rn, @aa:8	B					4		¬ (Rn8 of @aa:8) → Z	—	—	—	↑
BLD	BLD #xx:3, Rd	B	2						(#xx:3 of Rd8) → C	—	—	—	—

BST	BST #xx:3, Rd	B	2					$C \rightarrow (\#xx:3 \text{ of Rd8})$	—	—	—	—
	BST #xx:3, @ERd	B		4				$C \rightarrow (\#xx:3 \text{ of @ERd24})$	—	—	—	—
	BST #xx:3, @aa:8	B				4		$C \rightarrow (\#xx:3 \text{ of @aa:8})$	—	—	—	—
BIST	BIST #xx:3, Rd	B	2					$\neg C \rightarrow (\#xx:3 \text{ of Rd8})$	—	—	—	—
	BIST #xx:3, @ERd	B		4				$\neg C \rightarrow (\#xx:3 \text{ of @ERd24})$	—	—	—	—
	BIST #xx:3, @aa:8	B				4		$\neg C \rightarrow (\#xx:3 \text{ of @aa:8})$	—	—	—	—
BAND	BAND #xx:3, Rd	B	2					$C \wedge (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BAND #xx:3, @ERd	B		4				$C \wedge (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BAND #xx:3, @aa:8	B				4		$C \wedge (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BIAND	BIAND #xx:3, Rd	B	2					$C \wedge \neg (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BIAND #xx:3, @ERd	B		4				$C \wedge \neg (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BIAND #xx:3, @aa:8	B				4		$C \wedge \neg (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BOR	BOR #xx:3, Rd	B	2					$C \vee (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BOR #xx:3, @ERd	B		4				$C \vee (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BOR #xx:3, @aa:8	B				4		$C \vee (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BIOR	BIOR #xx:3, Rd	B	2					$C \vee \neg (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BIOR #xx:3, @ERd	B		4				$C \vee \neg (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BIOR #xx:3, @aa:8	B				4		$C \vee \neg (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BXOR	BXOR #xx:3, Rd	B	2					$C \oplus (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BXOR #xx:3, @ERd	B		4				$C \oplus (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BXOR #xx:3, @aa:8	B				4		$C \oplus (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—
BIXOR	BIXOR #xx:3, Rd	B	2					$C \oplus \neg (\#xx:3 \text{ of Rd8}) \rightarrow C$	—	—	—	—
	BIXOR #xx:3, @ERd	B		4				$C \oplus \neg (\#xx:3 \text{ of @ERd24}) \rightarrow C$	—	—	—	—
	BIXOR #xx:3, @aa:8	B				4		$C \oplus \neg (\#xx:3 \text{ of @aa:8}) \rightarrow C$	—	—	—	—

LDC	LDC #xx:8, CCR	B	2					#xx:8 → CCR	↑	↑	↑	↑	↑
	LDC Rs, CCR	B	2					Rs8 → CCR	↑	↑	↑	↑	↑
	LDC @ERs, CCR	W		4				@ERs → CCR	↑	↑	↑	↑	↑
	LDC @(d:16, ERs), CCR	W			6			@(d:16, ERs) → CCR	↑	↑	↑	↑	↑
	LDC @(d:24, ERs), CCR	W			10			@(d:24, ERs) → CCR	↑	↑	↑	↑	↑
	LDC @ERs+, CCR	W				4		@ERs → CCR ERs32+2 → ERs32	↑	↑	↑	↑	↑
	LDC @aa:16, CCR	W				6		@aa:16 → CCR	↑	↑	↑	↑	↑
	LDC @aa:24, CCR	W				8		@aa:24 → CCR	↑	↑	↑	↑	↑
STC	STC CCR, Rd	B	2					CCR → Rd8					
	STC CCR, @ERd	W		4				CCR → @ERd					
	STC CCR, @(d:16, ERd)	W			6			CCR → @(d:16, ERd)					
	STC CCR, @(d:24, ERd)	W			10			CCR → @(d:24, ERd)					
	STC CCR, @-ERd	W				4		ERd32-2 → ERd32 CCR → @ERd					
	STC CCR, @aa:16	W				6		CCR → @aa:16					
	STC CCR, @aa:24	W				8		CCR → @aa:24					
ANDC	ANDC #xx:8, CCR	B	2					CCR^#xx:8 → CCR	↑	↑	↑	↑	↑
ORC	ORC #xx:8, CCR	B	2					CCR∨#xx:8 → CCR	↑	↑	↑	↑	↑
XORC	XORC #xx:8, CCR	B	2					CCR⊕#xx:8 → CCR	↑	↑	↑	↑	↑
NOP	NOP	—					2	PC ← PC+2					

Instruction code:

1st byte		2nd byte	
AH	AL	BH	BL



AL / AH	0	1	2	3	4	5	6	7	8	9	A	B	C
0	NOP	Table A-2 (2)	STC	LDC	ORC	XORC	ANDC	LDC	ADD		Table A-2 (2)	Table A-2 (2)	
1	Table A-2 (2)	Table A-2 (2)	Table A-2 (2)	Table A-2 (2)	OR.B	XOR.B	AND.B	Table A-2 (2)	SUB		Table A-2 (2)	Table A-2 (2)	
2	MOV.B												
3	MOV.B												
4	BRA	BRN	BHI	BLS	BCC	BCS	BNE	BEQ	BVC	BVS	BPL	BMI	BGI
5	MULXU	DIVXU	MULXU	DIVXU	RTS	BSR	RTE	Table A-2 (2)	Table A-2 (2)		JMP		BSS
6	BSET	BNOT	BCLR	BTST	OR	XOR	AND	BSL					MOV
7					BOR	BXOR	BAND	BILD	BIST	MOV	Table A-2 (2)	Table A-2 (2)	EEMOV
8	ADD												
9	ADDX												
A	CMP												
B	SUBX												
C	OR												
D	XOR												
E	AND												

Instruction code:

1st byte		2nd byte	
AH	AL	BH	BL

BH AH/AL	0	1	2	3	4	5	6	7	8	9	A	B
01	MOV				LDC/STC				SLEEP			
0A	INC											
0B	ADDS					INC		INC		ADDS		
0F	DAA											
10	SHLL			SHLL					SHAL			SHAL
11	SHLR			SHLR					SHAR			SHAR
12	ROTXL			ROTXL					ROTL			ROTL
13	ROTXR			ROTXR					ROTR			ROTR
17	NOT			NOT			EXTU		EXTU			NEG
1A	DEC											
1B	SUBS					DEC		DEC		SUB		
1F	DAS											
58	BRA	BRN	BHI	BLS	BCC	BCS	BNE	BEQ	BVC	BVS	BPL	BMI
79	MOV	ADD	CMP	SUB	OR	XOR	AND					



CL	0	1	2	3	4	5	6	7	8	9	A	B
AH ALBH BLCH												
01406												
01C05	MULXS		MULXS									
01D05		DIVXS		DIVXS								
01F06				OR		XOR	AND					
7C06*1												
7C07*1			BTST		BOR	BXOR	BAND	BLD	BIOR	BIXOR	BIAND	BILD
7D06*1	BSET	BNOT	BCLR									
7D07*1	BSET	BNOT	BCLR									
7Eaa6*2												
7Eaa7*2			BTST		BOR	BXOR	BAND	BLD	BIOR	BIXOR	BIAND	BILD
7Faa6*2	BSET	BNOT	BCLR									
7Faa7*2	BSET	BNOT	BCLR									

Notes: 1. r is the register designation field.

BSET #0, @FF00

From table A.4:

$$I = L = 2, \quad J = K = M = N = 0$$

From table A.3:

$$S_1 = 2, \quad S_L = 2$$

Number of states required for execution = $2 \times 2 + 2 \times 2 = 8$

When instruction is fetched from on-chip ROM, branch address is read from on-chip ROM. on-chip RAM is used for stack area.

JSR @@ 30

From table A.4:

$$I = 2, \quad J = K = 1, \quad L = M = N = 0$$

From table A.3:

$$S_1 = S_J = S_K = 2$$

Number of states required for execution = $2 \times 2 + 1 \times 2 + 1 \times 2 = 8$

Note: * Depends on which on-chip peripheral module is accessed. See section 23.1, F
Addresses (Address Order).

ADDS	ADDS #1/2/4, ERd	1	
ADDX	ADDX #xx:8, Rd	1	
	ADDX Rs, Rd	1	
AND	AND.B #xx:8, Rd	1	
	AND.B Rs, Rd	1	
	AND.W #xx:16, Rd	2	
	AND.W Rs, Rd	1	
	AND.L #xx:32, ERd	3	
	AND.L ERs, ERd	2	
ANDC	ANDC #xx:8, CCR	1	
BAND	BAND #xx:3, Rd	1	
	BAND #xx:3, @ERd	2	1
	BAND #xx:3, @aa:8	2	1
Bcc	BRA d:8 (BT d:8)	2	
	BRN d:8 (BF d:8)	2	
	BHI d:8	2	
	BLS d:8	2	
	BCC d:8 (BHS d:8)	2	
	BCS d:8 (BLO d:8)	2	
	BNE d:8	2	
	BEQ d:8	2	
	BVC d:8	2	
	BVS d:8	2	
	BPL d:8	2	
	BMI d:8	2	
	BGE d:8	2	

	BCS d:16(BLO d:16)	2	
	BNE d:16	2	
	BEQ d:16	2	
	BVC d:16	2	
	BVS d:16	2	
	BPL d:16	2	
	BMI d:16	2	
	BGE d:16	2	
	BLT d:16	2	
	BGT d:16	2	
	BLE d:16	2	
<hr/>			
BCLR	BCLR #xx:3, Rd	1	
	BCLR #xx:3, @ERd	2	2
	BCLR #xx:3, @aa:8	2	2
	BCLR Rn, Rd	1	
	BCLR Rn, @ERd	2	2
	BCLR Rn, @aa:8	2	2
<hr/>			
BIAND	BIAND #xx:3, Rd	1	
	BIAND #xx:3, @ERd	2	1
	BIAND #xx:3, @aa:8	2	1
<hr/>			
BILD	BILD #xx:3, Rd	1	
	BILD #xx:3, @ERd	2	1
	BILD #xx:3, @aa:8	2	1

	BIXOR #xx:3, @aa:8	2	1
BLD	BLD #xx:3, Rd	1	
	BLD #xx:3, @ERd	2	1
	BLD #xx:3, @aa:8	2	1
BNOT	BNOT #xx:3, Rd	1	
	BNOT #xx:3, @ERd	2	2
	BNOT #xx:3, @aa:8	2	2
	BNOT Rn, Rd	1	
	BNOT Rn, @ERd	2	2
	BNOT Rn, @aa:8	2	2
BOR	BOR #xx:3, Rd	1	
	BOR #xx:3, @ERd	2	1
	BOR #xx:3, @aa:8	2	1
BSET	BSET #xx:3, Rd	1	
	BSET #xx:3, @ERd	2	2
	BSET #xx:3, @aa:8	2	2
	BSET Rn, Rd	1	
	BSET Rn, @ERd	2	2
	BSET Rn, @aa:8	2	2
BSR	BSR d:8	2	1
	BSR d:16	2	1
BST	BST #xx:3, Rd	1	
	BST #xx:3, @ERd	2	2
	BST #xx:3, @aa:8	2	2

	BXOR #xx:3, @aa:8	2	1
CMP	CMP.B #xx:8, Rd	1	
	CMP.B Rs, Rd	1	
	CMP.W #xx:16, Rd	2	
	CMP.W Rs, Rd	1	
	CMP.L #xx:32, ERd	3	
	CMP.L ERs, ERd	1	
DAA	DAA Rd	1	
DAS	DAS Rd	1	
DEC	DEC.B Rd	1	
	DEC.W #1/2, Rd	1	
	DEC.L #1/2, ERd	1	
DUVXS	DIVXS.B Rs, Rd	2	
	DIVXS.W Rs, ERd	2	
DIVXU	DIVXU.B Rs, Rd	1	
	DIVXU.W Rs, ERd	1	
EEPMOV	EEPMOV.B	2	$2n+2^{*1}$
	EEPMOV.W	2	$2n+2^{*1}$
EXTS	EXTS.W Rd	1	
	EXTS.L ERd	1	
EXTU	EXTU.W Rd	1	
	EXTU.L ERd	1	

	JSR @aa:8	2	1	1
LDC	LDC #xx:8, CCR	1		
	LDC Rs, CCR	1		
	LDC@ERs, CCR	2		1
	LDC@(d:16, ERs), CCR	3		1
	LDC@(d:24,ERs), CCR	5		1
	LDC@ERs+, CCR	2		1
	LDC@aa:16, CCR	3		1
	LDC@aa:24, CCR	4		1
MOV	MOV.B #xx:8, Rd	1		
	MOV.B Rs, Rd	1		
	MOV.B @ERs, Rd	1		1
	MOV.B @(d:16, ERs), Rd	2		1
	MOV.B @(d:24, ERs), Rd	4		1
	MOV.B @ERs+, Rd	1		1
	MOV.B @aa:8, Rd	1		1
	MOV.B @aa:16, Rd	2		1
	MOV.B @aa:24, Rd	3		1
	MOV.B Rs, @ERd	1		1
	MOV.B Rs, @(d:16, ERd)	2		1
	MOV.B Rs, @(d:24, ERd)	4		1
	MOV.B Rs, @-ERd	1		1
	MOV.B Rs, @aa:8	1		1

	MOV.W @aa:16, Rd	2	1
	MOV.W @aa:24, Rd	3	1
	MOV.W Rs, @ERd	1	1
	MOV.W Rs, @(d:16,ERd)	2	1
	MOV.W Rs, @(d:24,ERd)	4	1
MOV	MOV.W Rs, @-ERd	1	1
	MOV.W Rs, @aa:16	2	1
	MOV.W Rs, @aa:24	3	1
	MOV.L #xx:32, ERd	3	
	MOV.L ERs, ERd	1	
	MOV.L @ERs, ERd	2	2
	MOV.L @(d:16,ERs), ERd	3	2
	MOV.L @(d:24,ERs), ERd	5	2
	MOV.L @ERs+, ERd	2	2
	MOV.L @aa:16, ERd	3	2
	MOV.L @aa:24, ERd	4	2
	MOV.L ERs, @ERd	2	2
	MOV.L ERs, @(d:16,ERd)	3	2
	MOV.L ERs, @(d:24,ERd)	5	2
	MOV.L ERs, @-ERd	2	2
	MOV.L ERs, @aa:16	3	2
	MOV.L ERs, @aa:24	4	2
MOVFPPE	MOVFPPE @aa:16, Rd* ²	2	1
MOVTPPE	MOVTPPE Rs, @aa:16* ²	2	1

NOT	NOT.B Rd	1	
	NOT.W Rd	1	
	NOT.L ERd	1	
OR	OR.B #xx:8, Rd	1	
	OR.B Rs, Rd	1	
	OR.W #xx:16, Rd	2	
	OR.W Rs, Rd	1	
	OR.L #xx:32, ERd	3	
	OR.L ERs, ERd	2	
ORC	ORC #xx:8, CCR	1	
POP	POP.W Rn	1	1
	POP.L ERn	2	2
PUSH	PUSH.W Rn	1	1
	PUSH.L ERn	2	2
ROTL	ROTL.B Rd	1	
	ROTL.W Rd	1	
	ROTL.L ERd	1	
ROTR	ROTR.B Rd	1	
	ROTR.W Rd	1	
	ROTR.L ERd	1	
ROTXL	ROTXL.B Rd	1	
	ROTXL.W Rd	1	
	ROTXL.L ERd	1	

SHAR	SHAR.B Rd	1	
	SHAR.W Rd	1	
	SHAR.L ERd	1	
SHLL	SHLL.B Rd	1	
	SHLL.W Rd	1	
	SHLL.L ERd	1	
SHLR	SHLR.B Rd	1	
	SHLR.W Rd	1	
	SHLR.L ERd	1	
SLEEP	SLEEP	1	
STC	STC CCR, Rd	1	
	STC CCR, @ERd	2	1
	STC CCR, @(d:16,ERd)	3	1
	STC CCR, @(d:24,ERd)	5	1
	STC CCR, @-ERd	2	1
	STC CCR, @aa:16	3	1
	STC CCR, @aa:24	4	1
SUB	SUB.B Rs, Rd	1	
	SUB.W #xx:16, Rd	2	
	SUB.W Rs, Rd	1	
	SUB.L #xx:32, ERd	3	
	SUB.L ERs, ERd	1	
SUBS	SUBS #1/2/4, ERd	1	

- Notes:
1. n: Specified value in R4L. The source and destination operands are accessed n times respectively.
 2. It can not be used in this LSI.

transfer instructions	POP, PUSH	—	—	—	—	—	—	—	—	—	—	—	—
	MOVFP, MOVTP	—	—	—	—	—	—	—	—	—	—	—	—
Arithmetic operations	ADD, CMP	BWL	BWL	—	—	—	—	—	—	—	—	—	—
	SUB	WL	BWL	—	—	—	—	—	—	—	—	—	—
	ADDX, SUBX	B	B	—	—	—	—	—	—	—	—	—	—
	ADDS, SUBS	—	L	—	—	—	—	—	—	—	—	—	—
	INC, DEC	—	BWL	—	—	—	—	—	—	—	—	—	—
	DAA, DAS	—	B	—	—	—	—	—	—	—	—	—	—
	MULXU, MULXS, DIVXU, DIVXS	—	BW	—	—	—	—	—	—	—	—	—	—
	NEG	—	BWL	—	—	—	—	—	—	—	—	—	—
	EXTU, EXTS	—	WL	—	—	—	—	—	—	—	—	—	—
Logical operations	AND, OR, XOR	—	BWL	—	—	—	—	—	—	—	—	—	—
	NOT	—	BWL	—	—	—	—	—	—	—	—	—	—
Shift operations		—	BWL	—	—	—	—	—	—	—	—	—	—
Bit manipulations		—	B	B	—	—	—	B	—	—	—	—	—
Branching instructions	BCC, BSR	—	—	—	—	—	—	—	—	—	—	—	—
	JMP, JSR	—	—	○	—	—	—	—	—	—	○	○	—
	RTS	—	—	—	—	—	—	—	—	○	—	—	○
System control instructions	RTE	—	—	—	—	—	—	—	—	—	—	—	—
	SLEEP	—	—	—	—	—	—	—	—	—	—	—	—
	LDC	B	B	W	W	W	W	—	W	W	—	—	—
	STC	—	B	W	W	W	W	—	W	W	—	—	—
	ANDC, ORC, XORC	B	—	—	—	—	—	—	—	—	—	—	—
	NOP	—	—	—	—	—	—	—	—	—	—	—	—
Block data transfer instructions		—	—	—	—	—	—	—	—	—	—	—	—

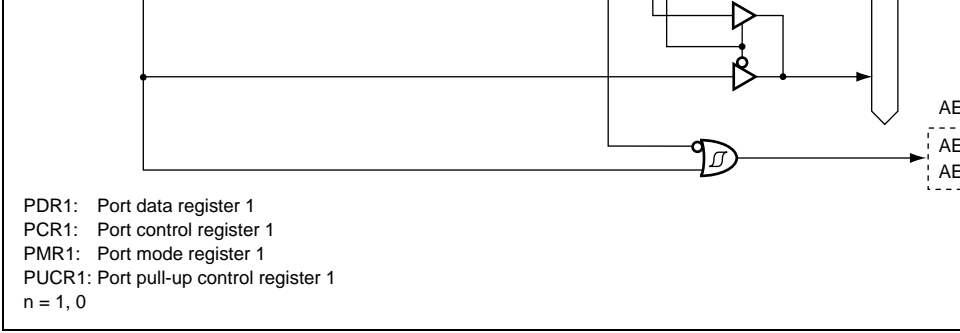


Figure B.1 (d) Port 1 Block Diagram (P11, P10)

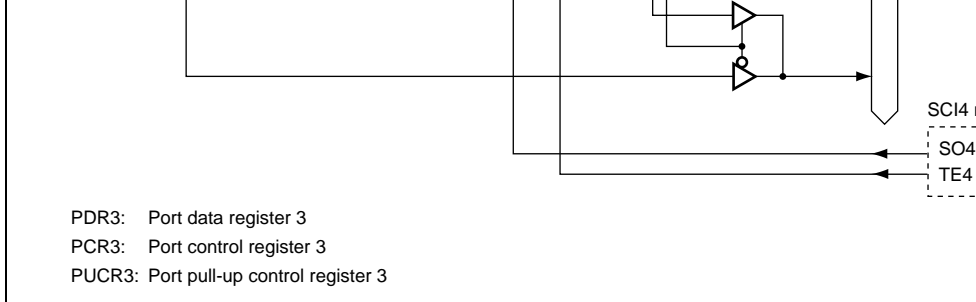


Figure B.2 (a) Port 3 Block Diagram (P37) (F-ZTAT Version)

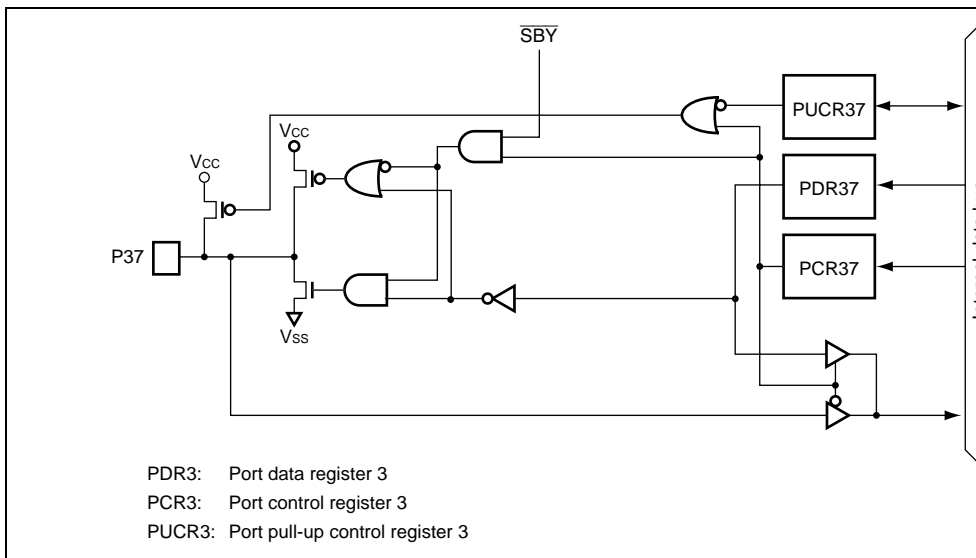


Figure B.2 (b) Port 3 Block Diagram (P37) (Masked ROM Version)

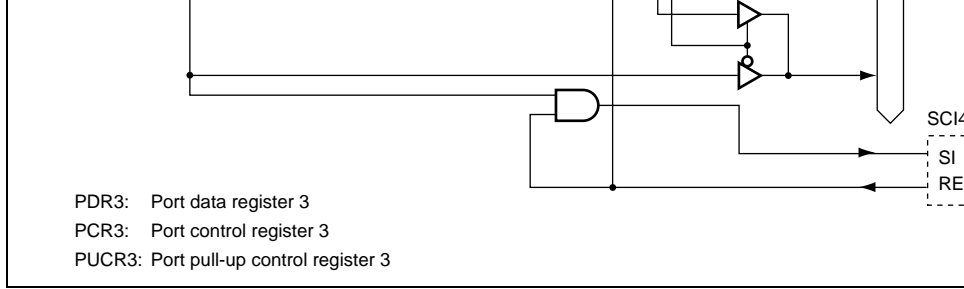


Figure B.2 (c) Port 3 Block Diagram (P36) (F-ZTAT Version)

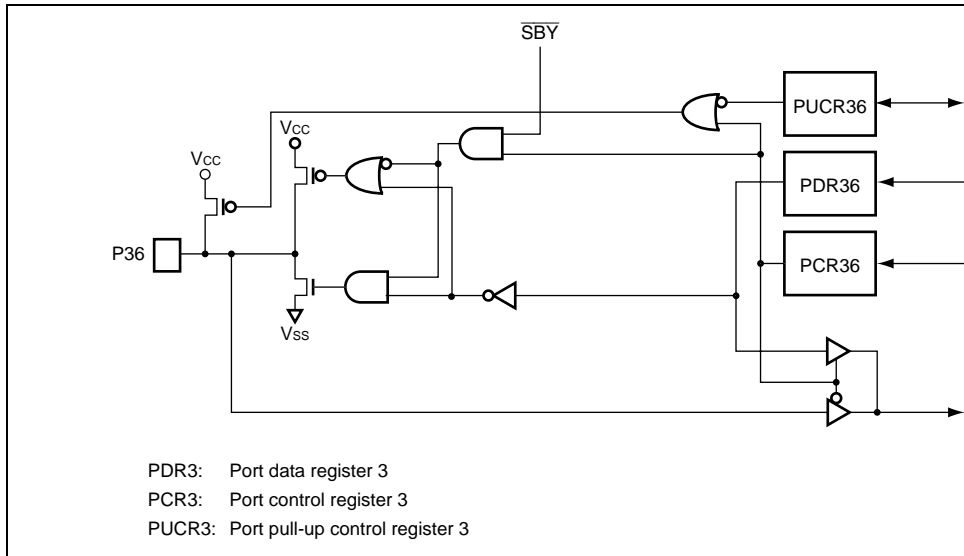


Figure B.2 (d) Port 3 Block Diagram (P36) (Masked ROM Version)

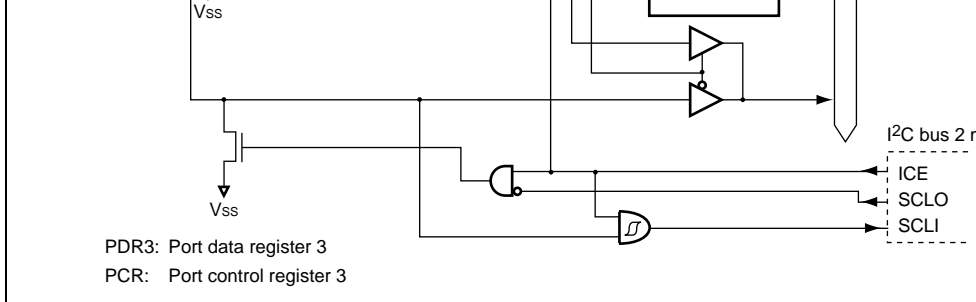


Figure B.2 (e) Port 3 Block Diagram (P32)

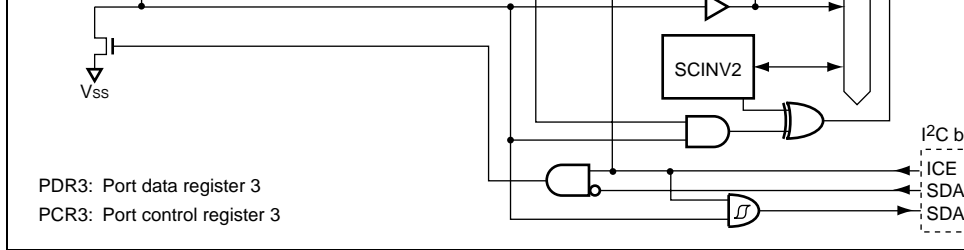


Figure B.2 (f) Port 3 Block Diagram (P31)

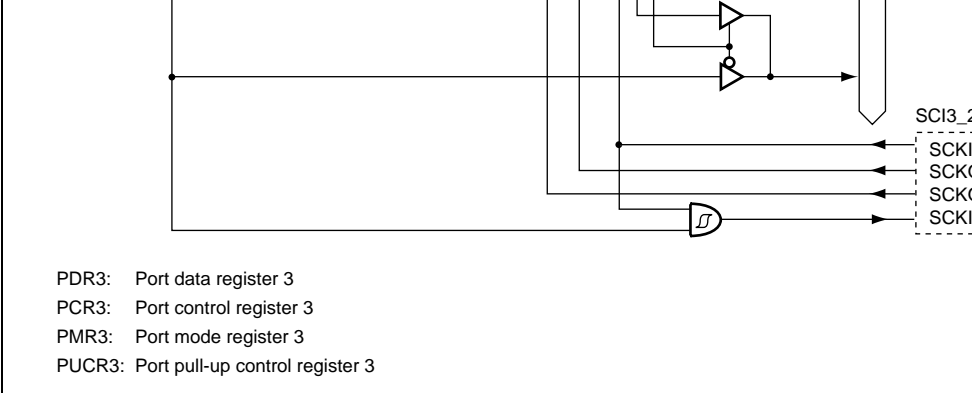


Figure B.2 (g) Port 3 Block Diagram (P30)

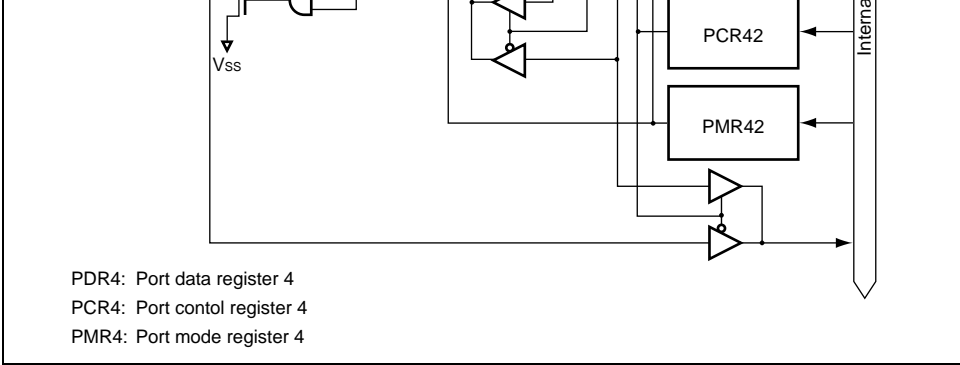


Figure B.3 (a) Port 4 Block Diagram (P42)

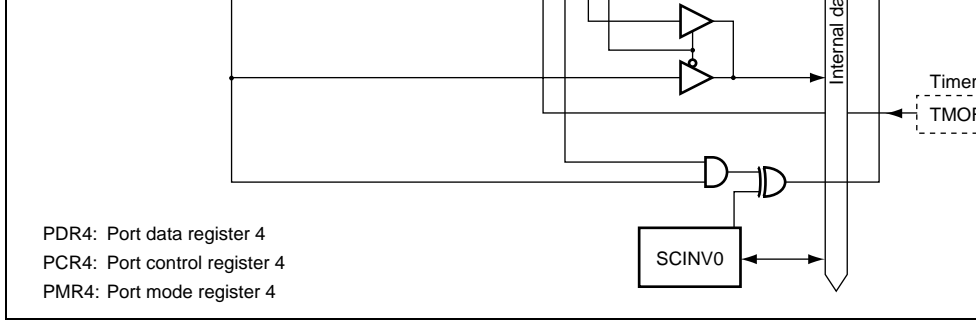


Figure B.3 (b) Port 4 Block Diagram (P41)

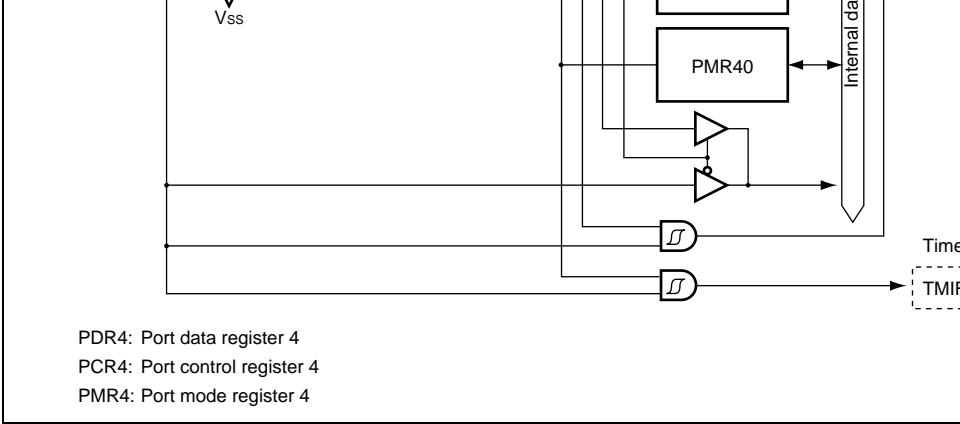


Figure B.3 (c) Port 4 Block Diagram (P40)

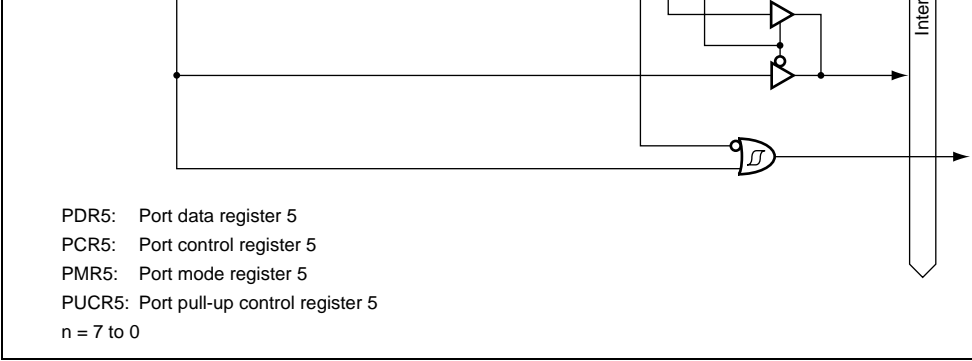


Figure B.4 Port 5 Block Diagram

PDR6: Port data register 6
 PCR6: Port control register 6
 PUCR6: Port pull-up control register 6
 n = 7 to 0

Figure B.5 Port 6 Block Diagram

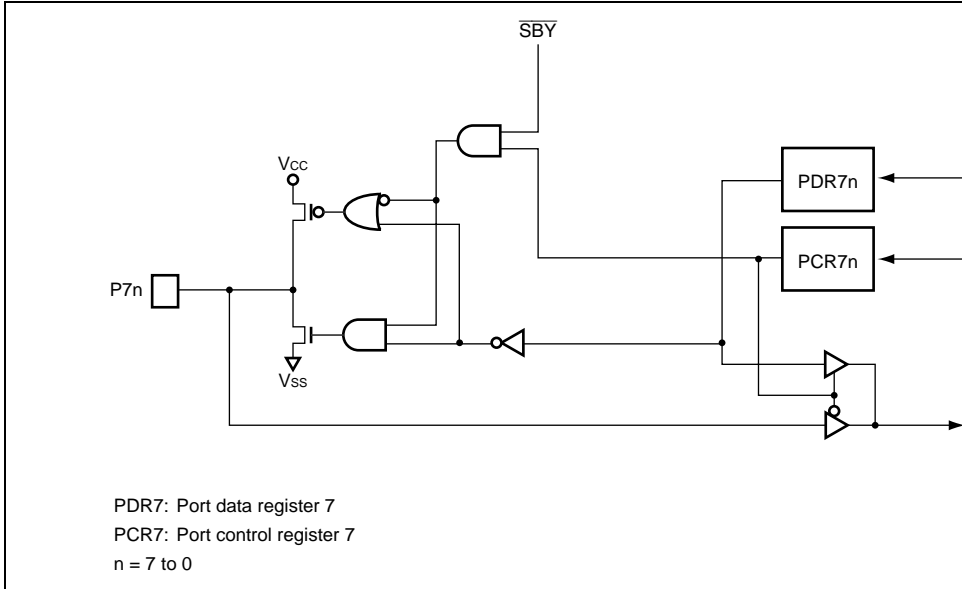


Figure B.6 Port 7 Block Diagram

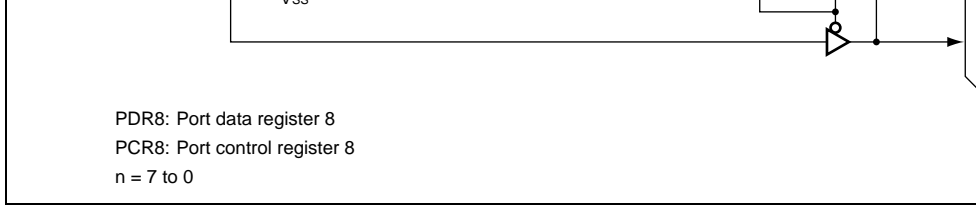


Figure B.7 Port 8 Block Diagram

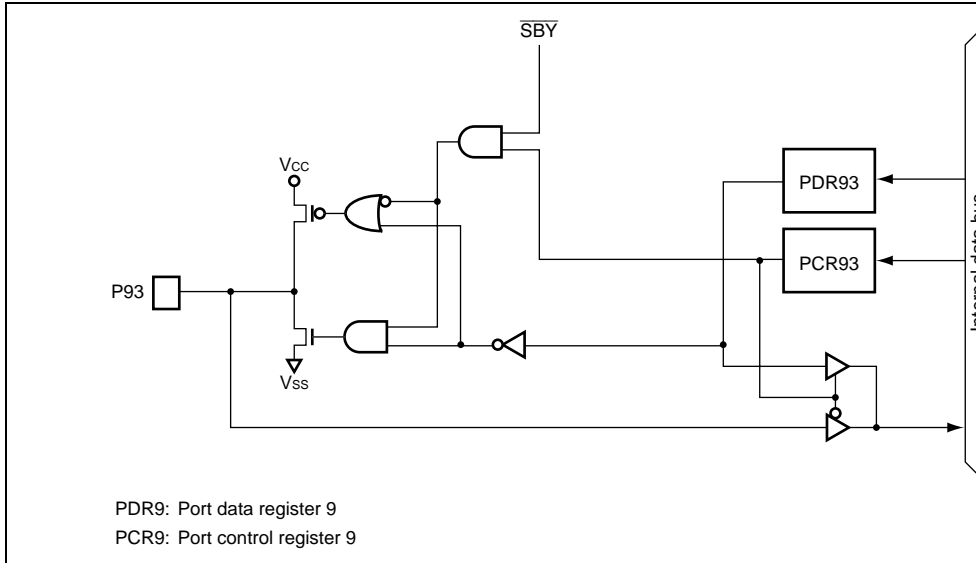
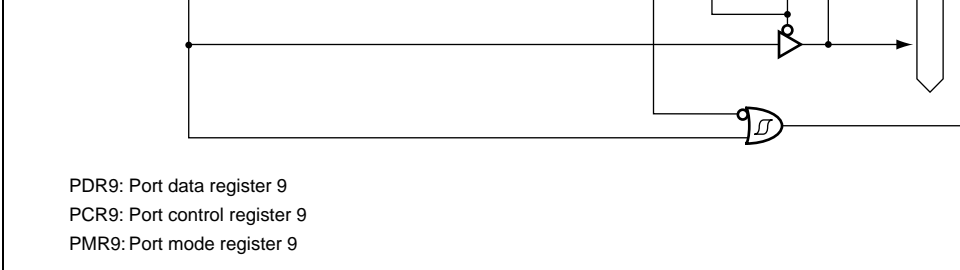


Figure B.8 (a) Port 9 Block Diagram (P93)



PDR9: Port data register 9
 PCR9: Port control register 9
 PMR9: Port mode register 9

Figure B.8 (b) Port 9 Block Diagram (P92)



PDR9: Port data register 9
 PCR9: Port control register 9
 PMR9: Port mode register 9
 n = 1, 0

Figure B.8 (c) Port 9 Block Diagram (P91, P90)

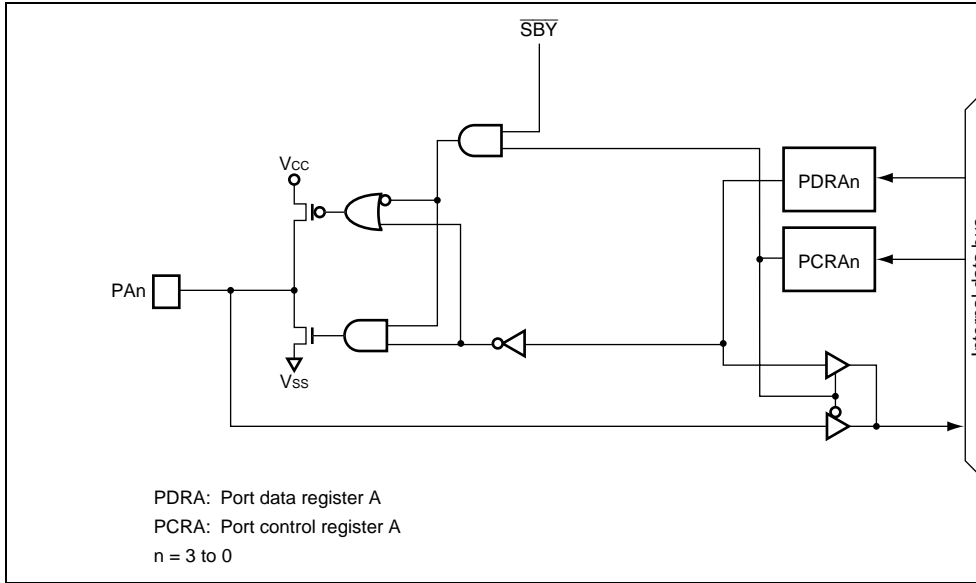


Figure B.9 Port A Block Diagram

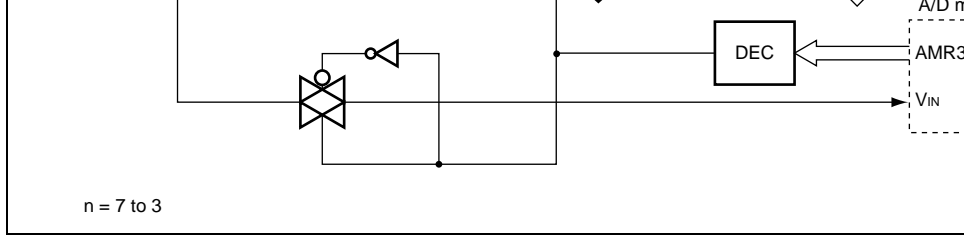


Figure B.10 (a) Port B Block Diagram (PB7 to PB3)

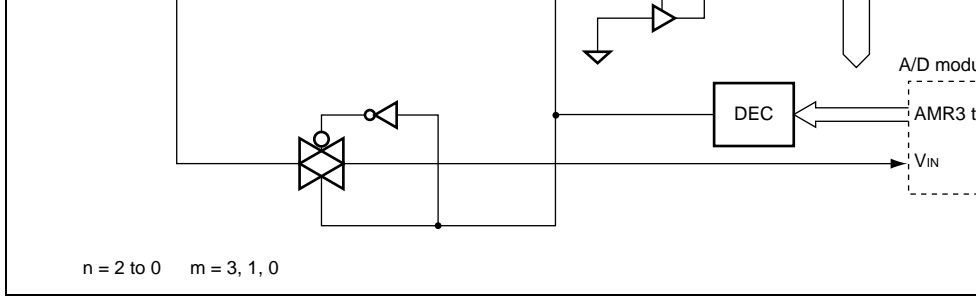


Figure B.10 (b) Port B Block Diagram (PB2 to PB0)

P57 to P50	High impedance	Retained	Retained	High impedance*	Functioning	Functioning
P67 to P60	High impedance	Retained	Retained	High impedance*	Functioning	Functioning
P77 to P70	High impedance	Retained	Retained	High impedance*	Functioning	Functioning
P87 to P80	High impedance	Retained	Retained	High impedance*	Functioning	Functioning
P93 to P90	High impedance	Retained	Retained	High impedance*	Functioning	Functioning
PA3 to PA0	High impedance	Retained	Retained	High impedance*	Functioning	Functioning
PB7 to PB5, PB4, PB3, PB2 to PB0	High impedance	High impedance	High impedance	High impedance*	High impedance	High impedance

Notes: * Registers are retained and output level is high impedance.

		HCD64F38076RCP10	F38076RCP10	Chip
		HCD64F38076RC4	—	Chip
		HCD64F38076RC10	—	Chip
Wide-range specifications		HD64F38076RH10W	F38076H10	80 pin QFF
		HD64F38076RW10W	F38076W10	80 pin TQFP
		HD64F38076RLP10WV	F38076RLP10WV	80 pin P-TL (TLP-85V)
Masked ROM version	Regular specifications	HD64338076RH	38076(***)H	80 pin QFF
		HD64338076RW	38076(***)W	80 pin TQFP
		HD64338076RLPV	38076R(***)LPV	80 pin P-TL (TLP-85V)
		HCD64338076R	—	Chip
Wide-range specifications		HD64338076RHW	38076(***)H	80 pin QFF
		HD64338076RWW	38076(***)W	80 pin TQFP
		HD64338076RLPWV	38076R(***)LPWV	80 pin P-TL (TLP-85V)

				(TLP-85V)	
H8/38074R	Masked ROM version	Regular specifications	HD64338074RH	38074(***)H	80 pin QF
			HD64338074RW	38074(***)W	80 pin TQ
			HD64338074RLPV	38074R(***)LPV	80 pin P-T (TLP-85V)
			HCD64338074R	—	Chip
	Wide-range specifications	HD64338074RHW	38074(***)H	80 pin QF	
		HD64338074RWW	38074(***)W	80 pin TQ	
		HD64338074RLPWV	38074R(***)LPWV	80 pin P-T (TLP-85V)	
H8/38073R	Masked ROM version	Regular specifications	HD64338073RH	38073(***)H	80 pin QF
			HD64338073RW	38073(***)W	80 pin TQ
			HD64338073RLPV	38073R(***)LPV	80 pin P-T (TLP-85V)
			HCD64338073R	—	Chip
	Wide-range specifications	HD64338073RHW	38073(***)H	80 pin QF	
		HD64338073RWW	38073(***)W	80 pin TQ	
		HD64338073RLPWV	38073R(***)LPWV	80 pin P-T (TLP-85V)	

[Legend]

(***) : ROM code

JEITA Package Code P-QFP80-14X14-0.65	RENESAS Code PRQP080UBA	Previous Code FP-80A/FP-80AV	MASST[yp.] 12g
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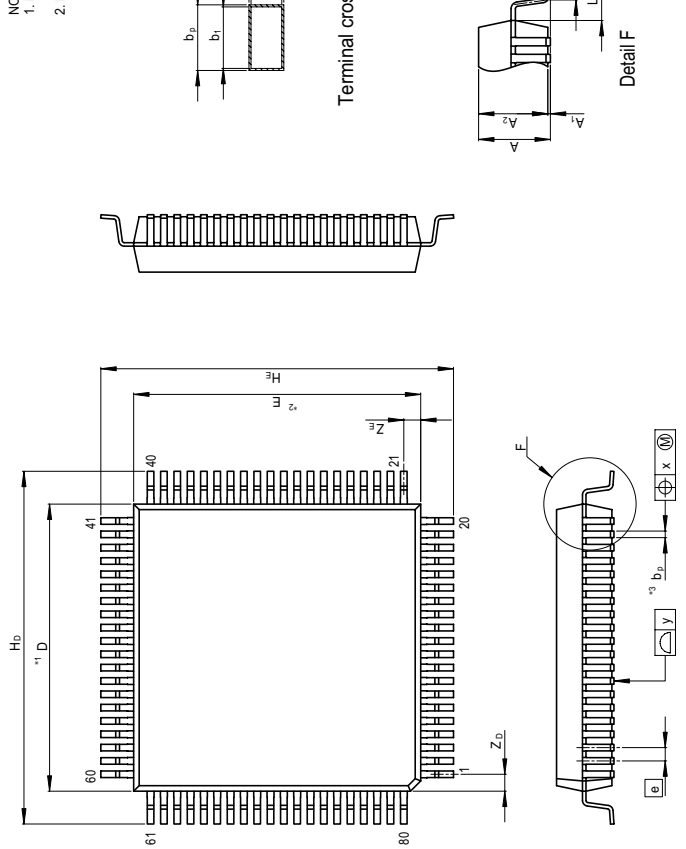


Figure D.1 Package Dimensions (FP-80A)

JEITA Package Code P-TQFP80-12x12-0.50	RENESAS Code PTQP080KC-A	Previous Code TFP-80C/TFP-80CV	MASS[Typ.] 0.4g
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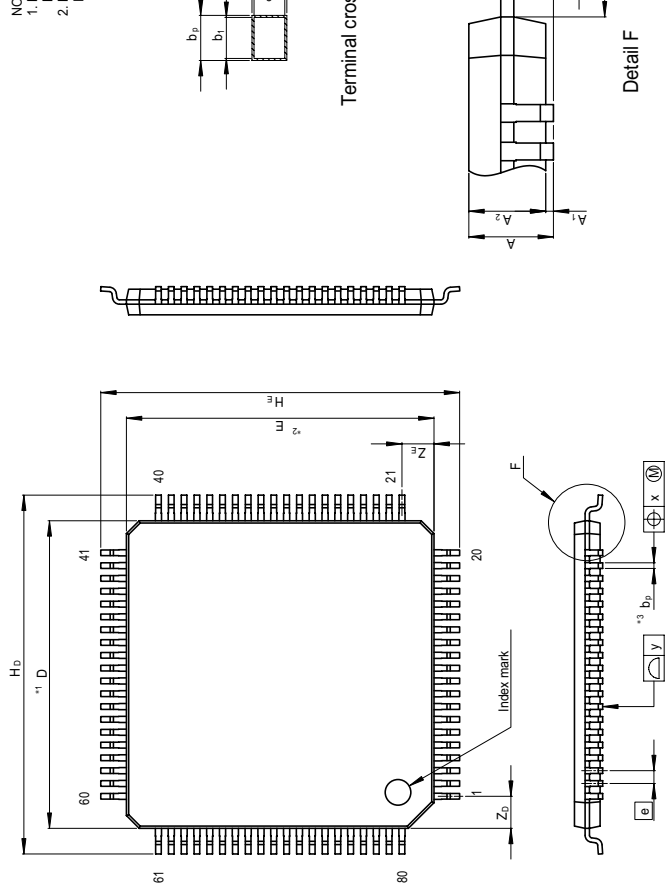


Figure D.2 Package Dimensions (TFP-80C)

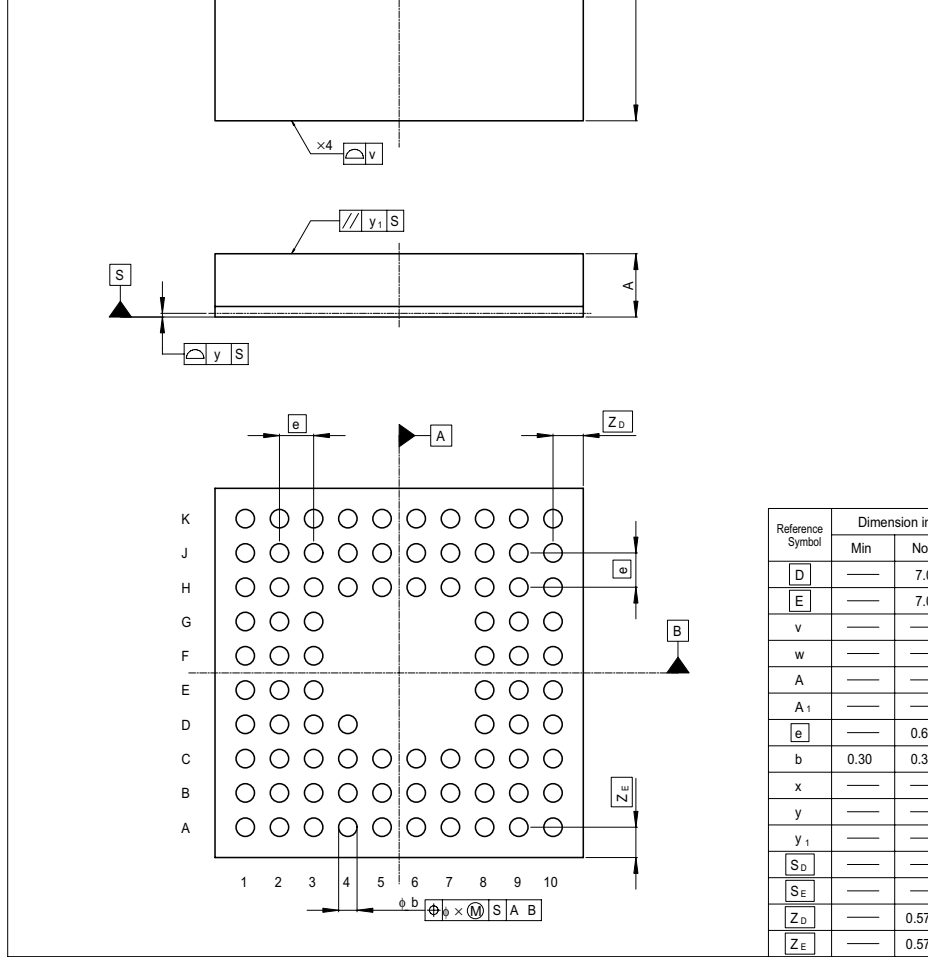


Figure D.3 Package Dimensions (TLP-85V)

Unit: mm

**Figure E.1 Cross-Sectional View of Chip
(HCD64338076R, HCD64338075R, HCD64338074R, and HCD64338073R)**

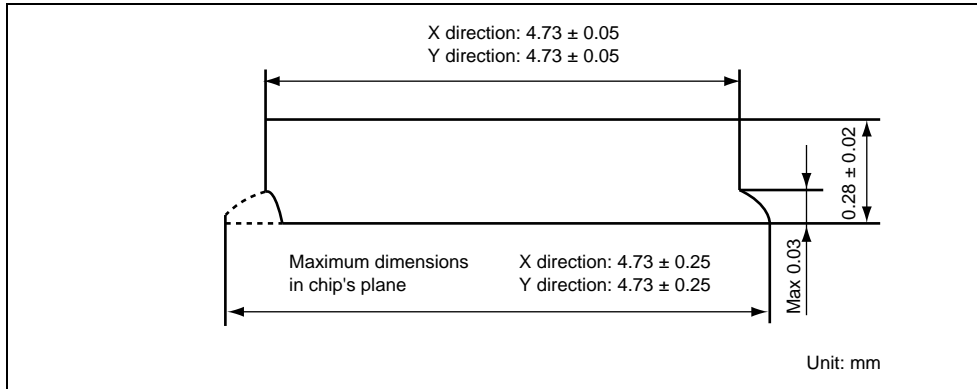


Figure E.2 Cross-Sectional View of Chip (HCD64F38076R)

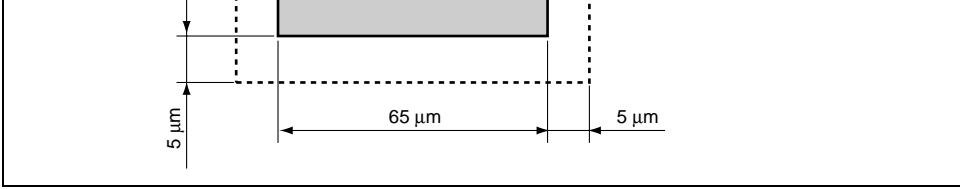
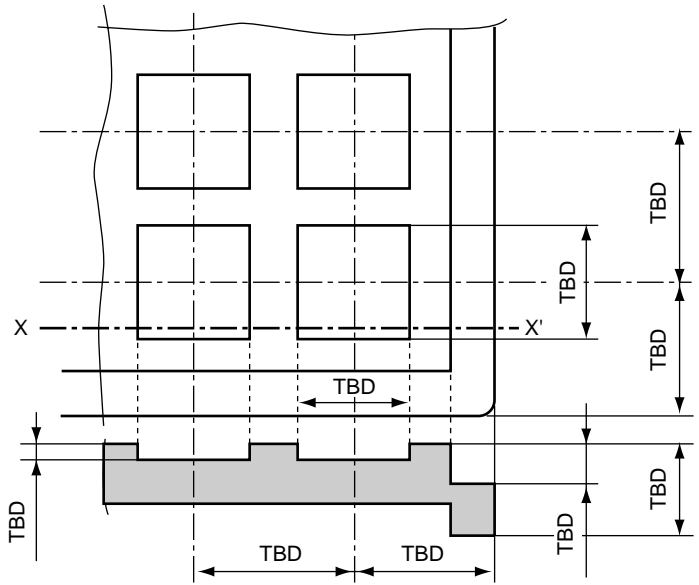


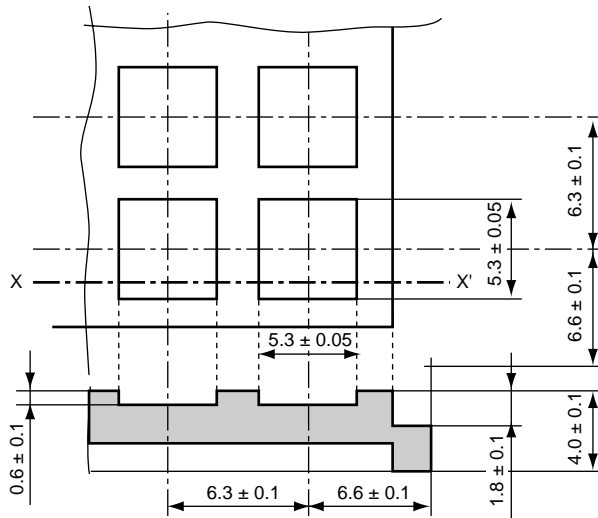
Figure F.1 Bonding Pad Form
(HCD64F38076R, HCD64338076R, HCD64338075R, HCD64338074R, and HCD64338073R)



X-X'

Unit: mm

Figure G.1 Chip Tray Specifications
(HCD64338076R, HCD64338075R, HCD64338074R, and HCD64338073R)



Cross-sectional view: X to X'

Unit: mm

Figure G.2 Chip Tray Specifications (HCD64F38076R)

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**Renesas 16-Bit Single-Chip Microcomputer
Hardware Manual
H8/38076R Group**

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